

# HAP-S1

## SERVICE MANUAL

Ver. 1.0 2013.10

US Model  
Canadian Model  
AEP Model  
UK Model



### Note:

Be sure to keep your PC used for service and checking of this unit always updated with the latest version of your anti-virus software. In case a virus affected unit was found during service, contact your Service Headquarters.

## SPECIFICATIONS

### AUDIO POWER SPECIFICATIONS

#### POWER OUTPUT AND TOTAL HARMONIC DISTORTION (for the USA and Canada only):

With 4 ohm loads, both channels driven, from 20 - 20,000Hz; rated 32 watts per channel minimum RMS power, with no more than 10 % total harmonic distortion from 250 milliwatts to rated output.

#### Amplifier section

POWER OUTPUT: 40 W + 40 W (4 ohms, 1 kHz, THD 10%)  
Rated Power Output: 35 W + 35 W (4 ohms, 1 kHz, THD 0.9%)  
Speaker impedance match: 4 ohms - 16 ohms  
S/N ratio: 100 dB (20 kHz LPF, A Network)  
Frequency response: 10 Hz - 100 kHz (+0 dB, -3 dB) (4 ohms, LINE IN)

#### Network section

##### Wired LAN

1000BASE-T/100BASE-TX/10BASE-T

##### Wireless LAN

Compatible standards: IEEE 802.11 b/g/n  
Frequency band/channel: 2.4 GHz band, channels 1-11 (models for the USA and Canada), channels 1-13 (models for Europe)

#### HDD section

##### Capacity

500 GB (\*)

\* Some portions of the capacity are used for data management. Therefore, the capacity a user can use is less than 500 GB.

#### Supported playback format

DSD (DSF, DSDIFF), LPCM (WAV, AIFF), FLAC, ALAC, ATRAC Advanced Lossless, ATRAC, MP3, AAC, WMA (2 channels)

#### Jack section

##### Input section

###### COAXIAL IN

Input impedance: 75 ohms

Supported playback format: LPCM 2ch

- Sampling frequency: 44.1 kHz, 48 kHz, 88.2 kHz, 96 kHz, 176.4 kHz, 192 kHz
- Quantization bits: 16 bits, 24 bits

###### OPTICAL IN

Supported playback format: LPCM 2ch

- Sampling frequency: 44.1 kHz, 48 kHz, 88.2 kHz, 96 kHz
- Quantization bits: 16 bits, 24 bits

##### LINE IN 1, 2

Input sensitivity: 500 mV

Input impedance: 100 kilohms

##### Output section

Output jacks

##### LINE OUT

Output impedance: 2.2 kilohms

2 Hz - 80 kHz (-3 dB)

##### PHONES (headphone jack)

Stereo jack: 8 ohms or higher

##### EXT port

Type A USB, Hi-Speed USB, for connecting an external hard disk drive

##### General and others

##### Power requirements

Models for the USA and Canada: AC 120 V 60 Hz

Models for Europe: AC 230 V 50/60 Hz

##### Power consumption

###### Models for the USA and Canada

On: 80 W

During standby mode (when [Network Standby] is set to [Off]): 0.3 W

During standby mode (when [Network Standby] is set to [On] and a wired LAN is used): 2.6 W

During standby mode (when [Network Standby] is set to [On] and a wireless LAN is used): 2.8 W

###### Models for Europe

On: 85 W

During standby mode (when [Network Standby] is set to [Off]): 0.3 W

During standby mode (when [Network Standby] is set to [On] and a wired LAN is used): 2.6 W

During standby mode (when [Network Standby] is set to [On] and a wireless LAN is used): 2.8 W

##### Dimensions (approx.) (w/h/d)

265 mm × 88 mm × 304 mm (10 1/2 in. × 3 1/2 in. × 12 in.) including projecting parts and controls

##### Mass (approx.)

5.8 kg (12 lbs 12 5/8 oz)

##### Supplied accessories

Remote control (1)

R03 (size-AAA) batteries (2)

AC power cord (mains lead) (1)

LAN cable (1)

Design and specifications are subject to change without notice.

## HDD AUDIO PLAYER SYSTEM

9-893-833-01

2013J33-1

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Sony Corporation

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## NOTES ON CHIP COMPONENT REPLACEMENT

- Never reuse a disconnected chip component.
- Notice that the minus side of a tantalum capacitor may be damaged by heat.

## FLEXIBLE CIRCUIT BOARD REPAIRING

- Keep the temperature of soldering iron around 270 °C during repairing.
- Do not touch the soldering iron on the same conductor of the circuit board (within 3 times).
- Be careful not to apply force on the conductor when soldering or unsoldering.

## SAFETY CHECK-OUT

After correcting the original service problem, perform the following safety check before releasing the set to the customer:

Check the antenna terminals, metal trim, "metallized" knobs, screws, and all other exposed metal parts for AC leakage.

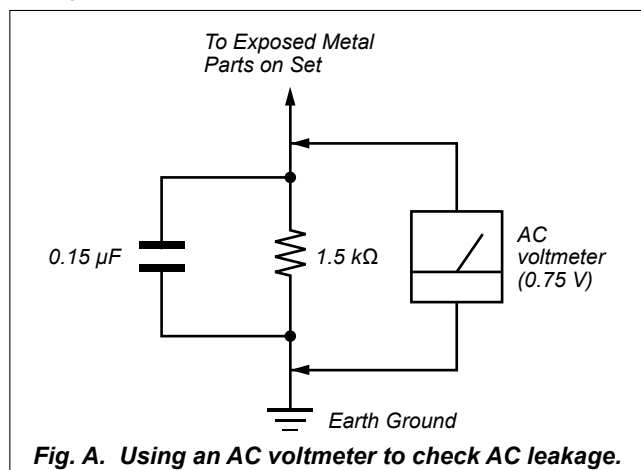
Check leakage as described below.

## LEAKAGE TEST

The AC leakage from any exposed metal part to earth ground and from all exposed metal parts to any exposed metal part having a return to chassis, must not exceed 0.5 mA (500 microamperes.).

Leakage current can be measured by any one of three methods.

1. A commercial leakage tester, such as the Simpson 229 or RCA WT-540A. Follow the manufacturers' instructions to use these instruments.
2. A battery-operated AC milliammeter. The Data Precision 245 digital multimeter is suitable for this job.
3. Measuring the voltage drop across a resistor by means of a VOM or battery-operated AC voltmeter. The "limit" indication is 0.75 V, so analog meters must have an accurate low-voltage scale. The Simpson 250 and Sanwa SH-63Trd are examples of a passive VOM that is suitable. Nearly all battery operated digital multimeters that have a 2 V AC range are suitable. (See Fig. A)



## SAFETY-RELATED COMPONENT WARNING!

COMPONENTS IDENTIFIED BY MARK  $\triangle$  OR DOTTED LINE WITH MARK  $\triangle$  ON THE SCHEMATIC DIAGRAMS AND IN THE PARTS LIST ARE CRITICAL TO SAFE OPERATION. REPLACE THESE COMPONENTS WITH SONY PARTS WHOSE PART NUMBERS APPEAR AS SHOWN IN THIS MANUAL OR IN SUPPLEMENTS PUBLISHED BY SONY.

## ATTENTION AU COMPOSANT AYANT RAPPORT À LA SÉCURITÉ!

LES COMPOSANTS IDENTIFIÉS PAR UNE MARQUE  $\triangle$  SUR LES DIAGRAMMES SCHÉMATIQUES ET LA LISTE DES PIÈCES SONT CRITIQUES POUR LA SÉCURITÉ DE FONCTIONNEMENT. NE REMPLACER CES COMPOSANTS QUE PAR DES PIÈCES SONY DONT LES NUMÉROS SONT DONNÉS DANS CE MANUEL OU DANS LES SUPPLÉMENTS PUBLIÉS PAR SONY.

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Accessories are given in the last of the electrical parts list.
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## SECTION 1 SERVICING NOTES

### UNLEADED SOLDER

Boards requiring use of unleaded solder are printed with the lead-free mark (LF) indicating the solder contains no lead.

**(Caution:** Some printed circuit boards may not come printed with the lead free mark due to their particular size)

### : LEAD FREE MARK

Unleaded solder has the following characteristics.

- Unleaded solder melts at a temperature about 40 °C higher than ordinary solder.

Ordinary soldering irons can be used but the iron tip has to be applied to the solder joint for a slightly longer time.

Soldering irons using a temperature regulator should be set to about 350 °C.

**Caution:** The printed pattern (copper foil) may peel away if the heated tip is applied for too long, so be careful!

- Strong viscosity  
Unleaded solder is more viscous (sticky, less prone to flow) than ordinary solder so use caution not to let solder bridges occur such as on IC pins, etc.
- Usable with ordinary solder  
It is best to use only unleaded solder but unleaded solder may also be added to ordinary solder.

### ABOUT THE ALLEGRO-ANT-L BOARD AND ALLEGRO-ANT-R BOARD

ALLEGRO-ANT-L and ALLEGRO-ANT-R boards are not covered in the servicing.

### NOTE OF REPLACING THE IC101, IC301, IC302, IC501 AND IC602 ON THE MAIN BOARD

IC101, IC301, IC302, IC501 and IC602 on the MAIN board cannot exchange with single. When these parts are damaged, exchange the complete mounted board.

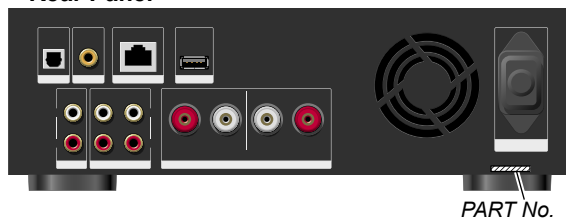
### NOTE OF REPLACING THE IC001 AND IC702 ON THE FPGA DSP BOARD

IC001 and IC702 on the FPGA DSP board cannot exchange with single. When these parts are damaged, exchange the complete mounted board.

### DESTINATION IDENTIFICATION

Distinguish by Part No. on the rear side of a main unit.

#### – Rear Panel –



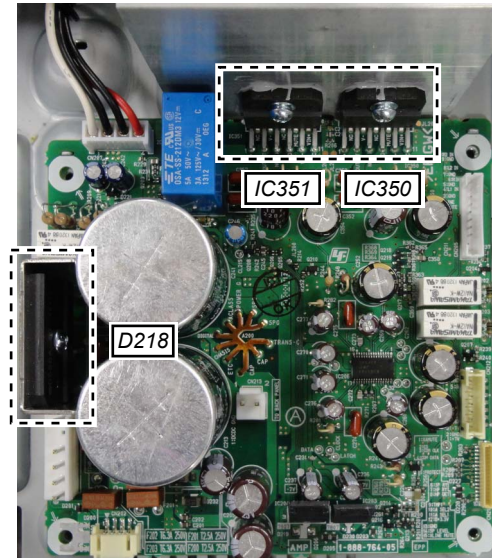
Destination	Part No.
US and Canadian models	4-464-753-1□
AEP and UK models	4-464-753-2□

### NOTE OF REPLACING THE D218, IC350 AND IC351 ON THE AMP BOARD AND THE COMPLETE AMP BOARD

When D218, IC350 and IC351 on the AMP board and the complete AMP board are replaced, it is necessary to spread the compound between these parts and the heat sink.

Spread the compound (TB2955Q) referring to the figure below.

#### – AMP Board (Component Side) –



### NOTE OF REPLACING THE HARD DISK DRIVE (Ref. No. HDD1)

When the hard disk drive (Ref. No. HDD1) is replaced, be sure to carry out the “Factory Reset” according to the following procedure.

Resetting to the factory default (Factory Reset)

You can reset the HDD AUDIO PLAYER to the factory default settings. All settings you have configured and all of the content stored on the internal hard disk drive will be deleted. (Sample tracks saved on the internal hard disk drive by default remain.)

1. Select [Settings] - [System Settings] in the Home screen.
2. Select [Factory Reset].
3. Select [Yes].  
The Factory Reset waiting screen appears.
4. When the Factory Reset complete screen appears, select [OK].  
When the Factory Reset is complete, the HDD AUDIO PLAYER restarts automatically.

#### Note

- If you perform the Factory Reset function while playing tracks, playback of the music files stops.
- If you perform the Factory Reset function while transferring music files, transfer of the music files stops.
- If you want to re-transfer music files that were transferred to the HDD AUDIO PLAYER before you performed the Factory Reset function, select the backup folder and check “Watch” in the Contents Settings window of HAP Music Transfer. Go to the Transfer Settings window and select [Clear] for [Transferred Files List] to delete the transfer history, and then automatically or manually transfer the files.

**NOTE OF REPLACING THE COMPLETE MAIN BOARD**

When the complete MAIN board is replaced, the following settings that is recorded on the MAIN board are cleared, and returned to their initial values.

- Network Settings
- Language, Brightness, Auto Standby, Sleep and Software Update Notification of System Settings
- DSEE and Volume Normalization of Audio Settings

Take the following step.

**Procedure:**

1. At the time of operation check after replacing the complete MAIN board, set the language same as the language settings that a customer was set, and returns the this unit to the customer.
2. Display the “1.Version Info” of the service DIAG mode on the liquid crystal display, and check that “3. Region” and “4. Model” accord with the customer’s unit.  
(Refer to “4-1. Version Info” on page 31)
3. Check the version of the “1. uCON ver.” and “2. MPU ver.” of “1.Version Info” is displayed on the liquid crystal display, and when it is not the latest version, carry out the “Network Update” of the “Settings”, and update to the latest version.

**Note:** After replacing the complete MAIN board, it is not necessary to carry out the “Factory Reset”.

Be careful to carry out the “Factory Reset”, and not to delete the contents in the hard disk drive (Ref. No. HDD1).

4. After replacing the complete MAIN board, an initial setting screen is displayed on the liquid crystal display at the time of the first start up, but is not displayed on the next time when it has been started up once.

When returning the unit that repair was completed to the customer, print and cut out the following explanation, and hand it over with the unit.

The MAC address for the wired LAN has been changed by this repair.

Customers who use the MAC address filtering function of the connected access point equipment should set it again.

Also, the following settings have been cleared and returned to their initial values.

Please set the following settings again.

- Network Settings
- Language, Brightness, Auto Standby, Sleep and Software Update Notification of System Settings
- DSEE and Volume Normalization of Audio Settings

**Note:** There are two kinds of MAC addresses, wired and wireless. Only wired MAC addresses are changed by this repair.

**CHECKING METHOD OF NETWORK CONNECTION**

It is necessary to check the network connection, when replacing the complete MAIN board, WLAN/BT COMBO card (Ref. No. WBC1) or coaxial (U.FL connector) cable (Ref. No. WR1, WR2). Check the connection of wireless and wired LAN, according to the following method.

If the WLAN/BT COMBO card has been changed, when returning the unit to the customer, print and cut out the following explanation, and hand it over with the unit.

The MAC address for the wireless LAN has been changed by this repair.

Customers who use the MAC address filtering function of the connected access point equipment should set it again.

**Note:** There are two kinds of MAC addresses, wired and wireless. Only wireless MAC addresses are changed by this repair.

**1. Checking Method of Wireless LAN Connection****Necessary Equipment:**

- Access point supporting WPS

**Procedure:**

1. Press the [I/⏻] key to turn the power on.
2. Press the [HOME] key to the display the “Home” menu on the liquid crystal display.
3. Rotate the [PUSH ENTER] knob to select “Settings” and press the [PUSH ENTER] knob.
4. Rotate the [PUSH ENTER] knob to select “Network Settings” and press the [PUSH ENTER] knob.
5. Rotate the [PUSH ENTER] knob to select “Internet Settings” and press the [PUSH ENTER] knob.
6. Rotate the [PUSH ENTER] knob to select “Wireless Setup” and press the [PUSH ENTER] knob.
7. Rotate the [PUSH ENTER] knob to select “Wi-Fi Protected Setup (WPS)” and press the [PUSH ENTER] knob.
8. After “Start” is displayed on the liquid crystal display, and press the [PUSH ENTER] knob.
9. Press the [WPS] key on the access point.
10. After “Next” is displayed on the liquid crystal display, press the [PUSH ENTER] knob.
11. When check of wireless LAN connection is completed, “Wireless Connection: OK” and “Internet Access: OK” and is displayed on the liquid crystal display.
12. Press the [PUSH ENTER] knob, and press the [I/⏻] key to turn the power off.

**Note:** Refer to the help guide about details of the checking method.

**2. Checking method of wired LAN connection****Necessary Equipment:**

- Router
- LAN cable

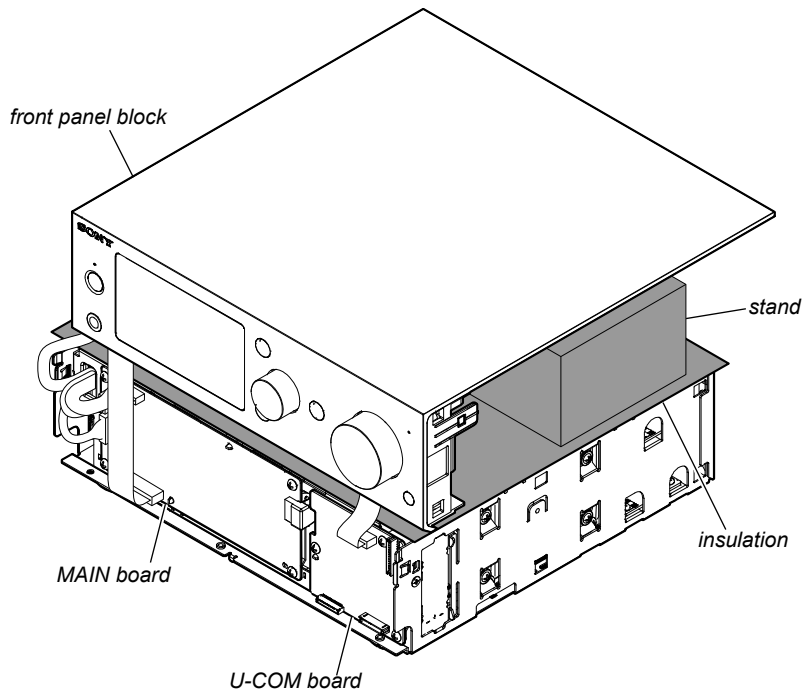
**Procedure:**

1. Connect the main unit to the router with the network LAN cable.
2. Press the [HOME] key to the display the “Home” menu on the liquid crystal display.
3. Rotate the [PUSH ENTER] knob to select “Settings” and press the [PUSH ENTER] knob.
4. Rotate the [PUSH ENTER] knob to select “Network Settings” and press the [PUSH ENTER] knob.
5. Rotate the [PUSH ENTER] knob to select “Internet Settings” and press the [PUSH ENTER] knob.
6. Rotate the [PUSH ENTER] knob to select “Wired Setup” and press the [PUSH ENTER] knob.
7. Rotate the [PUSH ENTER] knob to select “Auto” and press the [PUSH ENTER] knob.
8. After “Next” is displayed on the liquid crystal display, press the [PUSH ENTER] knob.
9. Rotate the [PUSH ENTER] knob to select “Save & Connect” and press the [PUSH ENTER] knob.
10. When wired LAN connection is completed, “Physical Connection: OK” and “Internet Access: OK” and is displayed on the liquid crystal display.
11. Press the [PUSH ENTER] knob, and press the [I/⏻] key to turn the power off.

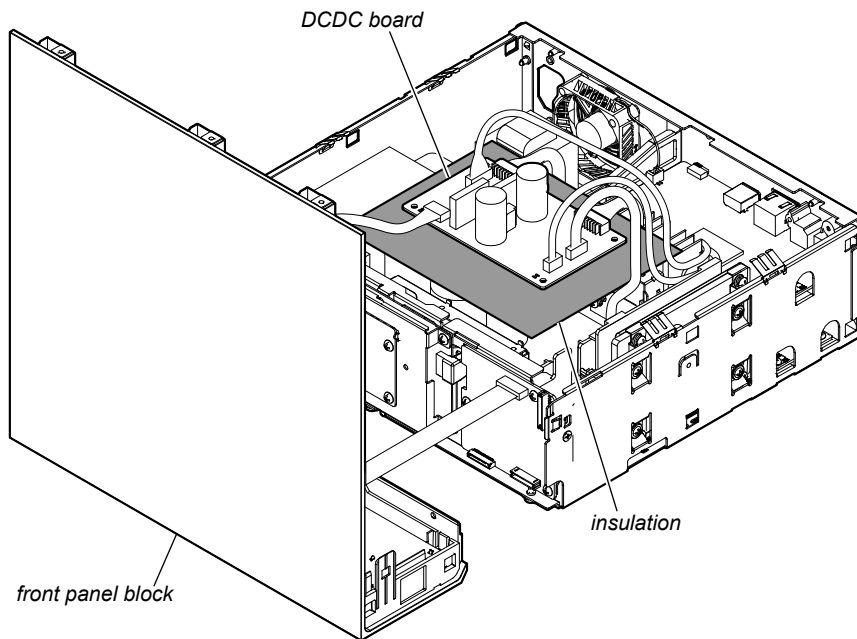
**Note:** Refer to the help guide about details of the checking method.

# HAP-S1

## MAIN BOARD SERVICE POSITION



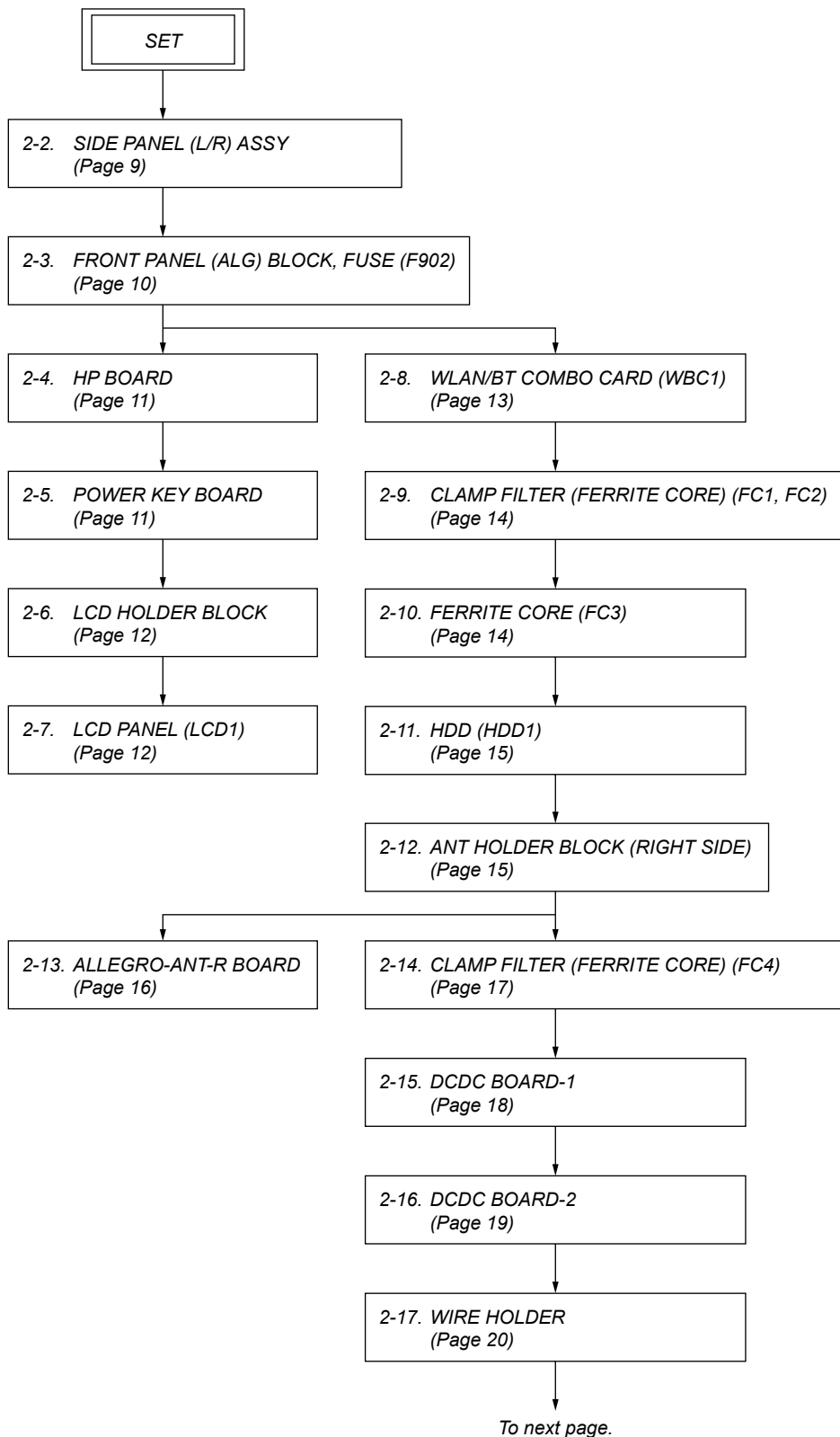
## DCDC BOARD SERVICE POSITION

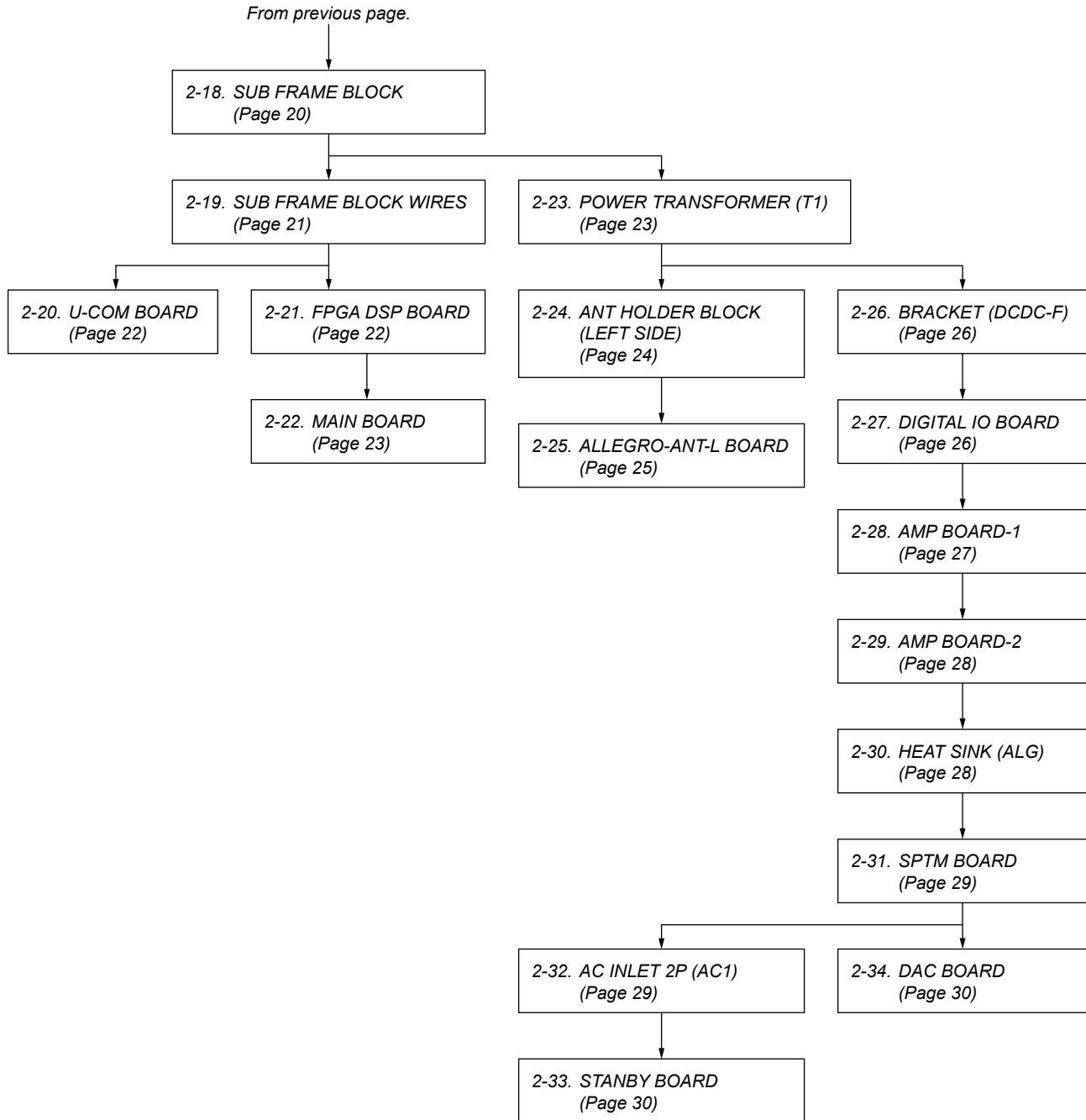


## SECTION 2 DISASSEMBLY

- This set can be disassembled in the order shown below.

### 2-1. DISASSEMBLY FLOW

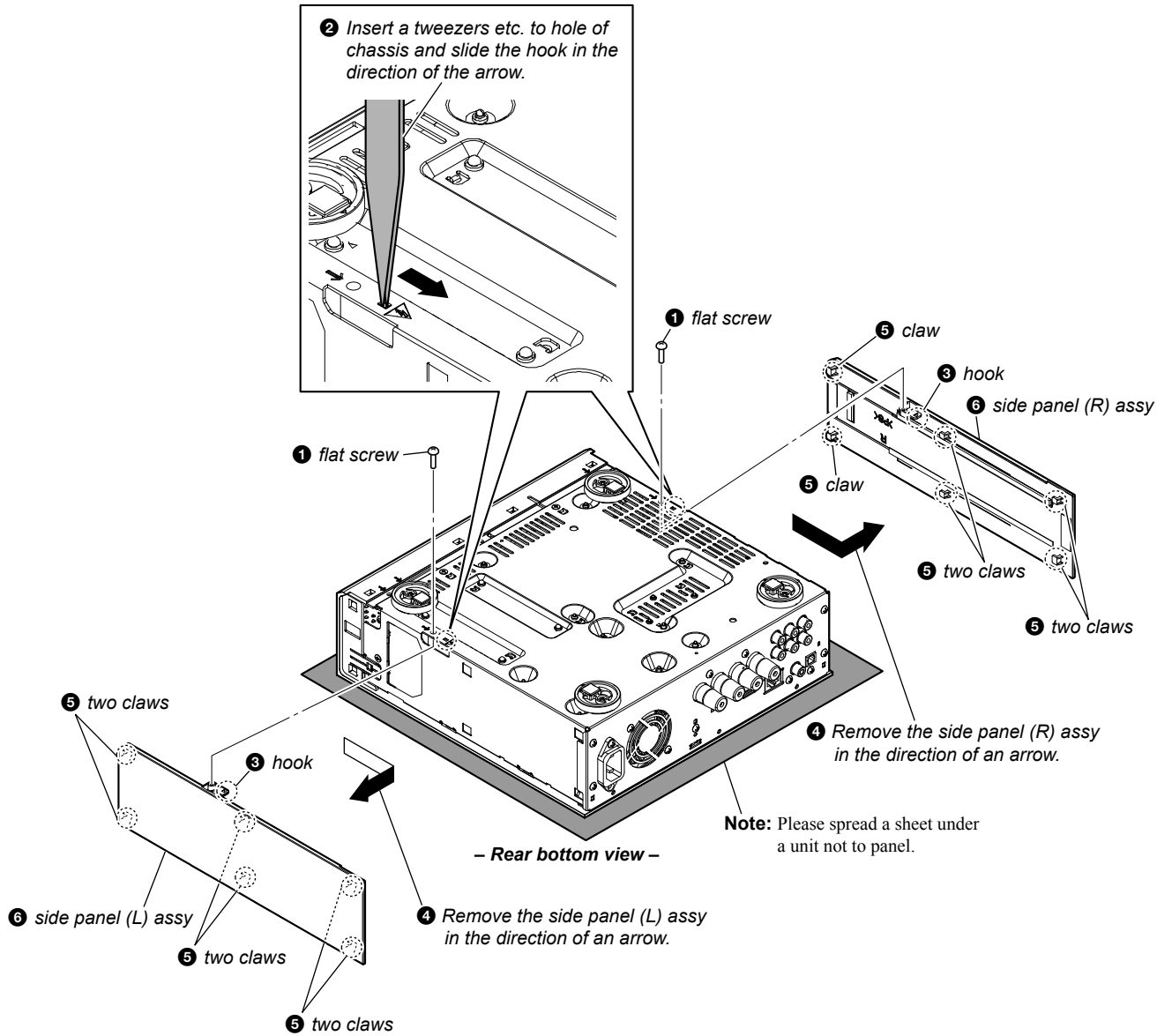




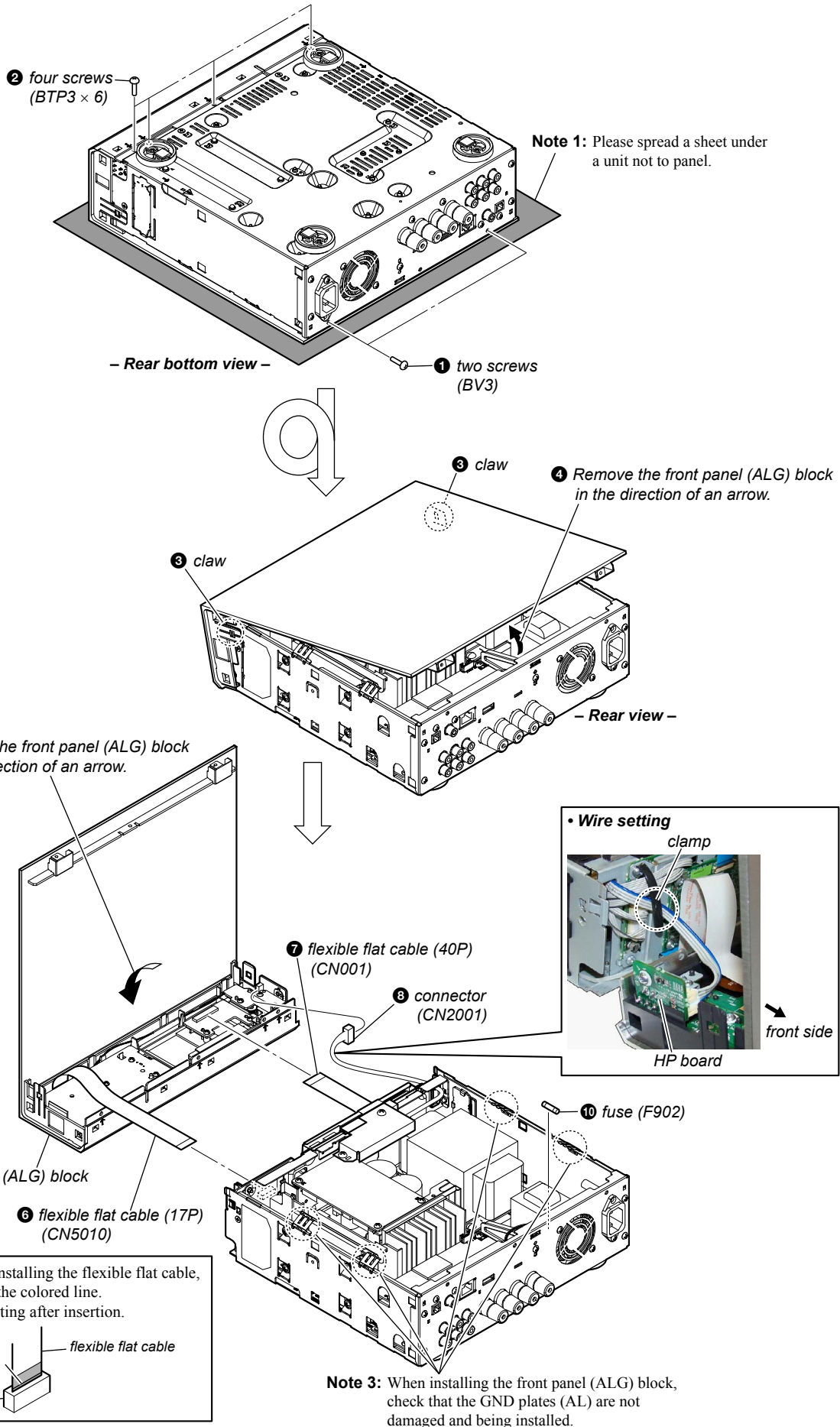


**Note:** Follow the disassembly procedure in the numerical order given.

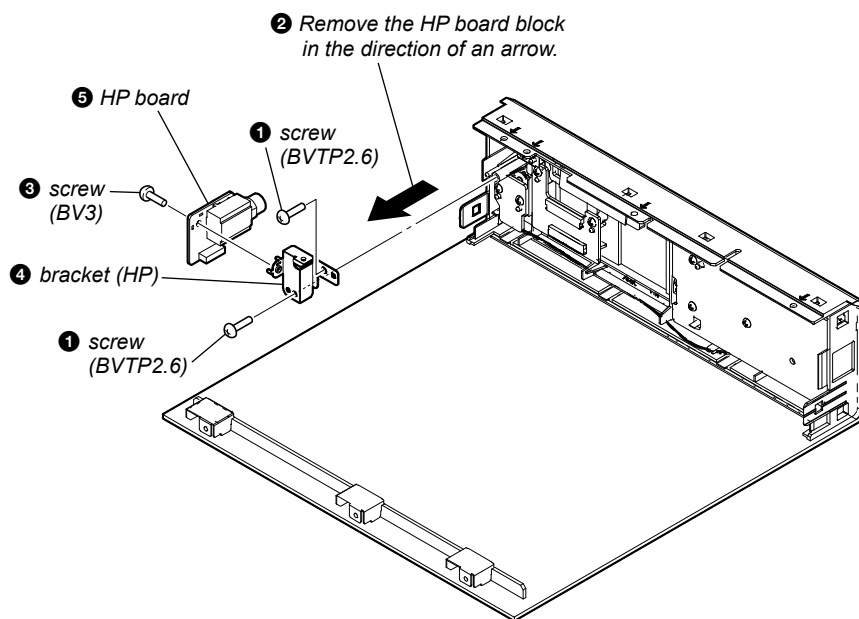
**2-2. SIDE PANEL (L/R) ASSY**



## 2-3. FRONT PANEL (ALG) BLOCK, FUSE (F902)

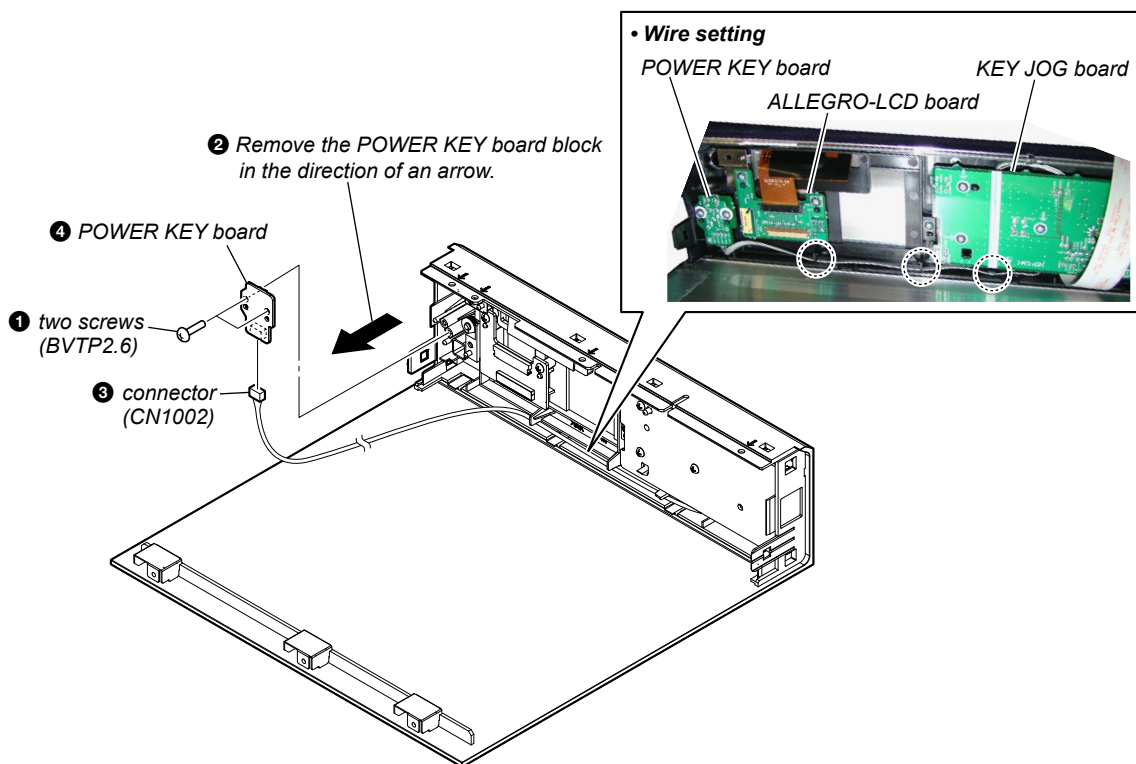


2-4. HP BOARD



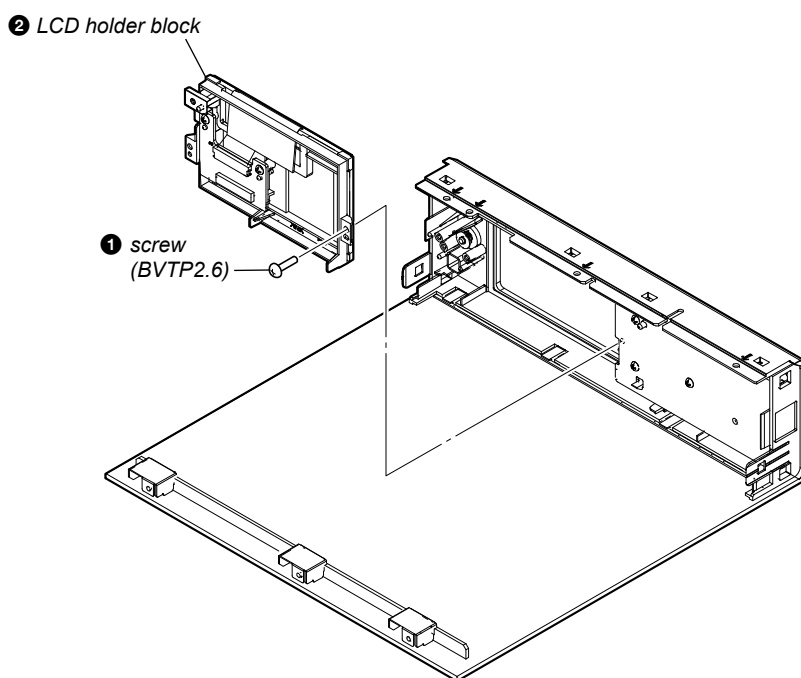
- Front panel (ALG) block rear bottom view -

2-5. POWER KEY BOARD



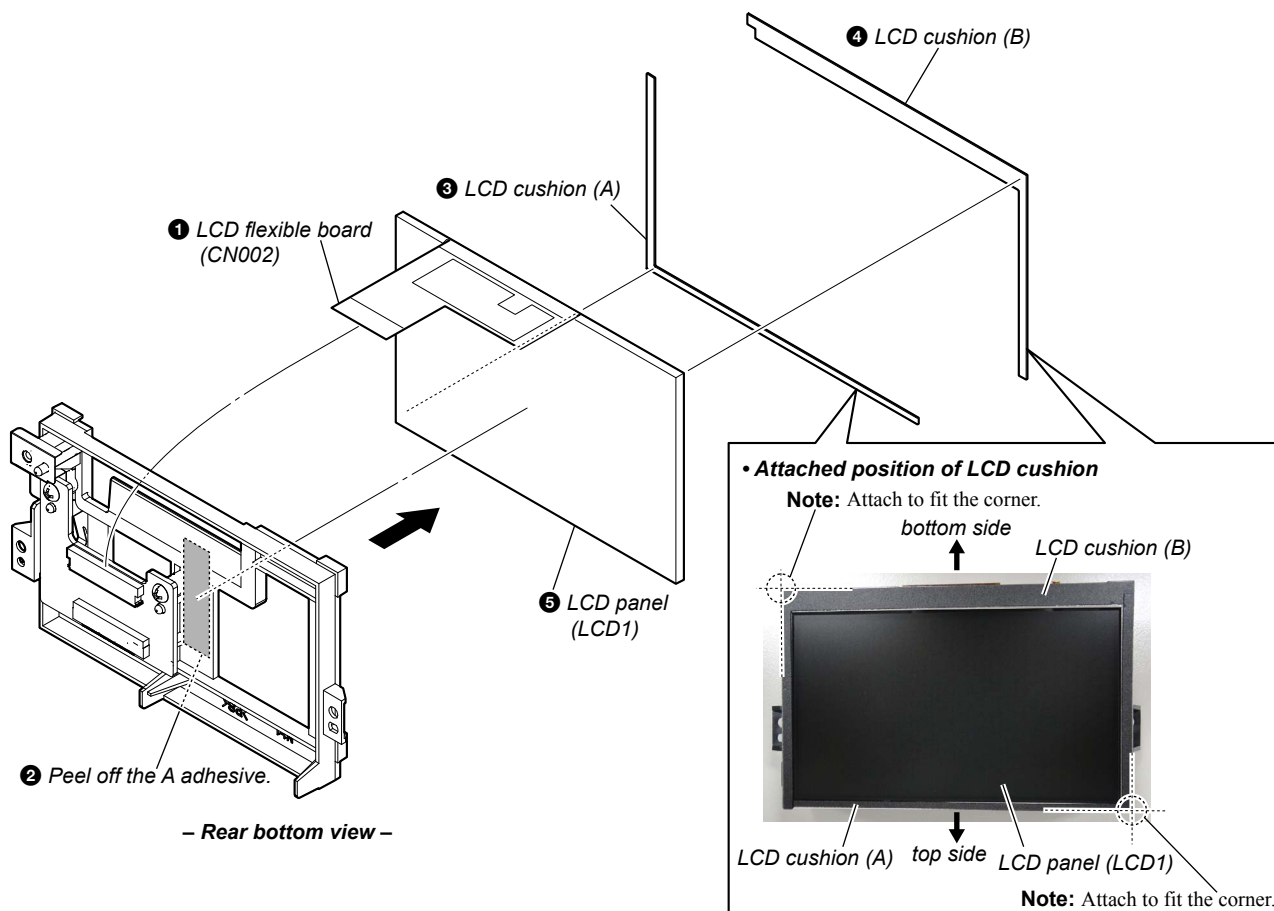
- Front panel (ALG) block rear bottom view -

## 2-6. LCD HOLDER BLOCK



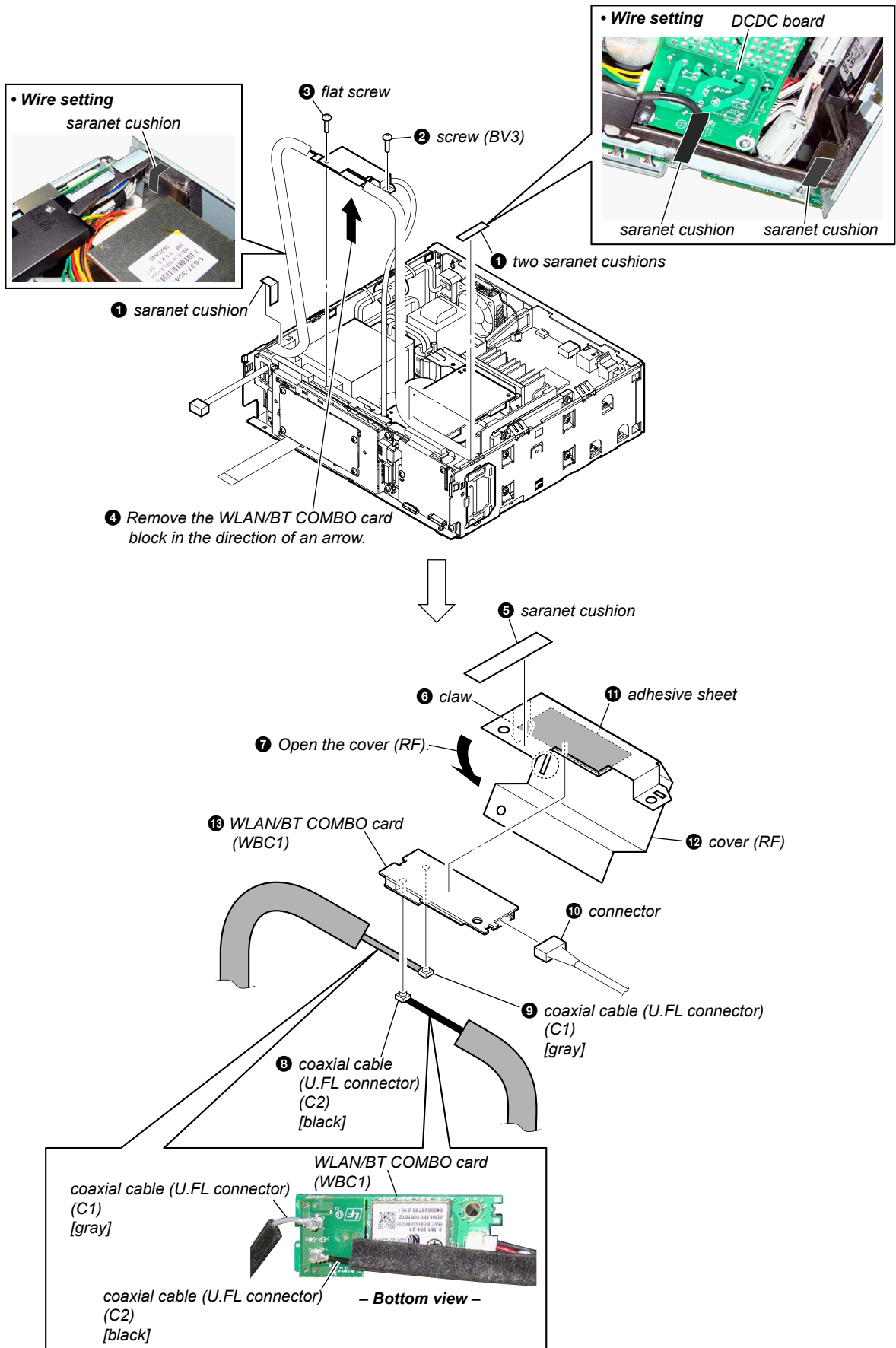
– Front panel (ALG) block rear bottom view –

## 2-7. LCD PANEL (LCD1)



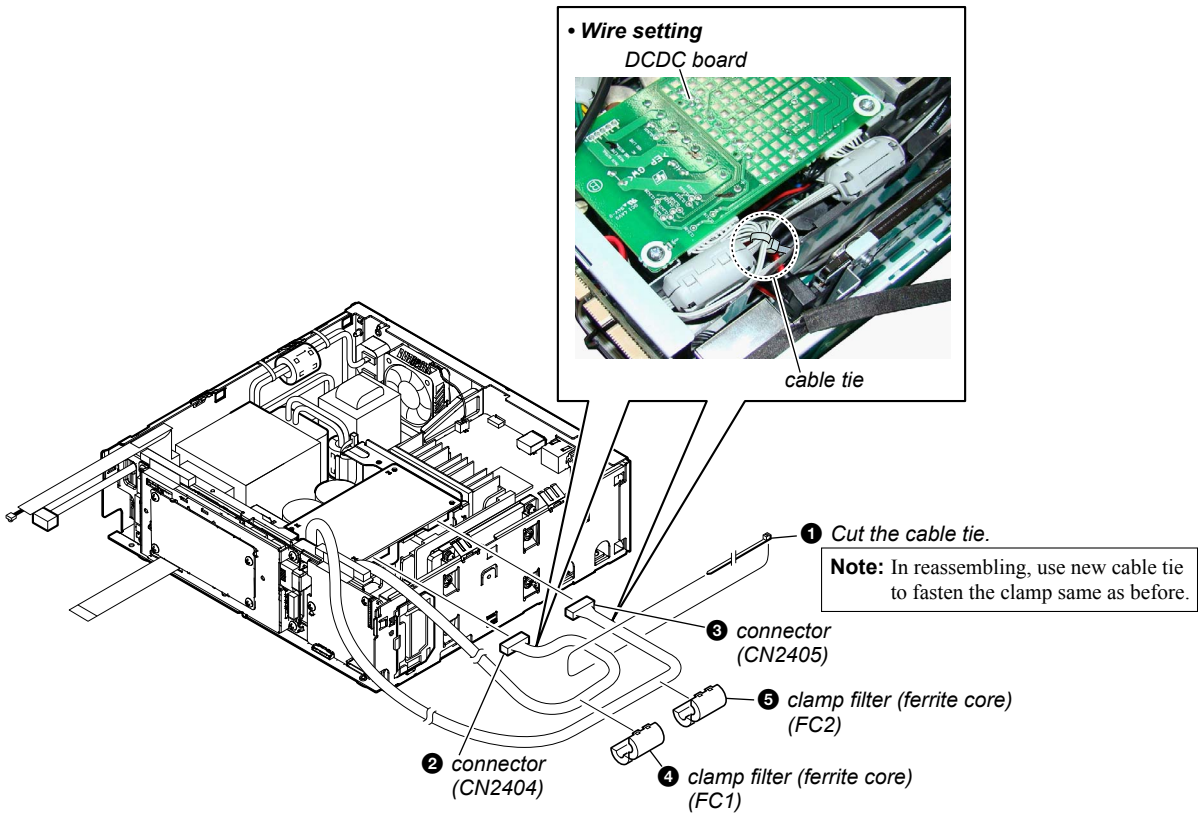
– Rear bottom view –

2-8. WLAN/BT COMBO CARD (WBC1)

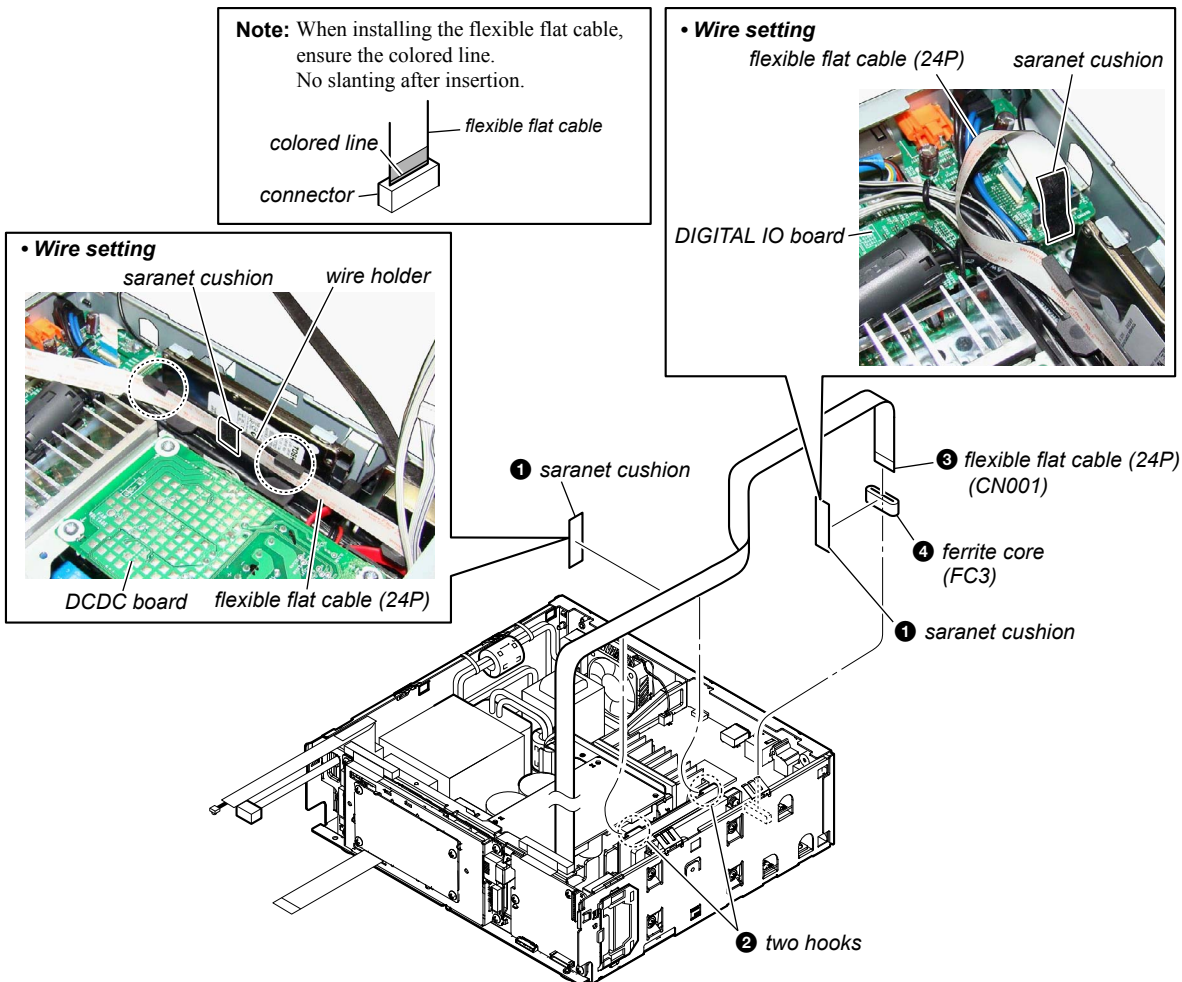


**Note:** When the WLAN/BT COMBO card (Ref. No. WBC1) is replaced, refer to “CHECKING METHOD OF NETWORK CONNECTION” on page 5.

2-9. CLAMP FILTER (FERRITE CORE) (FC1, FC2)

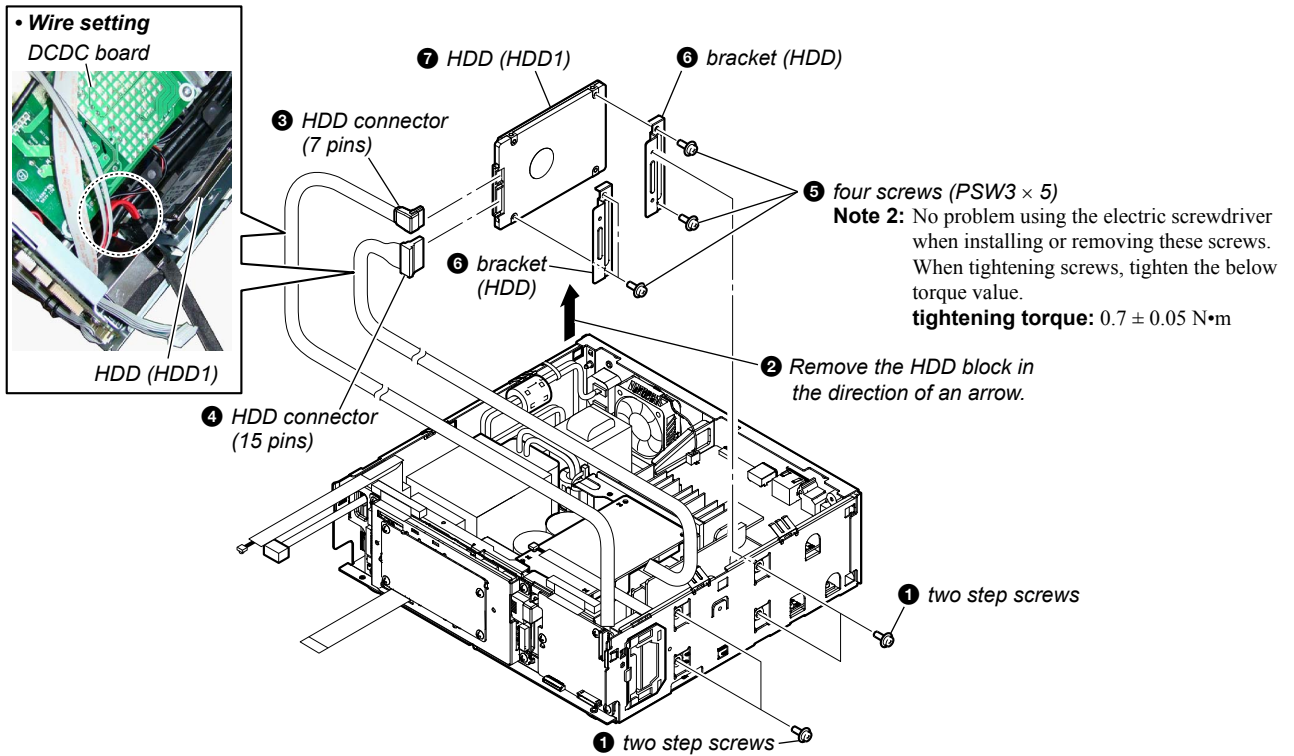


2-10. FERRITE CORE (FC3)

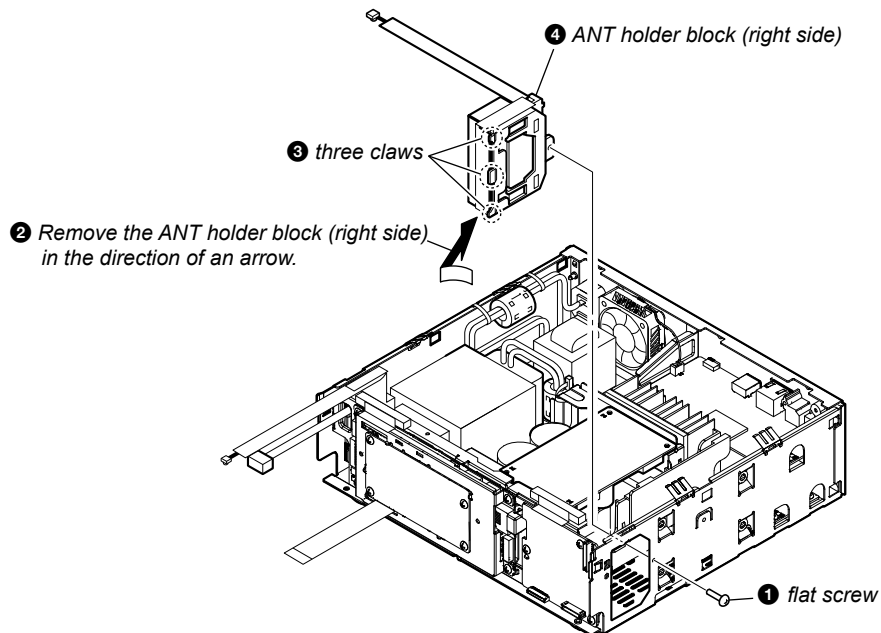


2-11. HDD (HDD1)

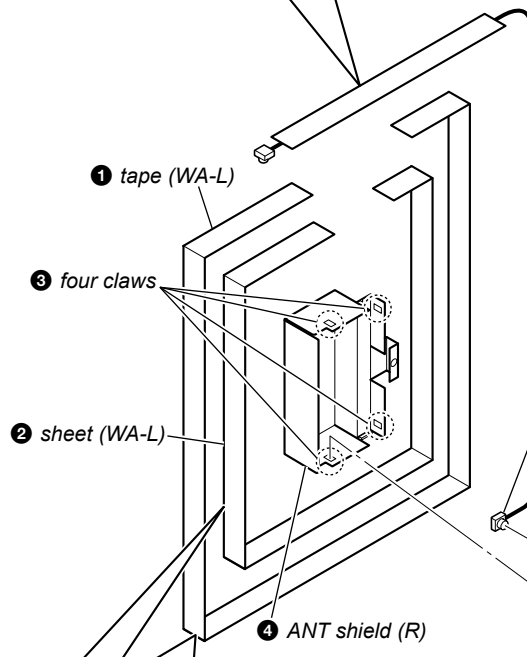
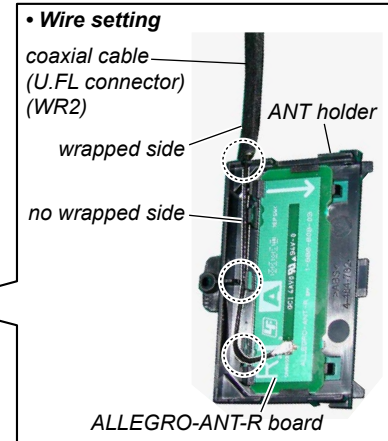
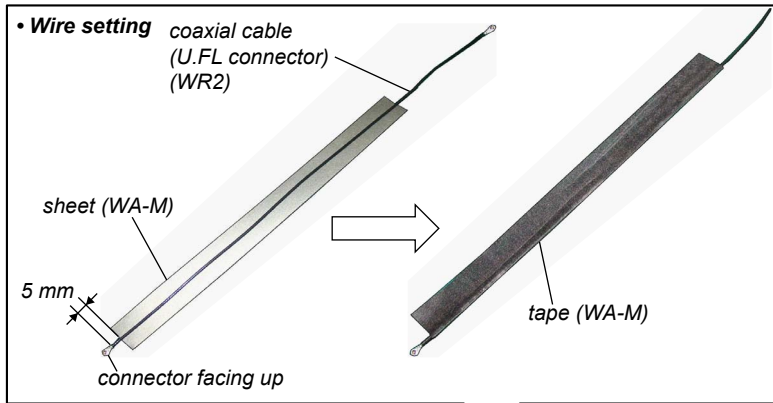
**Note 1:** When the hard disk drive (Ref. No. HDD1) is replaced, refer to “NOTE OF REPLACING THE HARD DISK DRIVE (Ref. No. HDD1)” on page 4.



2-12. ANT HOLDER BLOCK (RIGHT SIDE)



2-13. ALLEGRO-ANT-R BOARD



5 coaxial cable (U.FL connector) (WR2) (CN9002)

9 ALLEGRO-ANT-R board

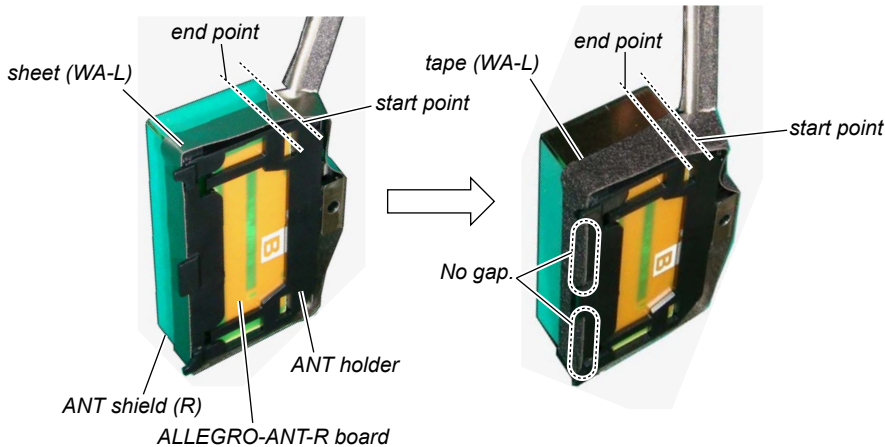
8 ANT holder

6 two claws

7 Remove the ALLEGRO-ANT-R board block in the direction of an arrow.

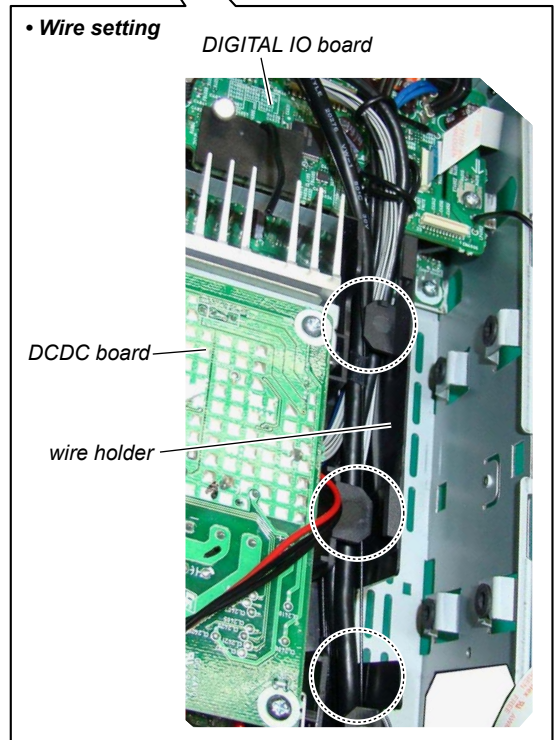
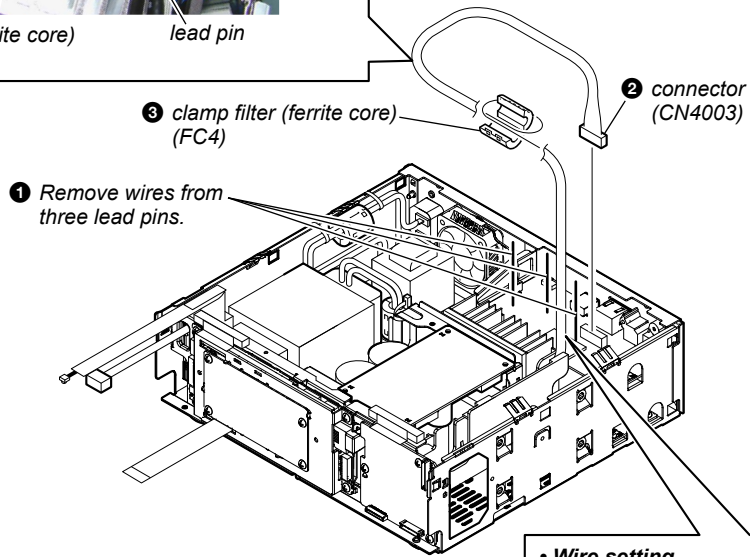
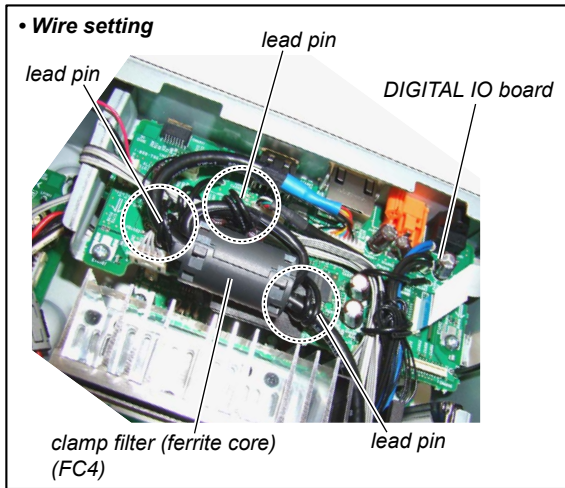
**Note:** The ALLEGRO-ANT-R board is not covered in the servicing.

• **Attached position of the sheet (WA-L) and the tape (WA-L)**

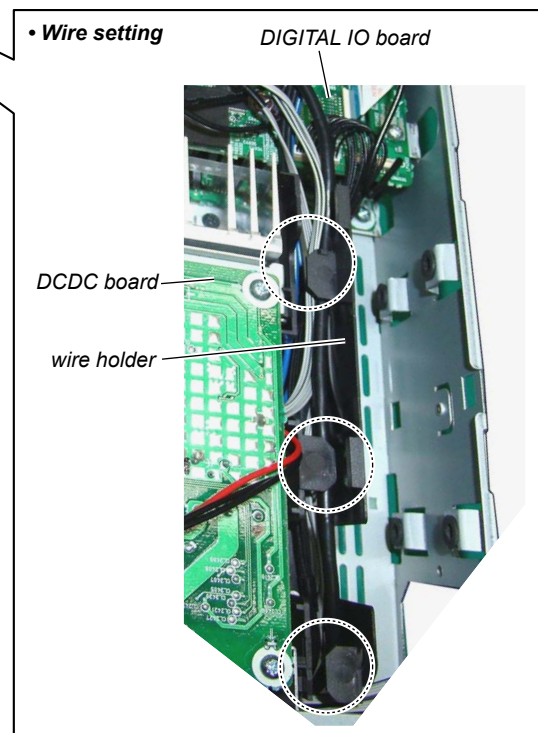
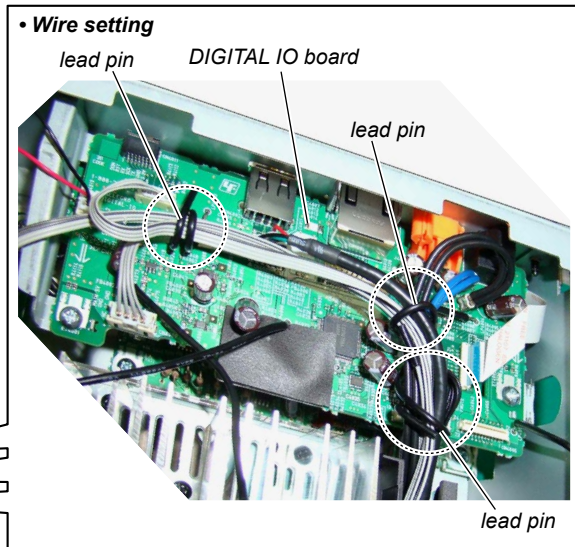
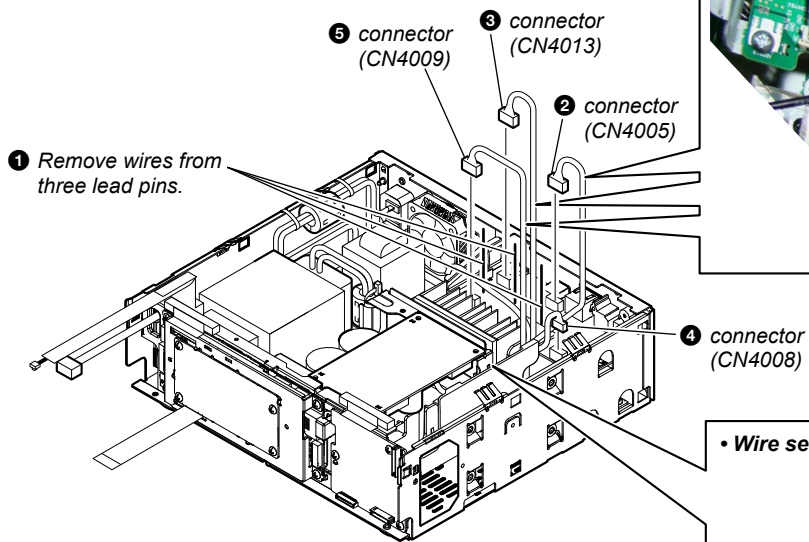




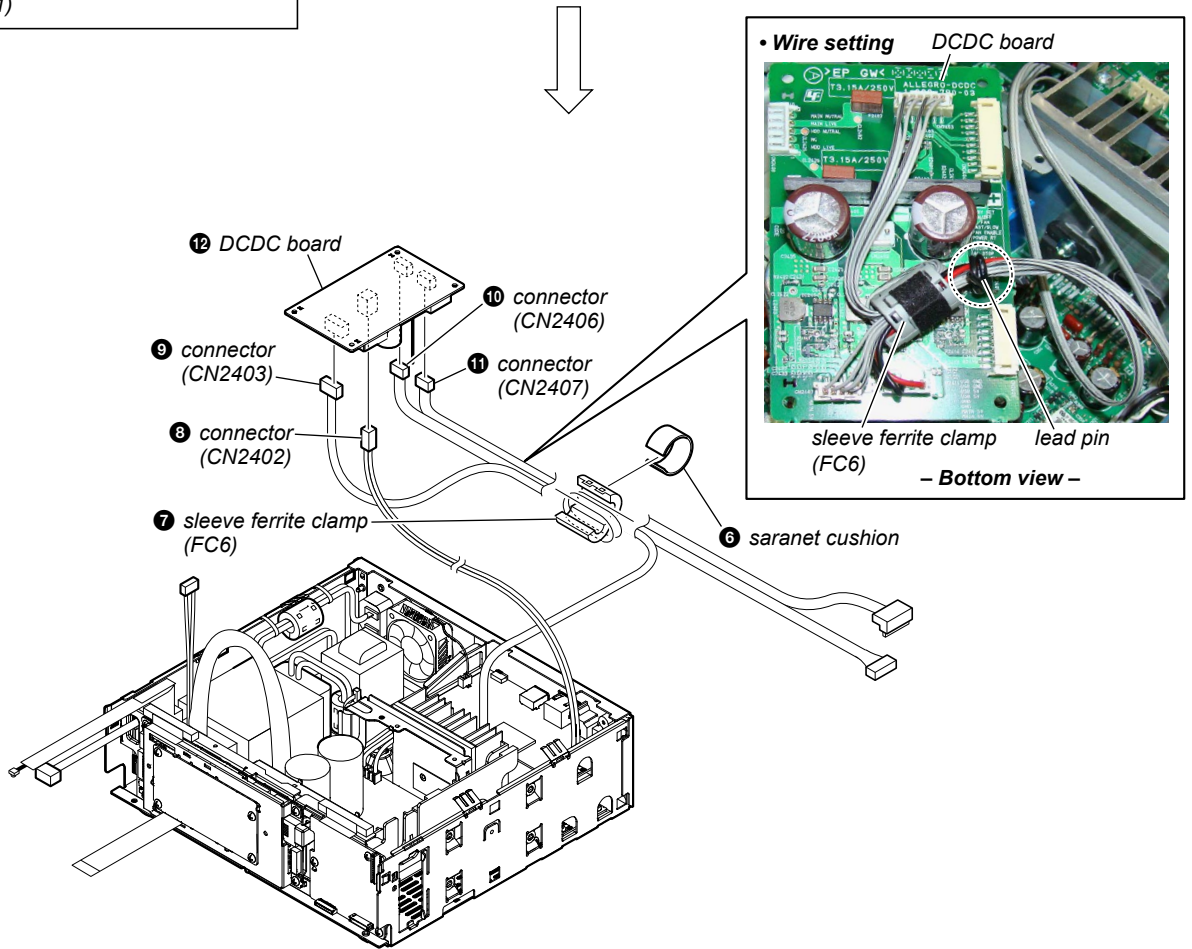
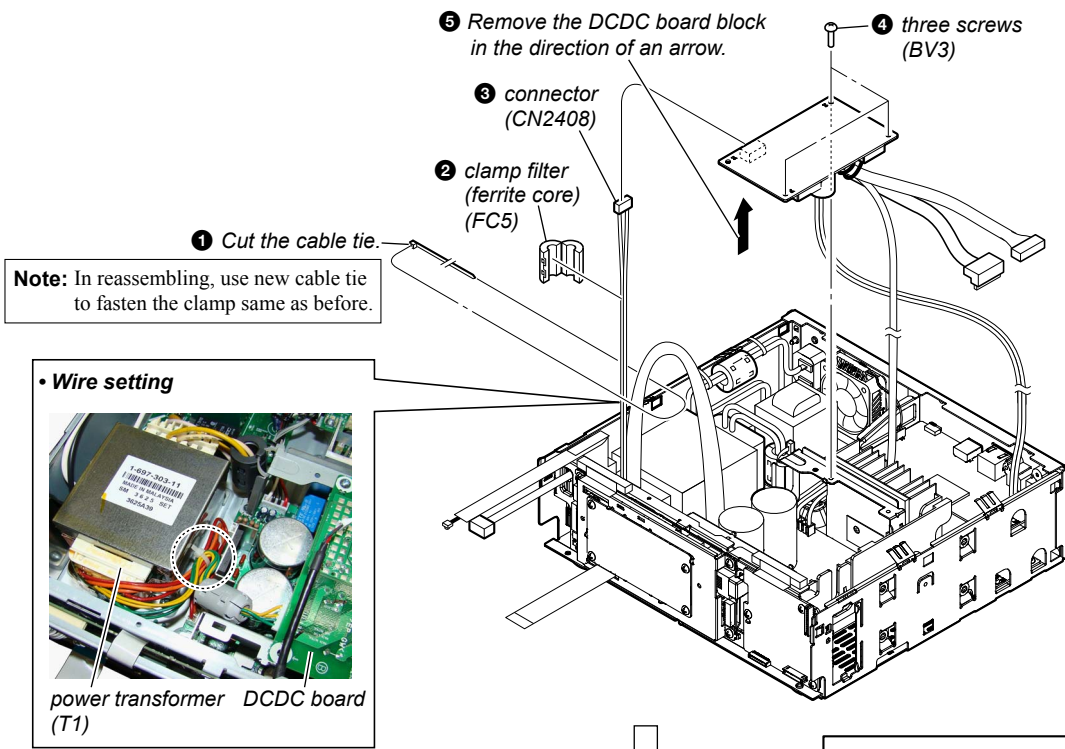
2-14. CLAMP FILTER (FERRITE CORE) (FC4)



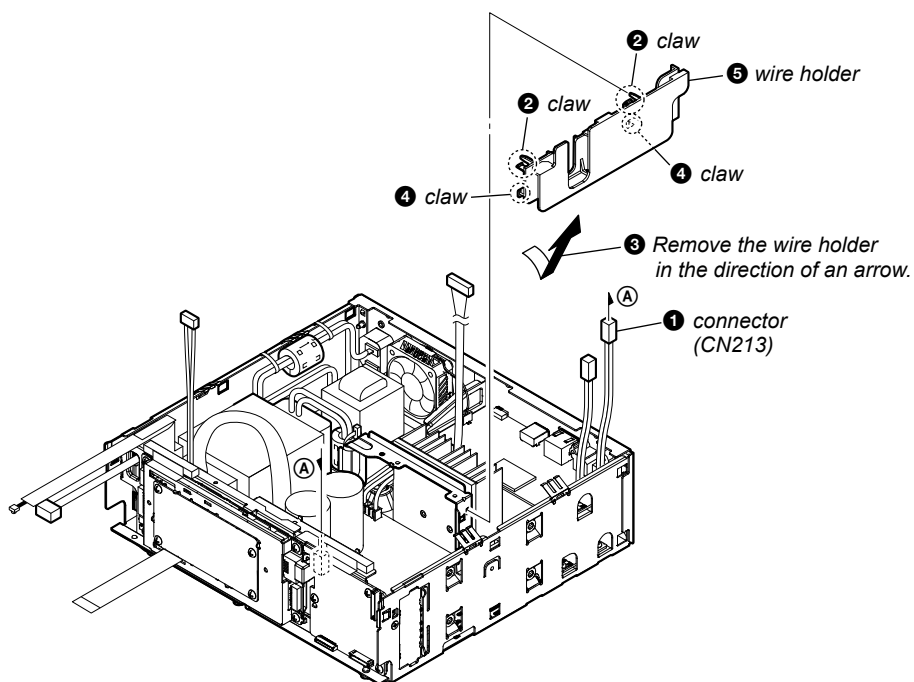
## 2-15. DCDC BOARD-1



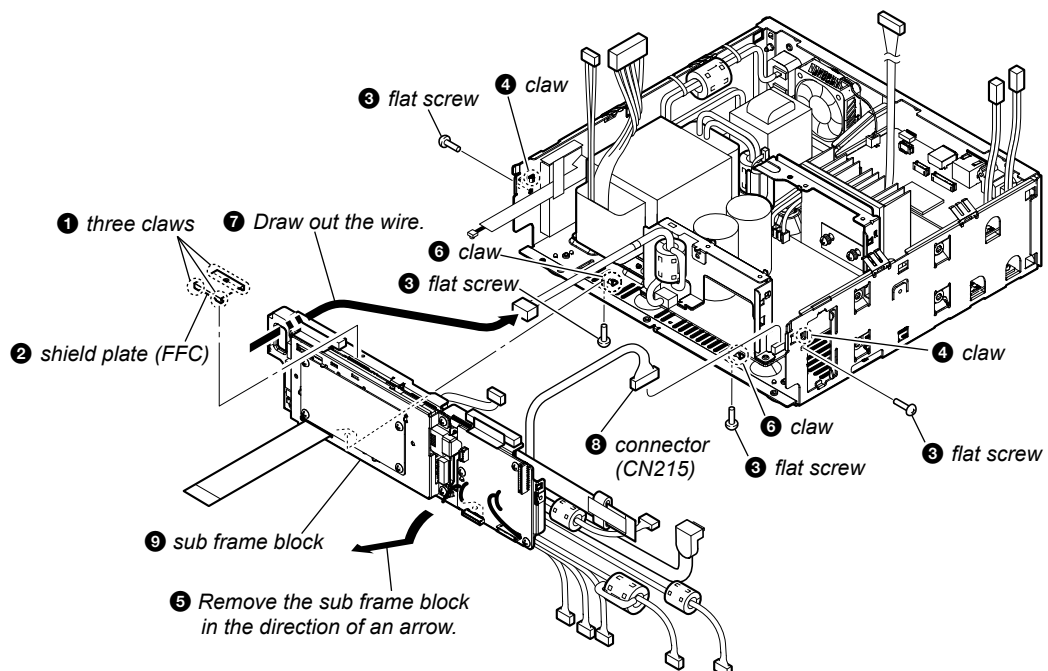
2-16. DCDC BOARD-2



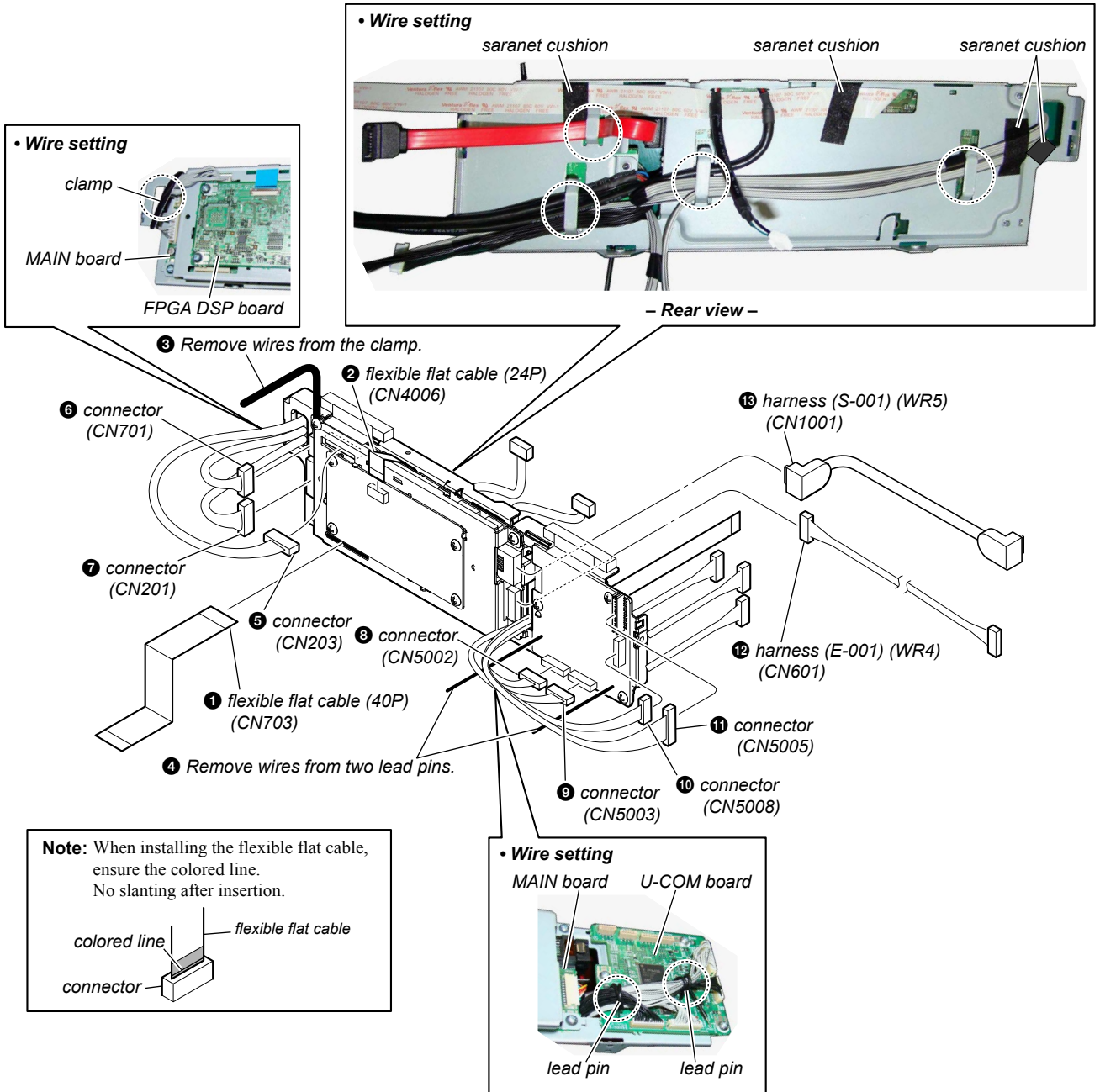
## 2-17. WIRE HOLDER



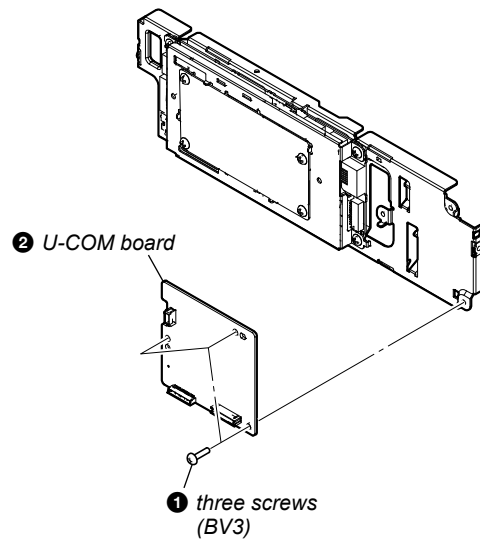
## 2-18. SUB FRAME BLOCK



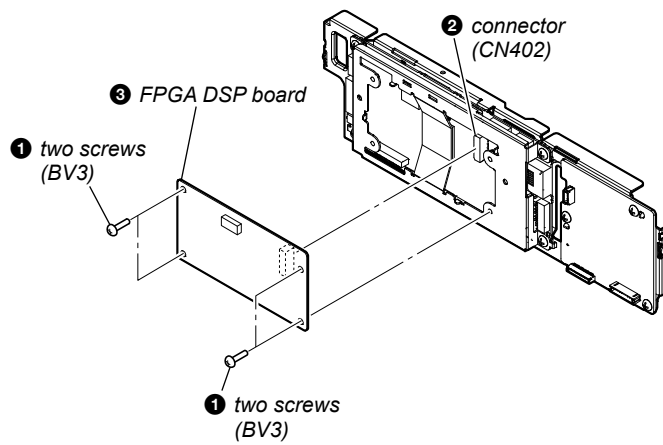
2-19. SUB FRAME BLOCK WIRES



## 2-20. U-COM BOARD

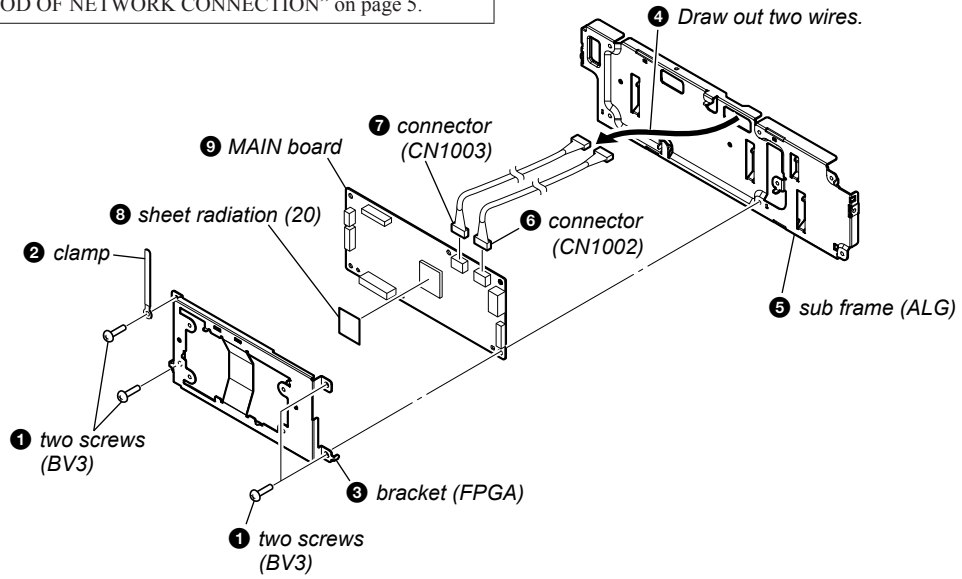


## 2-21. FPGA DSP BOARD

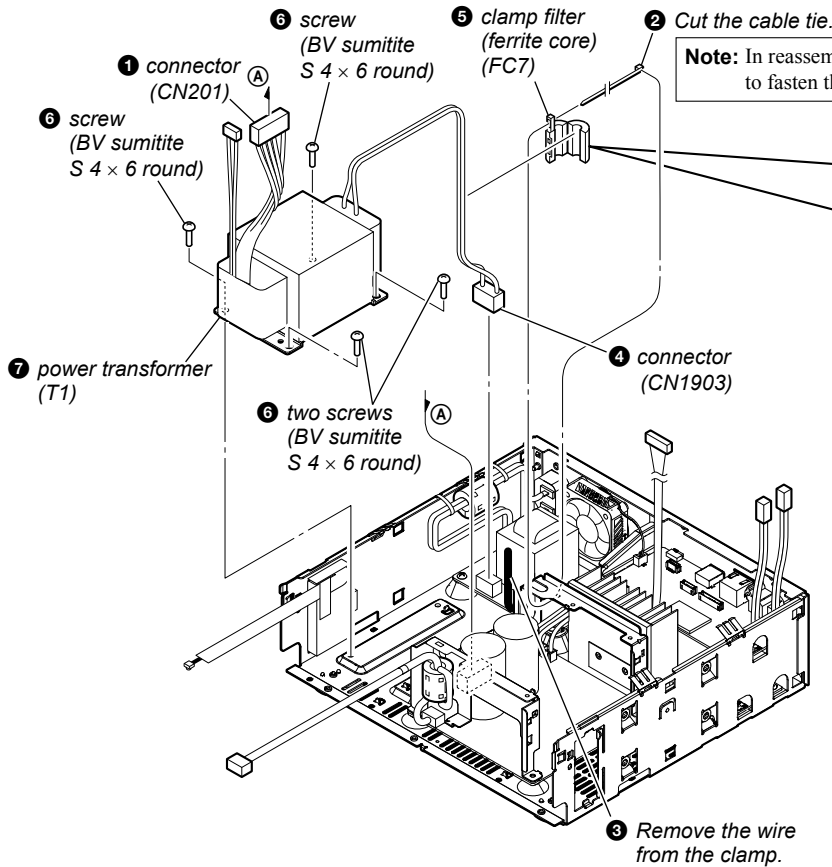


2-22. MAIN BOARD

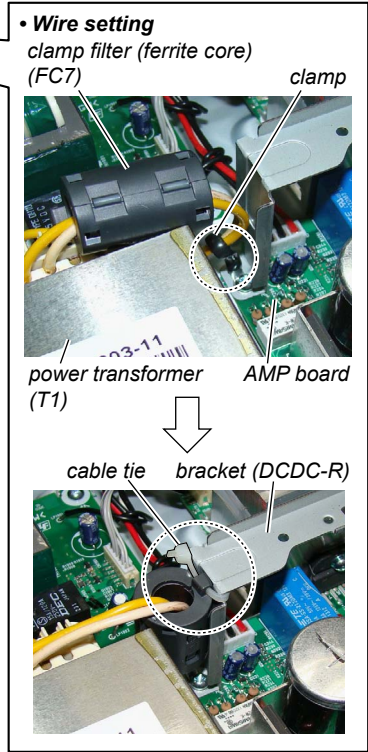
**Note:** When the complete MAIN board is replaced, refer to “NOTE OF REPLACING THE COMPLETE MAIN BOARD” and “CHECKING METHOD OF NETWORK CONNECTION” on page 5.



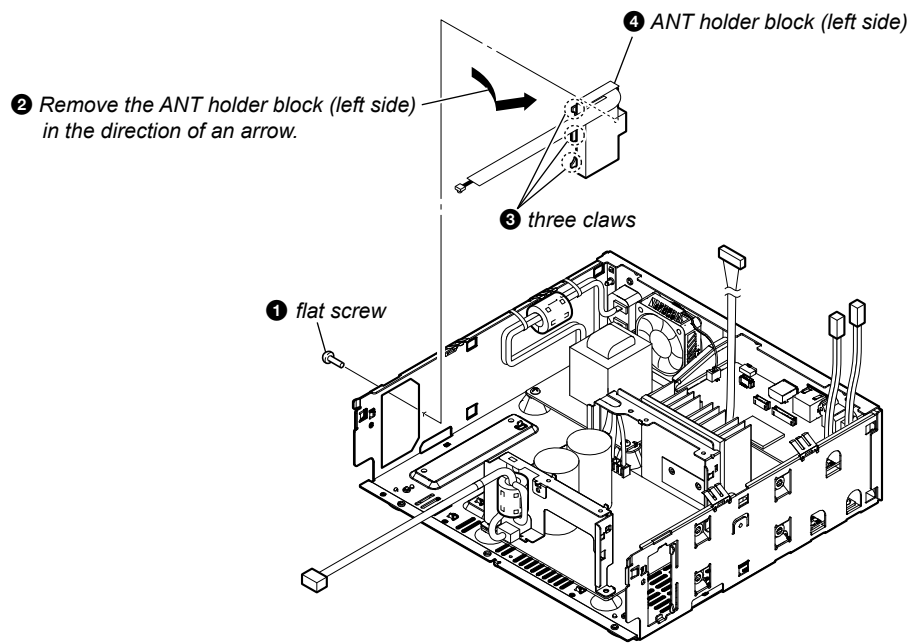
2-23. POWER TRANSFORMER (T1)



**Note:** In reassembling, use new cable tie to fasten the clamp same as before.

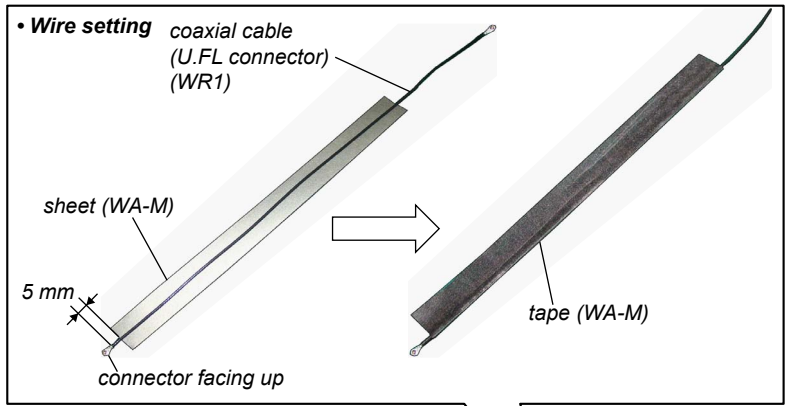


## 2-24. ANT HOLDER BLOCK (LEFT SIDE)

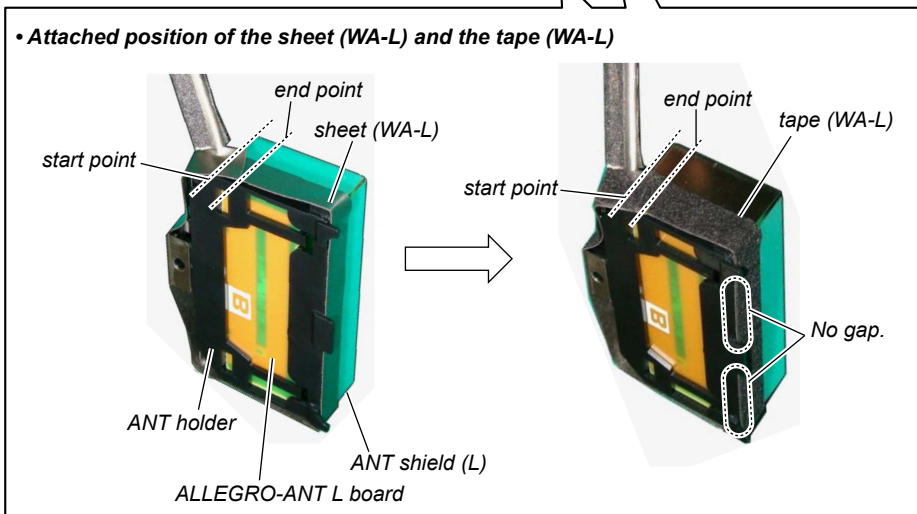
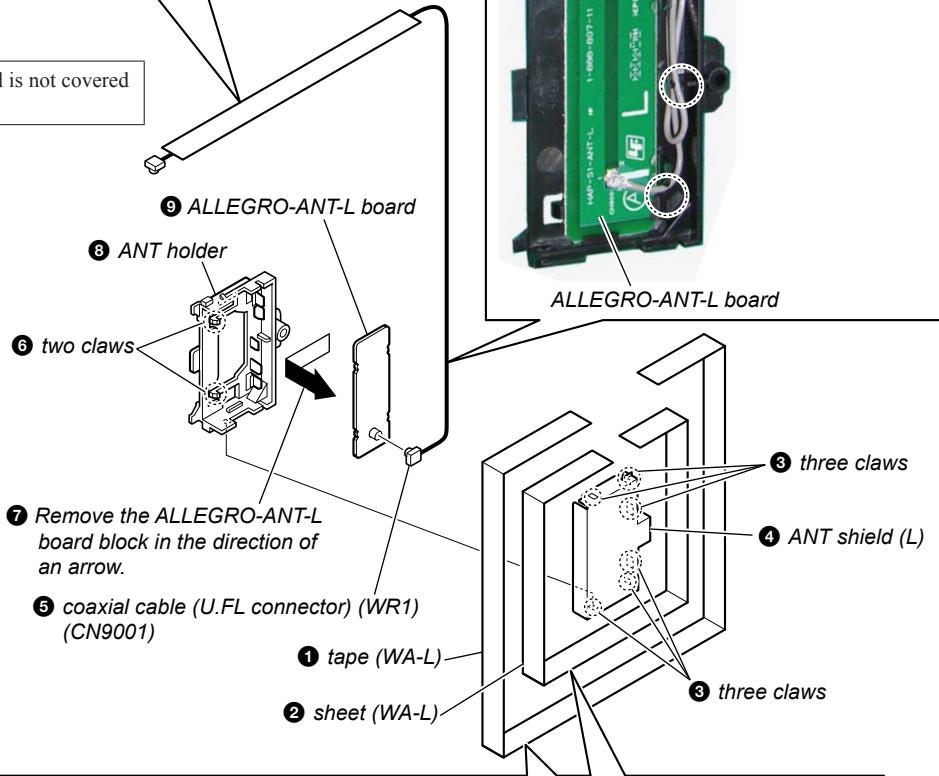
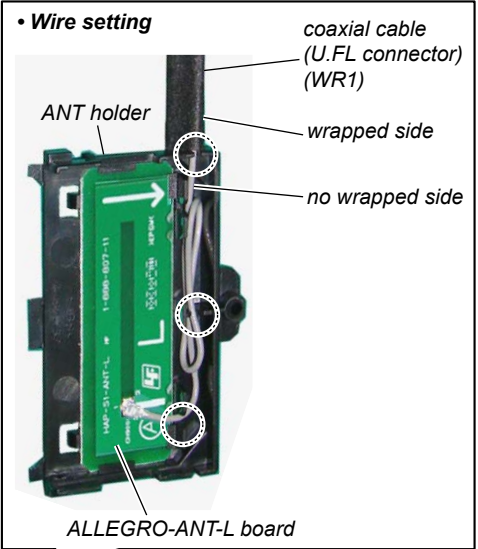




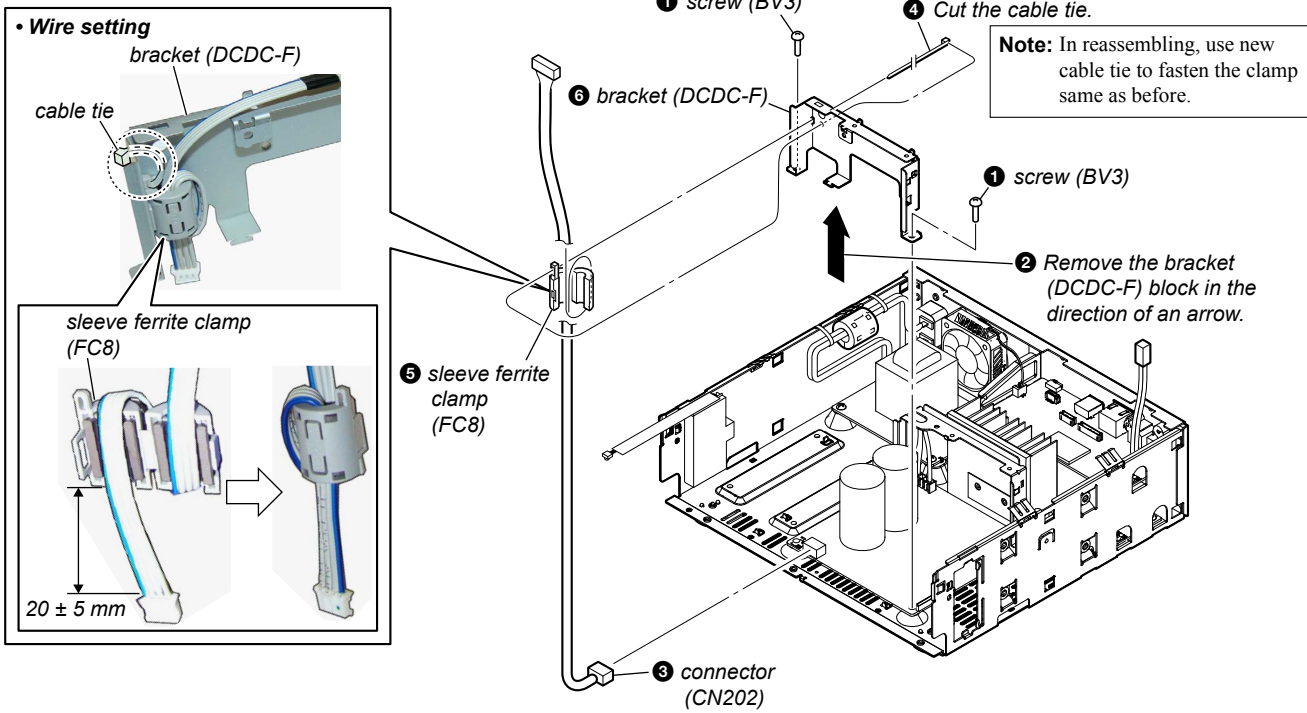
2-25. ALLEGRO-ANT-L BOARD



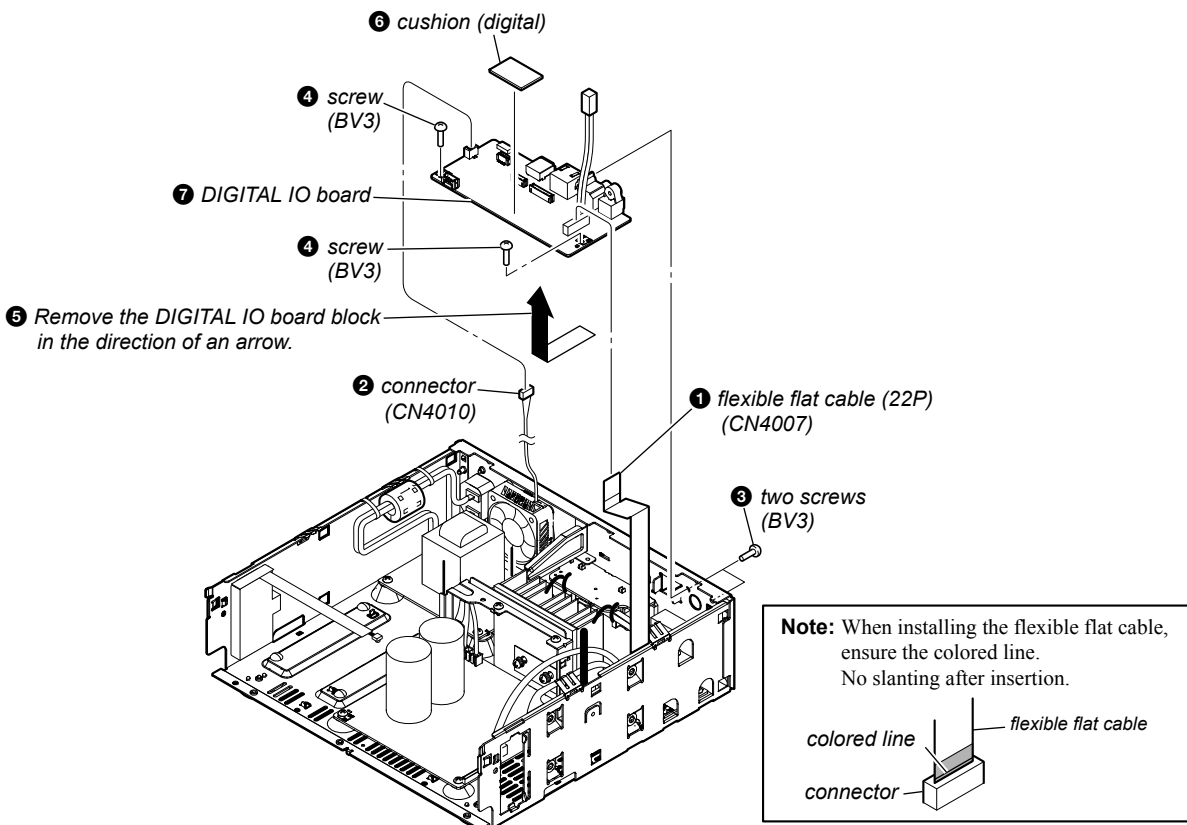
**Note:** The ALLEGRO-ANT-L board is not covered in the servicing.



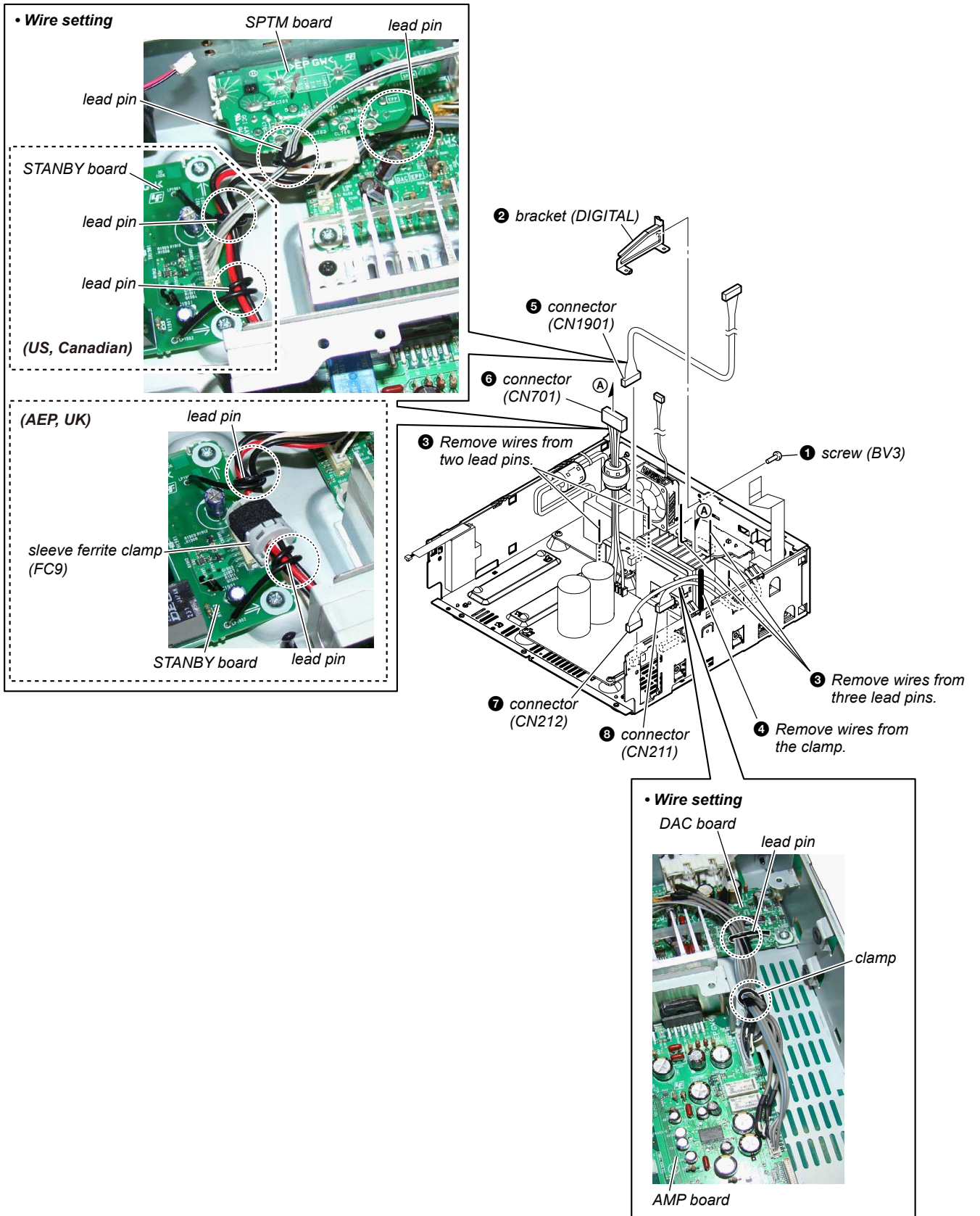
2-26. BRACKET (DCDC-F)



2-27. DIGITAL IO BOARD

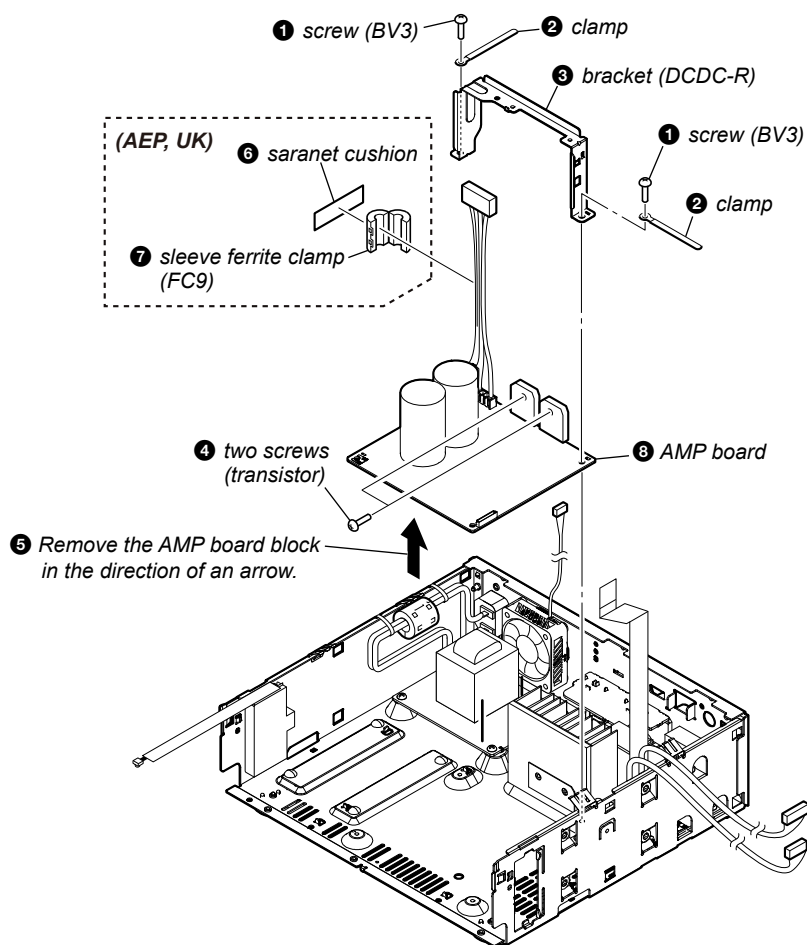


2-28. AMP BOARD-1

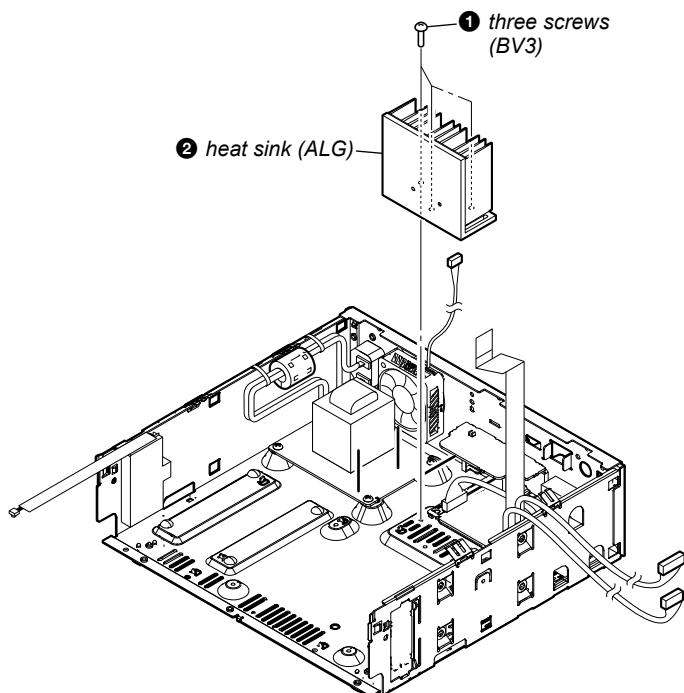


## 2-29. AMP BOARD-2

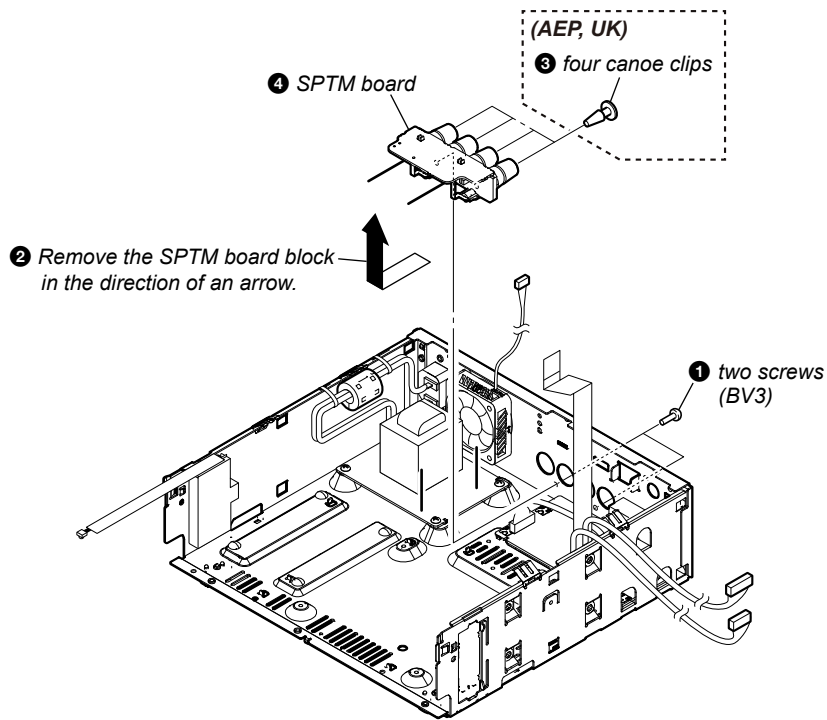
**Note:** When the complete AMP board is replaced, refer to “NOTE OF REPLACING THE D218, IC350 AND IC351 ON THE AMP BOARD AND THE COMPLETE AMP BOARD” on page 4.



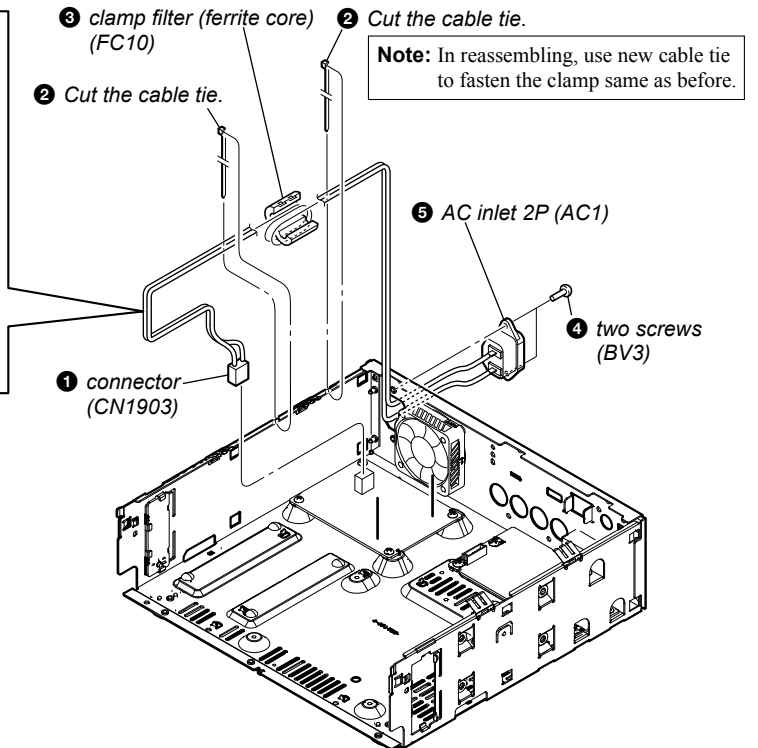
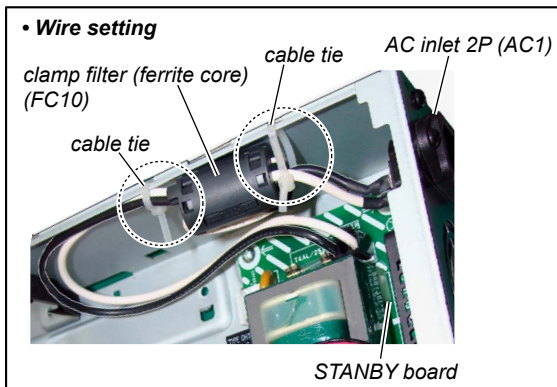
## 2-30. HEAT SINK (ALG)



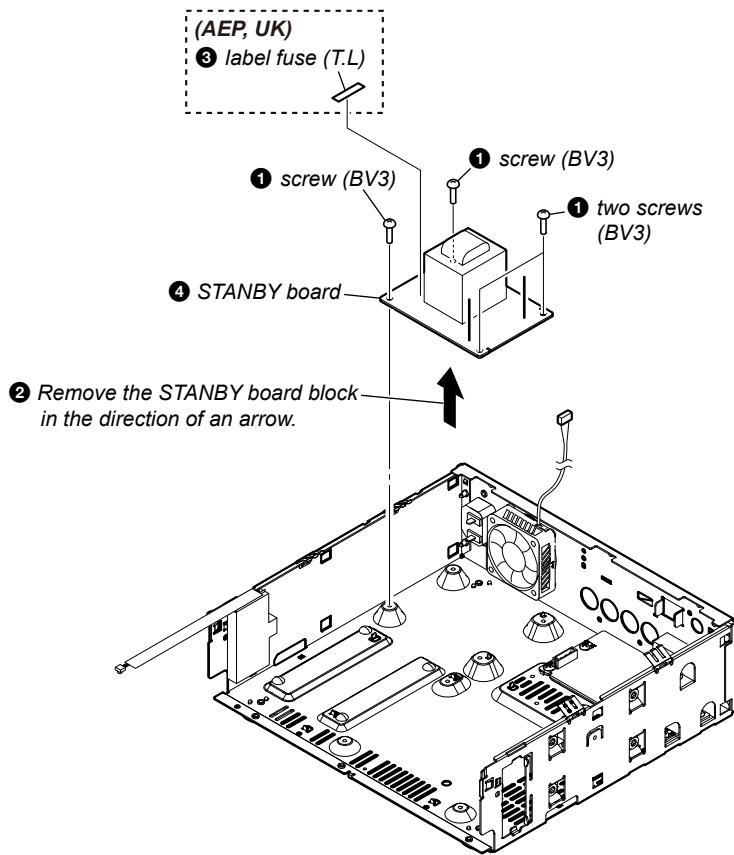
2-31. SPTM BOARD



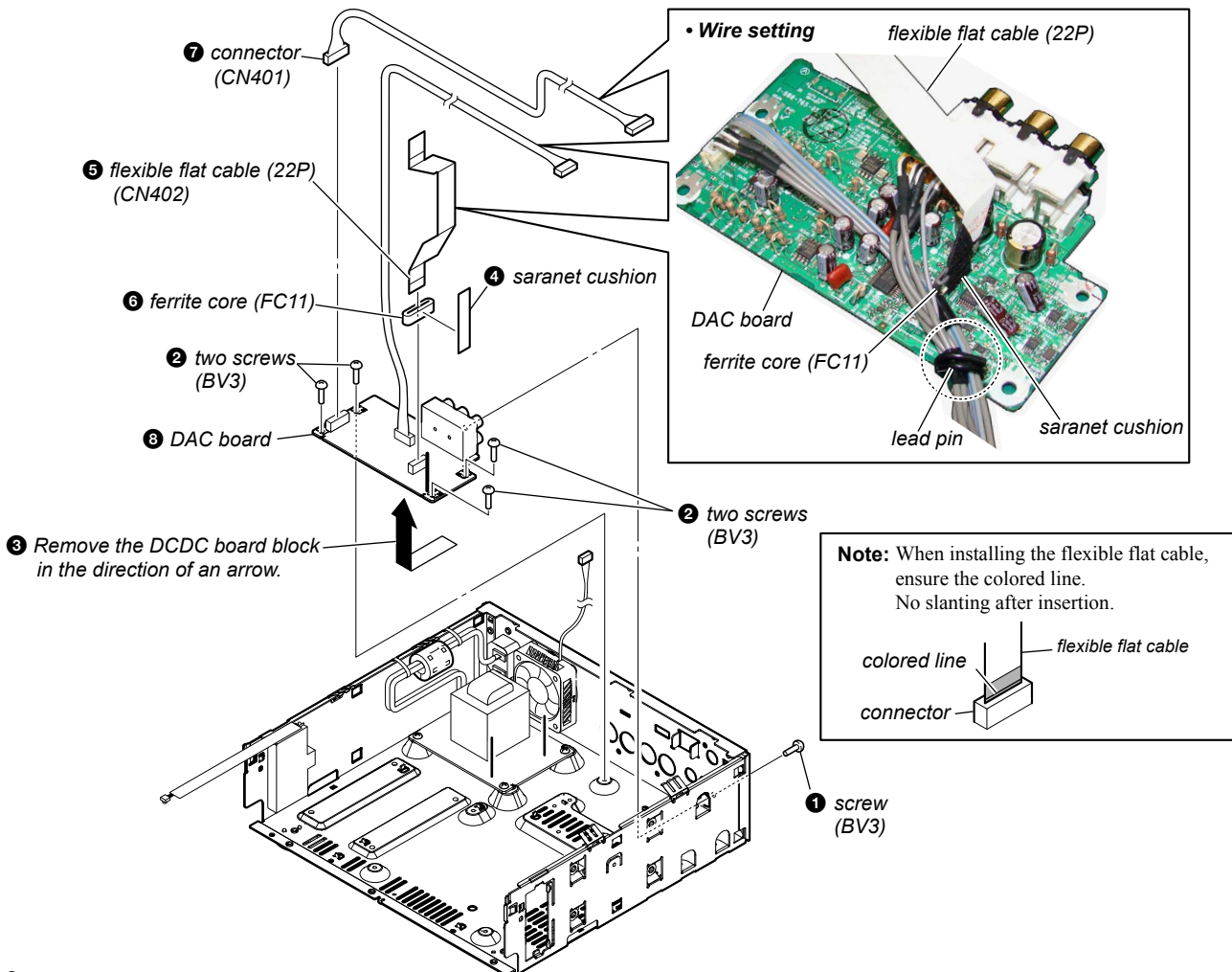
2-32. AC INLET 2P (AC1)



## 2-33. STANBY BOARD



## 2-34. DAC BOARD

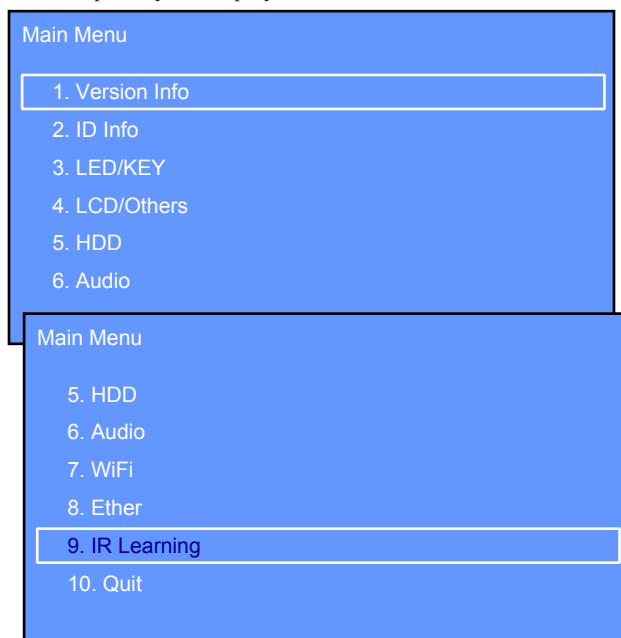


## SECTION 3 TEST MODE

### 1. Entering Method of The Service Diag Mode

#### Procedure:

1. Connect the power cord to an outlet.
2. After becoming the standby state, while holding down two keys of the [HOME] and [BACK], press two keys in order of the [▶II] → [I/⏻].
3. Enter the service DIAG mode, “Main Menu” is displayed on the liquid crystal display.



### 2. Operation Method of The Service DIAG Mode

It can operate the service DIAG mode with the key of the main unit or remote commander (RM-ANU183). A key having no particular description in the text, indicates the main unit key

#### Key Assign

Operation	Main unit key	Remote commander (RM-ANU183) key
Moves to the cursor and selects the item	PUSH ENTER (UP/DOWN)	◀◀/▶▶
Enters the item	PUSH ENTER	▶II
Returns to the main menu	HOME	–
Returns to the previous menu	BACK	–

### 3. Releasing Method of The Service DIAG Mode

- Press the [I/⏻] button (Except the state of “3-3.KEY Check”, “5-5.SMART Short Test” and “5-6.SMART Long Test”).
- Select the “10. QUIT” on the main menu.

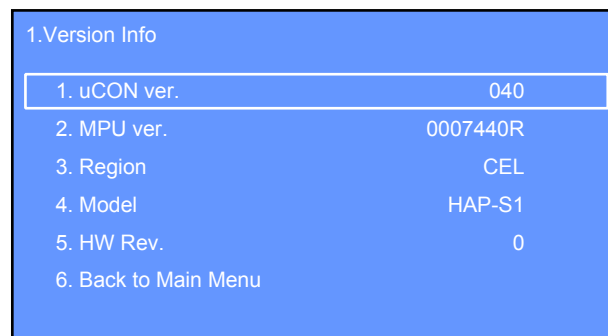
### 4. Operation of The Service DIAG Mode

#### 4-1. Version Info

It can display the version information.

#### Procedure:

1. Enter the service DIAG mode.  
(Refer to “1. Entering Method of The Service DIAG Mode”)
2. Rotate the [PUSH ENTER] knob to select the “1. Version Info”.
3. Press the [PUSH ENTER] knob to enter the “1. Version Info” mode.



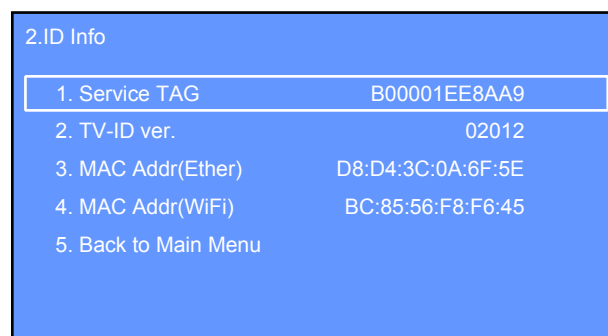
(Displayed characters/values in the above figure are example)

#### 4-2. ID Info

It can display the ID information.

#### Procedure:

1. Enter the service DIAG mode.  
(Refer to “1. Entering Method of The Service DIAG Mode”)
2. Rotate the [PUSH ENTER] knob to select the “2. ID Info”.
3. Press the [PUSH ENTER] knob to enter the “2. ID Info” mode.

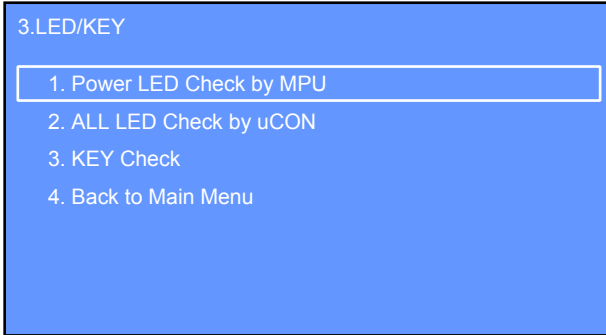


(Displayed characters/values in the above figure are example)

## 4-3. LED/KEY

### Procedure:

1. Enter the service DIAG mode.  
(Refer to “1. Entering Method of The Service DIAG Mode” on page 31)
2. Rotate the [PUSH ENTER] knob to select the “3. LED/KEY”.
3. Press the [PUSH ENTER] knob to enter the “3. LED/KEY” mode.



### 4-3-1. Power LED Check by MPU

It can check the [I/Ⓞ] LED.

### Procedure:

1. Enter the “3. LED/KEY” mode.  
(Refer to “4-3. LED/KEY”)
2. Rotate the [PUSH ENTER] knob to select the “1. Power LED Check by MPU”.
3. Press the [PUSH ENTER] knob to enter the “1. Power LED Check by MPU” mode.
4. The [I/Ⓞ] LED continues blinking.

### 4-3-2. ALL LED Check by uCON

It can check two LEDs of the [I/Ⓞ] and [DSEE].

### Procedure:

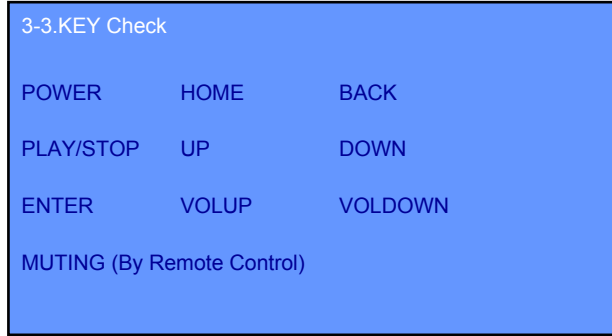
1. Enter the “3.LED/KEY” mode.  
(Refer to “4-3. LED/KEY”)
2. Rotate the [PUSH ENTER] knob to select the “2. ALL LED Check by uCON”.
3. Press the [PUSH ENTER] knob to enter the “2. ALL LED Check by uCON” mode.
4. Two LEDs of the [I/Ⓞ] and [DSEE] continues blinking.

## 4-3-3. KEY Check

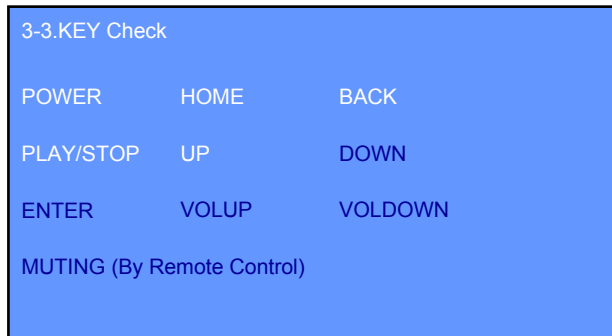
It can check the keys and knobs.

### Procedure:

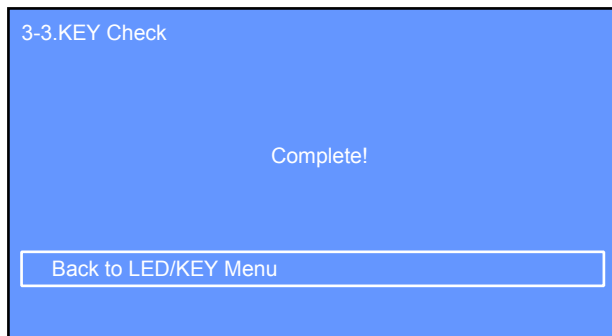
1. Enter the “3. LED/KEY” mode.  
(Refer to “4-3. LED/KEY”)
2. Rotate the [PUSH ENTER] knob to select the “3. KEY Check”.
3. Press the [PUSH ENTER] knob to enter the “3. KEY Check” mode.



4. Each time a key on the main unit or remote commander is pressed and each time a knob on the main unit is rotated, character on the liquid crystal display corresponding to the keys and knobs turns the white color.



5. When all character on the liquid crystal display corresponding to the keys and knobs turns the white color, following screen is displayed on the liquid crystal display.

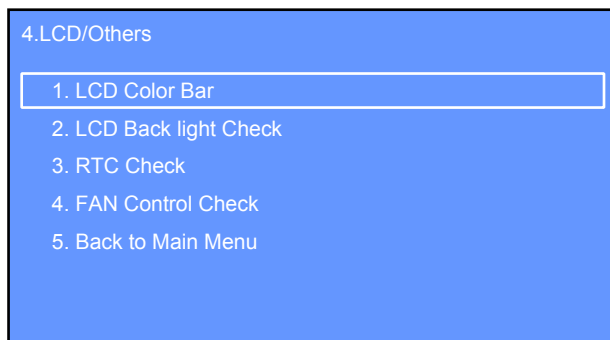




**4-4. LCD/Others**

**Procedure:**

1. Enter the service DIAG mode.  
(Refer to “1. Entering Method of The Service DIAG Mode” on page 31)
2. Rotate the [PUSH ENTER] knob to select the “4. LCD/Others”.
3. Press the [PUSH ENTER] knob to enter the “4. LCD/Others” mode.

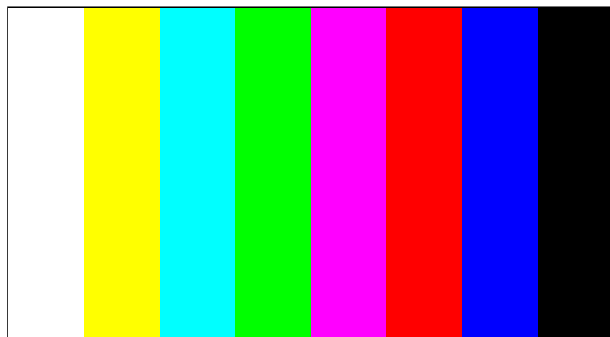


**4-4-1. LCD Color Bar**

It can check the liquid crystal display.

**Procedure:**

1. Enter the “4. LCD/Others” mode.  
(Refer to “4-4. LCD/Others”)
2. Rotate the [PUSH ENTER] knob to select the “1. LCD Color Bar”.
3. Press the [PUSH ENTER] knob to enter the “1. LCD Color Bar” mode.
4. The color bar is displayed on the liquid crystal display.

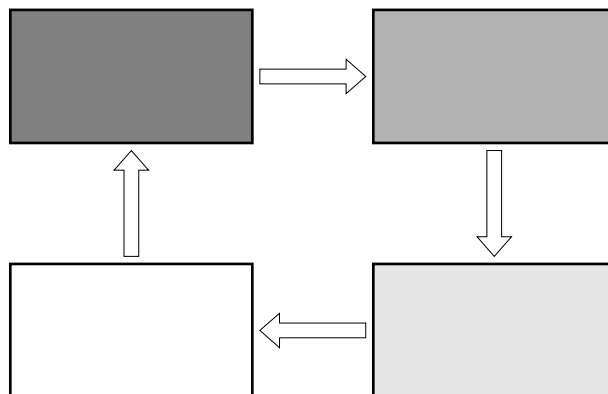


**4-4-2. LCD Back light Check**

It can check the liquid crystal display back light.

**Procedure:**

1. Enter the “4. LCD/Others” mode.  
(Refer to “4-4. LCD/Others”)
2. Rotate the [PUSH ENTER] knob to select the “2. LCD Back light Check”.
3. Press the [PUSH ENTER] knob to enter the “2. LCD Back light Check”.
4. The back light continues changing on the white screen as follows.

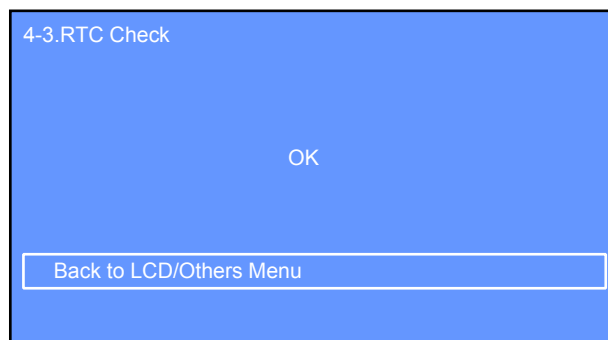


**4-4-3. RTC Check**

It can check the real time clock.

**Procedure:**

1. Enter the “4. LCD/Others” mode.  
(Refer to “4-4. LCD/Others”)
2. Rotate the [PUSH ENTER] knob to select the “3. RTC Check”.
3. Press the [PUSH ENTER] knob to enter the “3. RTC Check” mode.
4. The result of real time clock check “OK” or “NG” is displayed on the liquid crystal display.





- The SMART data is saved as a text file in the USB memory.  
(The file name is "hap\_smart\_data\_xxxxx\_yyyyy.log (xxxxx: hard disk drive model name, yyyy: hard disk drive serial number))
- Note 3:** This file uses Linux newline code "LF". You should use "Internet Explorer" or "text editor" that supports "LF" to open this file.
- Rotate the [PUSH ENTER] knob to scroll the SMART data on the liquid crystal display, and SMART ID is displayed on the liquid crystal display.

SMART ID	SMART raw value
5-4.SMART Data Read	SMART Attributes Data Structure revision number: 16 Vendor Specific SMART Attributes with Thresholds: ID# ATTRIBUTE_NAME FLAG VALUE WORST THRESH TYPE UPDATED WHEN_FAILED RAW_VALUE 1 Raw_Read_Error_Rate 0x000b 100 100 062 Pre-fail
5-4.SMART Data Read	3 Spin_Up_Time 0x0007 194 194 033 Pre-fail Always - 1 4 Start_Stop_Count 0x0012 100 100 000 Old_age Always - 140 5 Reallocated_Sector_Ct 0x0033 100 100 005 Pre-fail Always - 0 7 Seek_Error_Rate 0x000b 100 100 067 Pre-fail Always - 0 8 Seek Time Performance 0x0005 100 100 040 Pre-fail
5-4.SMART Data Read	194 Temperature_Celsius 0x0002 214 214 000 Old_age Always - 28 196 Reallocated_Event_Count 0x0032 100 100 000 Old_age Always - 0 197 Current_Pending_Sector 0x0022 100 100 000 Old_age Always - 0 198 Offline_Uncorrectable 0x0008 100 100 000 Old_age Offline - 0 199 LCMA_CRC_Error_Count 0x000a 200 200 000 Old_age Always 0
	The data was saved to USB memory
	Back to HDD Menu

(Displayed characters/values in the above figure are example)

- Check the SMART raw value of following SMART IDs is displayed on the liquid crystal display.

ID	Name
5	Reallocated sector count
196	Reallocated event count
197	Current pending sector count
198	Offline scan uncorrectable sector count

- If at least one of these ID's SMART raw value is not "0", SMART data check is NG.
- Note 4:** When the SMART data check is NG, replace the hard disk drive.

#### 4-6. Audio

##### Procedure:

- Enter the service DIAG mode.  
(Refer to "1. Entering Method of The Service DIAG Mode" on page 31)
- Rotate the [PUSH ENTER] knob to select the "6. Audio".
- Press the [PUSH ENTER] knob to enter the "6. Audio" mode.

6.Audio

1. Play Audio Data
2. Select Input
3. Back to Main Menu

##### 4-6-1. Play Audio Data

It can play back various audio data.

##### Procedure:

- Enter the "6. Audio" mode.  
(Refer to "4-6. Audio")
- Rotate the [PUSH ENTER] knob to select the "1. Play Audio Data".
- Press the [PUSH ENTER] knob to enter the "1. Play Audio Data" mode.  
(The volume control and muting function is available in this mode)

6-1.Play Audio Data

1. 1kHz DSD 0dB
2. 1kHz PCM 0dB 32bit/48kHz
3. 1kHz PCM 0dB 32bit/44.1kHz
4. 1kHz PCM 0dB 32bit/48kHz PCM Direct
5. 1kHz PCM 0dB 32bit/44.1kHz PCM Direct
6. stop

6-1.Play Audio Data

2. 1kHz PCM 0dB 32bit/48kHz
3. 1kHz PCM 0dB 32bit/44.1kHz
4. 1kHz PCM 0dB 32bit/48kHz PCM Direct
5. 1kHz PCM 0dB 32bit/44.1kHz PCM Direct
6. stop
7. Back to Audio Check Menu

- Select the audio data by rotating the [PUSH ENTER] knob and press the [PUSH ENTER] knob.

**Note 1:** "1. kHz DSD 0dB" does not play back continuously, and stops once after a few seconds.

**Note 2:** "4. 1kHz PCM 0dB 32bit/48kHz PCM Direct" and "5. 1kHz PCM 0dB 32bit/44.1kHz PCM Direct" cannot use in this unit.

- The selected audio data is played back.
- To stop the audio data, rotate the [PUSH ENTER] knob to select the "6. stop" and press the [PUSH ENTER] knob.

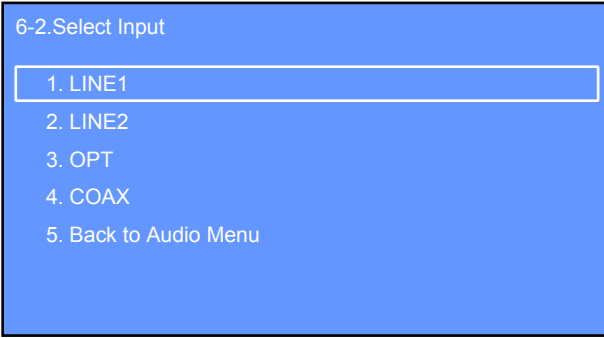
**Note 3:** When checking for the "3. OPT" or "4. COAX" in the "6-2. Select Input" after playing back the "1. kHz DSD 0dB", play back the "2. 1kHz PCM 0dB 32bit/44.1kHz" once, and then enter the "6-2. Select Input" mode.

## 4-6-2. Select Input

It can select the external audio input terminal.

### Procedure:

1. Enter the “6. Audio” mode.  
(Refer to “4-6. Audio” on page 35)
2. Rotate the [PUSH ENTER] knob to select the “2. Select Input”.
3. Press the [PUSH ENTER] knob to enter the “2. Select Input” mode.  
(The volume control and muting function is available in this mode)

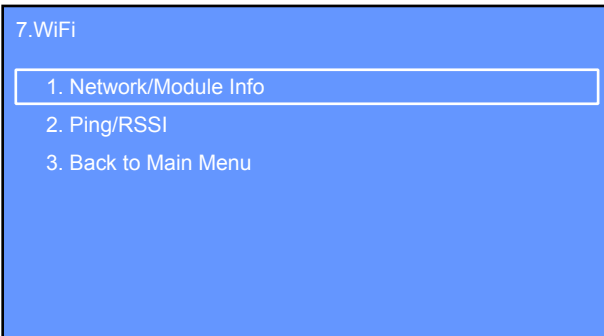


4. Select the external audio input terminal by rotating the [PUSH ENTER] knob and press the [PUSH ENTER] knob.
5. The audio data that input from selected external audio input terminal is output.

## 4-7. WiFi

### Procedure:

1. Set the SSID and KEY of the connecting access point with “SONY\_HAP\_TEST”.
2. Enter the service DIAG mode.  
(Refer to “1. Entering Method of The Service DIAG Mode” on page 31)
3. Rotate the [PUSH ENTER] knob to select the “7. WiFi”.
4. Press the [PUSH ENTER] knob to enter the “7. WiFi” mode.



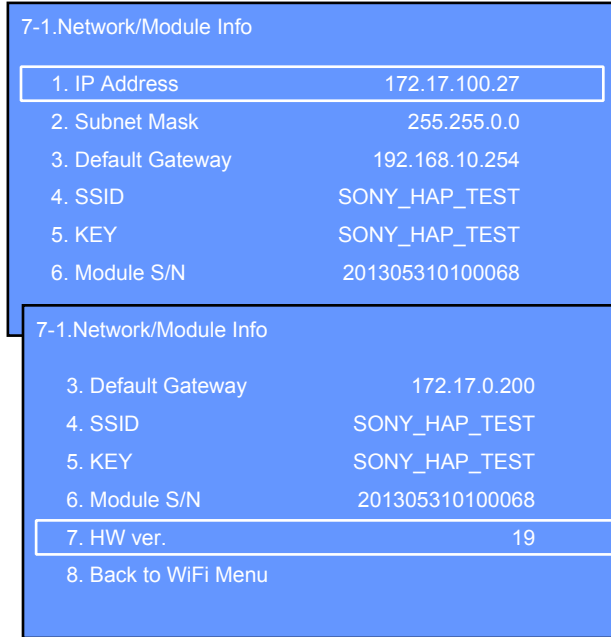
## 4-7-1. Network/Module Info

It can display the wireless network and module information.

### Procedure:

1. Enter the “7. WiFi” mode.  
(Refer to “4-7. WiFi”)
2. Rotate the [PUSH ENTER] knob to select the “1. Network/module Info”.
3. Press the [PUSH ENTER] knob to enter the “1. Network/module Info” mode.

**Note:** “1. IP Address”, “2. Subnet Mask” and “3. Default Gateway” supports only DHCP.



(Displayed characters/values in the above figure are example)

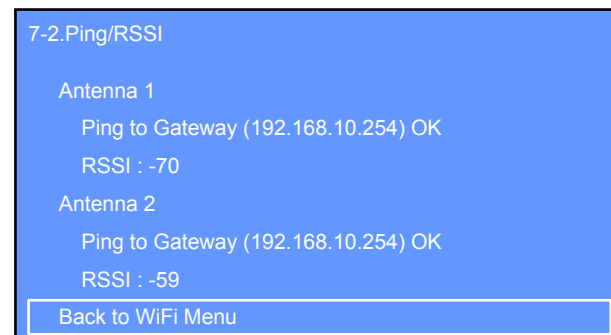
## 4-7-2. Ping/RSSI

It can display the results indicating whether or not the gateway responded to the PING and RSSI value.

**Note:** This mode supports only DHCP.

### Procedure:

1. Enter the “7. WiFi” mode.  
(Refer to “4-7. WiFi”)
2. Rotate the [PUSH ENTER] knob to select the “2. Ping/RSSI”.
3. Press the [PUSH ENTER] knob to enter the “2. Ping/RSSI” mode.
4. The results indicating whether or not the gateway responded to the PING and RSSI value is displayed on the liquid crystal display.  
(When the gateway does not respond to the PING, “Error!! Can’t get gateway-ip” is displayed on the liquid crystal display)

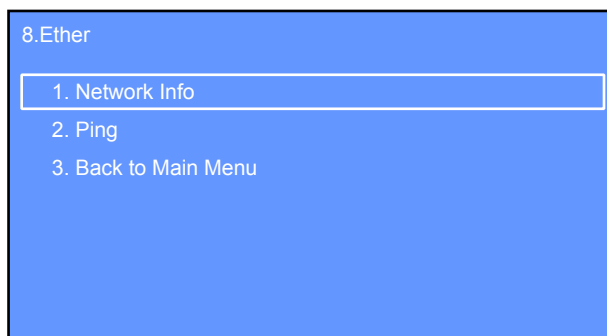


(Displayed characters/values in the above figure are example)

#### 4-8. Ether

##### Procedure:

1. Connect the main unit to the router with the network LAN cable.
2. Enter the service DIAG mode.  
(Refer to “1. Entering Method of The Service DIAG Mode” on page 31)
3. Rotate the [PUSH ENTER] knob to select the “8. Ether”.
4. Press the [PUSH ENTER] knob to enter the “8. Ether” mode.



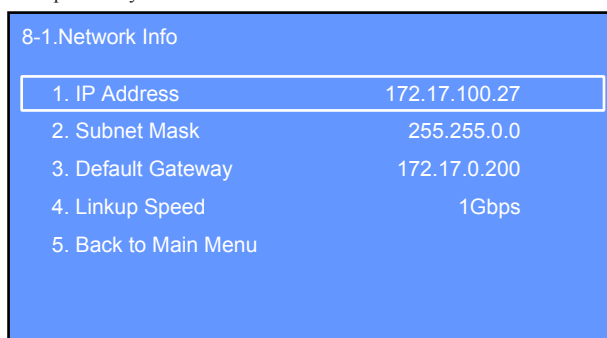
##### 4-8-1. Network Info

It can display the wired network information.

##### Procedure:

1. Enter the “8. Ether” mode.  
(Refer to “4-8. Ether”)
2. Rotate the [PUSH ENTER] knob to select the “1. Network Info”.
3. Press the [PUSH ENTER] knob to enter the “1. Network Info” mode.

**Note:** “1. IP Address”, “2. Subnet Mask” and “3. Default Gateway” supports only DHCP.



(Displayed characters/values in the above figure are example)

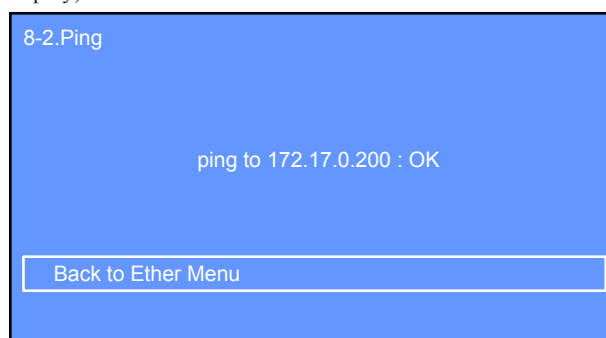
##### 4-8-2. Ping

It can display the results indicating whether or not the gateway responded to the PING.

**Note:** This mode supports only DHCP.

##### Procedure:

1. Enter the “8. Ether” mode.  
(Refer to “4-8. Ether”)
2. Rotate the [PUSH ENTER] knob to select the “2. Ping”.
3. Press the [PUSH ENTER] knob to enter the “2. Ping” mode.
4. The results indicating whether or not the gateway responded to the PING is displayed on the liquid crystal display.  
(When the gateway does not respond to the PING, “Error!! Can’t get gateway-ip” is displayed on the liquid crystal display)



(Displayed characters/values in the above figure are example)

##### 4-9. IR Learning

This item cannot use in this unit.

##### 4-10. Quit

Rotate the [PUSH ENTER] knob to select the “10. Quit” and press the [PUSH ENTER] knob, service DIAG mode is released.

## SECTION 4 ELECTRICAL CHECK

### HDD CHECK

It can check the result of hard disk drive test.

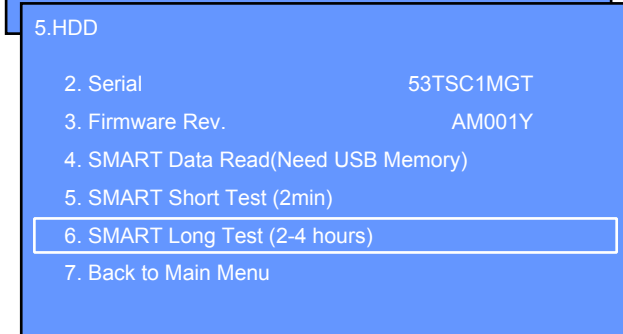
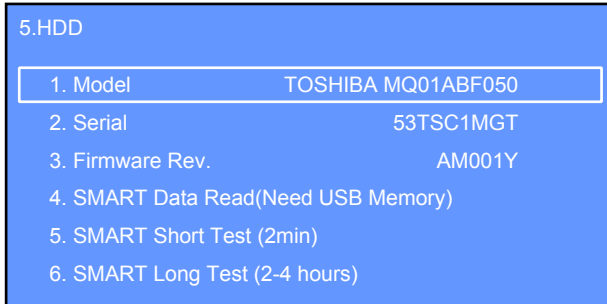
#### 1. Operation of The SMART Long Test

The SMART long test is mode to perform the overall test of hard disk drive.

When checking the hard disk drive, perform the SMART long test.

#### Procedure:

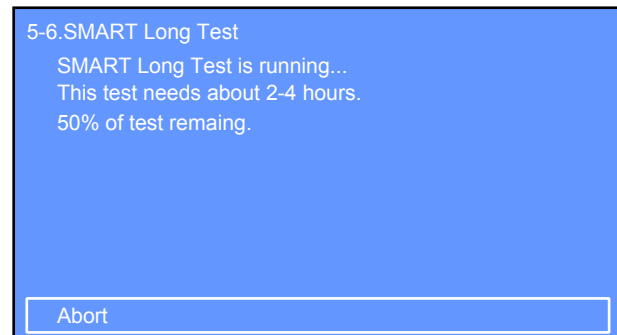
1. Enter the service DIAG mode.  
(Refer to “1. Entering method of the service DIAG mode” on page 31)
2. Rotate the [PUSH ENTER] knob to select the “5. HDD”.
3. Press the [PUSH ENTER] knob to enter the “5. HDD” mode.



(Displayed characters/values in the above figure are example)

4. Rotate the [PUSH ENTER] knob to select the “6. SMART Long Test (2-4 hours)”.
5. Press the [PUSH ENTER] knob to enter the “6. SMART Long Test (2-4 hours)” mode.

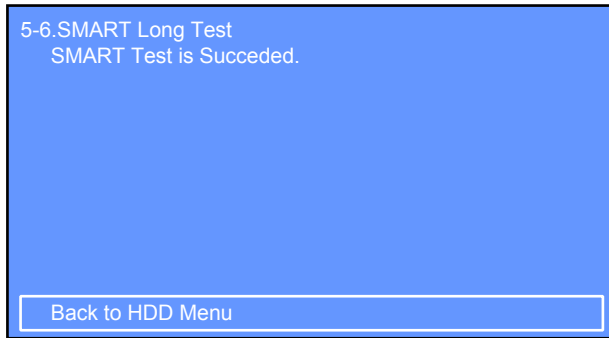
**Note 1:** Two keys of the [HOME] and [BACK] is invalid during SMART long test.



(Displayed characters/values in the above figure are example)

6. Press the [PUSH ENTER] knob to abort the SMART long test.

7. When the result of test is OK, following screen is displayed on the liquid crystal display.



**Note 2:** When “SMART Test is Failed.” is displayed on the liquid crystal display, refer to “3. Checking Method of The SMART Test Result” on page 39.

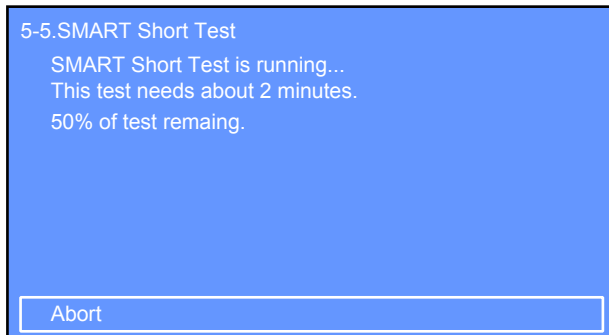
#### 2. Operation of The SMART Short Test

The SMART short test is mode to perform the simple test of hard disk drive in a short time.

#### Procedure:

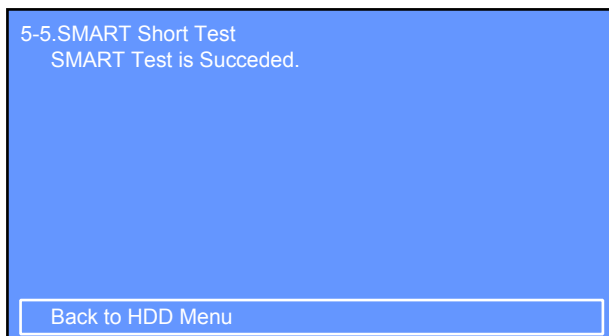
1. Enter the “5. HDD” mode.  
(Refer to “1. Operation of The SMART Long Test”)
2. Rotate the [PUSH ENTER] knob to select the “5. SMART Short Test (2min)”.
3. Press the [PUSH ENTER] knob to enter the “5. SMART Short Test (2min)” mode.

**Note 1:** Two keys of the [HOME] and [BACK] is invalid during SMART short test.



(Displayed characters/values in the above figure are example)

4. Press the [PUSH ENTER] knob to abort the SMART short test.
5. When the result of test is OK, following screen is displayed on the liquid crystal display.

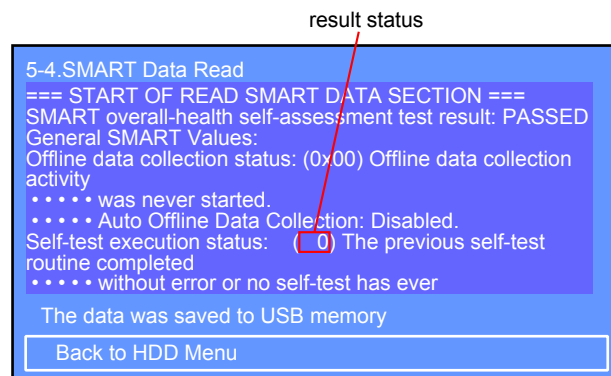


**Note 2:** When “SMART Test is Failed.” is displayed on the liquid crystal display, refer to “3. Checking Method of The SMART Test Result” on page 39.

**3. Checking Method of The SMART Test Result**

**Procedure:**

1. After the SMART test is completed, press the [PUSH ENTER] knob or [BACK] key to return to the “5. HDD” menu.
2. Rotate the [PUSH ENTER] knob to select the “4. SMART Data Read(Need USB Memory)” and press the [PUSH ENTER] knob.
3. Rotate the [PUSH ENTER] knob to scroll the SMART data on the liquid crystal display, and “START OF READ SMART DATA SECTION” is displayed on the liquid crystal display.



(Displayed characters/values in the above figure are example)

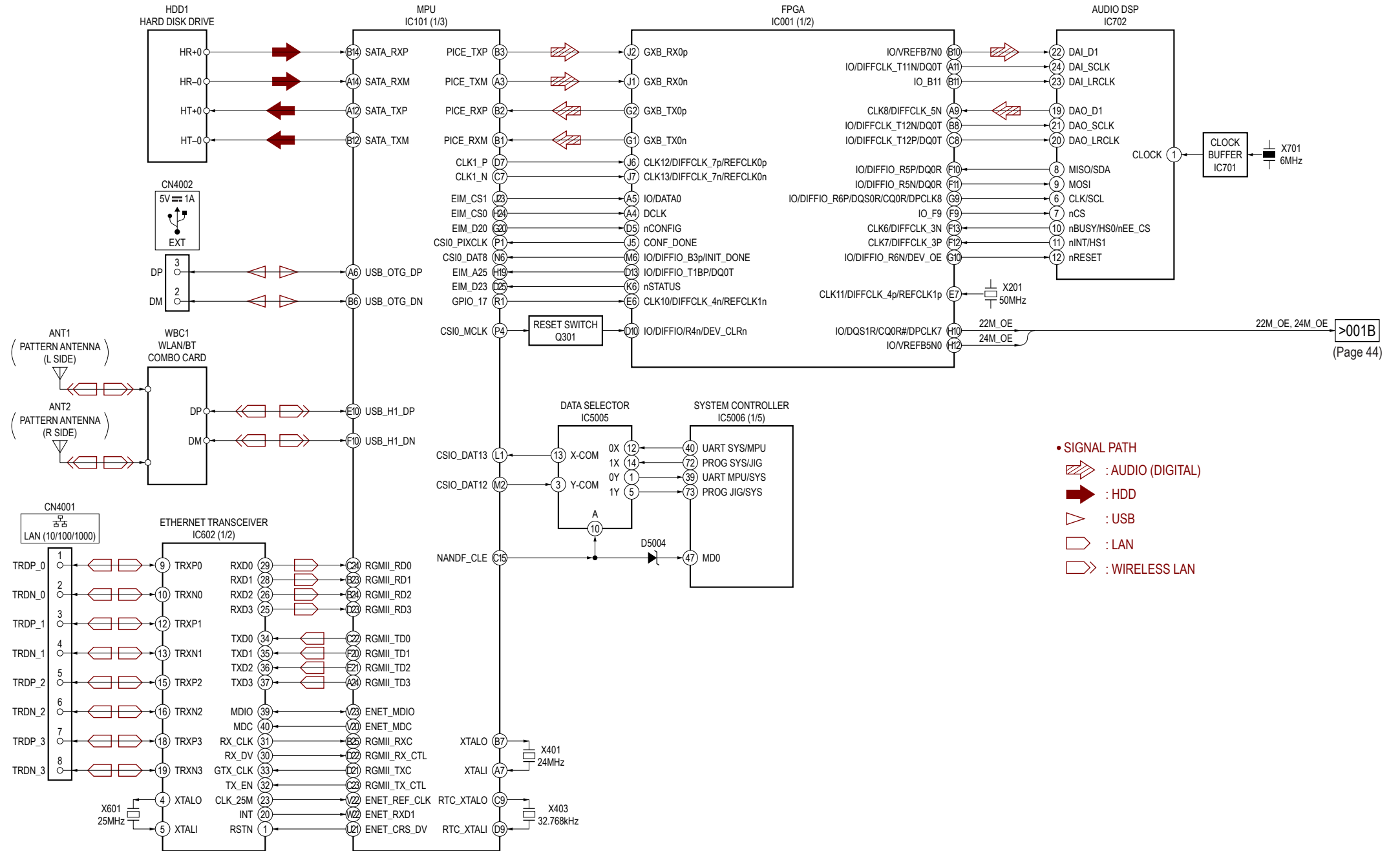
4. Read the result status value is displayed on the liquid crystal display, and check the error contents at the following table.

- Result status = XXh

Result status	Description
0Xh	The previous self-test routine completed without error or no self-test has ever been run
1Xh	The self-test routine was aborted by the host
2Xh	The self-test routine was interrupted by the host with a hardware or software reset
3Xh	A fatal error or unknown test error occurred while the device was executing its self-test routine and the device was unable to complete the self-test routine
4Xh	The previous self-test completed having a test element that failed and the test element that failed is not known.
5Xh	The previous self-test completed having the electrical element of the test failed
6Xh	The previous self-test completed having the servo and/or seek test element of the test failed
7Xh	The previous self-test completed having the read element of the test failed
8Xh	The previous self-test completed having a test element that failed and the device is suspected of having handling damage
9Xh – EXh	Reserved
FXh	Self-test routine in progress

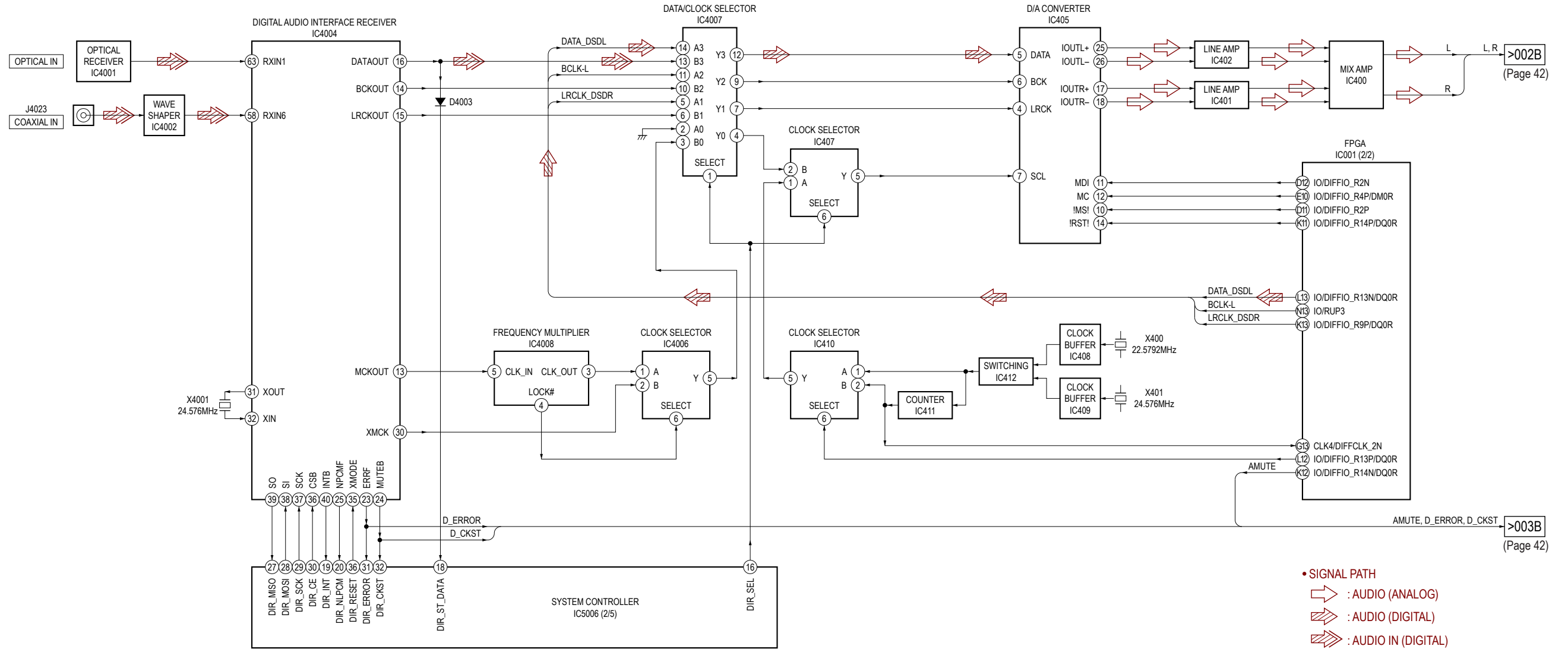
SECTION 5  
DIAGRAMS

5-1. BLOCK DIAGRAM - HDD/USB/LAN/FPGA/DSP Section -

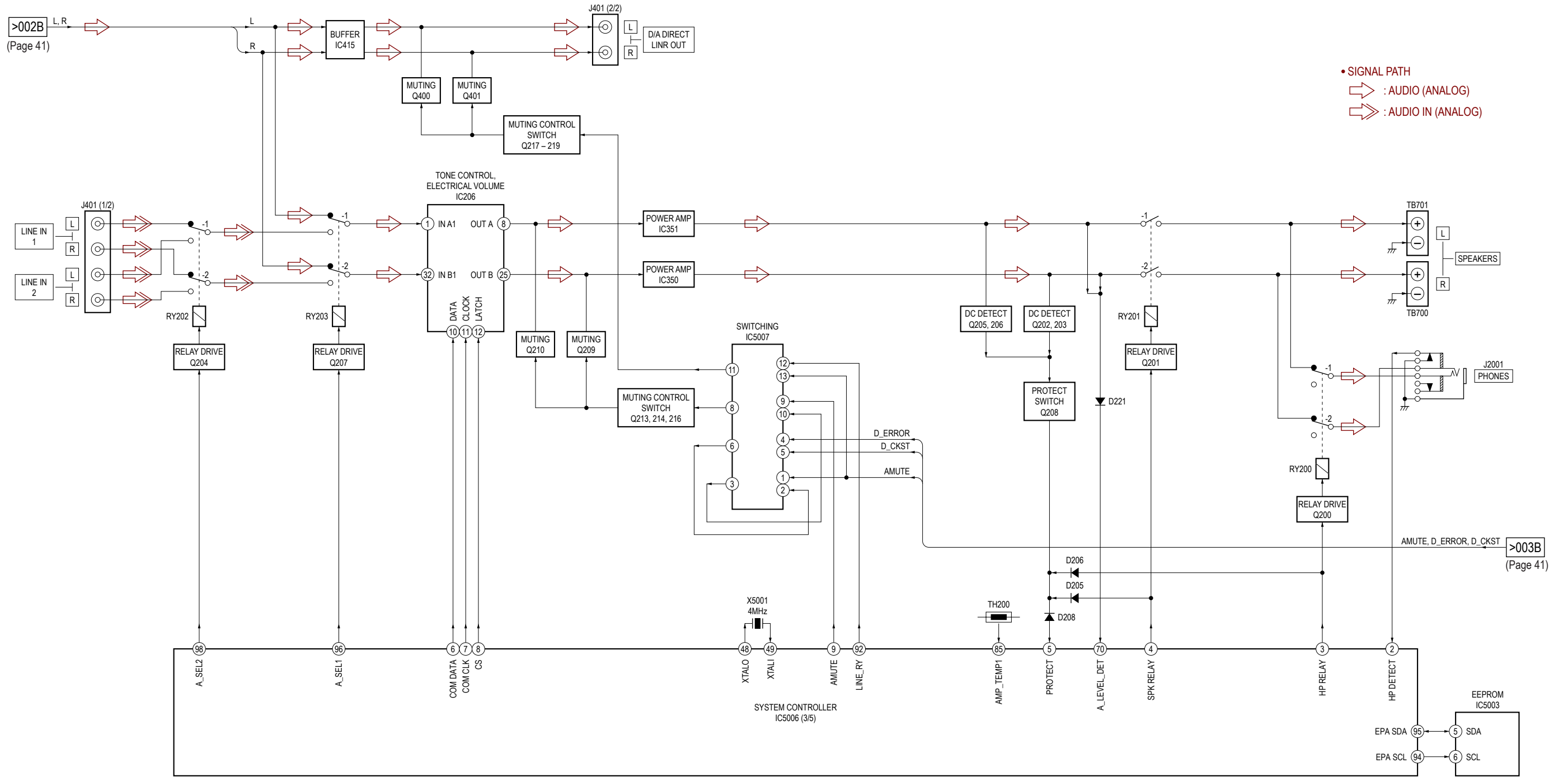




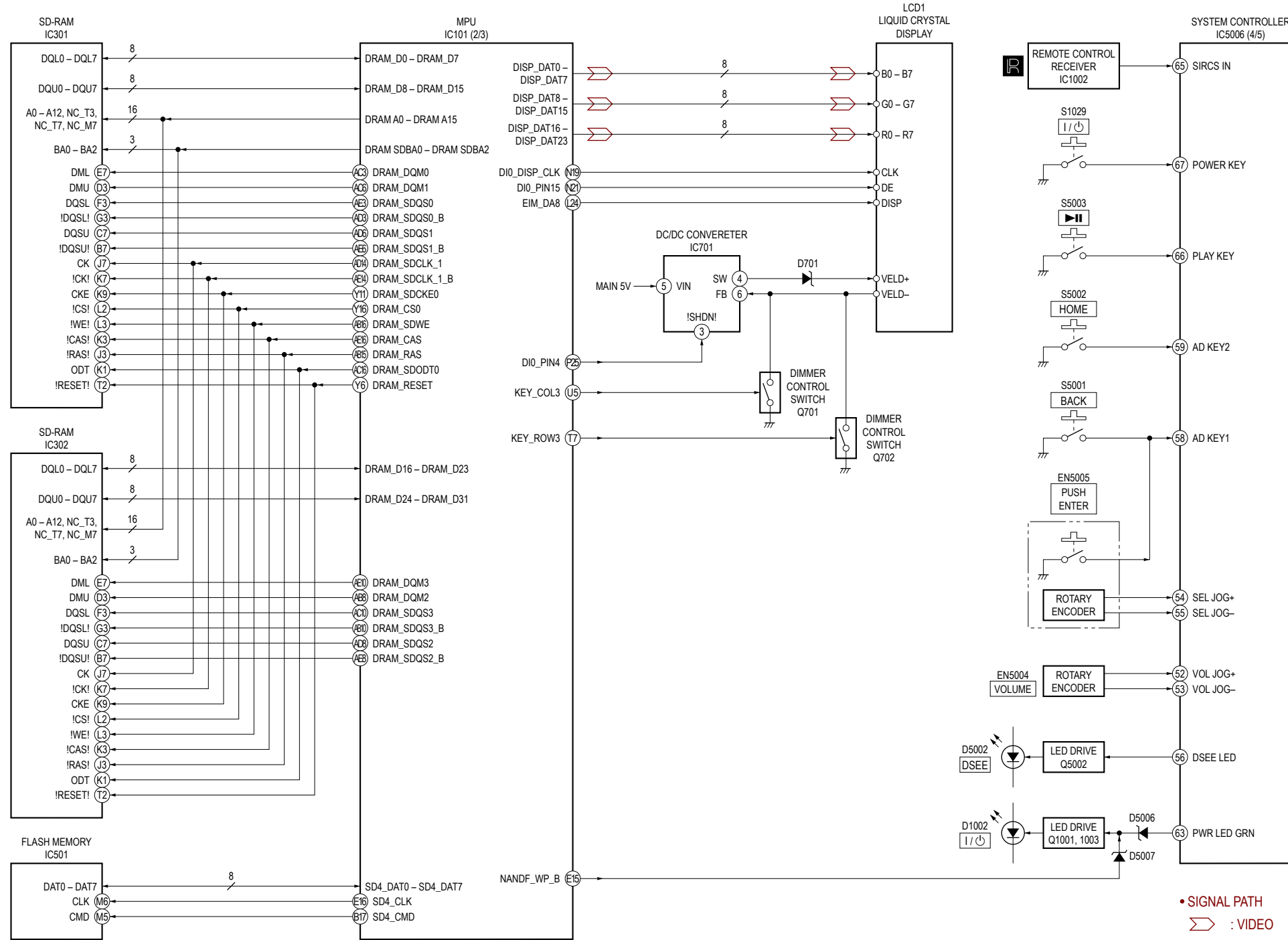
5-2. BLOCK DIAGRAM - DIGITAL AUDIO INPUT Section -



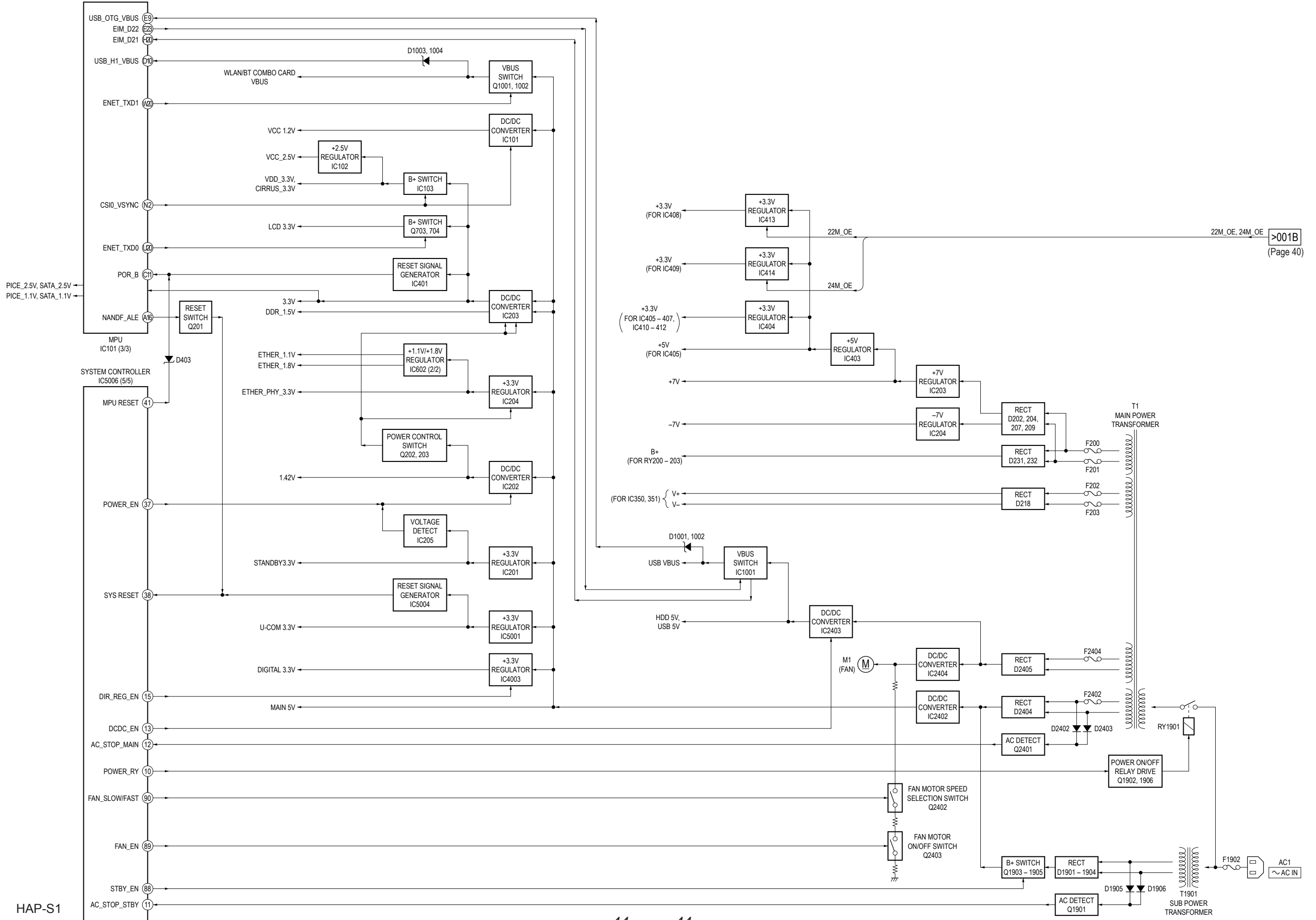
5-3. BLOCK DIAGRAM - ANALOG AUDIO INPUT/OUTPUT Section -



5-4. BLOCK DIAGRAM - MEMORY/PANEL Section -



5-5. BLOCK DIAGRAM - POWER SUPPLY Section -



>001B  
(Page 40)

**THIS NOTE IS COMMON FOR PRINTED WIRING BOARDS AND SCHEMATIC DIAGRAMS.**  
**(In addition to this, the necessary note is printed in each block.)**

**For Printed Wiring Boards.**

**Note:**

- : Parts extracted from the component side.
- : Parts extracted from the conductor side.
- △: Internal component.
- : Pattern from the side which enables seeing. (The other layers' patterns are not indicated.)

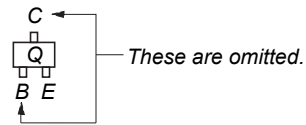
**Caution:**

Pattern face side: Parts on the pattern face side seen (Conductor Side) from the pattern face are indicated.  
 Parts face side: Parts on the parts face side seen from (Component Side) the parts face are indicated.

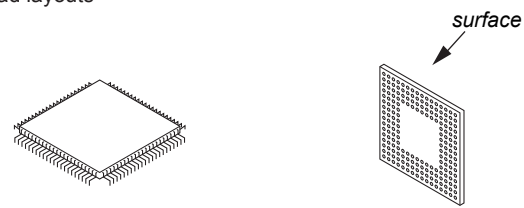
**Caution:**

Pattern face side: Parts on the pattern face side seen (SIDE B) from the pattern face are indicated.  
 Parts face side: Parts on the parts face side seen from (SIDE A) the parts face are indicated.

- FPGA DSP and MAIN boards are multi-layer printed board. However, the patterns of intermediate layers have not been included in diagrams.
- Indication of transistor.



- Lead layouts



Lead layout of conventional IC      CSP (Chip Size Package)

- Abbreviation  
 CND : Canadian model

**Note 1:** When the complete MAIN board is replaced, refer to "NOTE OF REPLACING THE COMPLETE MAIN BOARD" and "CHECKING METHOD OF NETWORK CONNECTION" on page 5.

**Note 2:** When the complete AMP board is replaced, refer to "NOTE OF REPLACING THE D218, IC350 AND IC351 ON THE AMP BOARD AND THE COMPLETE AMP BOARD" on page 4.

**For Schematic Diagrams.**

**Note:**

- All capacitors are in  $\mu\text{F}$  unless otherwise noted. (p: pF) 50 WV or less are not indicated except for electrolytics and tantalums.
- All resistors are in  $\Omega$  and 1/4 W or less unless otherwise specified.
- △: Internal component.
- ⊞: Nonflammable resistor.
- : Panel designation.

**Note:**

The components identified by mark △ or dotted line with mark △ are critical for safety. Replace only with part number specified.

**Note:**

Les composants identifiés par une marque △ sont critiques pour la sécurité. Ne les remplacer que par une pièce portant le numéro spécifié.

- : B+ Line.
- - -: B- Line.
- Voltages and waveforms are dc with respect to ground under no-signal conditions.  
 no mark: POWER ON
- Voltages are taken with VOM (Input impedance 10 M $\Omega$ ). Voltage variations may be noted due to normal production tolerances.
- Waveforms are taken with a oscilloscope. Voltage variations may be noted due to normal production tolerances.
- Circled numbers refer to waveforms.
- Signal path.
  - ⇨: AUDIO (ANALOG)
  - ⇨: AUDIO (DIGITAL)
  - ⇨: AUDIO IN (ANALOG)
  - ⇨: AUDIO IN (DIGITAL)
  - ⇨: HDD
  - ⇨: USB
  - ⇨: LAN
  - ⇨: WIRELESS LAN
  - ⇨: VIDEO

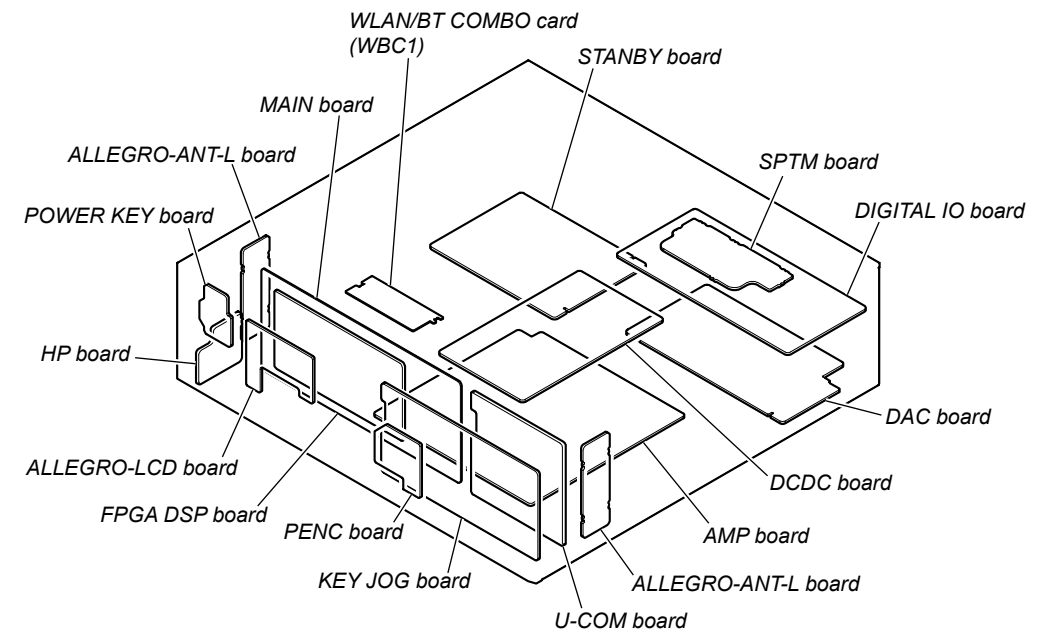
- The voltage and waveform of CSP (chip size package) cannot be measured, because its lead layout is different from that of conventional IC.

- Abbreviation  
 CND : Canadian model

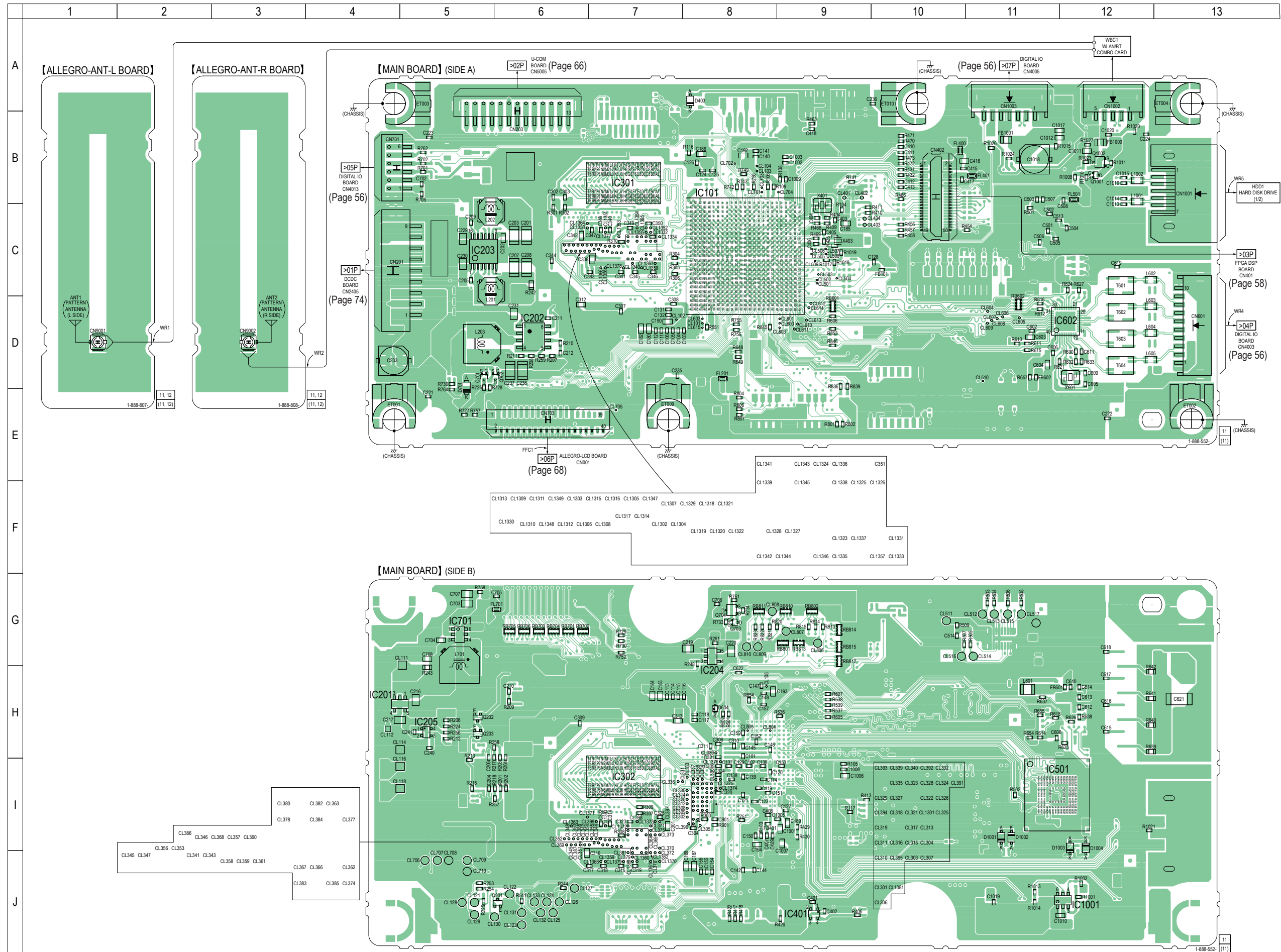
**Note 1:** When the complete MAIN board is replaced, refer to "NOTE OF REPLACING THE COMPLETE MAIN BOARD" and "CHECKING METHOD OF NETWORK CONNECTION" on page 5.

**Note 2:** When the complete AMP board is replaced, refer to "NOTE OF REPLACING THE D218, IC350 AND IC351 ON THE AMP BOARD AND THE COMPLETE AMP BOARD" on page 4.

• Circuit Boards Location



5-6. PRINTED WIRING BOARDS - MAIN Section - • See page 45 for Circuit Boards Location. •  : Uses unleaded solder.



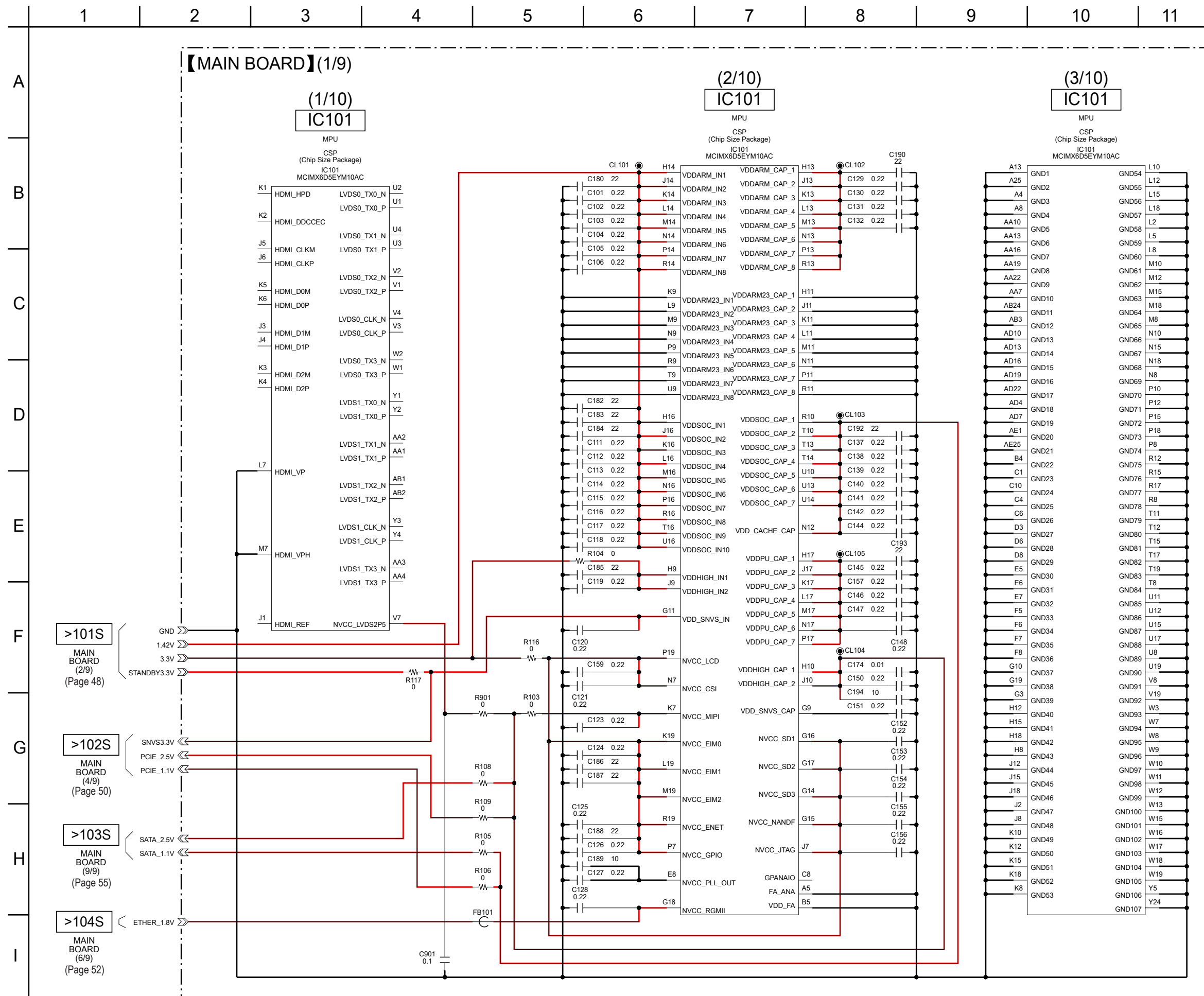
**Note 1:** The ALLEGRO-ANT-L and ALLEGRO-ANT-R boards are not covered in the servicing.

**Note 2:** IC101 on the MAIN board cannot exchange with single. When this part is damaged, exchange the complete mounted board.

**Note 3:** When the WLAN/BT COMBO card (Ref. No. WBC1) and coaxial (U.FL connector) cables (Ref. No. WR1, WR2) are replaced, refer to “CHECKING METHOD OF NETWORK CONNECTION” on page 5.

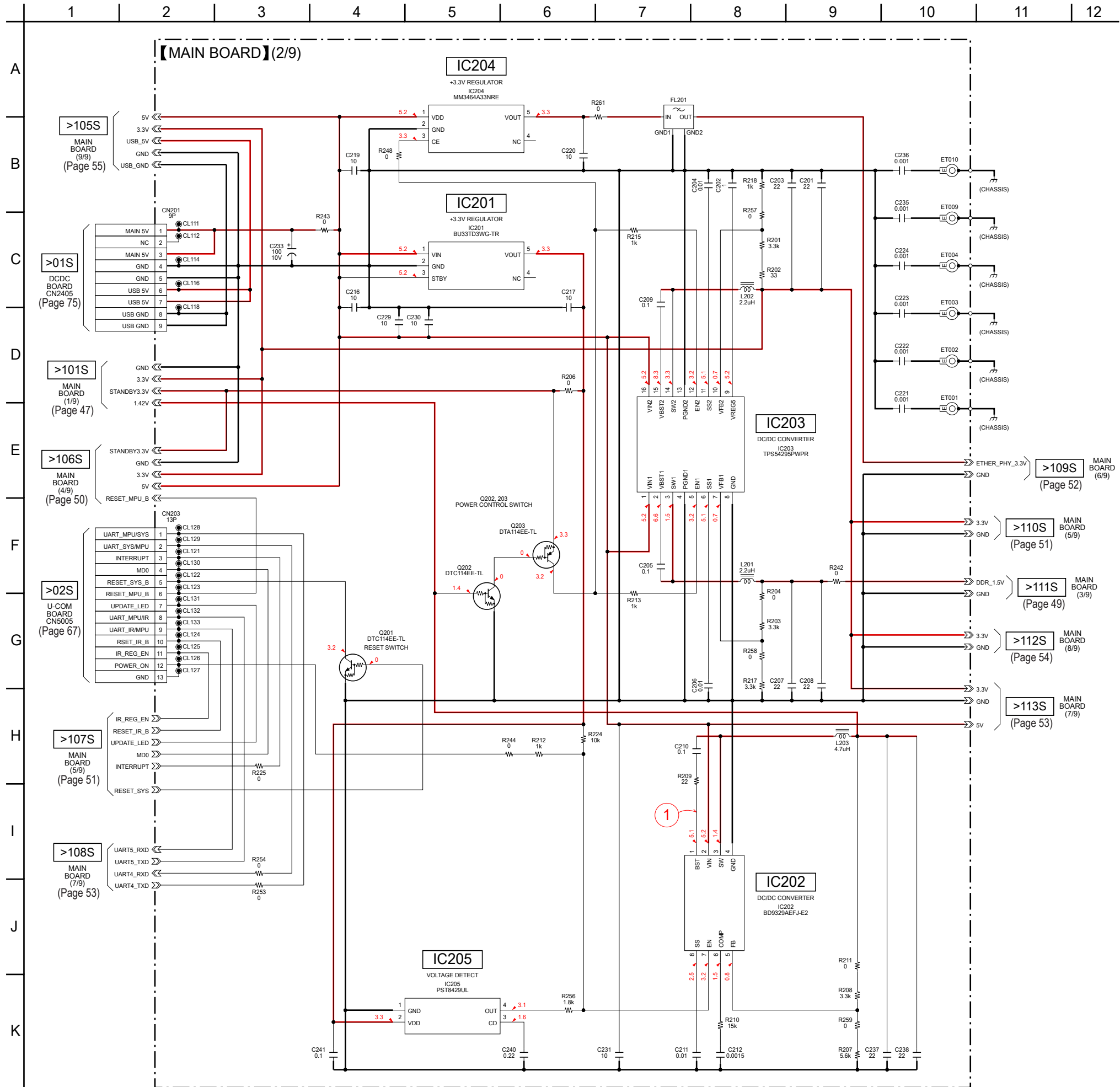
**Note 4:** When the hard disk drive (Ref. No. HDD1) is replaced, refer to “NOTE OF REPLACING THE HARD DISK DRIVE (Ref. No. HDD1)” on page 4.

5-7. SCHEMATIC DIAGRAM - MAIN Section (1/9) - See page 86 for IC Pin Function Description.



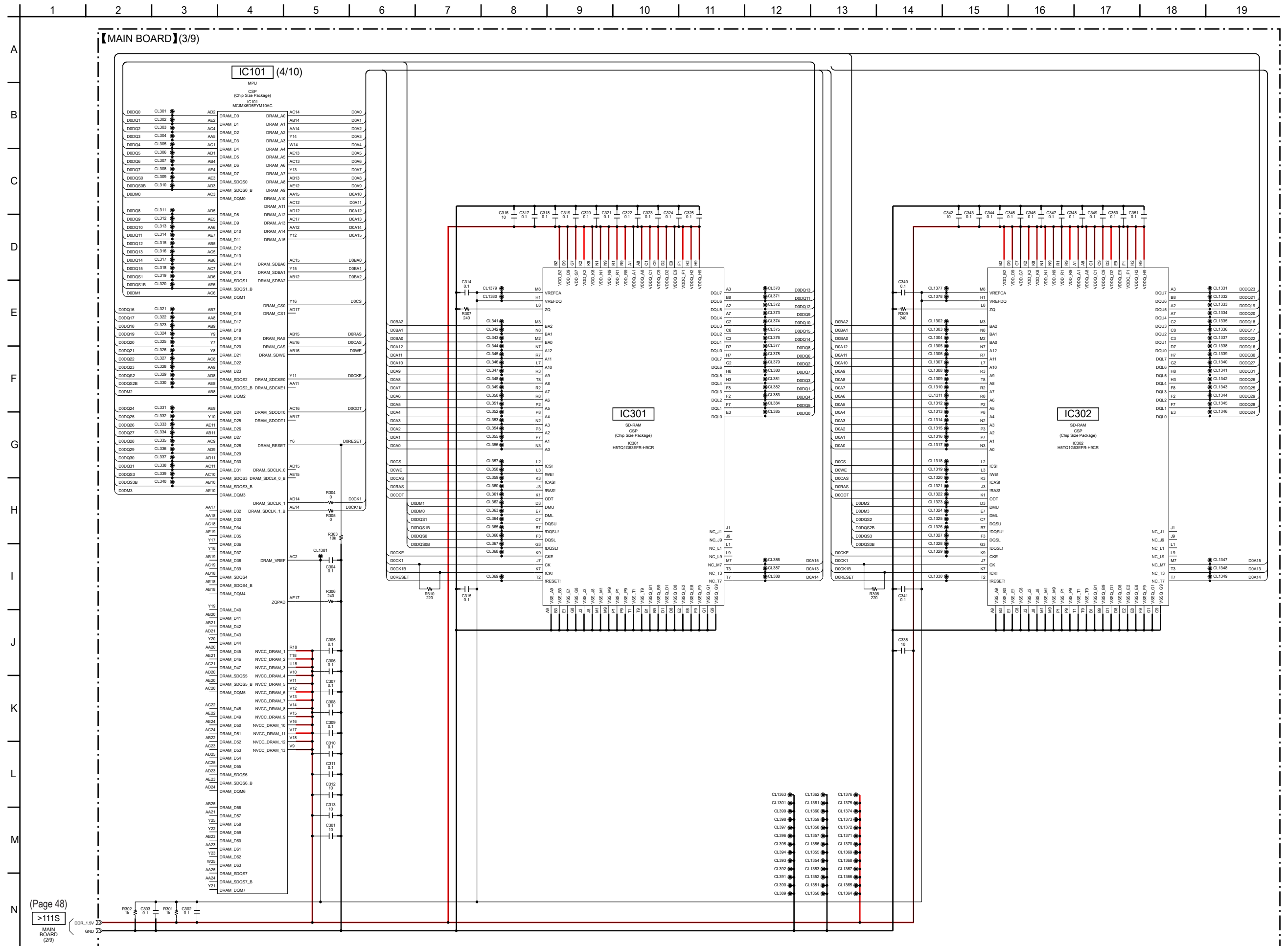
Note: IC101 on the MAIN board cannot exchange with single. When this part is damaged, exchange the complete mounted board.

5-8. SCHEMATIC DIAGRAM - MAIN Section (2/9) - • See page 73 for Waveforms. • See page 78 for IC Block Diagrams.



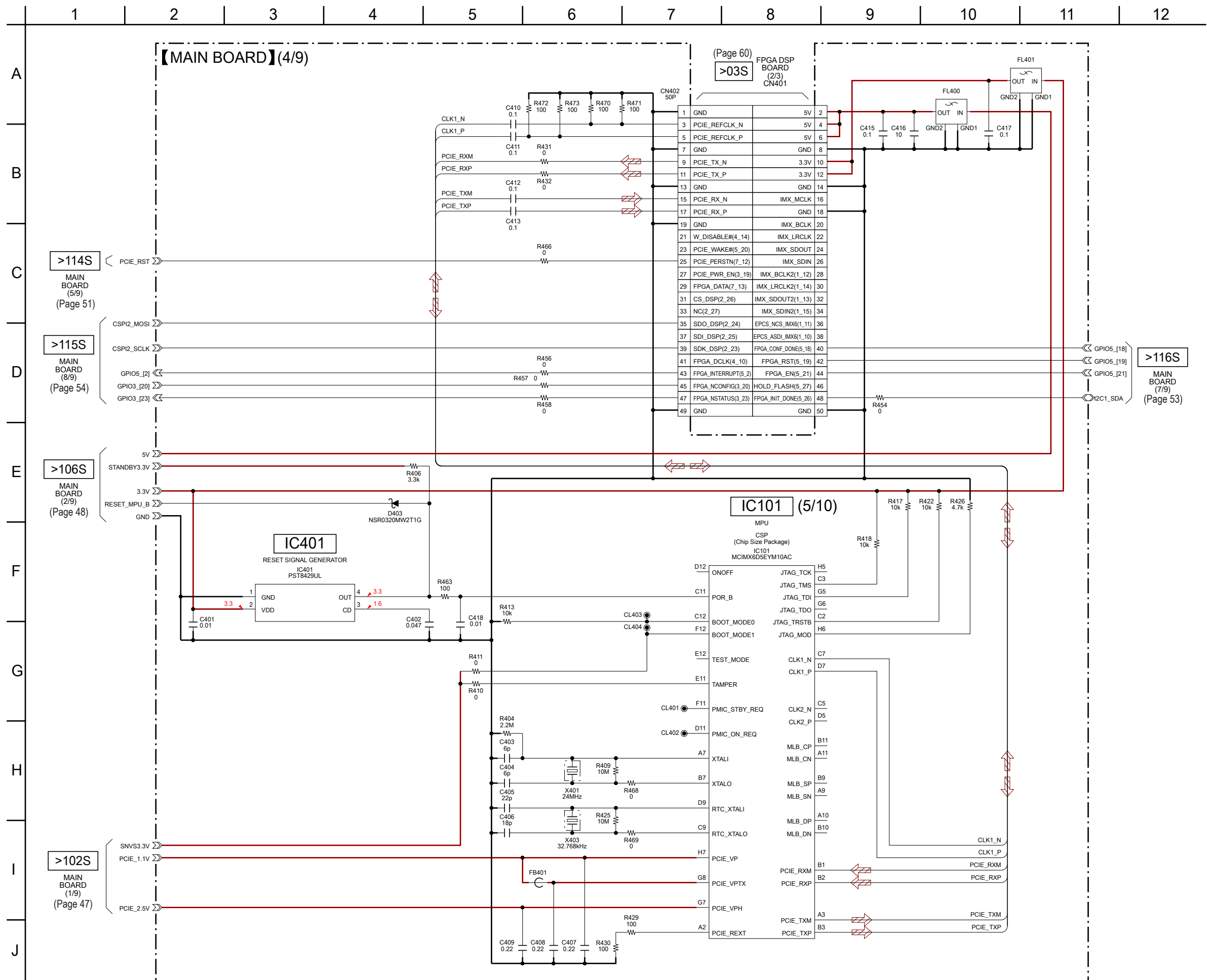


5-9. SCHEMATIC DIAGRAM - MAIN Section (3/9) - • See page 86 for IC Pin Function Description.



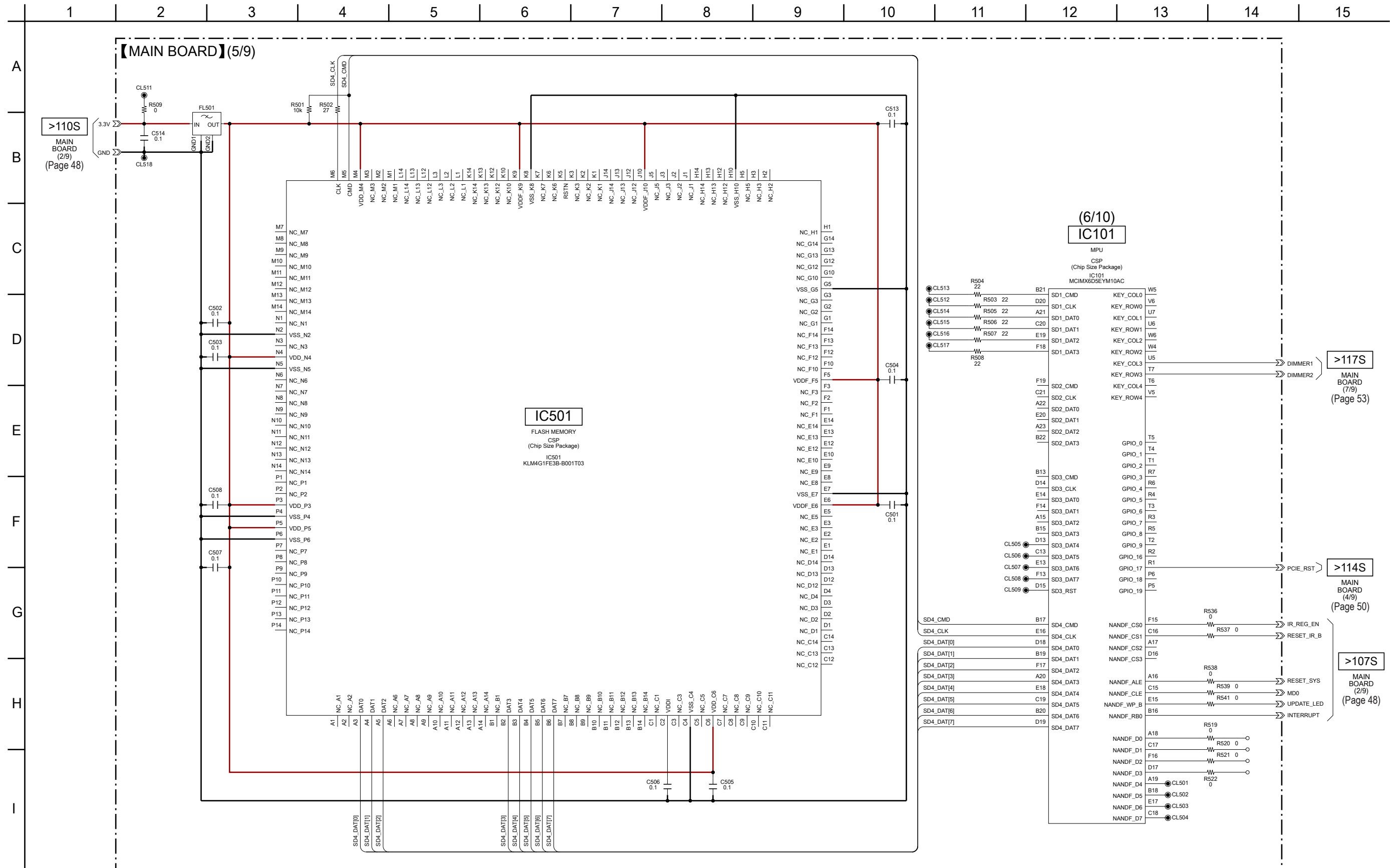
Note: IC101, IC301 and IC302 on the MAIN board cannot exchange with single. When these parts are damaged, exchange the complete mounted board.

5-10. SCHEMATIC DIAGRAM - MAIN Section (4/9) - See page 78 for IC Block Diagrams. • See page 86 for IC Pin Function Description.



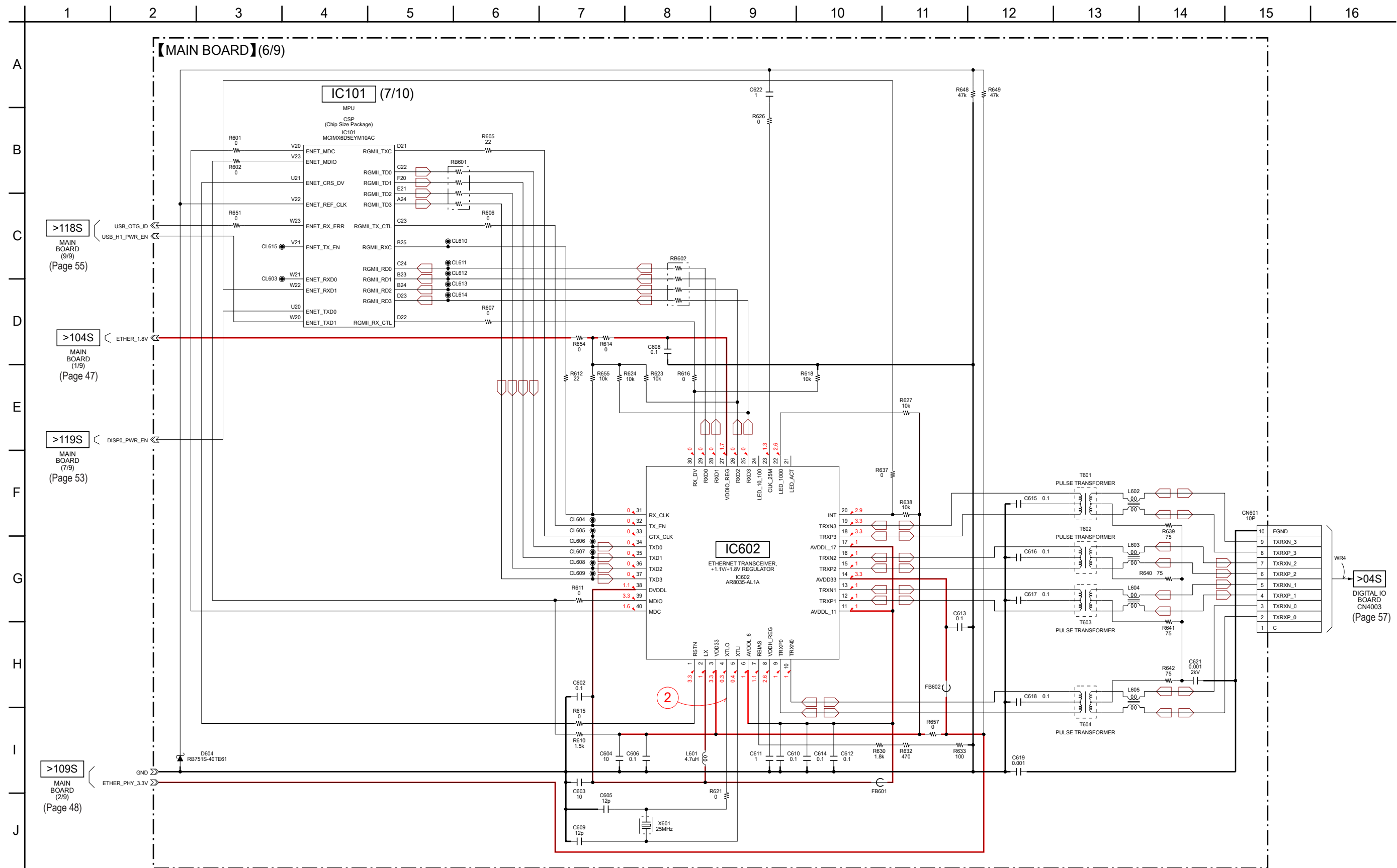
Note: IC101 on the MAIN board cannot exchange with single. When this part is damaged, exchange the complete mounted board.

5-11. SCHEMATIC DIAGRAM - MAIN Section (5/9) - • See page 86 for IC Pin Function Description.

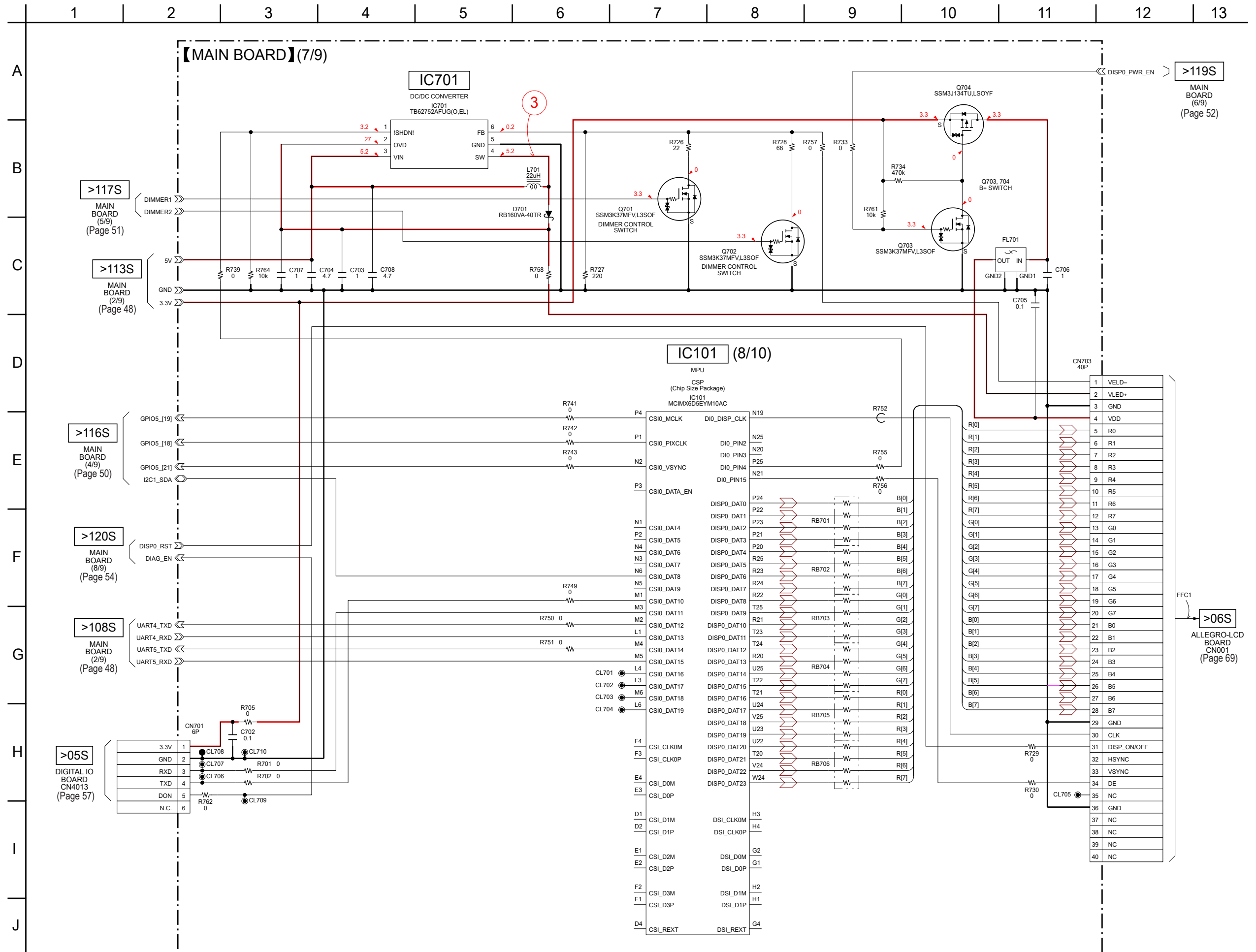


**Note:** IC101 and IC501 on the MAIN board cannot exchange with single. When these parts are damaged, exchange the complete mounted board.

5-12. SCHEMATIC DIAGRAM - MAIN Section (6/9) - • See page 73 for Waveforms. • See page 86 for IC Pin Function Description.

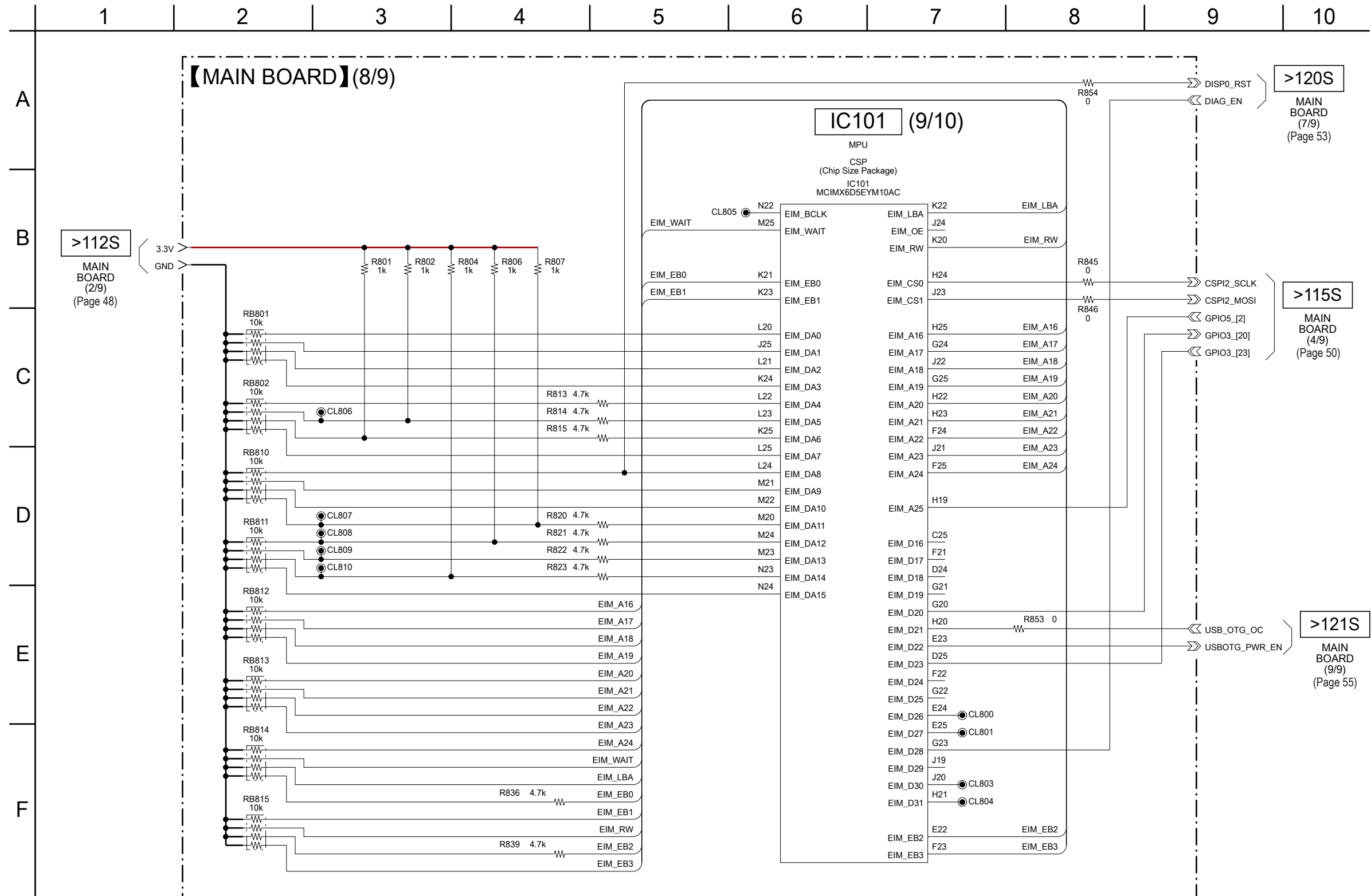


5-13. SCHEMATIC DIAGRAM - MAIN Section (7/9) - • See page 73 for Waveforms. • See page 86 for IC Pin Function Description.



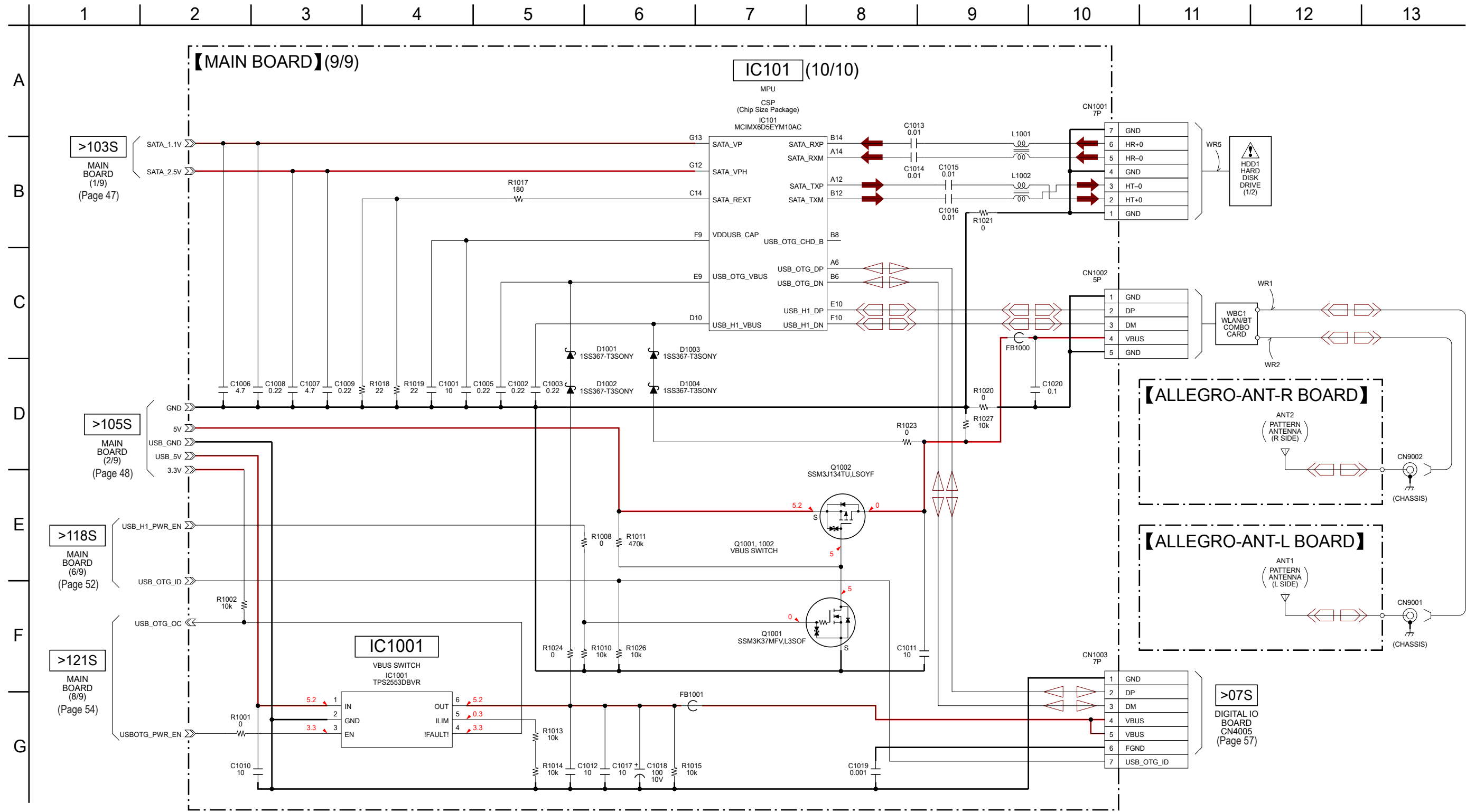
Note: IC101 on the MAIN board cannot exchange with single. When this part is damaged, exchange the complete mounted board.

5-14. SCHEMATIC DIAGRAM - MAIN Section (8/9) - • See page 86 for IC Pin Function Description.



**Note:** IC101 on the MAIN board cannot exchange with single. When this part is damaged, exchange the complete mounted board.

5-15. SCHEMATIC DIAGRAM - MAIN Section (9/9) - • See page 78 for IC Block Diagrams. • See page 86 for IC Pin Function Description.



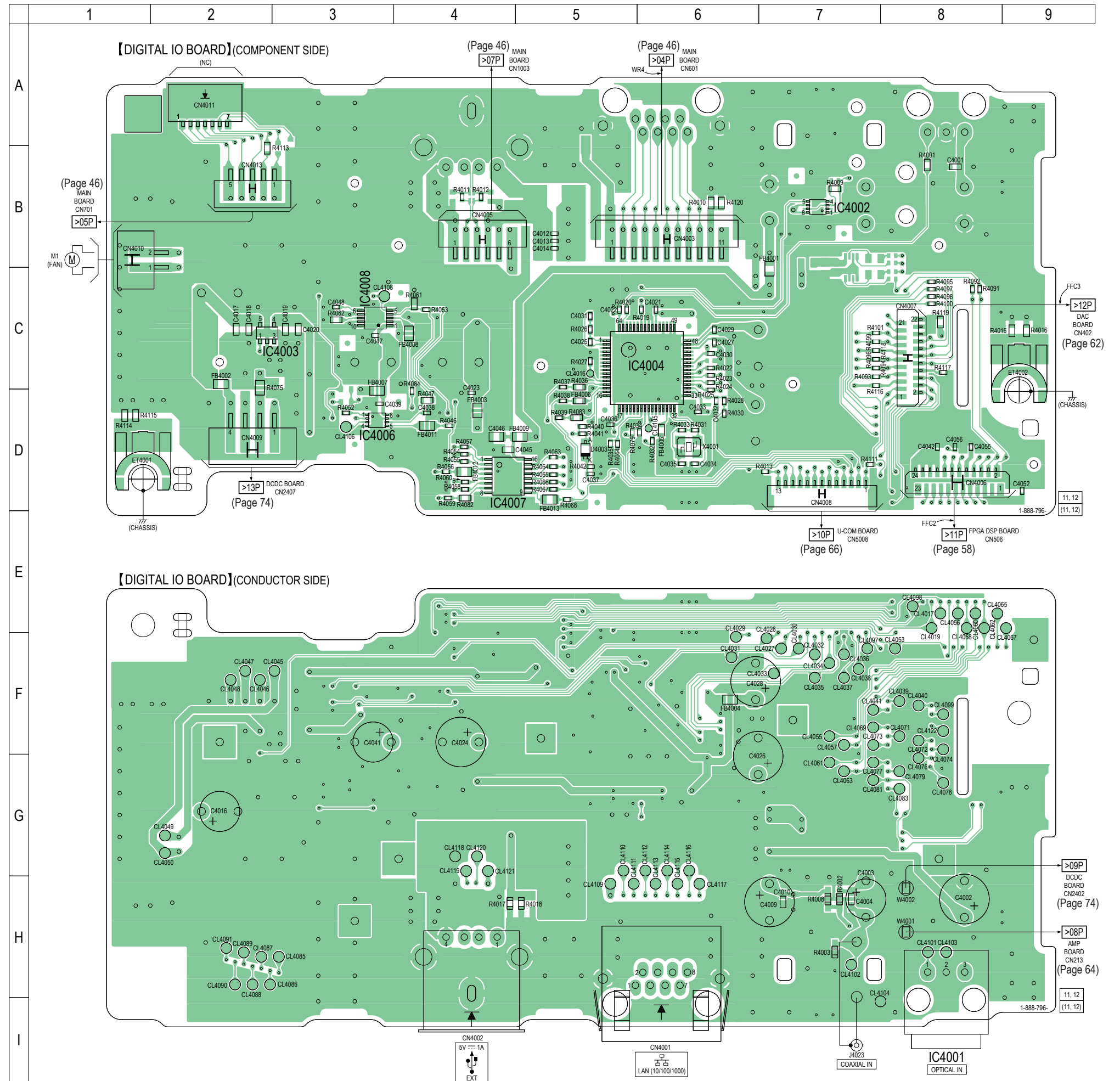
**Note 1:** The ALLEGRO-ANT-L and ALLEGRO-ANT-R boards are not covered in the servicing.

**Note 2:** IC101 on the MAIN board cannot exchange with single. When this part is damaged, exchange the complete mounted board.

**Note 3:** When the WLAN/BT COMBO card (Ref. No. WBC1) and coaxial (U.FL connector) cables (Ref. No. WR1, WR2) are replaced, refer to "CHECKING METHOD OF NETWORK CONNECTION" on page 5.

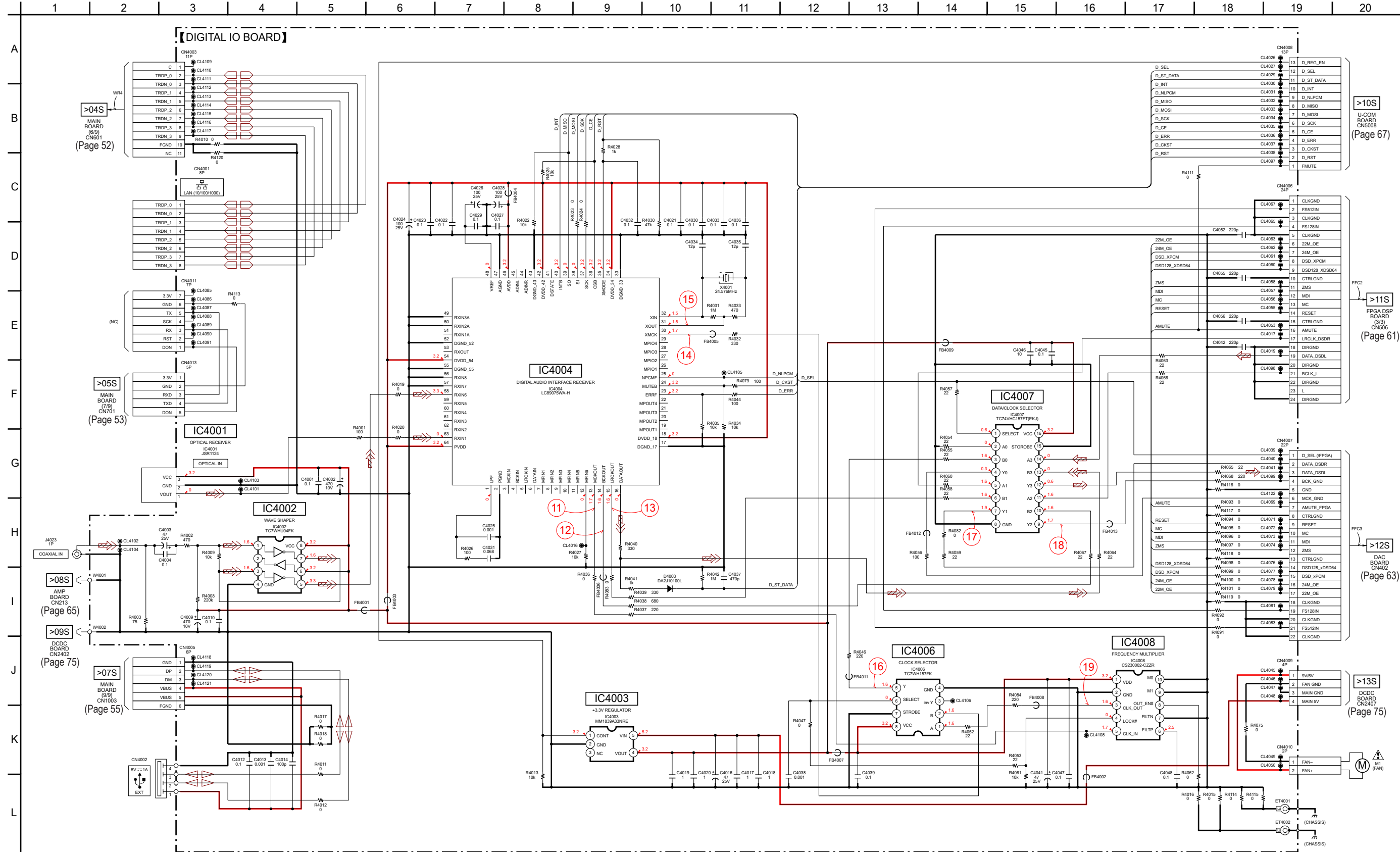
**Note 4:** When the hard disk drive (Ref. No. HDD1) is replaced, refer to "NOTE OF REPLACING THE HARD DISK DRIVE (Ref. No. HDD1)" on page 4.

5-16. PRINTED WIRING BOARD - DIGITAL IO Board - • See page 45 for Circuit Boards Location. •  : Uses unleaded solder.

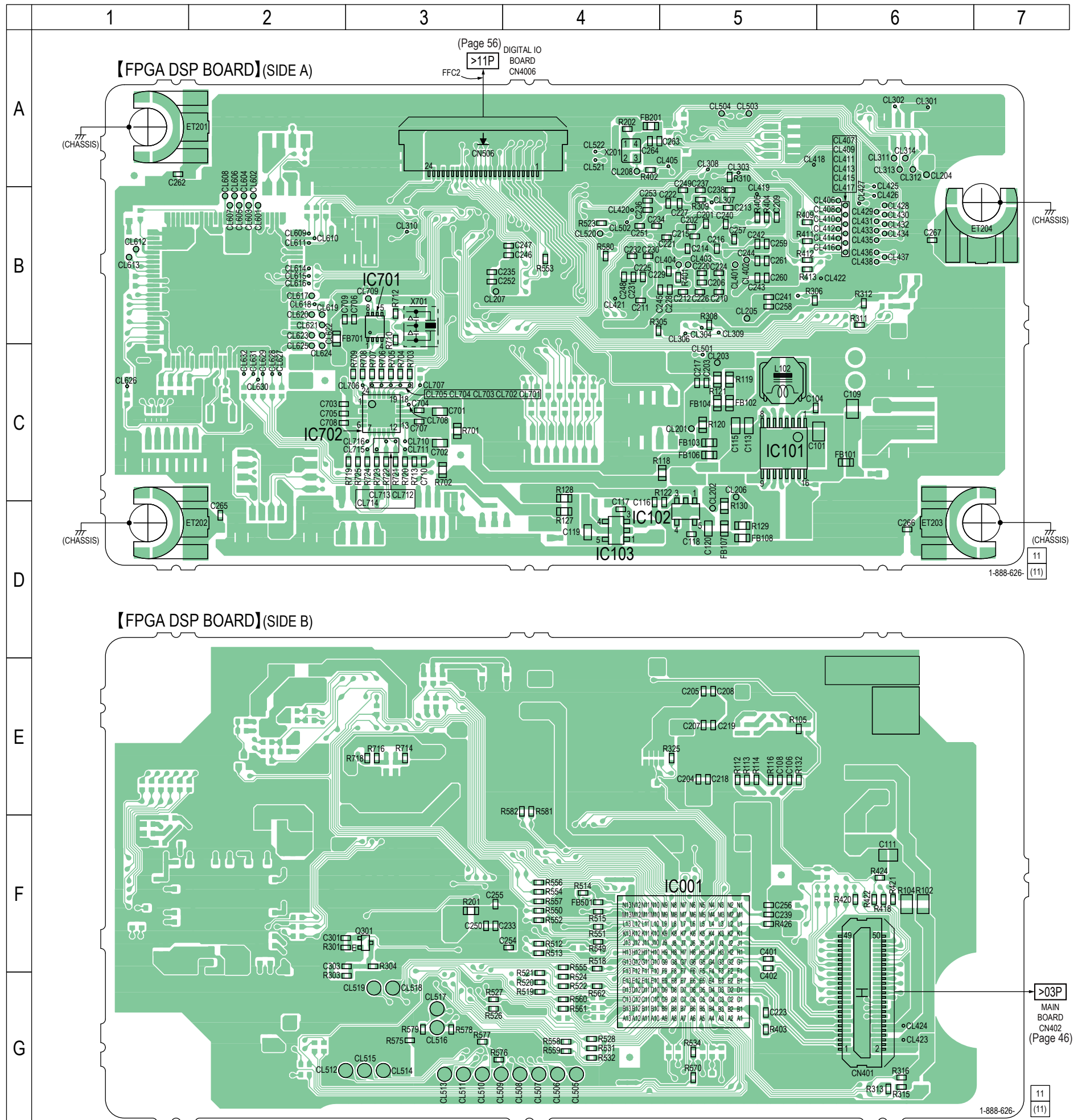




5-17. SCHEMATIC DIAGRAM - DIGITAL IO Board - • See page 73 for Waveforms. • See page 78 for IC Block Diagrams.

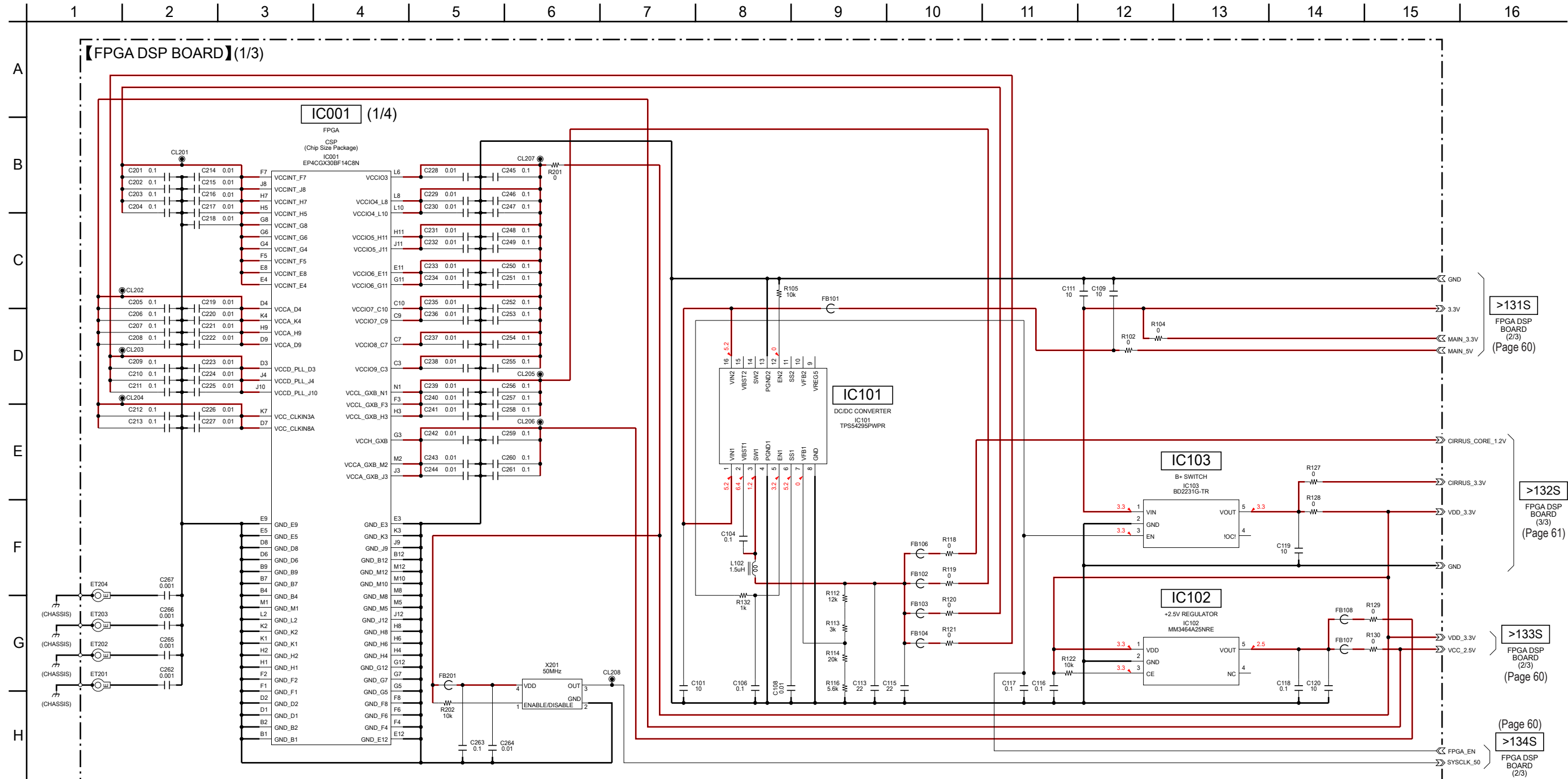


5-18. PRINTED WIRING BOARD - FPGA DSP Board - • See page 45 for Circuit Boards Location. •  : Uses unleaded solder.



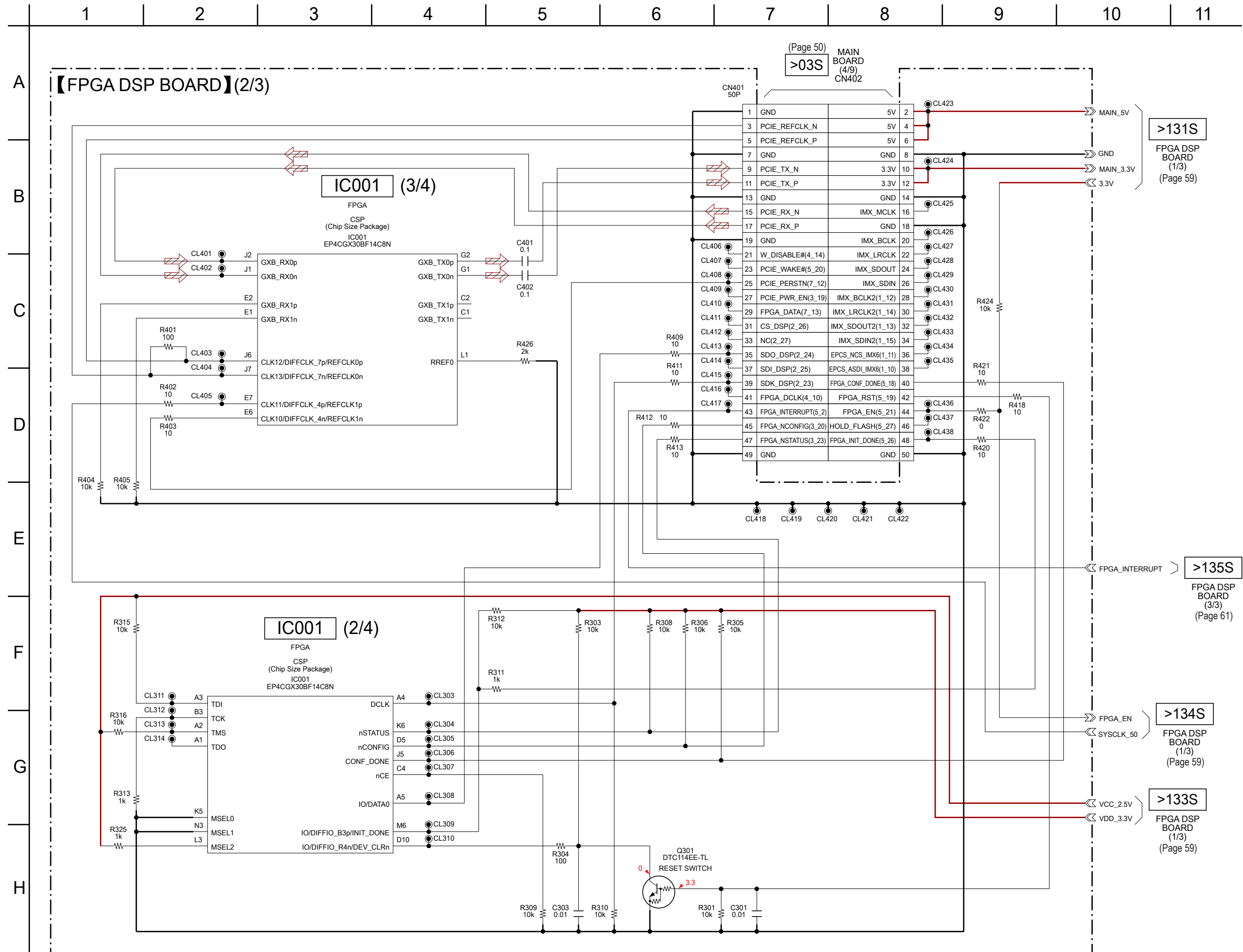
**Note:** IC001 and IC702 on the FPGA DSP board cannot exchange with single. When these parts are damaged, exchange the complete mounted board.

5-19. SCHEMATIC DIAGRAM - FPGA DSP Board (1/3) - • See page 78 for IC Block Diagrams. • See page 86 for IC Pin Function Description.



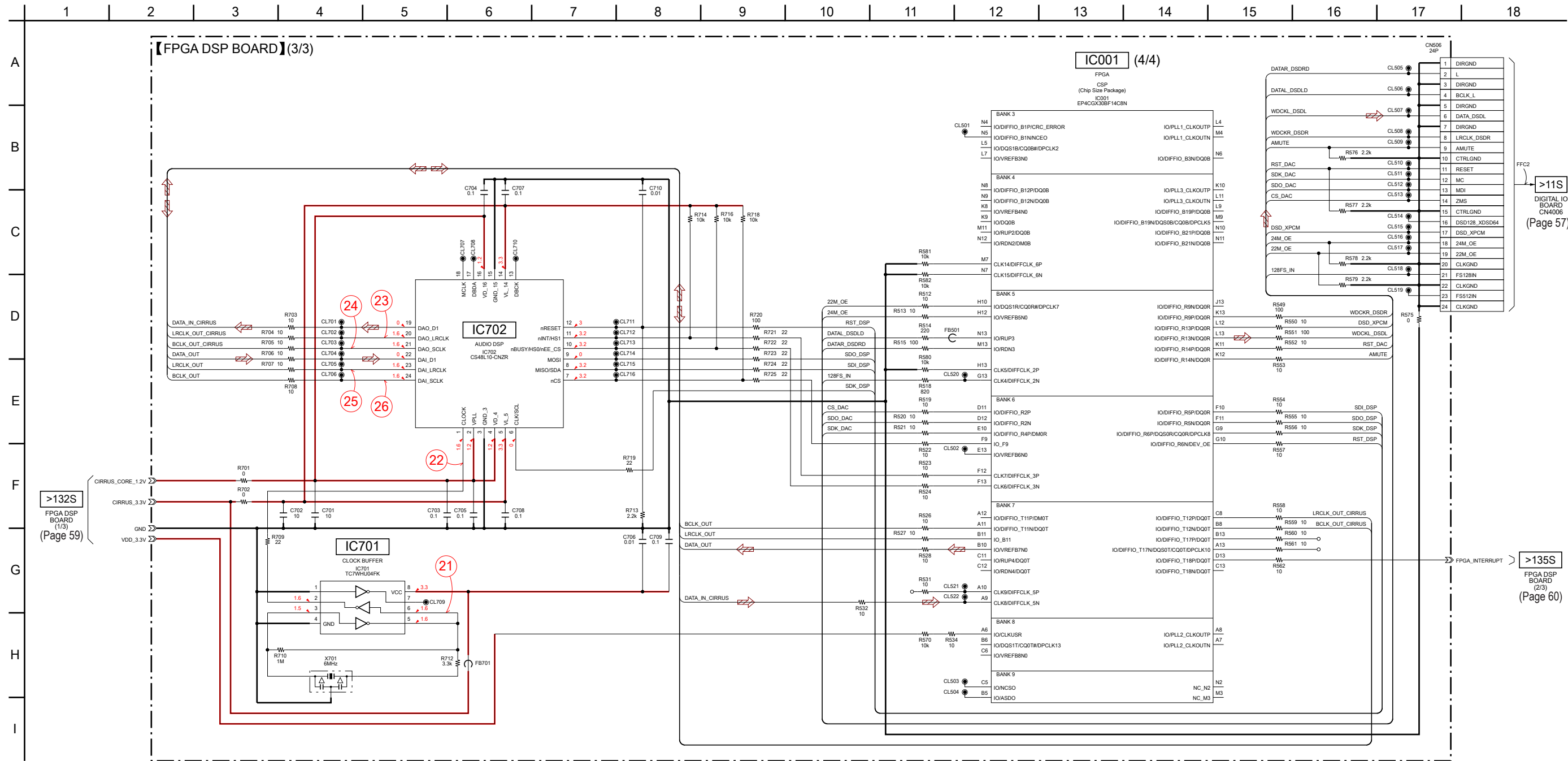
Note: IC001 on the FPGA DSP board cannot exchange with single. When this part is damaged, exchange the complete mounted board.

5-20. SCHEMATIC DIAGRAM - FPGA DSP Board (2/3) - • See page 86 for IC Pin Function Description.



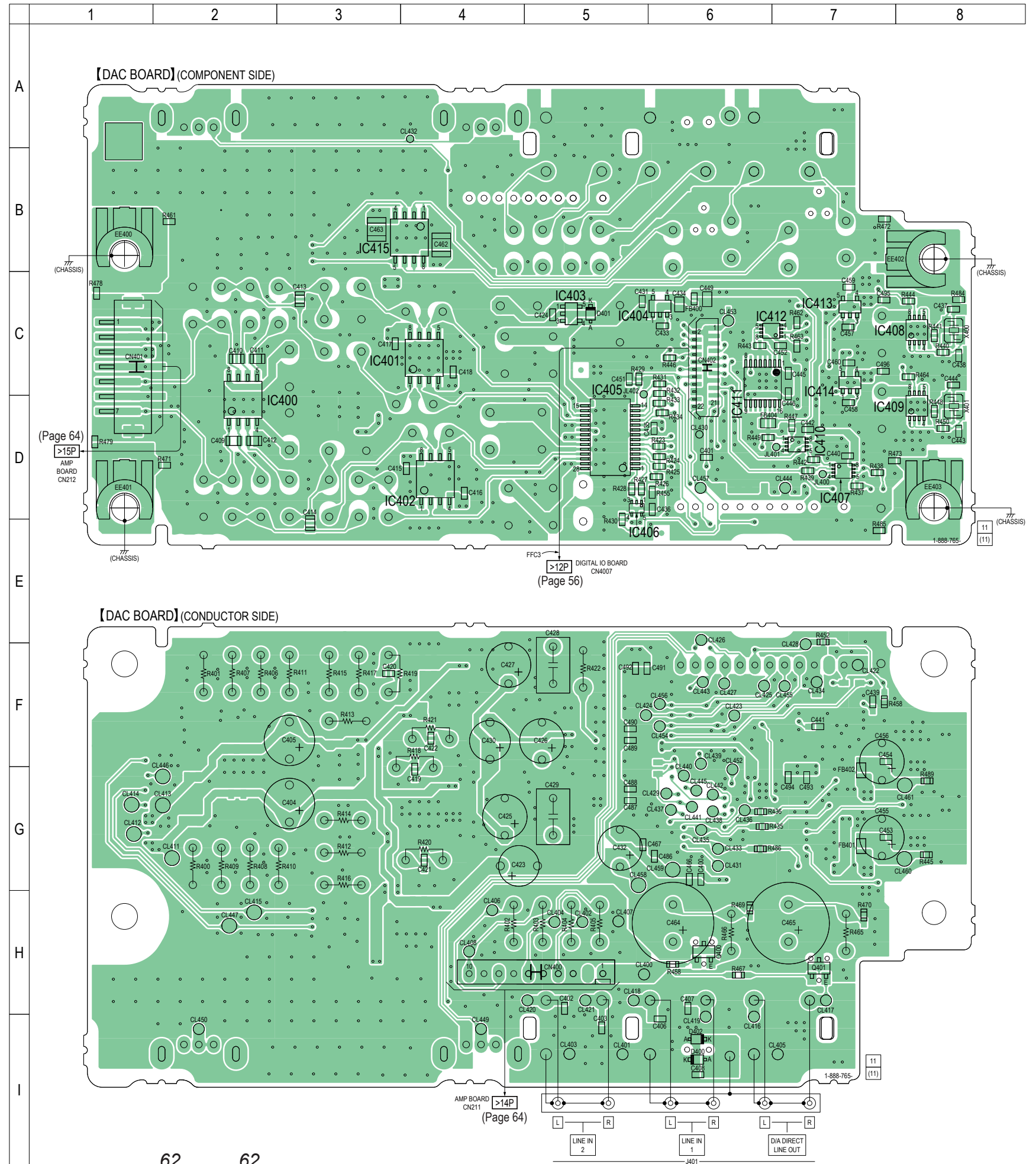
**Note:** IC001 on the FPGA DSP board cannot exchange with single. When this part is damaged, exchange the complete mounted board.

5-21. SCHEMATIC DIAGRAM - FPGA DSP Board (3/3) - • See page 73 for Waveforms. • See page 86 for IC Pin Function Description.

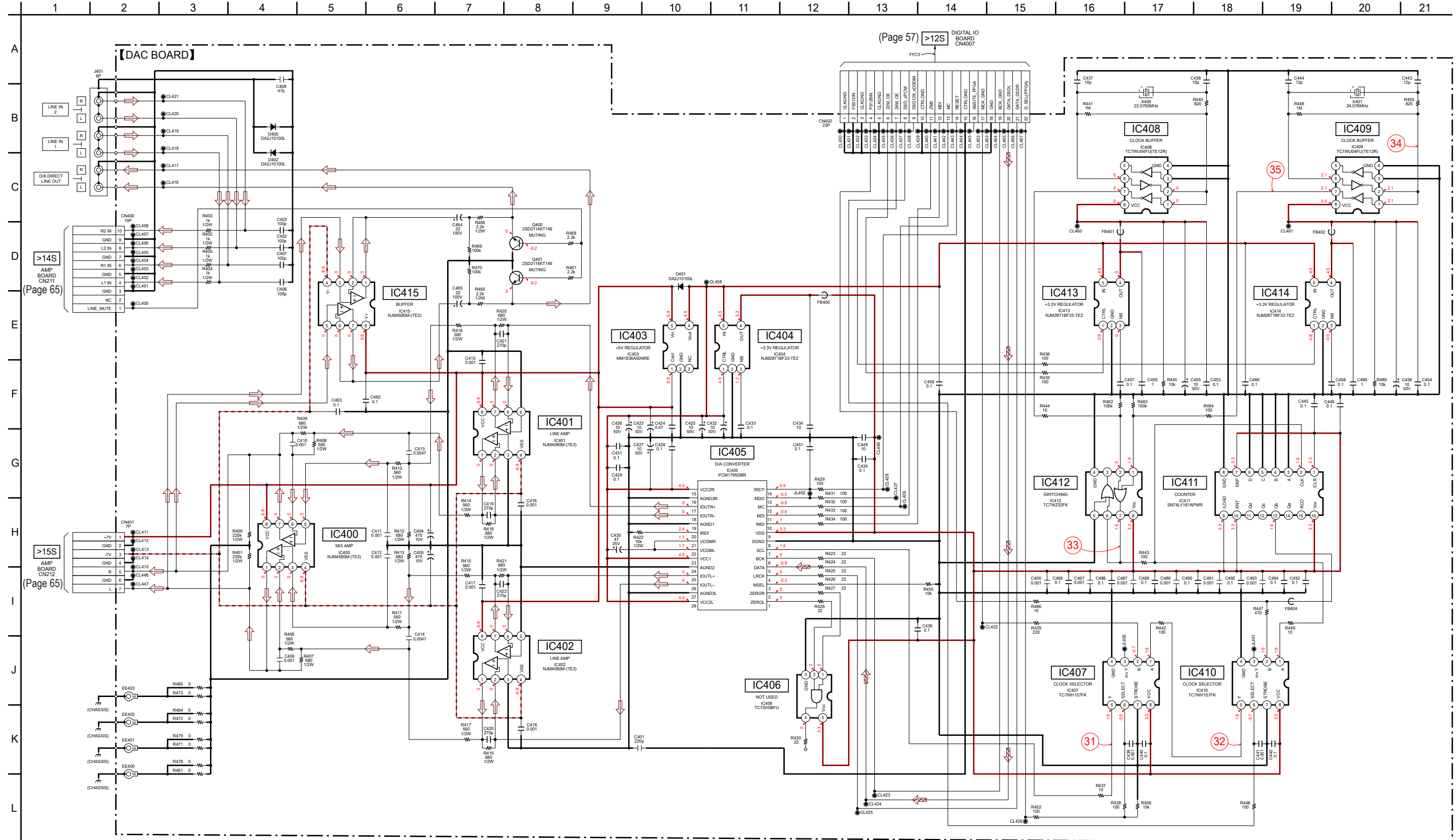


Note: IC001 and IC702 on the FPGA DSP board cannot exchange with single. When these parts are damaged, exchange the complete mounted board.

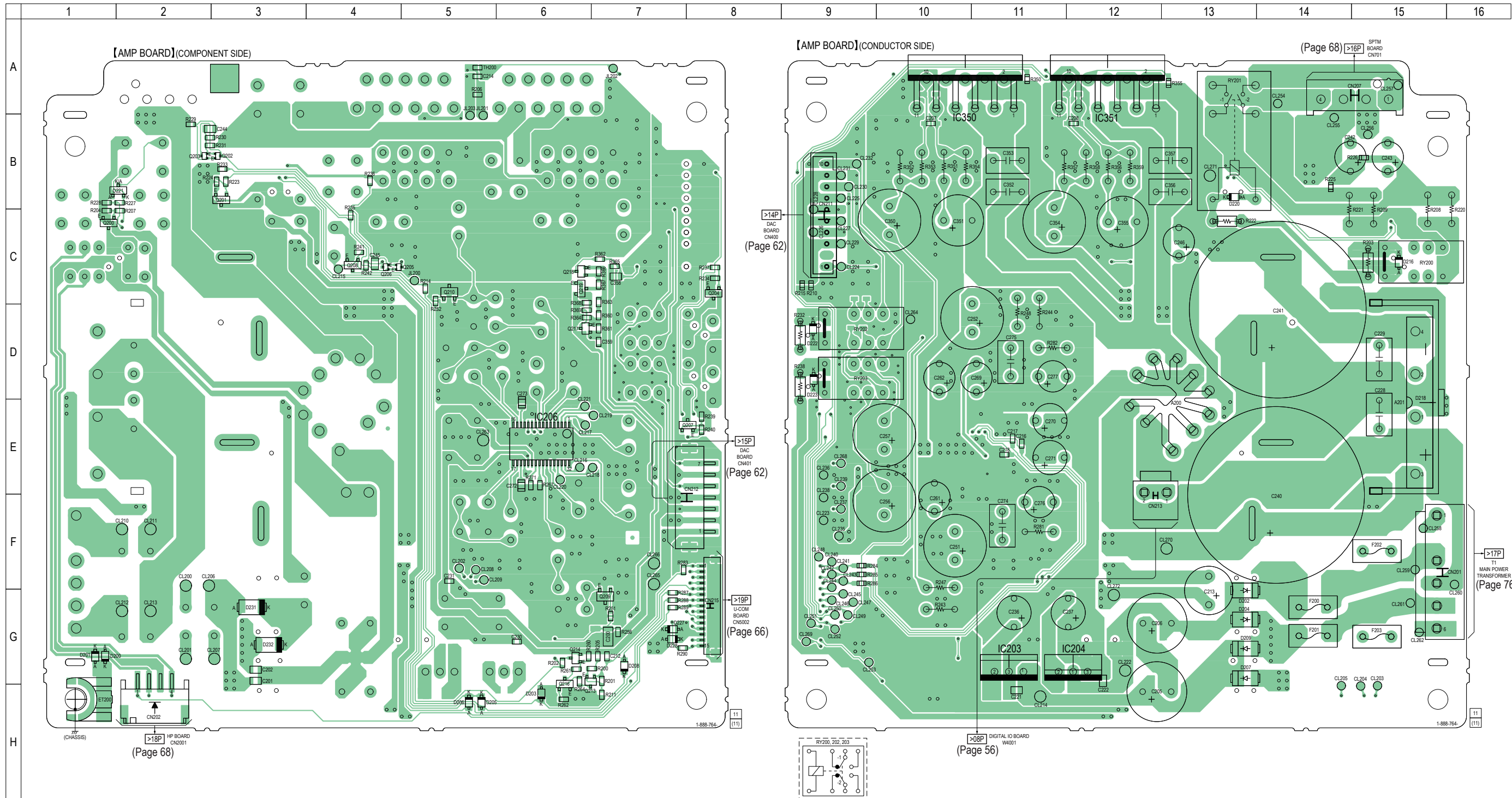
5-22. PRINTED WIRING BOARD - DAC Board - • See page 45 for Circuit Boards Location. •  : Uses unleaded solder.



5-23. SCHEMATIC DIAGRAM - DAC Board - • See page 73 for Waveforms. • See page 78 for IC Block Diagrams.

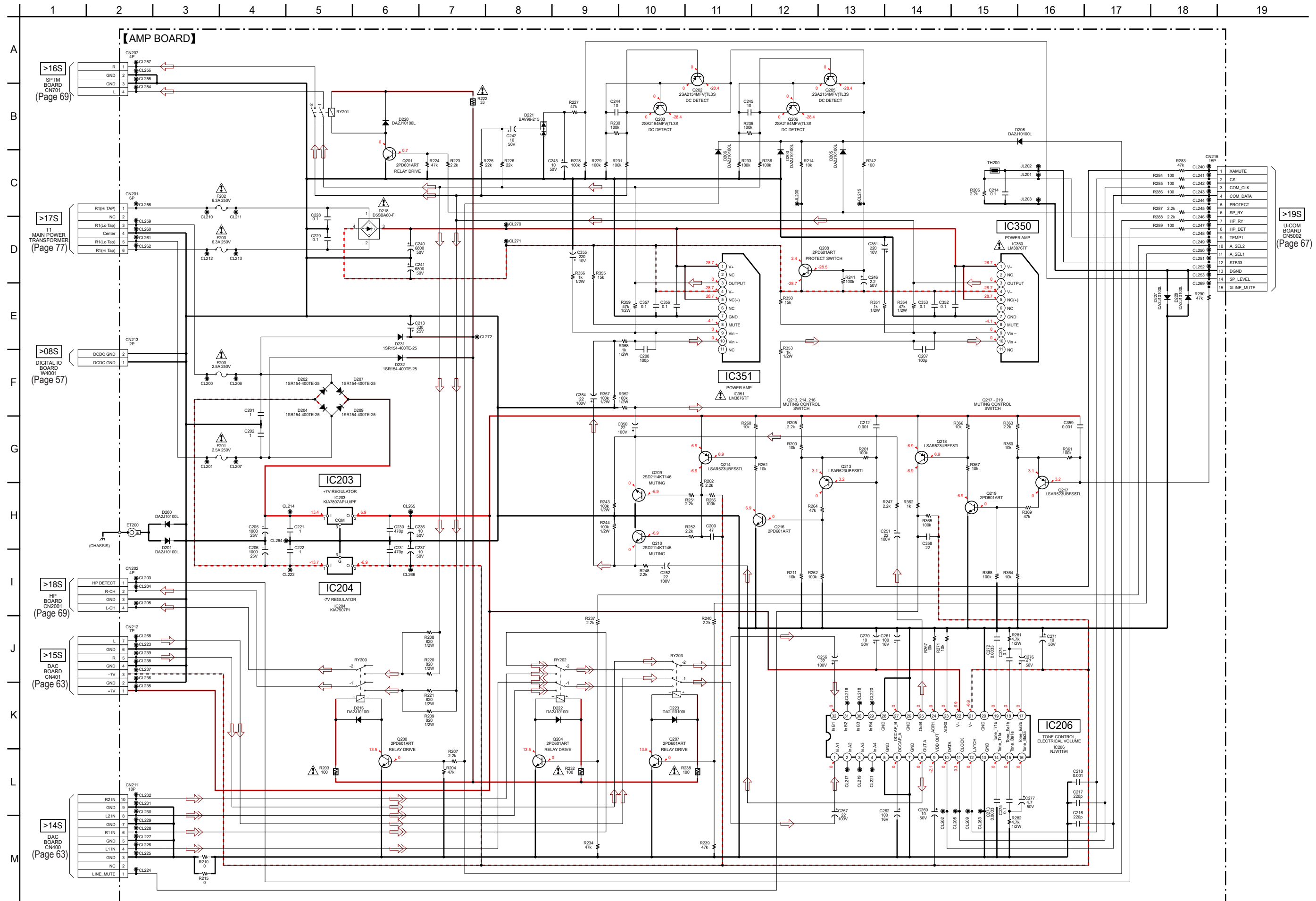


5-24. PRINTED WIRING BOARD - AMP Board - • See page 45 for Circuit Boards Location. •  : Uses unleaded solder.



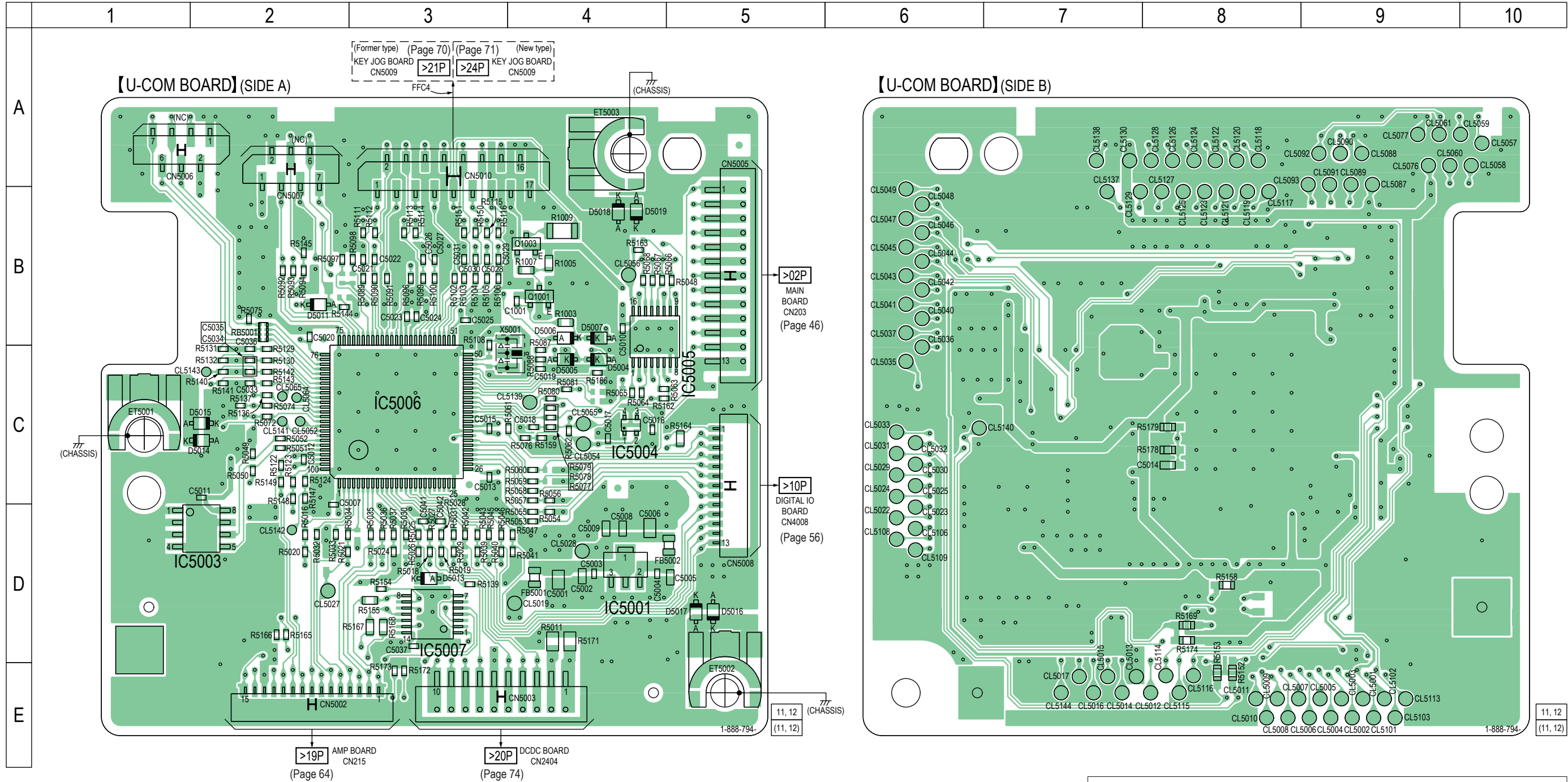


5-25. SCHEMATIC DIAGRAM - AMP Board - See page 78 for IC Block Diagrams.



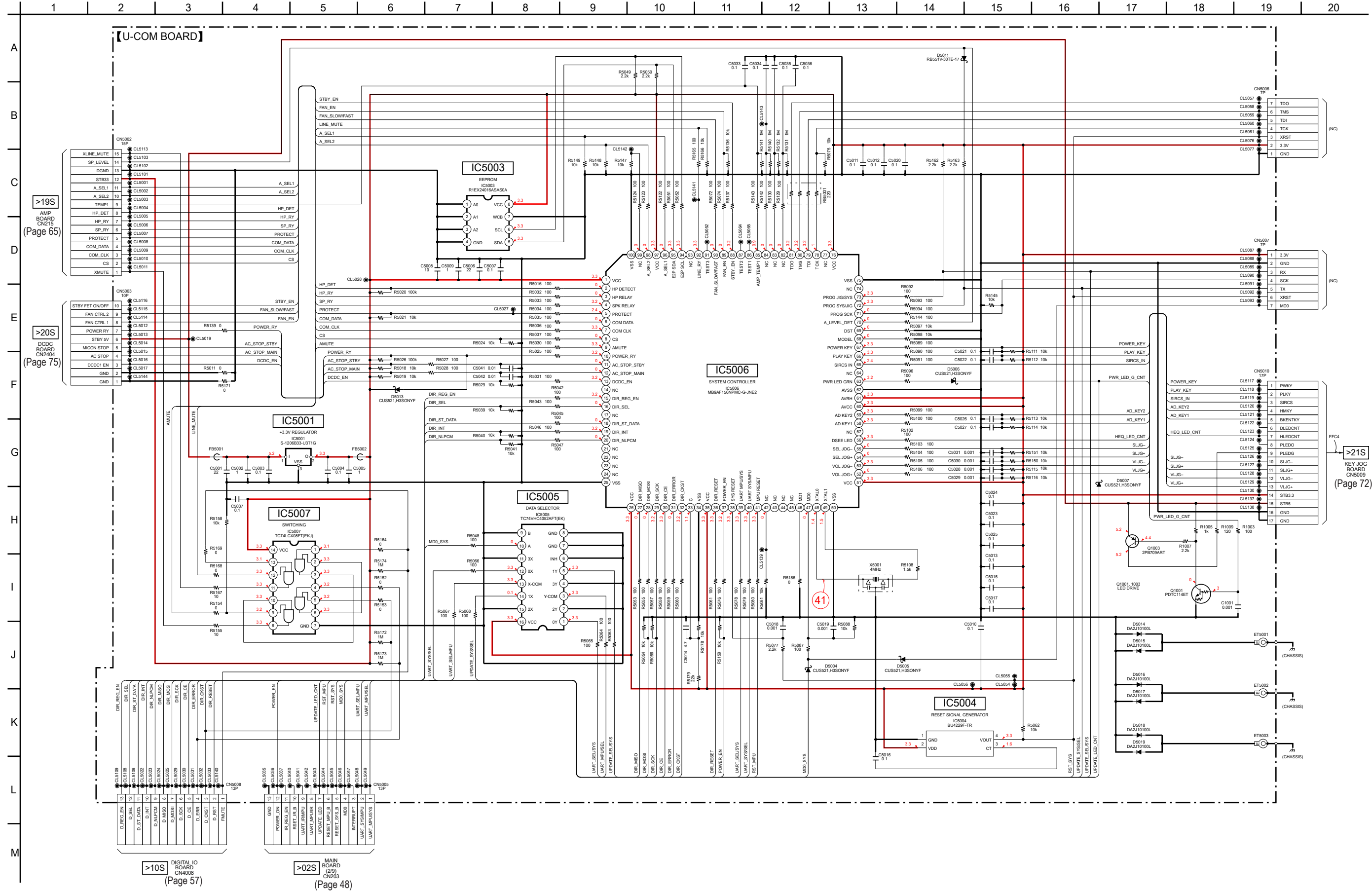
Note: When the complete AMP board is replaced, refer to "NOTE OF REPLACING THE D218, IC350 AND IC351 ON THE AMP BOARD AND THE COMPLETE AMP BOARD" on page 4.

5-26. PRINTED WIRING BOARD - U-COM Board - • See page 45 for Circuit Boards Location. •  : Uses unleaded solder.

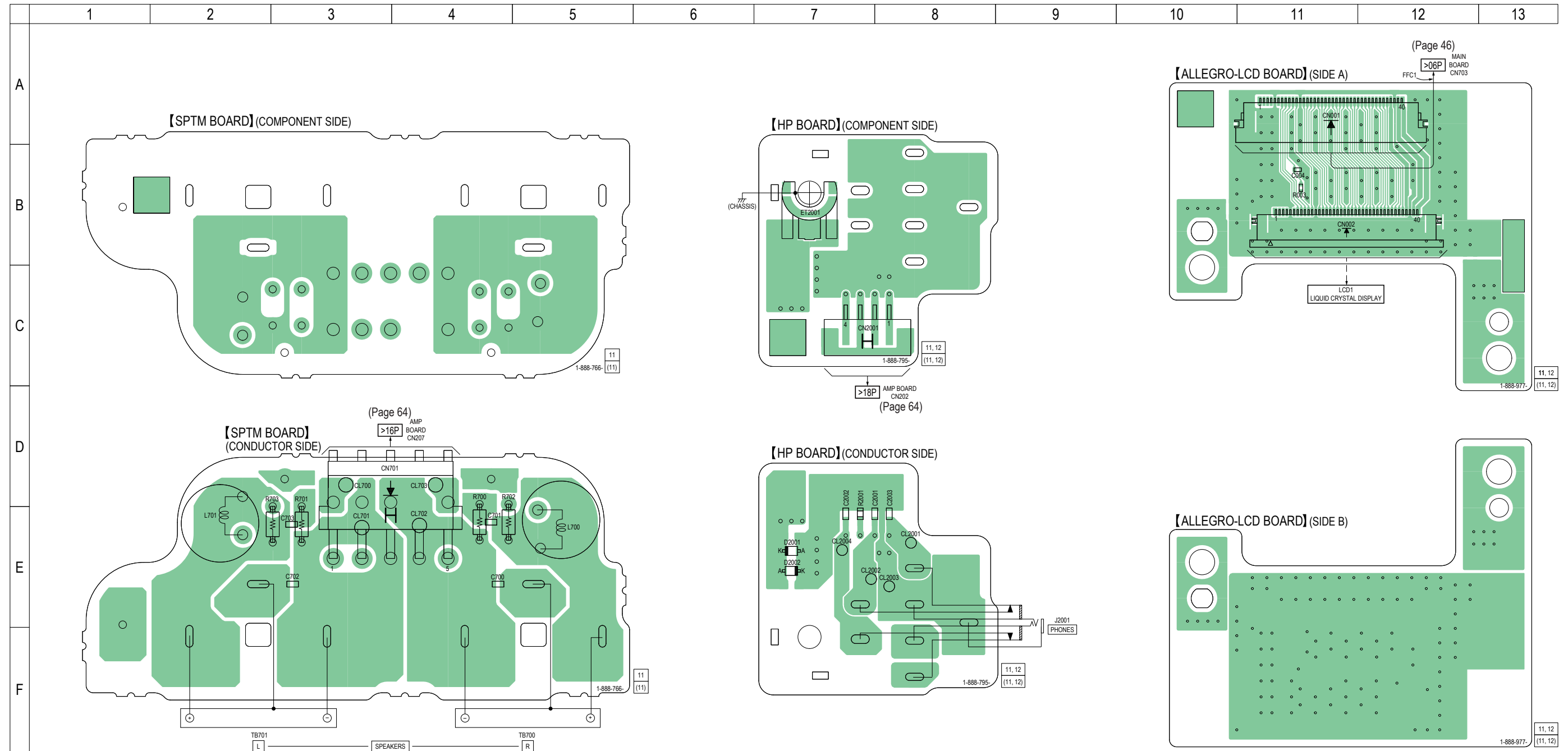


**Note:** Refer to the "KEY JOG AND POWER KEY BOARDS DISCRIMINATION" on page 71 for how to distinguish Former type and New type of KEY JOG and POWER KEY boards.

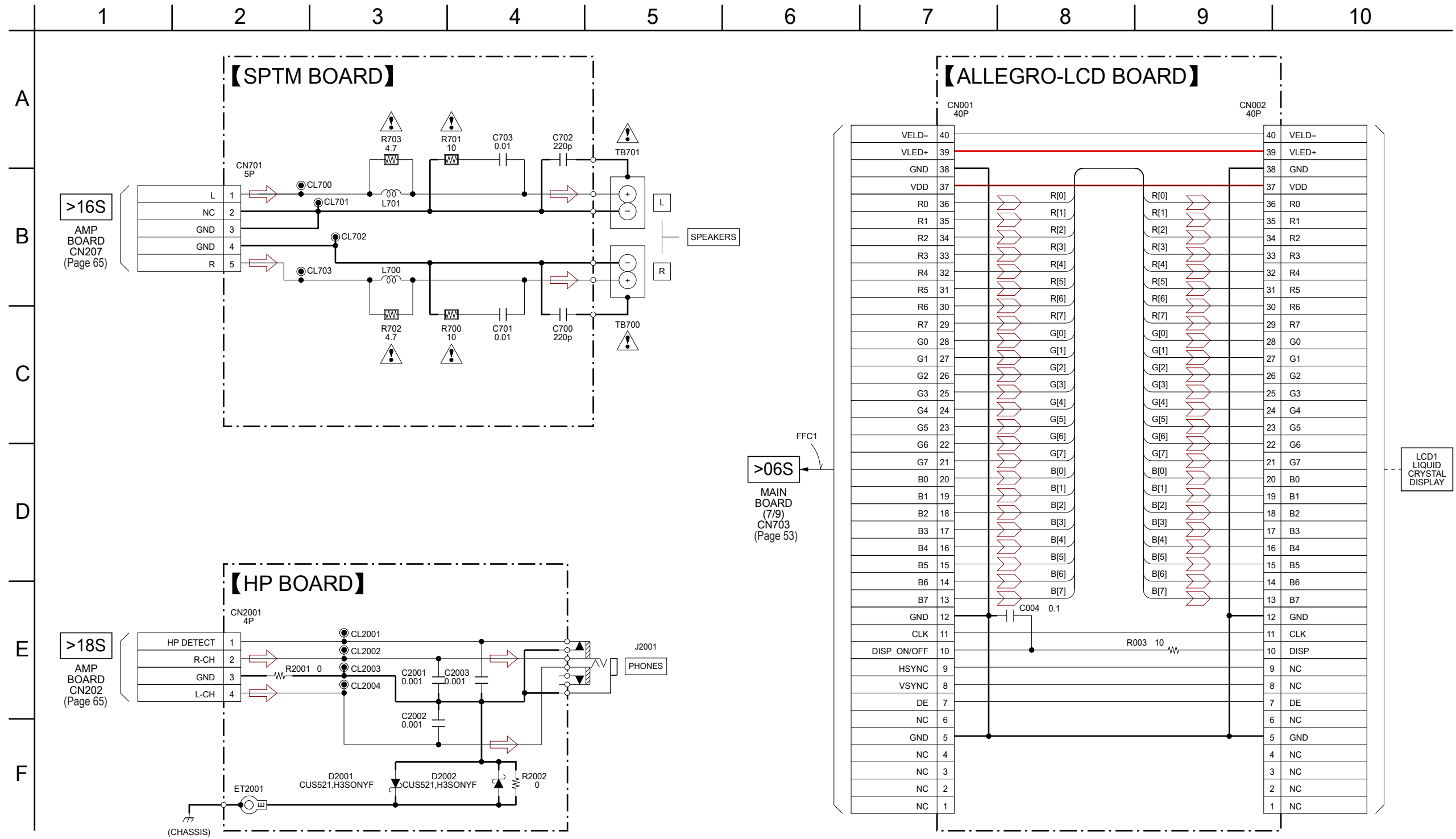
5-27. SCHEMATIC DIAGRAM - U-COM Board - • See page 73 for Waveforms. • See page 78 for IC Block Diagrams. • See page 86 for IC Pin Function Description.



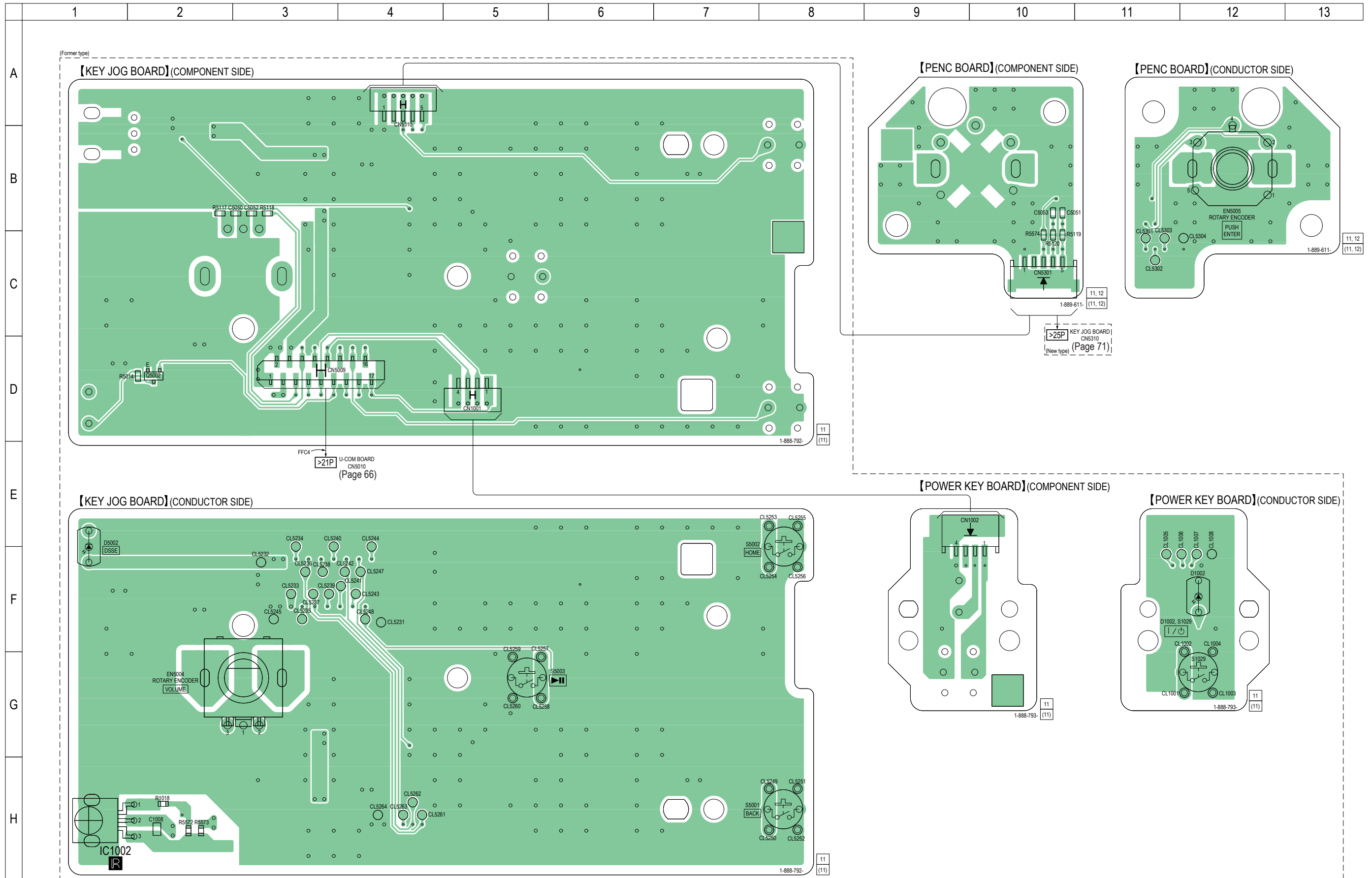
5-28. PRINTED WIRING BOARDS - OUTPUT/LCD Section - • See page 45 for Circuit Boards Location. •  : Uses unleaded solder.



5-29. SCHEMATIC DIAGRAM - OUTPUT/LCD Section -

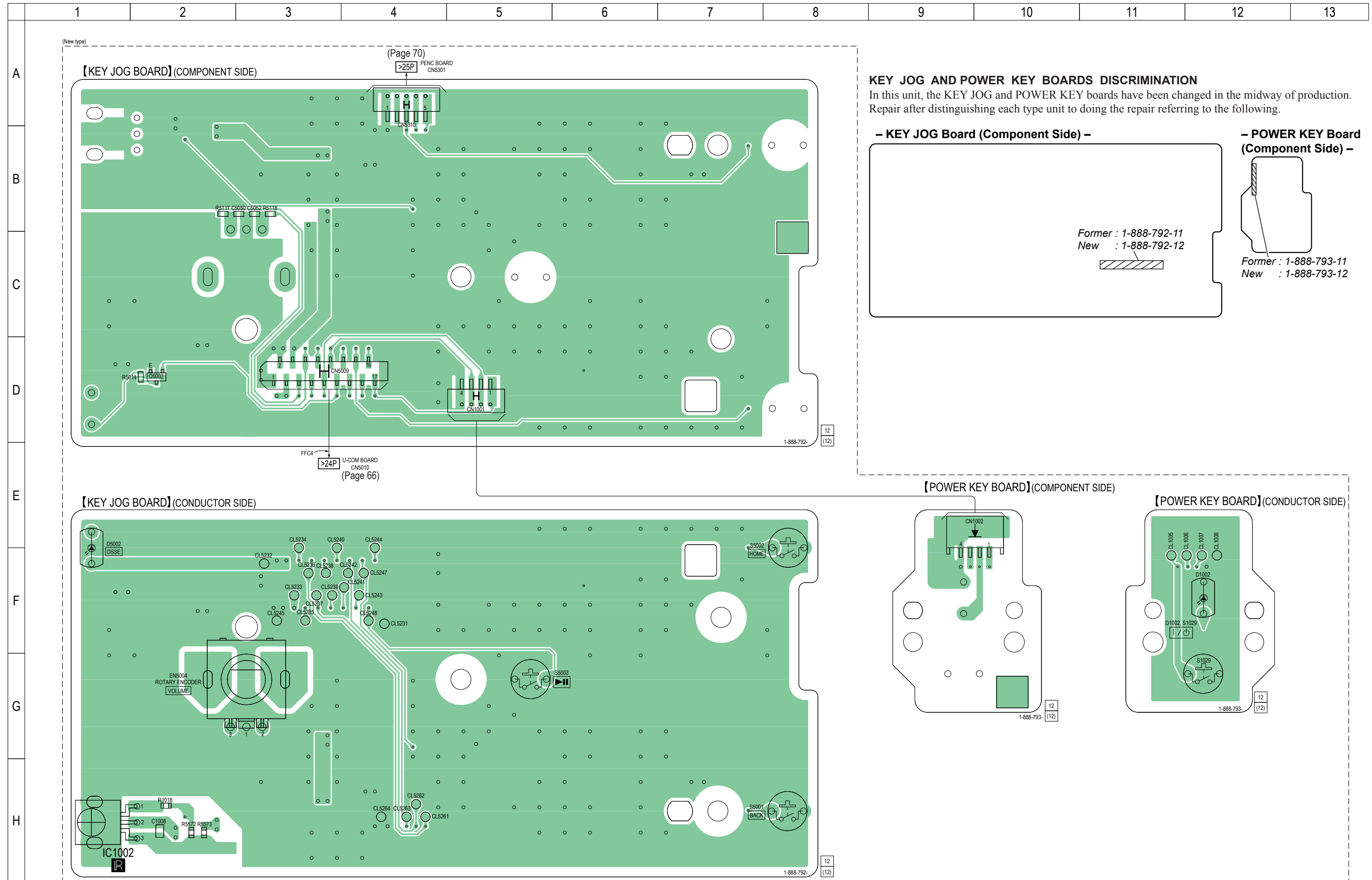


5-30. PRINTED WIRING BOARDS - KEY Section (1/2) - • See page 45 for Circuit Boards Location. •  : Uses unleaded solder.

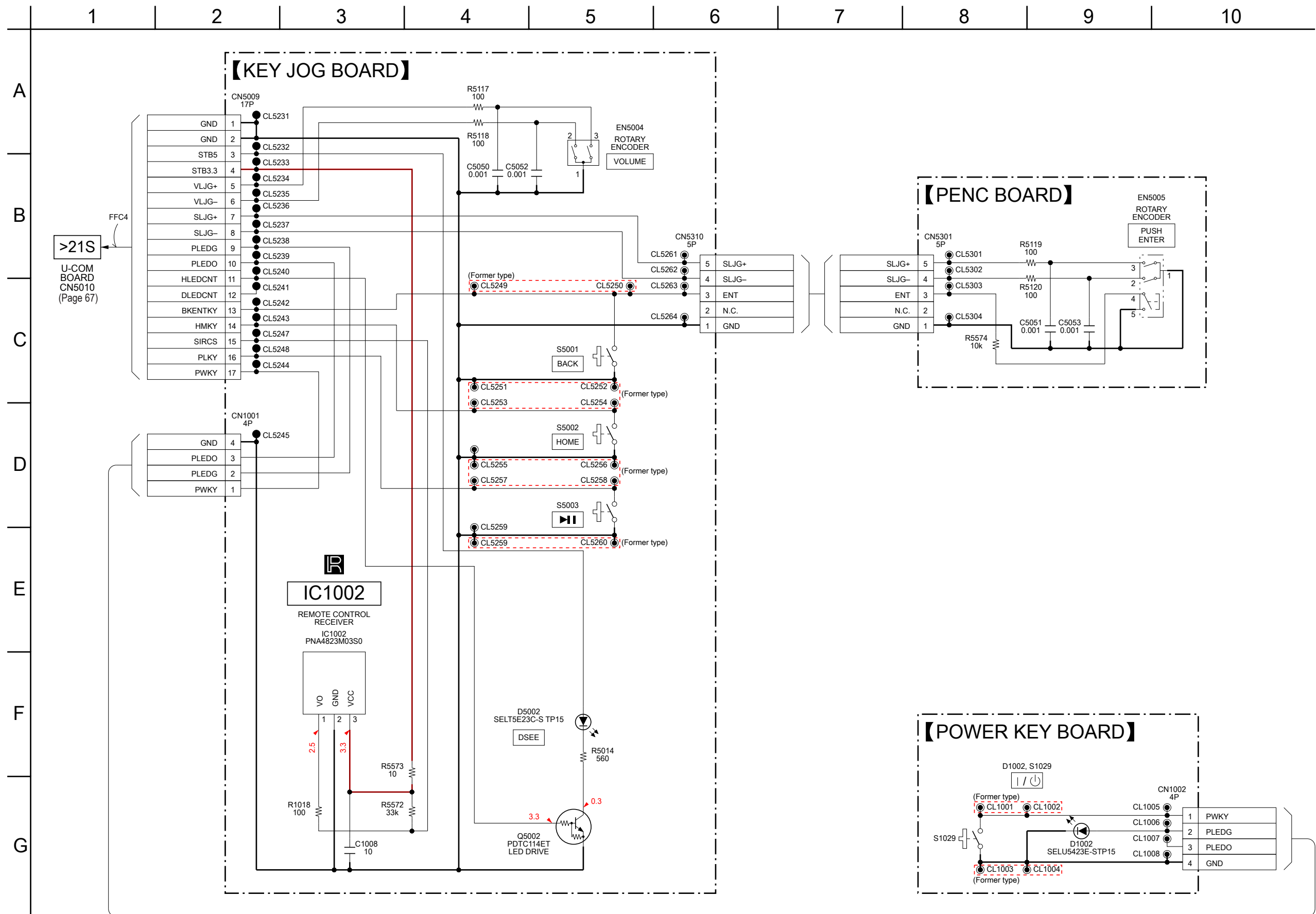


**Note:** Refer to the "KEY JOG AND POWER KEY BOARDS DISCRIMINATION" on page 71 for how to distinguish Former type and New type of KEY JOG and POWER KEY boards.

5-31. PRINTED WIRING BOARDS - KEY Section (2/2) - • See page 45 for Circuit Boards Location. •  : Uses unleaded solder.



5-32. SCHEMATIC DIAGRAM - KEY Section -

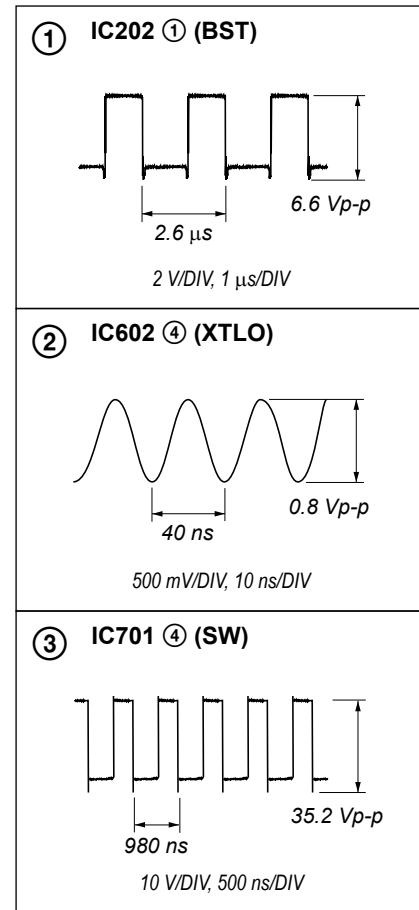


**Note:** Refer to the "KEY JOG AND POWER KEY BOARDS DISCRIMINATION" on page 71 for how to distinguish Former type and New type of KEY JOG and POWER KEY boards.

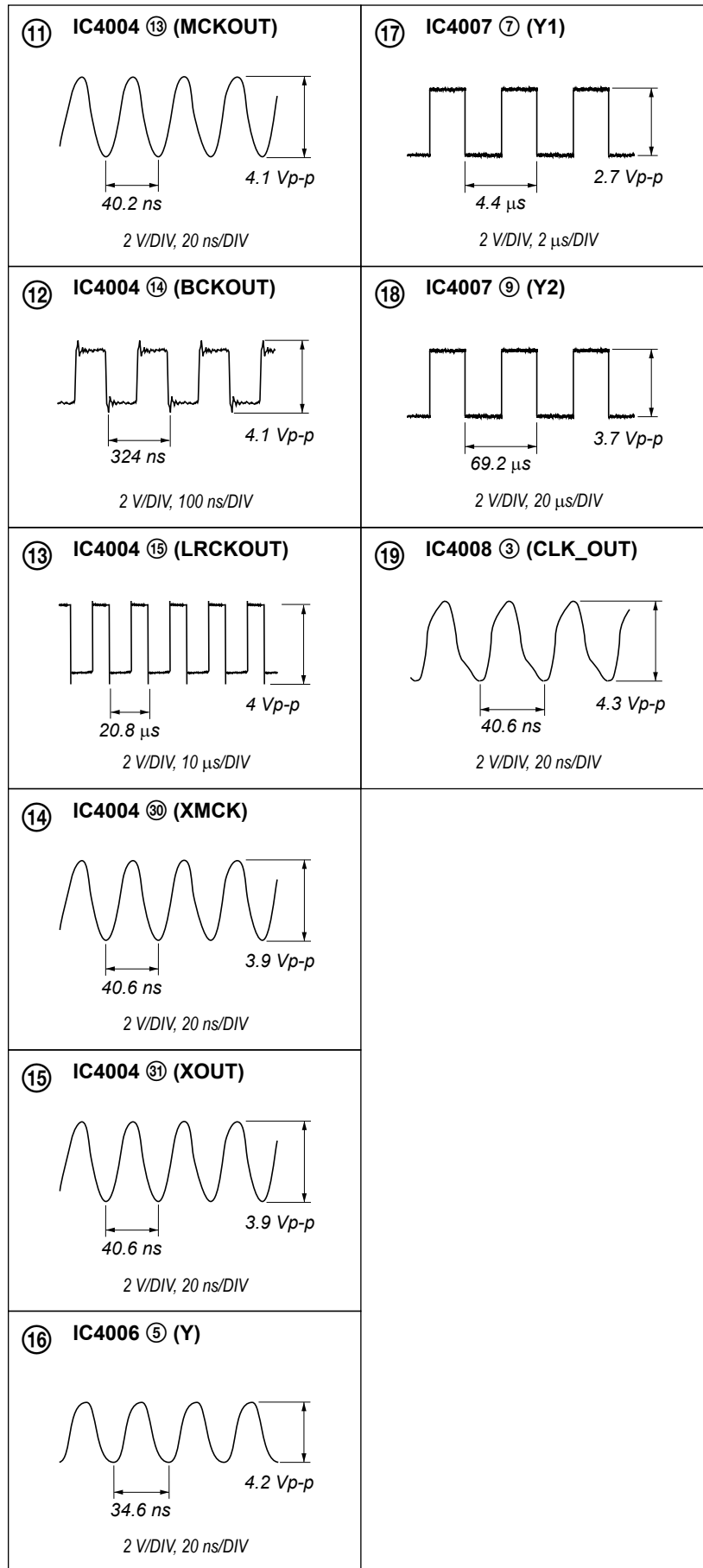


• Waveforms

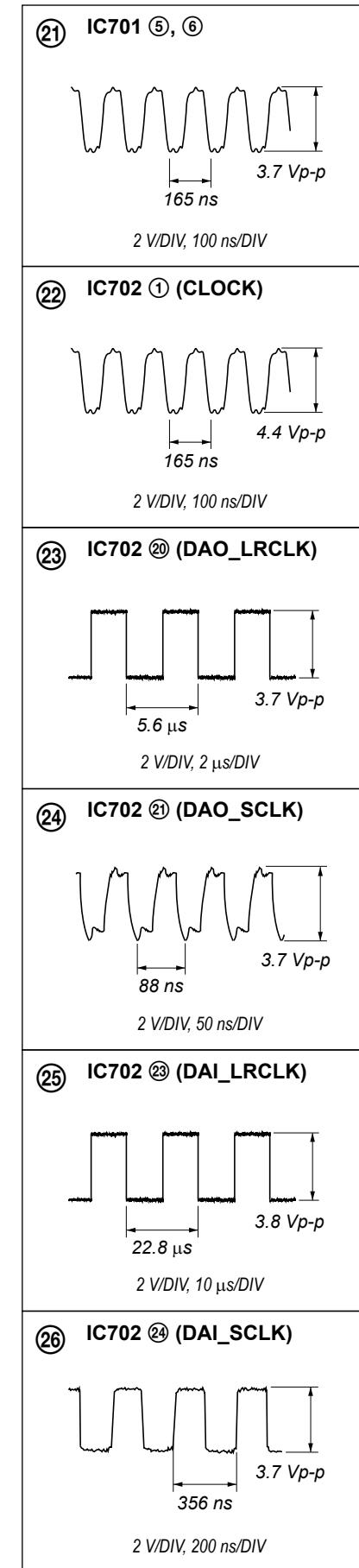
– MAIN Board –



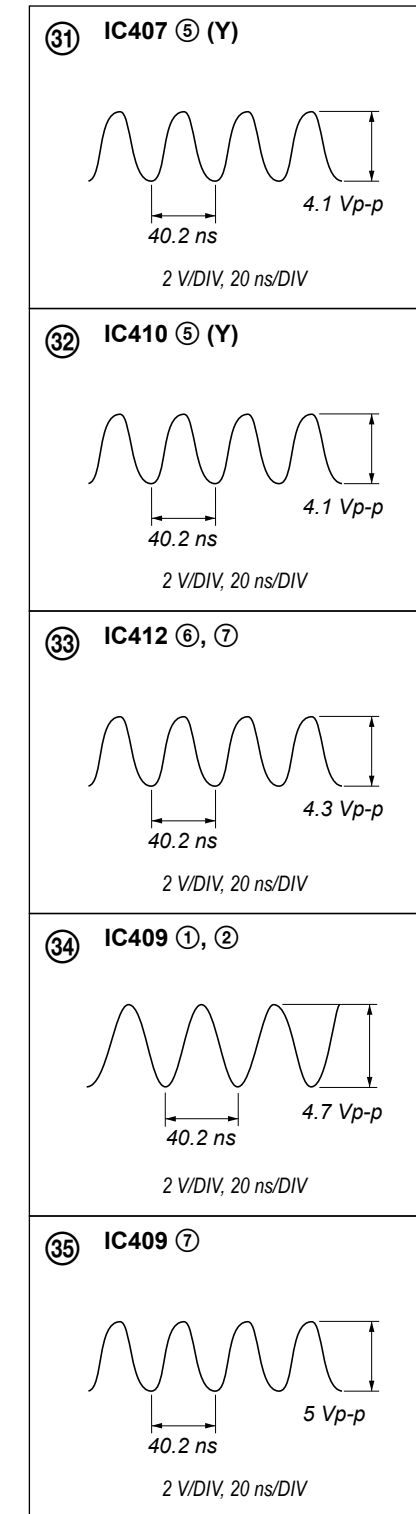
– DIGITAL IO Board –



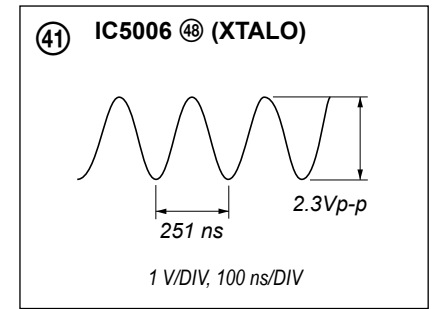
– FPGA DSP Board –



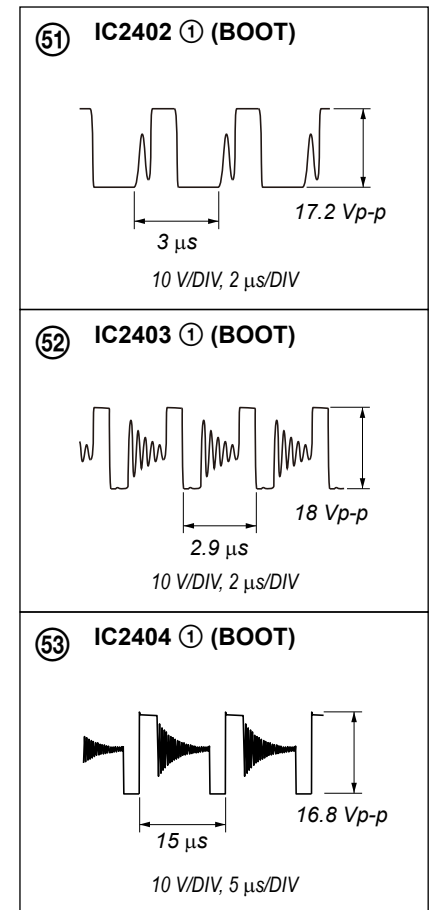
– DAC Board –



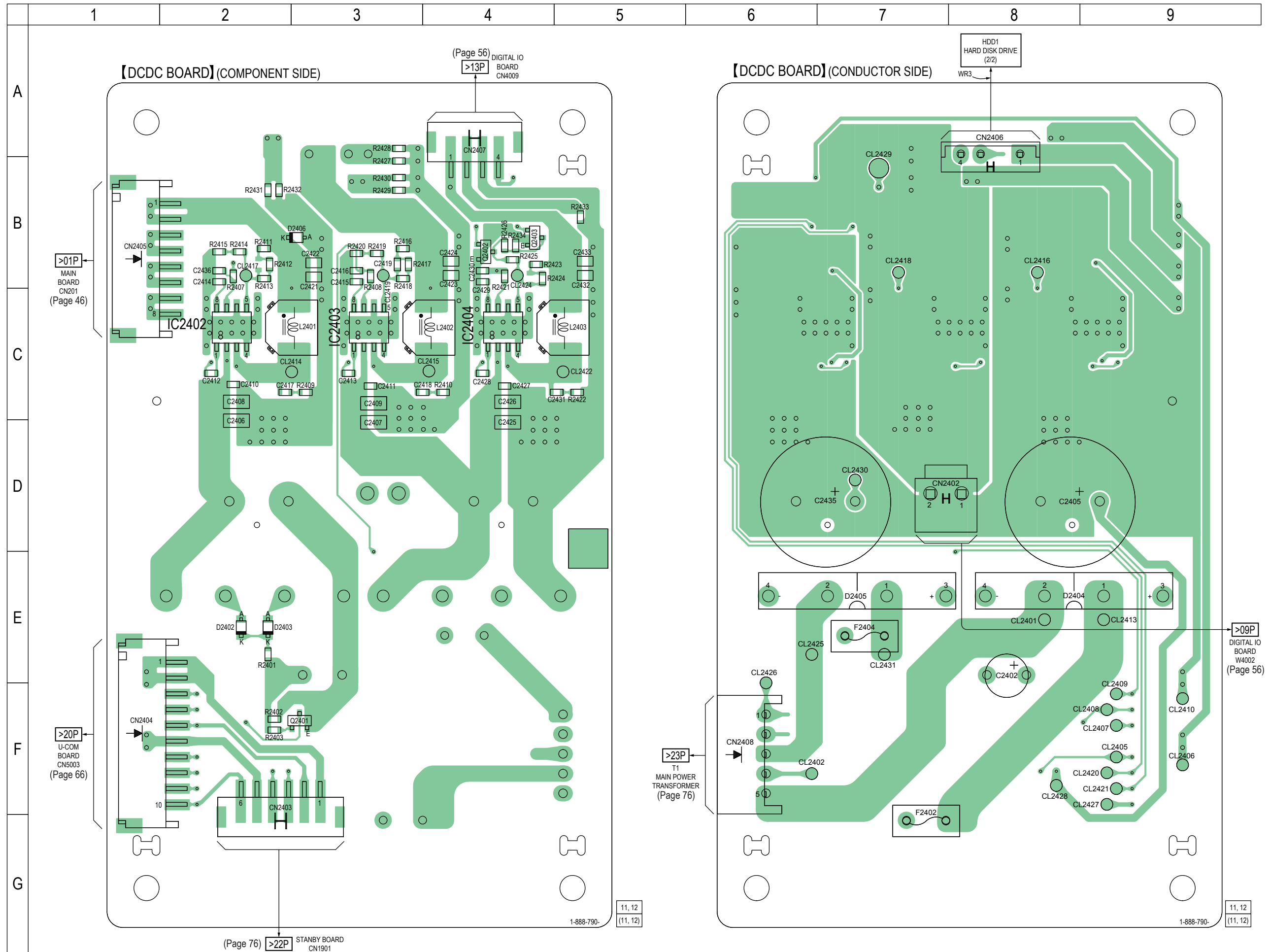
– U-COM Board –



– DCDC Board –

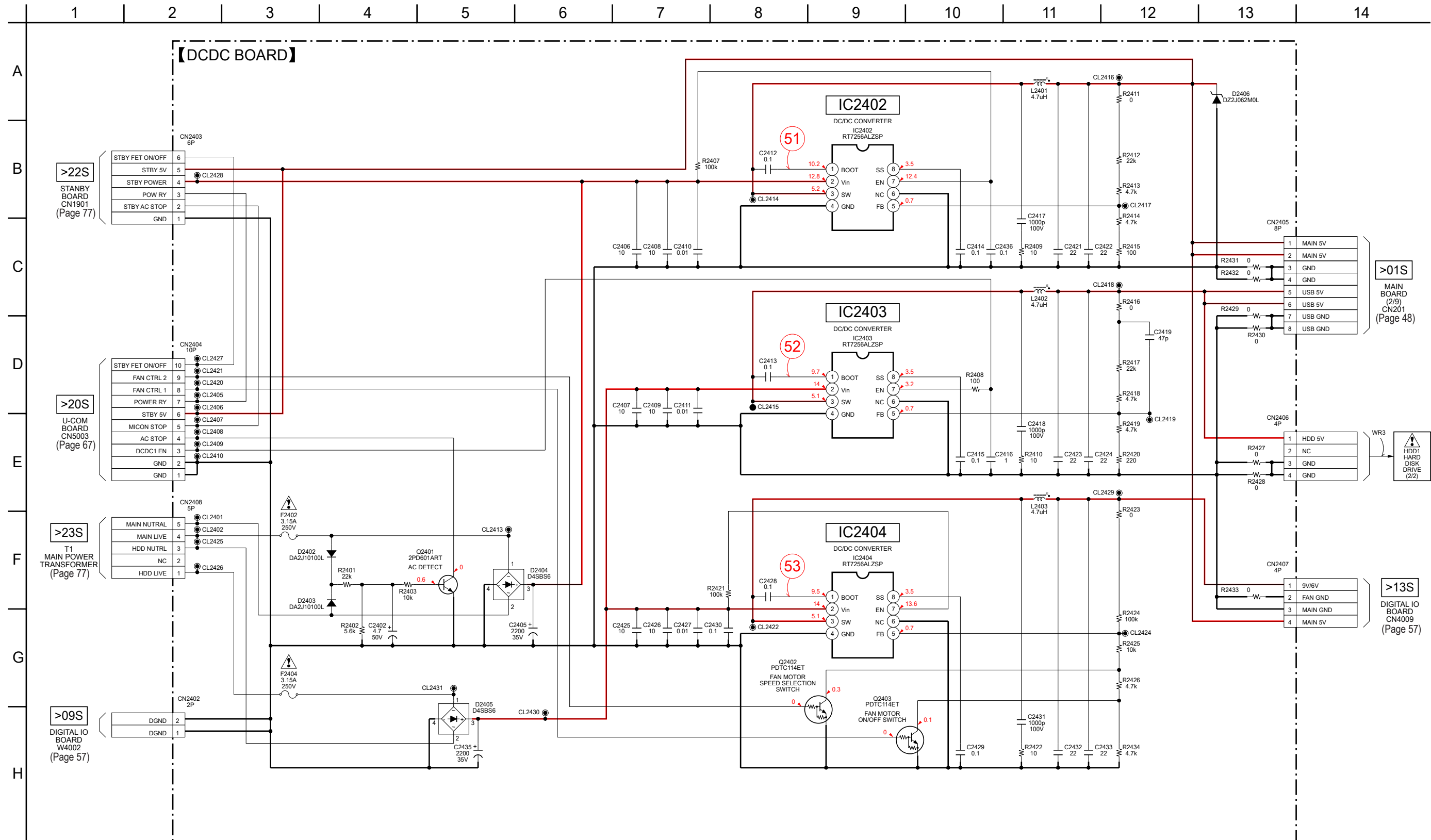


5-33. PRINTED WIRING BOARD - DCDC Board - • See page 45 for Circuit Boards Location. •  : Uses unleaded solder.



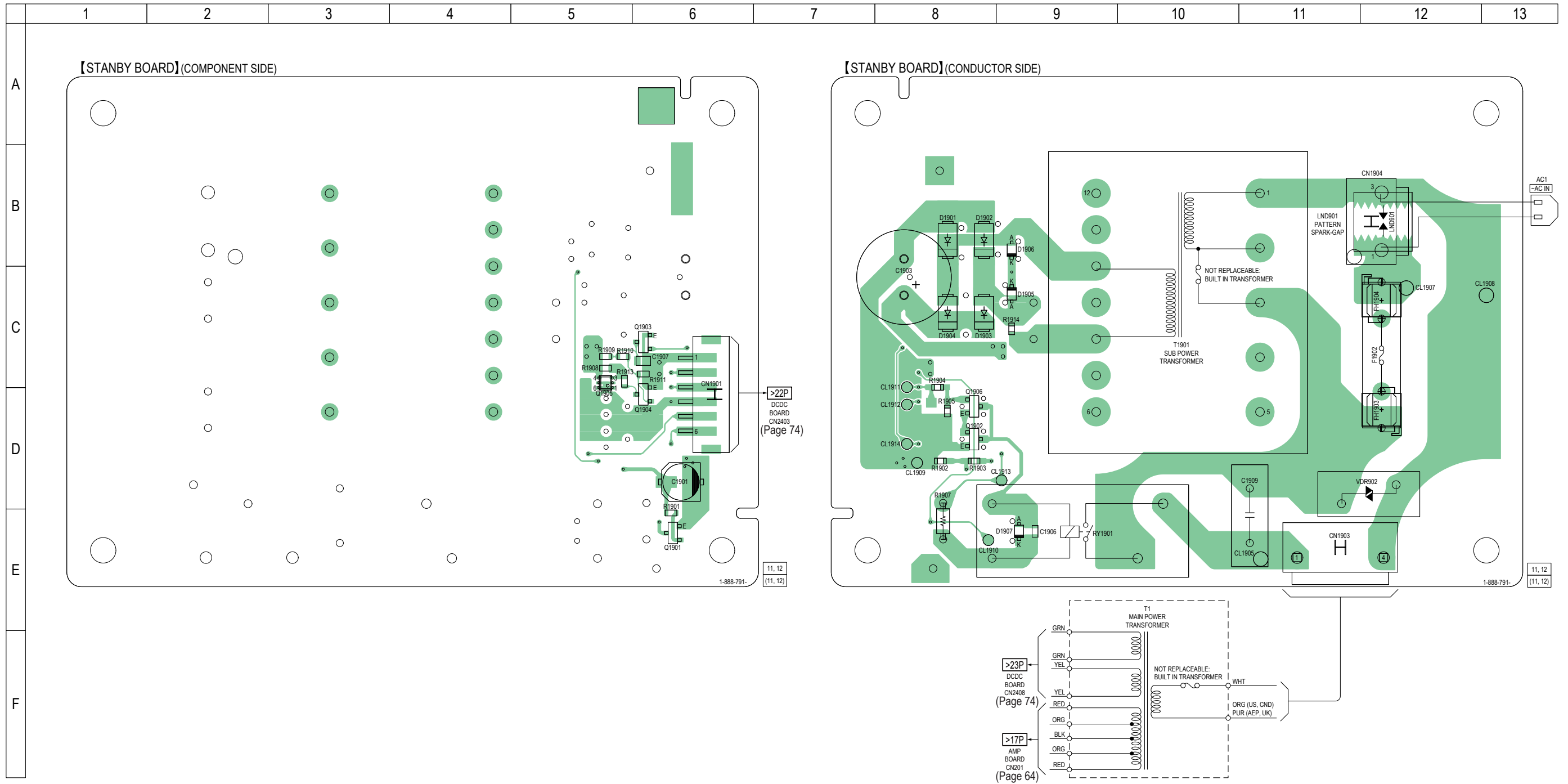
**Note:** When the hard disk drive (Ref. No. HDD1) is replaced, refer to “NOTE OF REPLACING THE HARD DISK DRIVE (Ref. No. HDD1)” on page 4.

5-34. SCHEMATIC DIAGRAM - DCDC Board - • See page 73 for Waveforms. • See page 78 for IC Block Diagrams.

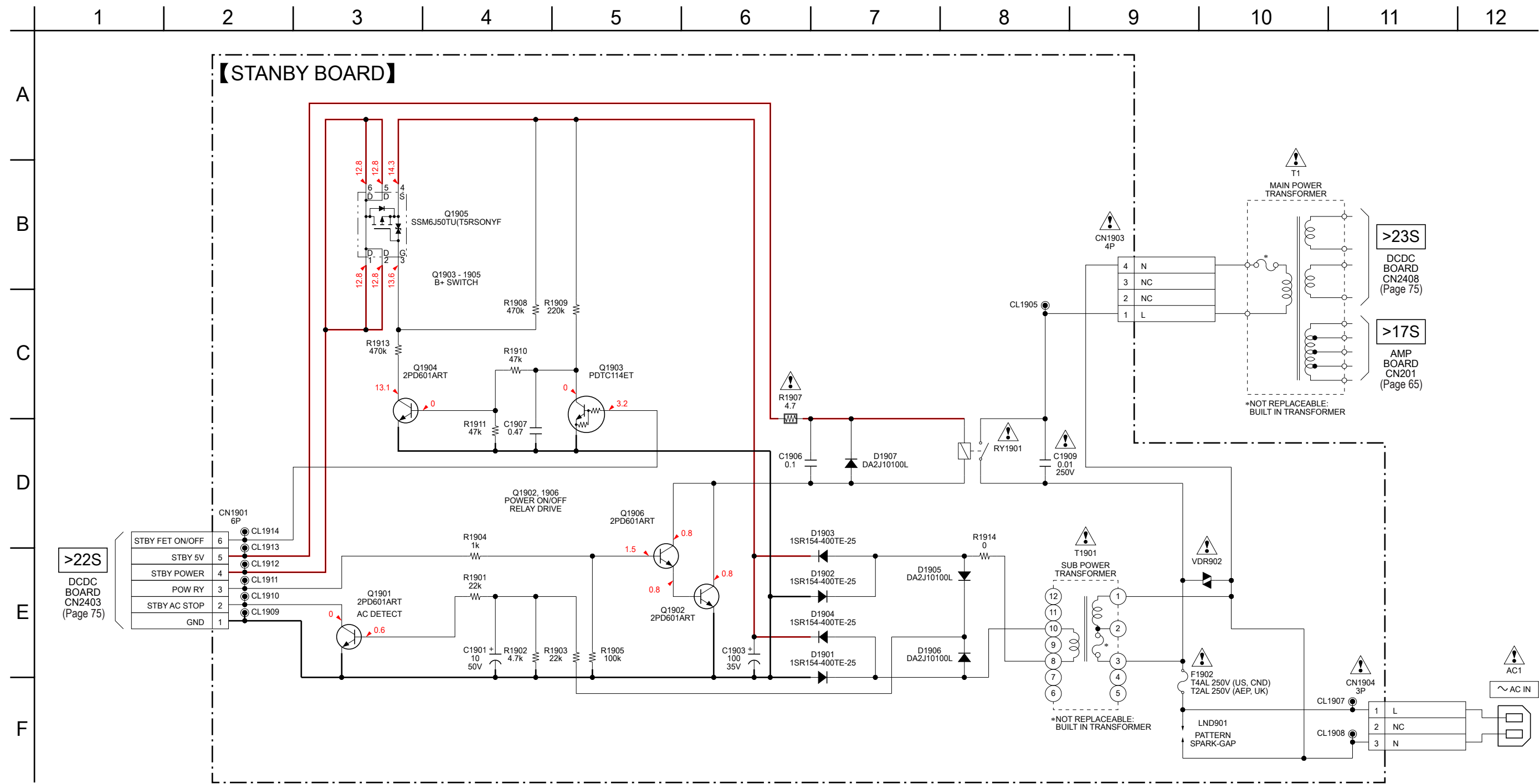


**Note:** When the hard disk drive (Ref. No. HDD1) is replaced, refer to "NOTE OF REPLACING THE HARD DISK DRIVE (Ref. No. HDD1)" on page 4.

5-35. PRINTED WIRING BOARD - STANBY Board - • See page 45 for Circuit Boards Location. •  : Uses unleaded solder.

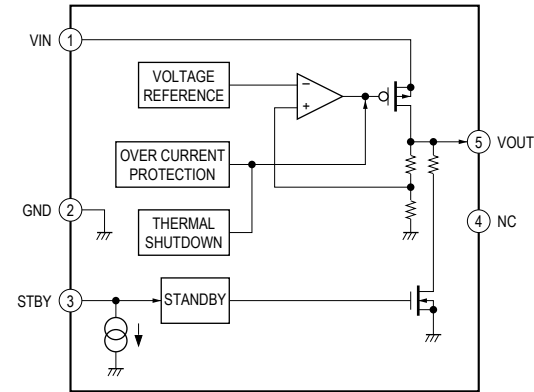


5-36. SCHEMATIC DIAGRAM - STANBY Board -

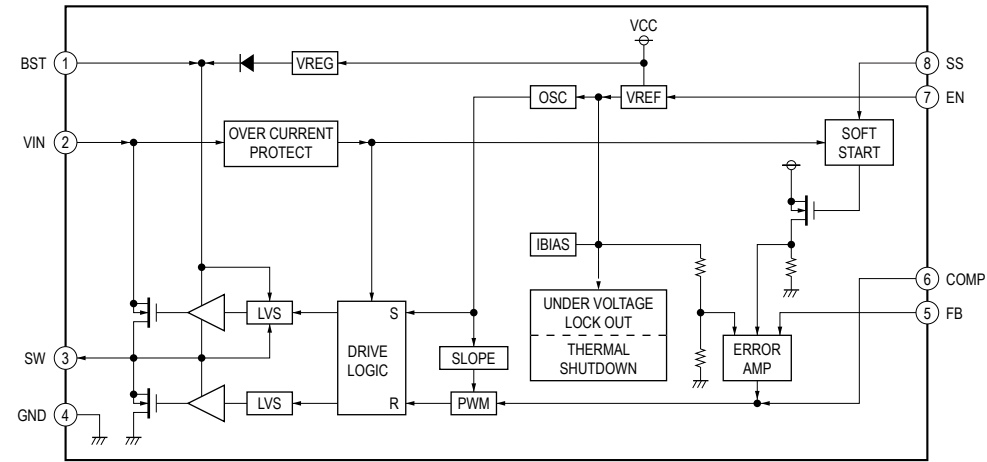


• IC Block Diagrams

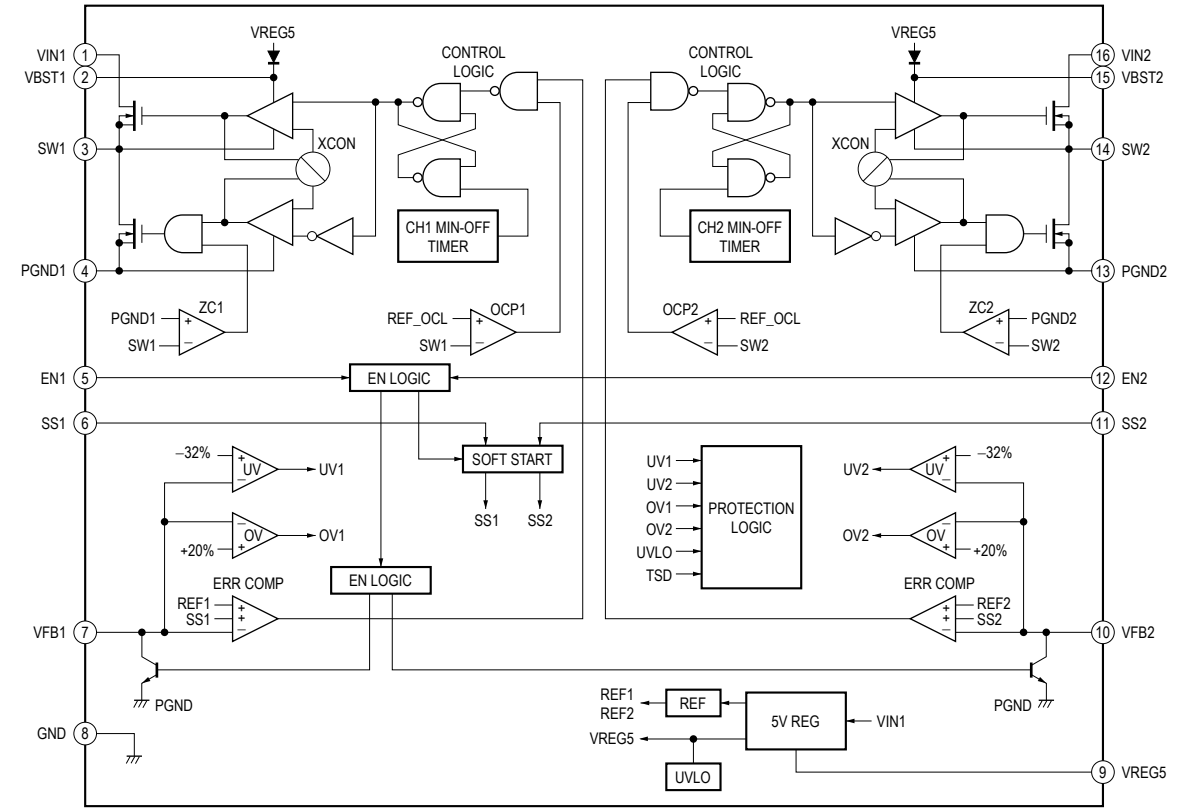
– MAIN Board –  
IC201 BU33TD3WG-TR



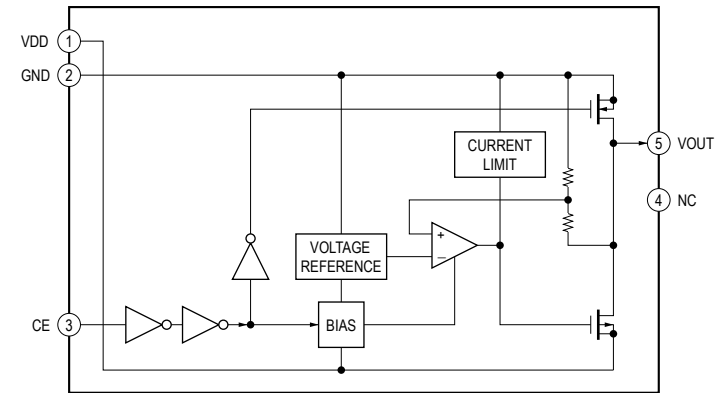
IC202 BD9329AEFJ-E2



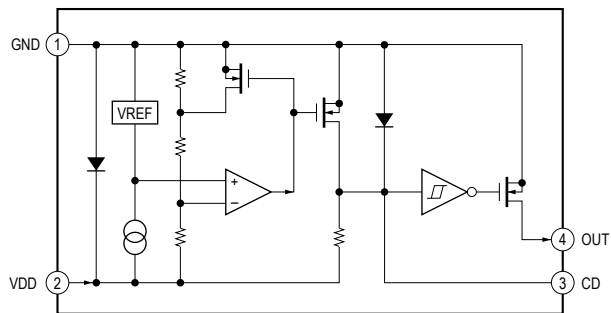
IC203 TPS54295PWPR



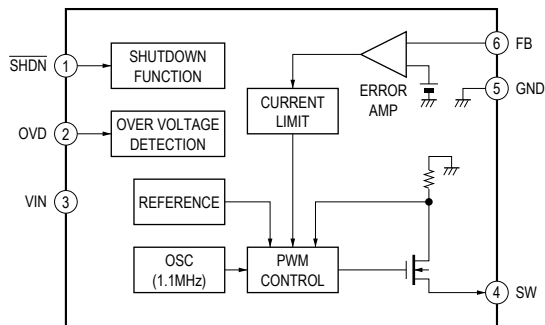
IC204 MM3464A33NRE



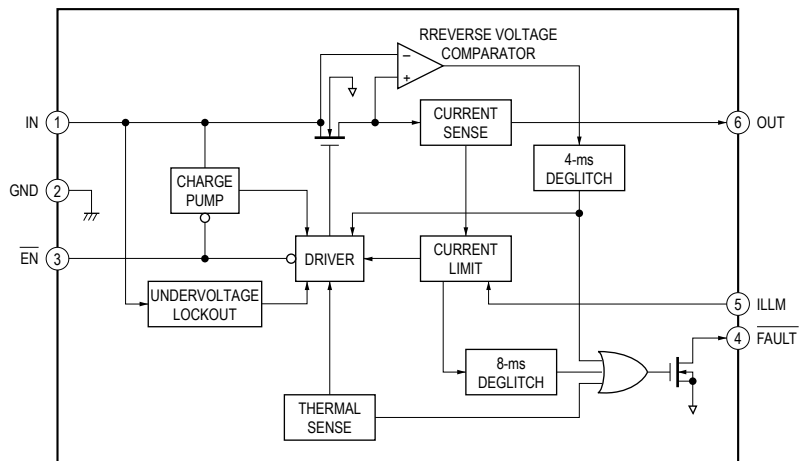
**IC205, 401 PST8429UL**



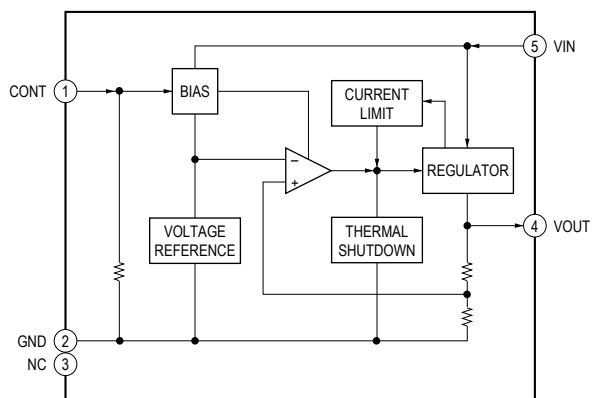
**IC701 TB62752AFUG (O, EL)**



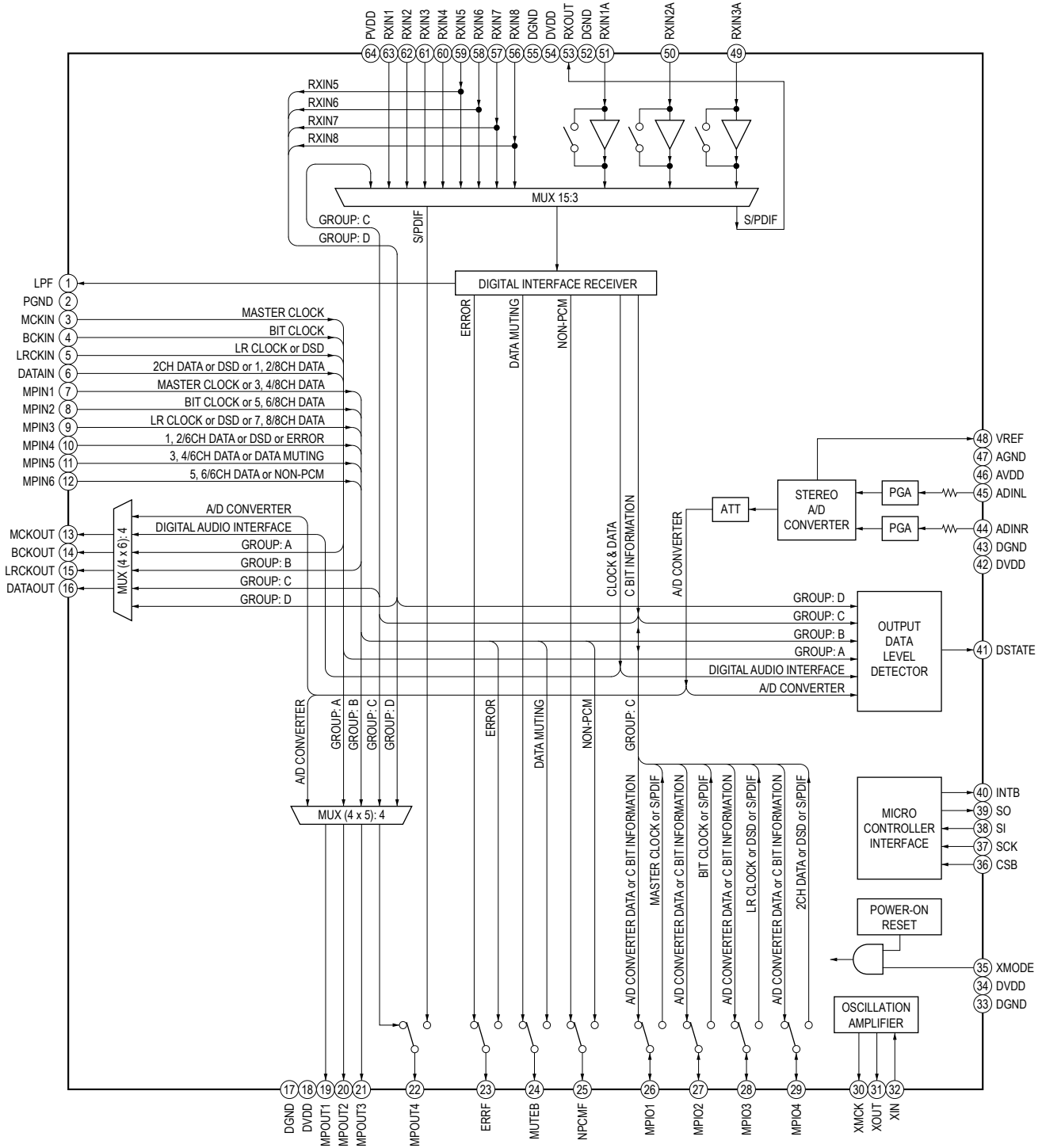
**IC1001 TPS2553DBVR**



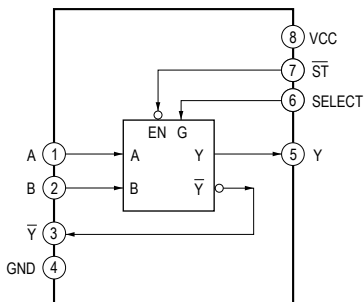
**- DIGITAL IO Board -  
IC4003 MM1839A33NRE**



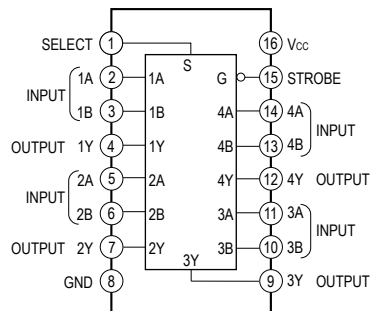
## IC4004 LC89075WA-H



## IC4006 TC7WH157FK

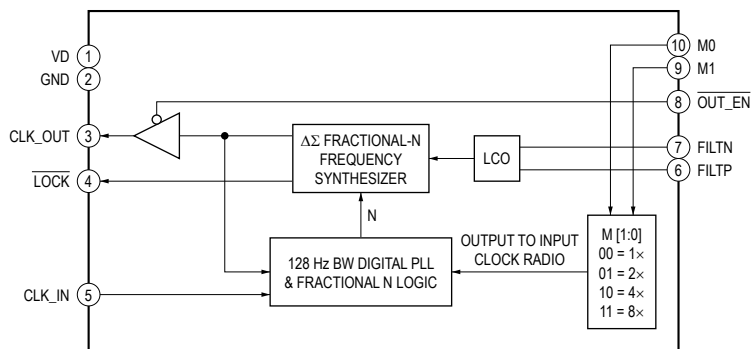


## IC4007 TC74VHC157FT (EKJ)

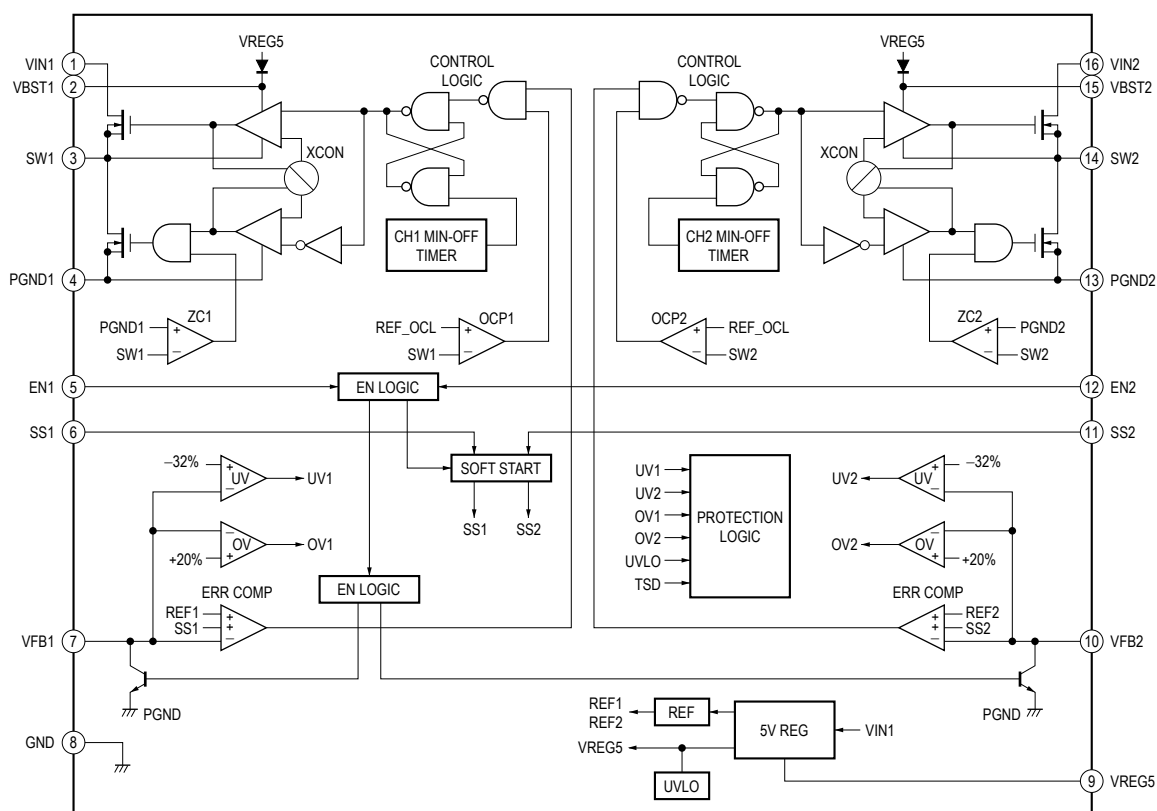




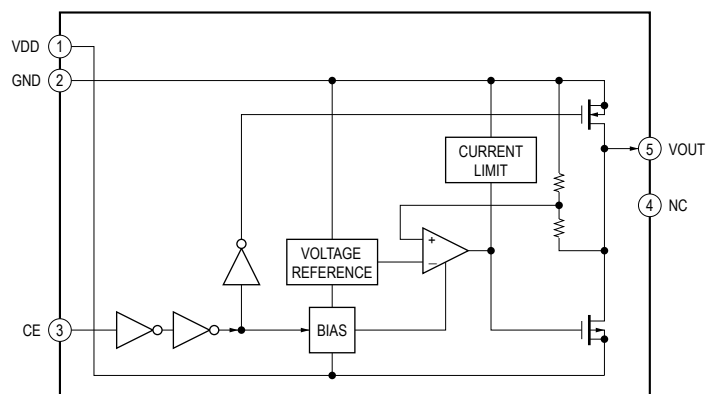
**IC4008 CS230002-CZZR**



**- FPGA DSP Board -  
IC101 TPS54295PWR**

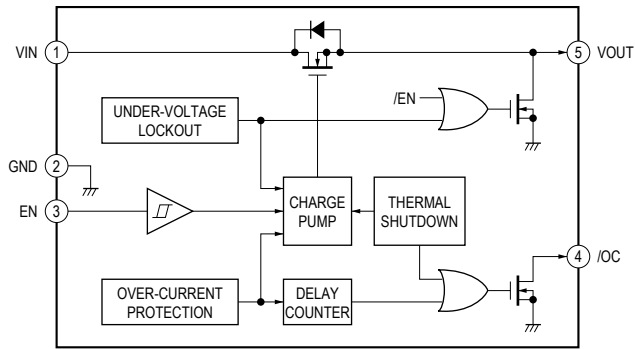


**IC102 MM3464A25NRE**

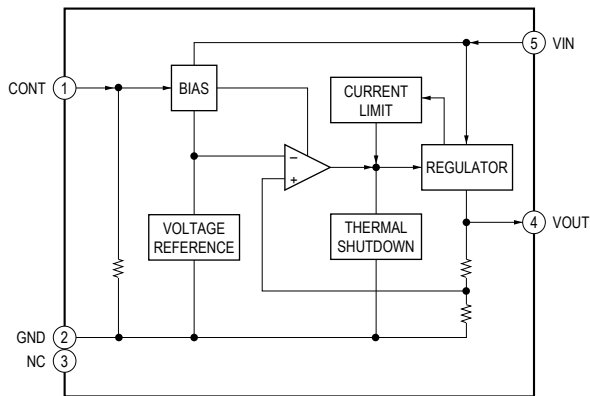


# HAP-S1

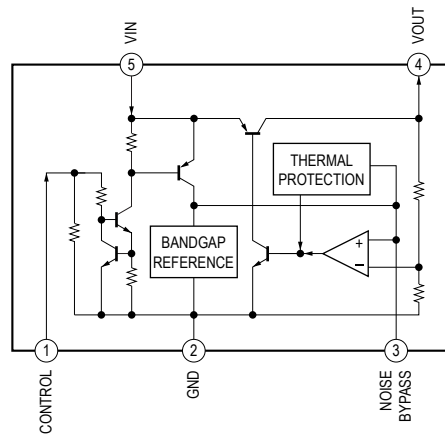
## IC103 BD2231G-TR



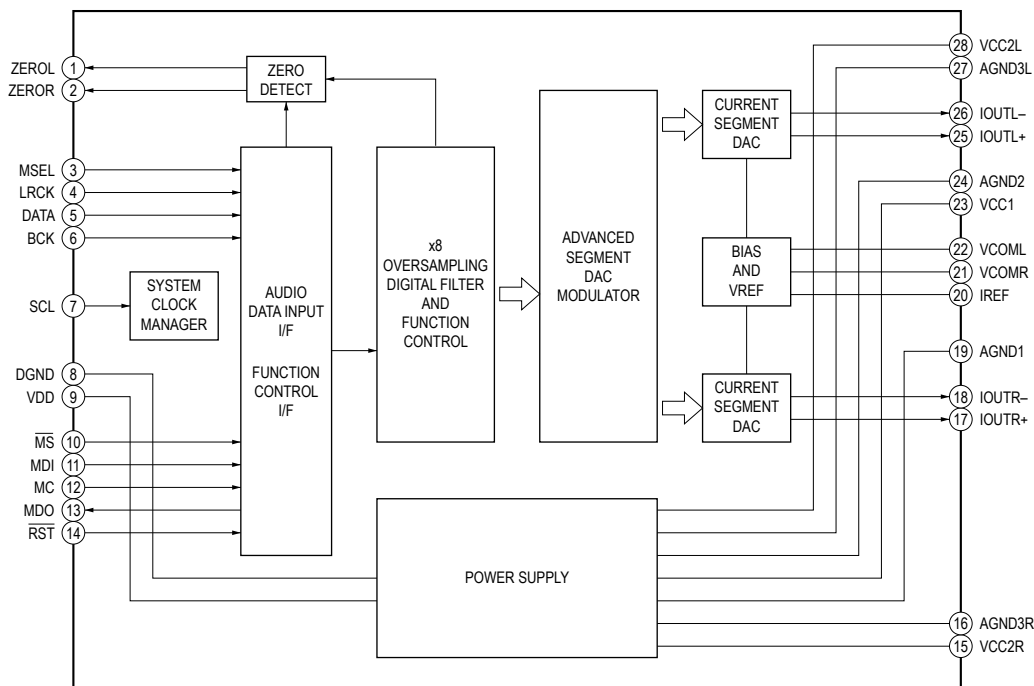
## - DAC Board - IC403 MM1836A50NRE



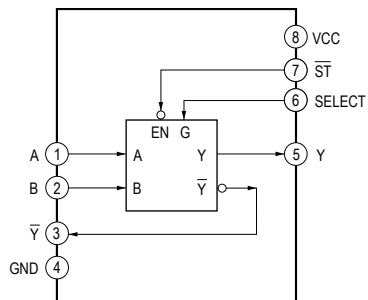
## IC404, 413, 414 NJM2871BF33-TE2



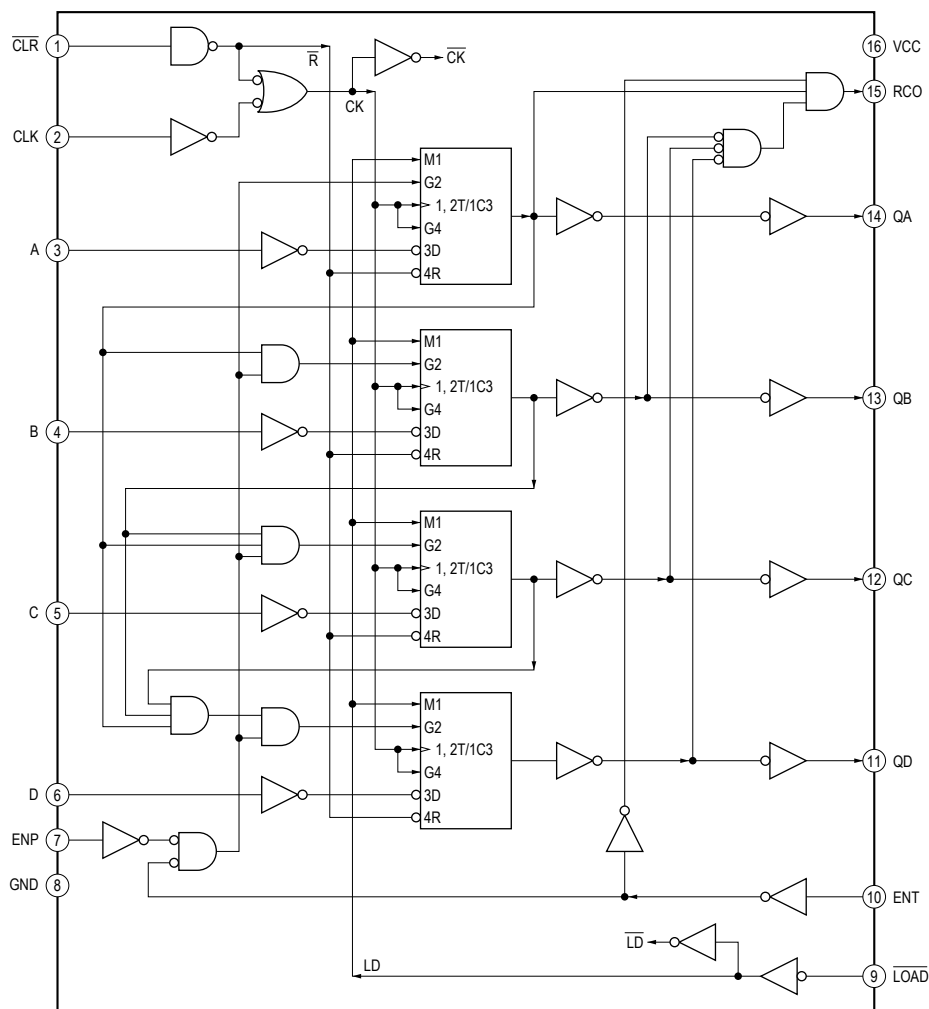
## IC405 PCM1795DBR



IC407, 410 TC7WH157FK

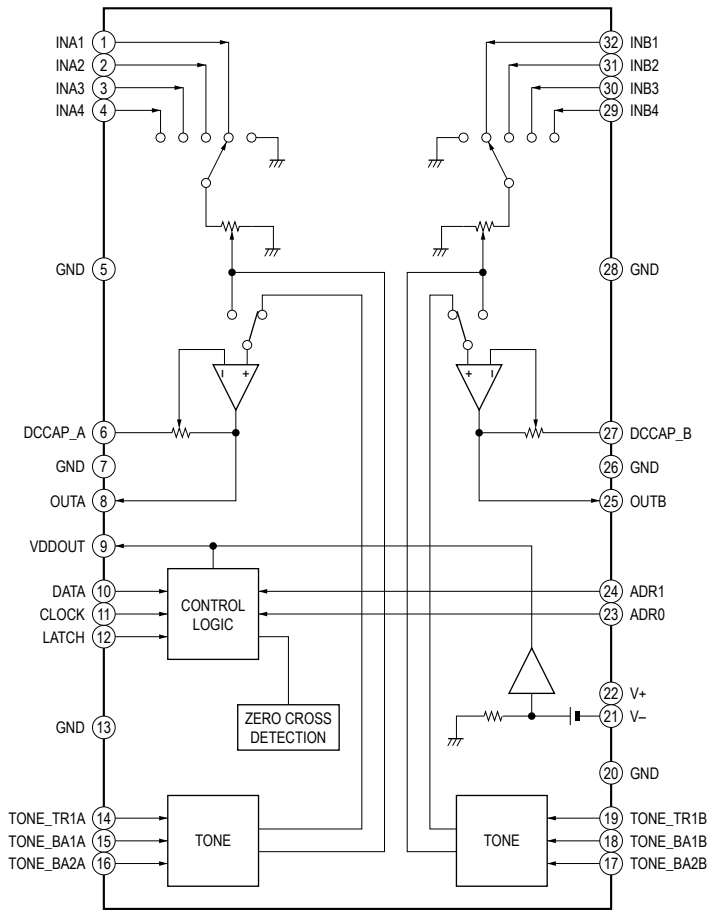


IC411 HD74LV161ATELL

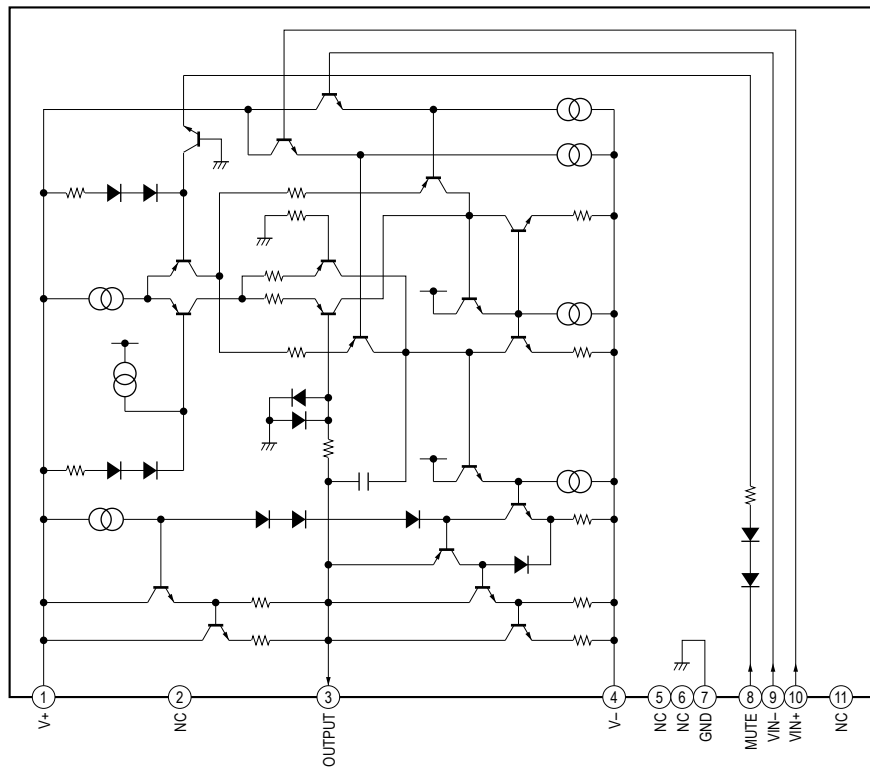


# HAP-S1

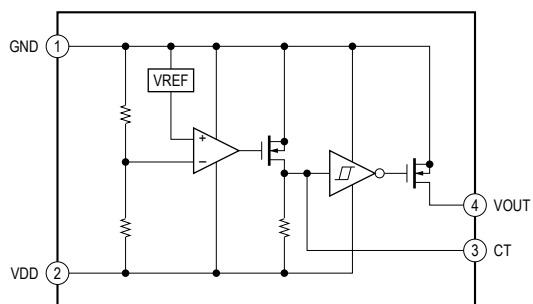
## - AMP Board - IC206 NJW1194



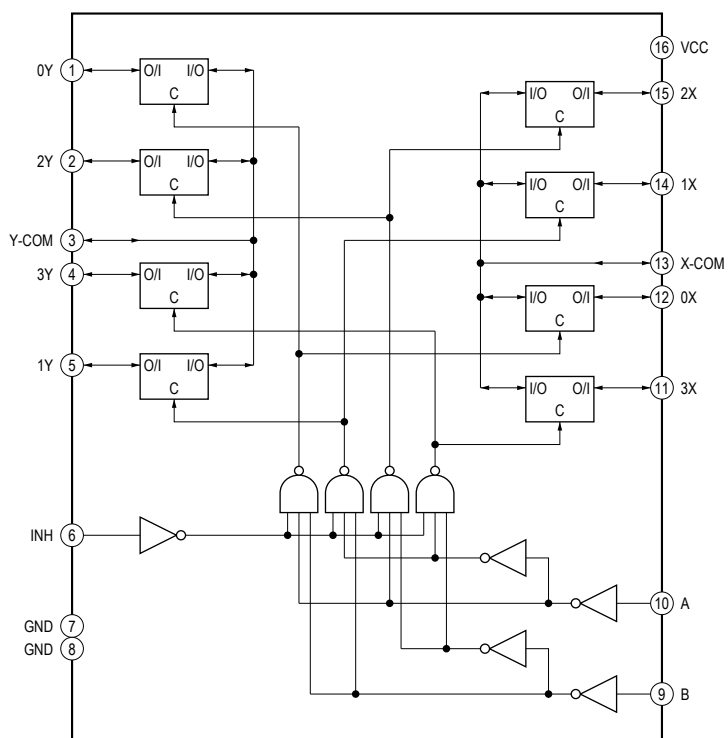
## IC350, 351 LM3876TF



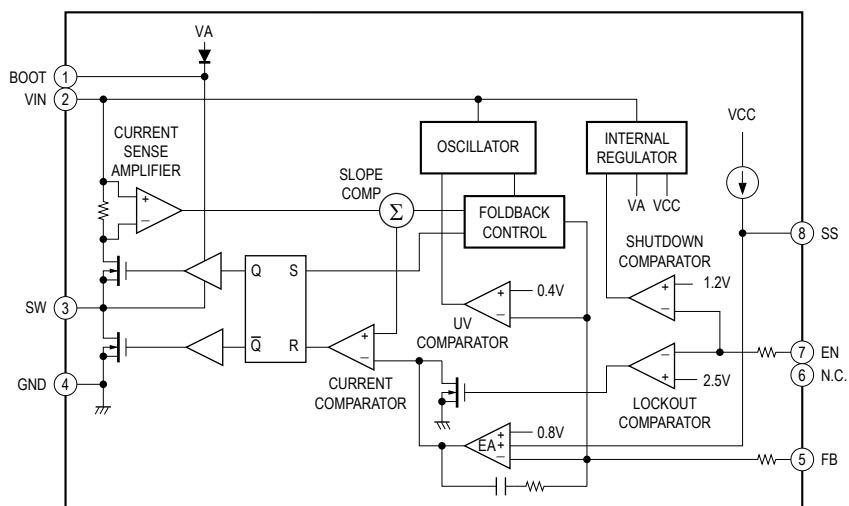
**- U-COM Board -  
IC5004 BU4229F-TR**



**IC5005 TC74VHC4052AFT (EK)**



**- DCDC Board -  
IC2402 - 2404 RT7256ALZSP**



## • IC Pin Function Description

## MAIN BOARD IC101 MCIMX6D5EYM10AC (MPU)

Pin No.	Pin Name	I/O	Description
A2	PCIE_REXT	-	Terminal for the Impedance calibration
A3	PCIE_TXM	O	Transmit data (negative) output to the FPGA
A4	GND3	-	Ground terminal
A5	FA_ANA	-	Not used
A6	USB_OTG_DP	I/O	Two-way USB data (positive) with the USB connector
A7	XTALI	I	System clock input terminal (24 MHz)
A8	GND4	-	Ground terminal
A9	MLB_SN	-	Not used
A10	MLB_DP	-	Not used
A11	MLB_CN	-	Not used
A12	SATA_TXP	O	Transmit data (positive) output to the hard disk drive
A13	GND1	-	Ground terminal
A14	SATA_RXM	I	Receive data (negative) input from the hard disk drive
A15	SD3_DAT2	I/O	Two-way data bus terminal Not used
A16	NANDF_ALE	O	Reset signal output to the system controller "H": reset
A17	NANDF_CS2	-	Not used
A18	NANDF_D0	I/O	Two-way data bus terminal Not used
A19	NANDF_D4	-	Not used
A20	SD4_DAT3	I/O	Two-way data bus with the flash memory
A21	SD1_DAT0	I/O	Two-way data bus terminal Not used
A22, A23	SD2_DAT0, SD2_DAT2	-	Not used
A24	RGMII_TD3	O	RGMII transmit data output to the ethernet transceiver
A25	GND2	-	Ground terminal
B1	PCIE_RXM	I	Receive data (negative) input from the FPGA
B2	PCIE_RXP	I	Receive data (positive) input from the FPGA
B3	PCIE_TXP	O	Transmit data (positive) output to the FPGA
B4	GND22	-	Ground terminal
B5	VDD_FA	-	Not used
B6	USB_OTG_DN	I/O	Two-way USB data (negative) with the USB connector
B7	XTALO	O	System clock output terminal (24 MHz)
B8	USB_OTG_CHD_B	-	Not used
B9	MLB_SP	-	Not used
B10	MLB_DN	-	Not used
B11	MLB_CP	-	Not used
B12	SATA_TXM	O	Transmit data (negative) output to the hard disk drive
B13	SD3_CMD	-	Not used
B14	SATA_RXP	I	Receive data (positive) input from the hard disk drive
B15	SD3_DAT3	-	Not used
B16	NANDF_RB0	O	Interrupt signal output terminal Not used
B17	SD4_CMD	O	Command signal output to the flash memory
B18	NANDF_D5	-	Not used
B19, B20	SD4_DAT1, SD4_DAT6	I/O	Two-way data bus with the flash memory
B21	SD1_CMD	-	Not used
B22	SD2_DAT3	-	Not used
B23, B24	RGMII_RD1, RGMII_RD2	I	RGMII receive data input from the ethernet transceiver
B25	RGMII_RXC	I	RGMII receive clock signal input from the ethernet transceiver
C1	GND23	-	Ground terminal
C2	JTAG_TRSTB	-	Not used
C3	JTAG_TMS	-	Not used
C4	GND25	-	Ground terminal
C5	CLK2_N	-	Not used
C6	GND26	-	Ground terminal
C7	CLK1_N	O	Clock signal (negative) output to the FPGA
C8	GPANAIO	-	Not used

Pin No.	Pin Name	I/O	Description
C9	RTC_XTALO	O	Real time clock output terminal (32.768 kHz)
C10	GND24	-	Ground terminal
C11	POR_B	I	Reset signal input from reset signal generator and system controller "L": reset
C12	BOOT_MODE0	I	Boot mode setting terminal Fixed at "L"
C13	SD3_DAT5	-	Not used
C14	SATA_REXT	-	Terminal for the impedance calibration
C15	NANDF_CLE	O	Update signal output to the system controller "H": update
C16	NANDF_CS1	O	Reset signal output terminal Not used
C17	NANDF_D1	I/O	Two-way data bus terminal Not used
C18	NANDF_D7	-	Not used
C19	SD4_DAT5	I/O	Two-way data bus with the flash memory
C20	SD1_DAT1	I/O	Two-way data bus terminal Not used
C21	SD2_CLK	-	Not used
C22	RGMII_TD0	O	RGMII transmit data output to the ethernet transceiver
C23	RGMII_TX_CTL	O	RGMII transmit data enable signal output to the ethernet transceiver
C24	RGMII_RD0	I	RGMII receive data input from the ethernet transceiver
C25	EIM_D16	-	Not used
D1	CSI_D1M	-	Not used
D2	CSI_D1P	-	Not used
D3	GND27	-	Ground terminal
D4	CSI_REXT	-	Not used
D5	CLK2_P	-	Not used
D6	GND28	-	Ground terminal
D7	CLK1_P	O	Clock signal (positive) output to the FPGA
D8	GND29	-	Ground terminal
D9	RTC_XTALI	I	Real time clock input terminal (32.768 kHz)
D10	USB_H1_VBUS	I	Power supply of the USB interface for the WLAN/BT COMBO card
D11	PMIC_ON_REQ	O	Not used
D12	ONOFF	-	Not used
D13	SD3_DAT4	-	Not used
D14	SD3_CLK	-	Not used
D15	SD3_RST	-	Not used
D16	NANDF_CS3	-	Not used
D17	NANDF_D3	-	Not used
D18, D19	SD4_DAT0, SD4_DAT7	I/O	Two-way data bus with the flash memory
D20	SD1_CLK	O	Clock signal output terminal Not used
D21	RGMII_TXC	O	RGMII transmit clock signal output to the ethernet transceiver
D22	RGMII_RX_CTL	I	RGMII receive data valid signal input from the ethernet transceiver
D23	RGMII_RD3	I	RGMII receive data input from the ethernet transceiver
D24	EIM_D18	-	Not used
D25	EIM_D23	I	Status signal input from the FPGA
E1	CSI_D2M	-	Not used
E2	CSI_D2P	-	Not used
E3	CSI_D0P	-	Not used
E4	CSI_D0M	-	Not used
E5 to E7	GND30 to GND32	-	Ground terminal
E8	NVCC_PLL_OUT	-	Power supply terminal for the PLL output Not used
E9	USB_OTG_VBUS	I	Power supply of the USB interface for the USB connector
E10	USB_H1_DP	I/O	Two-way USB data (positive) with the WLAN/BT COMBO card
E11	TAMPER	I	Mode setting terminal Fixed at "H"
E12	TEST_MODE	I	Mode setting terminal Not used
E13	SD3_DAT6	-	Not used
E14	SD3_DAT0	-	Not used
E15	NANDF_WP_B	O	LED drive signal output terminal "H": LED on
E16	SD4_CLK	O	Clock signal output to the flash memory
E17	NANDF_D6	-	Not used
E18	SD4_DAT4	I/O	Two-way data bus with the flash memory
E19	SD1_DAT2	I/O	Two-way data bus terminal Not used
E20	SD2_DAT1	-	Not used

Pin No.	Pin Name	I/O	Description
E21	RGMII_TD2	O	RGMII transmit data output to the ethernet transceiver
E22	EIM_EB2	I	Boot mode setting terminal Fixed at "L"
E23	EIM_D22	O	VBUS power on/off control signal output terminal for the USB connector "H": power on
E24, E25	EIM_D26, EIM_D27	-	Not used
F1	CSI_D3P	-	Not used
F2	CSI_D3M	-	Not used
F3	CSI_CLK0P	-	Not used
F4	CSI_CLK0M	-	Not used
F5 to F8	GND33 to GND36	-	Ground terminal
F9	VDDUSB_CAP1	O	Internal regulator output terminal
F10	USB_H1_DN	I/O	Two-way USB data (negative) with the WLAN/BT COMBO card
F11	PMIC_STBY_REQ	O	Not used
F12	BOOT_MODE1	I	Boot mode setting terminal Fixed at "H"
F13	SD3_DAT7	-	Not used
F14	SD3_DAT1	-	Not used
F15	NANDF_CS0	-	Not used
F16	NANDF_D2	-	Not used
F17	SD4_DAT2	I/O	Two-way data bus with the flash memory
F18	SD1_DAT3	-	Not used
F19	SD2_CMD	-	Not used
F20	RGMII_TD1	O	RGMII transmit data output to the ethernet transceiver
F21, F22	EIM_D17, EIM_D24	-	Not used
F23	EIM_EB3	I	Boot mode setting terminal Fixed at "L"
F24, F25	EIM_A22, EIM_A24	I	Boot mode setting terminal Fixed at "L"
G1	DSI_D0P	-	Not used
G2	DSI_D0M	-	Not used
G3	GND39	-	Ground terminal
G4	DSI_REXT	-	Not used
G5	JTAG_TDI	-	Not used
G6	JTAG_TDO	-	Not used
G7	PCIE_VPH	-	Power supply terminal for the PCIe interface (+2.5V)
G8	PCIE_VPTX	-	Power supply terminal for the PCIe interface (+1.1V)
G9	VDD_SNV5_CAP	O	Internal regulator output terminal
G10	GND37	-	Ground terminal
G11	VDD_SNV5_IN	-	Power supply terminal for the SNVS Regulator (+3.3V)
G12	SATA_VPH	-	Power supply terminal for the SATA interface (+2.5V)
G13	SATA_VP	-	Power supply terminal for the SATA interface (+1.1V)
G14	NVCC_SD3	O	Internal regulator output terminal
G15	NVCC_NANDF	O	Internal regulator output terminal
G16, G17	NVCC_SD1, NVCC_SD2	O	Internal regulator output terminal
G18	NVCC_RGMII	-	Power supply terminal for the ENET interface (+1.8V)
G19	GND38	-	Ground terminal
G20	EIM_D20	O	Configuration signal output to the FPGA
G21, G22	EIM_D19, EIM_D25	-	Not used
G23	EIM_D28	I	Diag mode enable signal input terminal
G24, G25	EIM_A17, EIM_A19	I	Boot mode setting terminal Fixed at "L"
H1	DSI_D1P	-	Not used
H2	DSI_D1M	-	Not used
H3	DSI_CLK0M	-	Not used
H4	DSI_CLK0P	-	Not used
H5	JTAG_TCK	-	Not used
H6	JTAG_MOD	-	Not used
H7	PCIE_VP	-	Power supply terminal for the PCIe interface (+1.1V)
H8	GND43	-	Ground terminal
H9	VDDHIGH_IN1	-	Power supply terminal for the +2.5V regulator (+3.3V)
H10	VDDHIGH_CAP1	O	Internal regulator output terminal (+2.5V)
H11	VDDARM23_CAP1	O	Internal regulator output terminal Not used



Pin No.	Pin Name	I/O	Description
H12	GND40	-	Ground terminal
H13	VDDARM_CAP1	O	Internal regulator output terminal
H14	VDDARM_IN1	-	Power supply terminal for the cores regulator (+1.42V)
H15	GND41	-	Ground terminal
H16	VDDSOC_IN1	-	Power supply terminal for the SOC and PU regulators (+1.42V)
H17	VDDPU_CAP1	O	Internal regulator output terminal
H18	GND42	-	Ground terminal
H19	EIM_A25	I	Interrupt signal input from the FPGA
H20	EIM_D21	I	VBUS power over current detection signal input terminal for the USB connector
H21	EIM_D31	-	Not used
H22, H23	EIM_A20, EIM_A21	I	Boot mode setting terminal Fixed at "L"
H24	EIM_CS0	O	Serial data transfer clock signal output to the FPGA
H25	EIM_A16	I	Boot mode setting terminal Fixed at "L"
J1	HDMI_REF	-	Not used
J2	GND47	-	Ground terminal
J3	HDMI_D1M	-	Not used
J4	HDMI_D1P	-	Not used
J5	HDMI_CLKM	-	Not used
J6	HDMI_CLKP	-	Not used
J7	NVCC_JTAG	O	Internal regulator output terminal
J8	GND48	-	Ground terminal
J9	VDDHIGH_IN2	-	Power supply terminal for the +2.5V regulator (+3.3V)
J10	VDDHIGH_CAP2	O	Internal regulator output terminal (+2.5V)
J11	VDDARM23_CAP2	O	Internal regulator output terminal Not used
J12	GND44	-	Ground terminal
J13	VDDARM_CAP2	O	Internal regulator output terminal
J14	VDDARM_IN2	-	Power supply terminal for the cores regulator (+1.42V)
J15	GND45	-	Ground terminal
J16	VDDSOC_IN2	-	Power supply terminal for the SOC and PU regulators (+1.42V)
J17	VDDPU_CAP2	O	Internal regulator output terminal
J18	GND46	-	Ground terminal
J19, J20	EIM_D29, EIM_D30	-	Not used
J21, J22	EIM_A23, EIM_A18	I	Boot mode setting terminal Fixed at "L"
J23	EIM_CS1	O	Configuration data output to the FPGA
J24	EIM_OE	-	Not used
J25	EIM_DA1	I	Boot mode setting terminal Fixed at "L"
K1	HDMI_HPD	-	Not used
K2	HDMI_DDCCEC	-	Not used
K3	HDMI_D2M	-	Not used
K4	HDMI_D2P	-	Not used
K5	HDMI_D0M	-	Not used
K6	HDMI_D0P	-	Not used
K7	NVCC_MIPI	-	Power supply terminal for the MIPI interface (+2.5V)
K8	GND53	-	Ground terminal
K9	VDDARM23_IN1	-	Power supply terminal for the cores regulator Not used
K10	GND49	-	Ground terminal
K11	VDDARM23_CAP3	O	Internal regulator output terminal Not used
K12	GND50	-	Ground terminal
K13	VDDARM_CAP3	O	Internal regulator output terminal
K14	VDDARM_IN3	-	Power supply terminal for the cores regulator (+1.42V)
K15	GND51	-	Ground terminal
K16	VDDSOC_IN3	-	Power supply terminal for the SOC and PU regulators (+1.42V)
K17	VDDPU_CAP3	O	Internal regulator output terminal
K18	GND52	-	Ground terminal
K19	NVCC_EIM0	-	Power supply terminal for the EMI interface (+3.3V)
K20	EIM_RW	I	Boot mode setting terminal Fixed at "L"
K21	EIM_EB0	I	Boot mode setting terminal Fixed at "L"
K22	EIM_LBA	I	Boot mode setting terminal Fixed at "L"
K23	EIM_EB1	I	Boot mode setting terminal Fixed at "L"

Pin No.	Pin Name	I/O	Description
K24	EIM_DA3	I	Boot mode setting terminal Fixed at "L"
K25	EIM_DA6	I	Boot mode setting terminal Fixed at "H"
L1	CSI0_DAT13	I	Serial data or program data input from the system controller
L2	GND58	-	Ground terminal
L3, L4	CSI0_DAT17, CSI0_DAT16	-	Not used
L5	GND59	-	Ground terminal
L6	CSI0_DAT19	-	Not used
L7	HDMI_VP	-	Power supply terminal for the HDMI interface Not used
L8	GND60	-	Ground terminal
L9	VDDARM23_IN2	-	Power supply terminal for the cores regulator Not used
L10	GND54	-	Ground terminal
L11	VDDARM23_CAP4	O	Internal regulator output terminal Not used
L12	GND55	-	Ground terminal
L13	VDDARM_CAP4	O	Internal regulator output terminal
L14	VDDARM_IN4	-	Power supply terminal for the cores regulator (+1.42V)
L15	GND56	-	Ground terminal
L16	VDDSOC_IN4	-	Power supply terminal for the SOC and PU regulators (+1.42V)
L17	VDDPU_CAP4	O	Internal regulator output terminal
L18	GND57	-	Ground terminal
L19	NVCC_EIM1	-	Power supply terminal for the EMI interface (+3.3V)
L20 to L22	EIM_DA0, EIM_DA2, EIM_DA4	I	Boot mode setting terminal Fixed at "L"
L23	EIM_DA5	I	Boot mode setting terminal Fixed at "H"
L24	EIM_DA8	O	Reset signal output to the liquid crystal display "L": reset
L25	EIM_DA7	I	Boot mode setting terminal Fixed at "L"
M1	CSI0_DAT10	O	Transmit data output terminal
M2	CSI0_DAT12	O	Serial data or program data output to the system controller
M3	CSI0_DAT11	I	Receive data input terminal
M4	CSI0_DAT14	O	Transmit data output terminal Not used
M5	CSI0_DAT15	I	Receive data input terminal Not used
M6	CSI0_DAT18	-	Not used
M7	HDMI_VPH	-	Power supply terminal for the HDMI interface Not used
M8	GND65	-	Ground terminal
M9	VDDARM23_IN3	-	Power supply terminal for the cores regulator Not used
M10	GND61	-	Ground terminal
M11	VDDARM23_CAP5	O	Internal regulator output terminal Not used
M12	GND62	-	Ground terminal
M13	VDDARM_CAP5	O	Internal regulator output terminal
M14	VDDARM_IN5	-	Power supply terminal for the cores regulator (+1.42V)
M15	GND63	-	Ground terminal
M16	VDDSOC_IN5	-	Power supply terminal for the SOC and PU regulators (+1.42V)
M17	VDDPU_CAP5	O	Internal regulator output terminal
M18	GND64	-	Ground terminal
M19	NVCC_EIM2	-	Power supply terminal for the EMI interface (+3.3V)
M20	EIM_DA11	I	Boot mode setting terminal Fixed at "H"
M21 to M23	EIM_DA9, EIM_DA10, EIM_DA13	I	Boot mode setting terminal Fixed at "L"
M24	EIM_DA12	I	Boot mode setting terminal Fixed at "H"
M25	EIM_WAIT	I	Boot mode setting terminal Fixed at "L"
N1	CSI0_DAT4	-	Not used
N2	CSI0_VSYNC	O	Power on/off control signal output terminal for the FPGA power "H": power on
N3 to N5	CSI0_DAT7, CSI0_DAT6, CSI0_DAT9	-	Not used
N6	CSI0_DAT8	I	INIT_DONE signal input from the FPGA
N7	NVCC_CSI	I	Power supply terminal for the camera sensor interface (+3.3V)
N8	GND69	-	Ground terminal
N9	VDDARM23_IN4	-	Power supply terminal for the cores regulator Not used
N10	GND66	-	Ground terminal

Pin No.	Pin Name	I/O	Description
N11	VDDARM23_CAP6	O	Internal regulator output terminal Not used
N12	VDD_CACHE_CAP	O	Internal regulator output terminal (+1.1V)
N13	VDDARM_CAP6	O	Internal regulator output terminal
N14	VDDARM_IN6	-	Power supply terminal for the cores regulator (+1.42V)
N15	GND67	-	Ground terminal
N16	VDDSOC_IN6	-	Power supply terminal for the SOC and PU regulators (+1.42V)
N17	VDDPU_CAP6	O	Internal regulator output terminal
N18	GND68	-	Ground terminal
N19	DI0_DISP_CLK	O	Clock signal output to the liquid crystal display
N20	DI0_PIN3	-	Not used
N21	DI0_PIN15	O	Data enable signal output to the liquid crystal display
N22	EIM_BCLK	-	Not used
N23	EIM_DA14	I	Boot mode setting terminal Fixed at "L"
N24	EIM_DA15	I	Boot mode setting terminal Fixed at "H"
N25	DI0_PIN2	-	Not used
P1	CSI0_PIXCLK	I	CONF_DONE signal input from the FPGA
P2	CSI0_DAT5	-	Not used
P3	CSI0_DATA_EN	-	Not used
P4	CSI0_MCLK	O	Reset signal output to the FPGA "L": reset
P5, P6	GPIO_19, GPIO_18	-	Not used
P7	NVCC_GPIO	-	Power supply terminal for the GPIO interface (+3.3V)
P8	GND74	-	Ground terminal
P9	VDDARM23_IN5	-	Power supply terminal for the cores regulator Not used
P10	GND70	-	Ground terminal
P11	VDDARM23_CAP7	O	Internal regulator output terminal Not used
P12	GND71	-	Ground terminal
P13	VDDARM_CAP7	O	Internal regulator output terminal
P14	VDDARM_IN7	-	Power supply terminal for the cores regulator (+1.42V)
P15	GND72	-	Ground terminal
P16	VDDSOC_IN7	-	Power supply terminal for the SOC and PU regulators (+1.42V)
P17	VDDPU_CAP7	O	Internal regulator output terminal
P18	GND73	-	Ground terminal
P19	NVCC_LCD	-	Power supply terminal for the LCD interface (+3.3V)
P20 to P24	DISP0_DAT4, DISP0_DAT3, DISP0_DAT1, DISP0_DAT2, DISP0_DAT0	O	RGB signal (blue) output to the liquid crystal display
P25	DI0_PIN4	O	Liquid crystal display backlight on/off control signal output terminal "H": backlight on
R1	GPIO_17	O	Reset signal output to the PCIe transceiver "L": reset
R2 to R7	GPIO_16, GPIO_7, GPIO_5, GPIO_8, GPIO_4, GPIO_3	-	Not used
R8	GND78	-	Ground terminal
R9	VDDARM23_IN6	-	Power supply terminal for the cores regulator Not used
R10	VSSSOC_CAP1	O	Internal regulator output terminal (+1.1V)
R11	VDDARM23_CAP8	O	Internal regulator output terminal Not used
R12	GND75	-	Ground terminal
R13	VDDARM_CAP8	O	Internal regulator output terminal
R14	VDDARM_IN8	-	Power supply terminal for the cores regulator (+1.42V)
R15	GND76	-	Ground terminal
R16	VDDSOC_IN8	-	Power supply terminal for the SOC and PU regulators (+1.42V)
R17	GND77	-	Ground terminal
R18	NVCC_DRAM1	-	Power supply terminal for the DDR interface (+1.5V)
R19	NVCC_ENET	-	Power supply terminal for the ENET interface (+3.3V)
R20 to R22	DISP0_DAT13, DISP0_DAT10, DISP0_DAT8	O	RGB signal (green) output to the liquid crystal display
R23 to R25	DISP0_DAT6, DISP0_DAT7, DISP0_DAT5	O	RGB signal (blue) output to the liquid crystal display

Pin No.	Pin Name	I/O	Description
T1 to T5	GPIO_2, GPIO_9, GPIO_6, GPIO_1, GPIO_0	-	Not used
T6	KEY_COL4	-	Not used
T7	KEY_ROW3	O	Liquid crystal display dimmer control signal output terminal
T8	GND84	-	Ground terminal
T9	VDDARM23_IN7	-	Power supply terminal for the cores regulator Not used
T10	VSSSOC_CAP2	O	Internal regulator output terminal (+1.1V)
T11, T12	GND79, GND80	-	Ground terminal
T13, T14	VSSSOC_CAP3, VSSSOC_CAP4	O	Internal regulator output terminal (+1.1V)
T15	GND81	-	Ground terminal
T16	VDDSOC_IN9	-	Power supply terminal for the SOC and PU regulators (+1.42V)
T17	GND82	-	Ground terminal
T18	NVCC_DRAM2	-	Power supply terminal for the DDR interface (+1.5V)
T19	GND83	-	Ground terminal
T20, T21	DISP0_DAT21, DISP0_DAT16	O	RGB signal (red) output to the liquid crystal display
T22 to T25	DISP0_DAT15, DISP0_DAT11, DISP0_DAT12, DISP0_DAT9	O	RGB signal (green) output to the liquid crystal display
U1	LVDS0_TX0_P	-	Not used
U2	LVDS0_TX0_N	-	Not used
U3	LVDS0_TX1_P	-	Not used
U4	LVDS0_TX1_N	-	Not used
U5	KEY_COL3	O	Liquid crystal display dimmer control signal output terminal
U6	KEY_ROW1	-	Not used
U7	KEY_COL1	-	Not used
U8	GND89	-	Ground terminal
U9	VDDARM23_IN8	-	Power supply terminal for the cores regulator Not used
U10	VSSSOC_CAP5	O	Internal regulator output terminal (+1.1V)
U11, U12	GND85, GND86	-	Ground terminal
U13, U14	VSSSOC_CAP6, VSSSOC_CAP7	O	Internal regulator output terminal (+1.1V)
U15	GND87	-	Ground terminal
U16	VDDSOC_IN10	-	Power supply terminal for the SOC and PU regulators (+1.42V)
U17	GND88	-	Ground terminal
U18	NVCC_DRAM3	-	Power supply terminal for the DDR interface (+1.5V)
U19	GND90	-	Ground terminal
U20	ENET_TXD0	O	Power on/off control signal output terminal for the liquid crystal display "H": power on
U21	ENET_CRS_DV	O	Reset signal output to the ethernet transceiver "L": reset
U22 to U24	DISP0_DAT20, DISP0_DAT19, DISP0_DAT17	O	RGB signal (red) output to the liquid crystal display
U25	DISP0_DAT14	O	RGB signal (green) output to the liquid crystal display
V1	LVDS0_TX2_P	-	Not used
V2	LVDS0_TX2_N	-	Not used
V3	LVDS0_CLK_P	-	Not used
V4	LVDS0_CLK_N	-	Not used
V5, V6	KEY_ROW4, KEY_ROW0	-	Not used
V7	NVCC_LVDS2P5	-	Power supply terminal for the LVDS display interface (+2.5V)
V8	GND91	-	Ground terminal
V9 to V18	NVCC_DRAM13, NVCC_DRAM4 to NVCC_DRAM12	-	Power supply terminal for the DDR interface (+1.5V)
V19	GND92	-	Ground terminal
V20	ENET_MDC	O	Management data clock signal output to the ethernet transceiver
V21	ENET_TX_EN	-	Not used
V22	ENET_REF_CLK	I	25 MHz clock signal input from the ethernet transceiver
V23	ENET_MDIO	I/O	Two-way management data bus with the ethernet transceiver

Pin No.	Pin Name	I/O	Description
V24, V25	DISP0_DAT22, DISP0_DAT18	O	RGB signal (red) output to the liquid crystal display
W1	LVDS0_TX3_P	-	Not used
W2	LVDS0_TX3_N	-	Not used
W3	GND93	-	Ground terminal
W4	KEY_ROW2	-	Not used
W5, W6	KEY_COL0, KEY_COL2	-	Not used
W7 to W13	GND94 to GND100	-	Ground terminal
W14	DRAM_A4	O	Address signal output to the SD-RAM
W15 to W19	GND101 to GND105	-	Ground terminal
W20	ENET_TXD1	O	VBUS power on/off control signal output terminal for the WLAN/BT COMBO card "H": power on
W21	ENET_RXD0	-	Not used
W22	ENET_RXD1	I	Interrupt signal input from the ethernet transceiver
W23	ENET_RX_ER	O	ID signal output terminal for the USB OTG Not used
W24	DISP0_DAT23	O	RGB signal (red) output to the liquid crystal display
W25	DRAM_D63	-	Not used
Y1	LVDS1_TX0_N	-	Not used
Y2	LVDS1_TX0_P	-	Not used
Y3	LVDS1_CLK_N	-	Not used
Y4	LVDS1_CLK_P	-	Not used
Y5	GND106	-	Ground terminal
Y6	DRAM_RESET	O	Reset signal output to the SD-RAM "L": reset
Y7 to Y10	DRAM_D20, DRAM_D21, DRAM_D19, DRAM_D25	I/O	Two-way data bus with the SD-RAM
Y11	DRAM_SDCKE0	O	Clock enable signal output to the SD-RAM
Y12 to Y14	DRAM_A15, DRAM_A7, DRAM_A3	O	Address signal output to the SD-RAM
Y15	DRAM_SDBA1	O	Bank address signal output to the SD-RAM
Y16	DRAM_CS0	O	Chip select signal output to the SD-RAM
Y17 to Y20	DRAM_D36, DRAM_D37, DRAM_D40, DRAM_D44	-	Not used
Y21	DRAM_DQM7	-	Not used
Y22, Y23	DRAM_D59, DRAM_D62	-	Not used
Y24	GND107	-	Ground terminal
Y25	DRAM_D58	-	Not used
AA1	LVDS1_TX1_P	-	Not used
AA2	LVDS1_TX1_N	-	Not used
AA3	LVDS1_TX3_N	-	Not used
AA4	LVDS1_TX3_P	-	Not used
AA5, AA6	DRAM_D3, DRAM_D10	I/O	Two-way data bus with the SD-RAM
AA7	GND10	-	Ground terminal
AA8, AA9	DRAM_D17, DRAM_D23	I/O	Two-way data bus with the SD-RAM
AA10	GND5	-	Ground terminal
AA11	DRAM_SDCKE1	-	Not used
AA12	DRAM_A14	O	Address signal output to the SD-RAM
AA13	GND6	-	Ground terminal
AA14, AA15	DRAM_A2, DRAM_A10	O	Address signal output to the SD-RAM
AA16	GND7	-	Ground terminal
AA17, AA18	DRAM_D32, DRAM_D33	-	Not used

Pin No.	Pin Name	I/O	Description
AA19	GND8	-	Ground terminal
AA20, AA21	DRAM_D45, DRAM_D57	-	Not used
AA22	GND9	-	Ground terminal
AA23	DRAM_D61	-	Not used
AA24	DRAM_SDQS7_B	-	Not used
AA25	DRAM_SDQS7	-	Not used
AB1	LVDS1_TX2_N	-	Not used
AB2	LVDS1_TX2_P	-	Not used
AB3	GND12	-	Ground terminal
AB4 to AB7	DRAM_D6, DRAM_D12, DRAM_D14, DRAM_D16	I/O	Two-way data bus with the SD-RAM
AB8	DRAM_DQM2	O	Data mask (upper byte) signal output to the SD-RAM
AB9	DRAM_D18	I/O	Two-way data bus with the SD-RAM
AB10	DRAM_SDQS3_B	O	Data strobe signal (lower byte) output to the SD-RAM
AB11	DRAM_D27	I/O	Two-way data bus with the SD-RAM
AB12	DRAM_SDBA2	O	Bank address signal output to the SD-RAM
AB13, AB14	DRAM_A8, DRAM_A1	O	Address signal output to the SD-RAM
AB15	DRAM_RAS	O	Row address signal output to the SD-RAM
AB16	DRAM_SDWE	O	Write enable signal output to the SD-RAM
AB17	DRAM_SDODT1	-	Not used
AB18	DRAM_DQM4	-	Not used
AB19 to AB23	DRAM_D38, DRAM_D41, DRAM_D42, DRAM_D52, DRAM_D60	-	Not used
AB24	GND11	-	Ground terminal
AB25	DRAM_D56	-	Not used
AC1	DRAM_D4	I/O	Two-way data bus with the SD-RAM
AC2	DRAM_VREF	I	Reference voltage input terminal
AC3	DRAM_DQM0	O	Data mask (lower byte) signal output to the SD-RAM
AC4, AC5	DRAM_D2, DRAM_D13	I/O	Two-way data bus with the SD-RAM
AC6	DRAM_DQM1	O	Data mask (upper byte) signal output to the SD-RAM
AC7 to AC9	DRAM_D15, DRAM_D22, DRAM_D28	I/O	Two-way data bus with the SD-RAM
AC10	DRAM_SDQS3	O	Data strobe signal (lower byte) output to the SD-RAM
AC11	DRAM_D31	I/O	Two-way data bus with the SD-RAM
AC12 to AC14	DRAM_A11, DRAM_A6, DRAM_A0	O	Address signal output to the SD-RAM
AC15	DRAM_SDBA0	O	Bank address signal output to the SD-RAM
AC16	DRAM_SDODT0	O	On die termination signal output to the SD-RAM
AC17	DRAM_A13	O	Address signal output to the SD-RAM
AC18, AC19	DRAM_D34, DRAM_D39	-	Not used
AC20	DRAM_DQM5	-	Not used
AC21 to AC25	DRAM_D47, DRAM_D48, DRAM_D53, DRAM_D51, DRAM_D55	-	Not used
AD1, AD2	DRAM_D5, DRAM_D0	I/O	Two-way data bus with the SD-RAM
AD3	DRAM_SDQS0_B	O	Data strobe signal (lower byte) output to the SD-RAM
AD4	GND18	-	Ground terminal
AD5	DRAM_D8	I/O	Two-way data bus with the SD-RAM
AD6	DRAM_SDQS1	O	Data strobe signal (upper byte) output to the SD-RAM

Pin No.	Pin Name	I/O	Description
AD7	GND19	-	Ground terminal
AD8	DRAM_SDQS2	O	Data strobe signal (upper byte) output to the SD-RAM
AD9	DRAM_D29	I/O	Two-way data bus with the SD-RAM
AD10	GND13	-	Ground terminal
AD11	DRAM_D30	I/O	Two-way data bus with the SD-RAM
AD12	DRAM_A12	O	Address signal output to the SD-RAM
AD13	GND14	-	Ground terminal
AD14	DRAM_SDCLK_1	O	Clock signal output to the SD-RAM
AD15	DRAM_SDCLK_0	-	Not used
AD16	GND15	-	Ground terminal
AD17	DRAM_CS1	-	Not used
AD18	DRAM_SDQS4	-	Not used
AD19	GND16	-	Ground terminal
AD20	DRAM_SDQS5	-	Not used
AD21	DRAM_D43	-	Not used
AD22	GND17	-	Ground terminal
AD23	DRAM_SDQS6	-	Not used
AD24	DRAM_DQM6	-	Not used
AD25	DRAM_D54	-	Not used
AE1	GND20	-	Ground terminal
AE2	DRAM_D1	I/O	Two-way data bus with the SD-RAM
AE3	DRAM_SDQS0	O	Data strobe signal (lower byte) output to the SD-RAM
AE4, AE5	DRAM_D7, DRAM_D9	I/O	Two-way data bus with the SD-RAM
AE6	DRAM_SDQS1_B	O	Data strobe signal (upper byte) output to the SD-RAM
AE7	DRAM_D11	I/O	Two-way data bus with the SD-RAM
AE8	DRAM_SDQS2_B	O	Data strobe signal (upper byte) output to the SD-RAM
AE9	DRAM_D24	I/O	Two-way data bus with the SD-RAM
AE10	DRAM_DQM3	O	Data mask (lower byte) signal output to the SD-RAM
AE11	DRAM_D26	I/O	Two-way data bus with the SD-RAM
AE12, AE13	DRAM_A9, DRAM_A5	O	Address signal output to the SD-RAM
AE14	DRAM_SDCLK_1_B	O	Clock signal output to the SD-RAM
AE15	DRAM_SDCLK_0_B	-	Not used
AE16	DRAM_CAS	O	Column address signal output to the SD-RAM
AE17	ZQPAD	I	External calibration resistor connection terminal
AE18	DRAM_SDQS4_B	-	Not used
AE19	DRAM_D35	-	Not used
AE20	DRAM_SDQS5_B	-	Not used
AE21, AE22	DRAM_D46, DRAM_D49	-	Not used
AE23	DRAM_SDQS6_B	-	Not used
AE24	DRAM_D50	-	Not used
AE25	GND21	-	Ground terminal

## MAIN BOARD IC602 AR8035-AL1A (ETHERNET TRANSCEIVER, +1.1V/+1.8V REGULATOR)

Pin No.	Pin Name	I/O	Description
1	RSTN	I	Reset signal input from the MPU "L": reset
2	LX	O	Internal regulator output terminal (+1.1V)
3	VDD33	-	Power supply terminal (+3.3V)
4	XTALO	O	System clock output terminal (25 MHz)
5	XTALI	I	System clock input terminal (25 MHz)
6	AVDDL_6	-	Power supply terminal (+1.1V)
7	RBIAS	O	Bias current setting terminal
8	VDDH_REG	O	Internal regulator output terminal (+2.5V)
9	TRXP0	I/O	Two-way data (positive) bus with the LAN jack
10	TRXN0	I/O	Two-way data (negative) bus with the LAN jack
11	AVDDL_11	-	Power supply terminal (+1.1V)
12	TRXP1	I/O	Two-way data (positive) bus with the LAN jack
13	TRXN1	I/O	Two-way data (negative) bus with the LAN jack
14	AVDD33	-	Power supply terminal (+3.3V)
15	TRXP2	I/O	Two-way data (positive) bus with the LAN jack
16	TRXN2	I/O	Two-way data (negative) bus with the LAN jack
17	AVDDL_17	-	Power supply terminal (+1.1V)
18	TRXP3	I/O	Two-way data (positive) bus with the LAN jack
19	TRXN3	I/O	Two-way data (negative) bus with the LAN jack
20	INT	O	Interrupt signal output to the MPU
21	LED_ACT	O	LED drive signal output terminal Not used
22	LED_1000	O	LED drive signal output terminal Not used
23	CLK_25M	O	25 MHz clock signal output to the MPU
24	LED_10_100	O	LED drive signal output terminal Not used
25, 26	RXD3, RXD2	O	RGMII receive data output to the MPU
27	VDDIO_REG	O	Internal regulator output terminal (+1.8V)
28, 29	RXD1, RXD0	O	RGMII receive data output to the MPU
30	RX_DV	O	RGMII receive data valid signal output to the MPU
31	RX_CLK	O	RGMII receive clock signal output to the MPU
32	TX_EN	I	RGMII transmit data enable signal input from the MPU
33	GTX_CLK	I	RGMII transmit clock signal input from the MPU
34 to 37	TXD0 to TXD3	I	RGMII transmit data input from the MPU
38	DVDDL	-	Power supply terminal (+1.1V)
39	MDIO	I/O	Two-way management data bus with the MPU
40	MDC	I	Management data clock signal input from the MPU



## FPGA DSP BOARD IC001 EP4CGX30BF14C8N (FPGA)

Pin No.	Pin Name	I/O	Description
A1	TDO	O	Data output terminal for the JTAG Not used
A2	TMS	I	Mode selection signal input terminal for the JTAG Not used
A3	TDI	I	Data input terminal for the JTAG Not used
A4	DCCLK	I	Serial data transfer clock signal input from the MPU
A5	IO/DATA0	I	Configuration data input from the MPU
A6	IO/CLKUSR	I	Not used
A7	IO/PLL2_CLKOUTN	O	Not used
A8	IO/PLL2_CLKOUTP	O	Not used
A9	CLK8/DIFFCLK_5N	I	Audio data input from the audio DSP
A10	CLK9/DIFFCLK_5p	I	Not used
A11	IO/DIFFCLK_T11N/ DQ0T	O	Bit clock signal output to the audio DSP
A12	IO/DIFFCLK_T11P/ DQ0T	O	Not used
A13	IO/DIFFIO_T17N/ DQS0T/CQ0T/ DPCLK10	O	Not used
B1, B2	GND_B1, GND_B2	-	Ground terminal
B3	TCK	I	Clock signal input terminal for the JTAG Not used
B4	GND_B4	-	Ground terminal
B5	IO/ASDO	O	Not used
B6	IO/DQS1T/CQ0T#/ DPCLK13	O	Not used
B7	GND_B7	-	Ground terminal
B8	IO/DIFFCLK_T12N/ DQ0T	O	Bit clock signal output to the audio DSP
B9	GND_B9	-	Ground terminal
B10	IO/VREFB7N0	O	Audio data output to the audio DSP
B11	IO_B11	O	L/R sampling clock signal output to the audio DSP
B12	GND_B12	-	Ground terminal
B13	IO/DIFFIO_T17P/ DQ0T	O	Not used
C1	GXB_TX1n	O	Not used
C2	GXB_TX1p	O	Not used
C3	VCCIO9_C3	-	Power supply terminal (+3.3V)
C4	nCE	I	Chip enable signal input terminal Not used
C5	IO/NSCO	O	Not used
C6	IO/VREFB8N0	O	Not used
C7	VCCIO8_C7	-	Power supply terminal (+3.3V)
C8	IO/DIFFCLK_T12P/ DQ0T	O	L/R sampling clock signal output to the audio DSP
C9, C10	VCCIO7_C9, VCCIO7_C10	-	Power supply terminal (+3.3V)
C11	IO/PUP4/DQ0T	O	Not used
C12	IO/PDN4/DQ0T	O	Not used
C13	IO/DiFFIO_T1BN/ DQ0T	O	Not used
D1, D2	GND_D1, GND_D2	-	Ground terminal
D3	VCCD_PLL_D3	-	Power supply terminal (+1.2V)
D4	VCCA_D4	-	Power supply terminal (+2.5V)
D5	nCONFIG	I	Configuration signal input from the MPU
D6	GND_D6	-	Ground terminal
D7	VCC_CLKIN8A	-	Power supply terminal (+2.5V)
D8	GND_D8	-	Ground terminal
D9	VCCA_D9	-	Power supply terminal (+2.5V)
D10	IO/DIFFIO_R4n/ DEV_CLRn	I	Reset signal input from the MPU "L": reset
D11	IO/DIFFIO_R2P	O	Chip select signal output to the D/A converter
D12	IO/DIFFIO_R2N	O	Serial data output to the D/A converter
D13	IO/DIFFIO_T1BP/ DQ0T	O	Interrupt signal output to the MPU

Pin No.	Pin Name	I/O	Description
E1	GXB_RX1p	O	Not used
E2	GXB_RX1n	O	Not used
E3	GND_E3	-	Ground terminal
E4	VCCINT_E4	-	Power supply terminal (+1.2V)
E5	GND_E5	-	Ground terminal
E6	CLK10/DIFFCLK_4n/ REFCLK1n	I	Reset signal input from the MPU "L": reset
E7	CLK11/DIFFCLK_4p/ REFCLK1p	I	50 MHz clock signal input terminal
E8	VCCINT_E8	-	Power supply terminal (+1.2V)
E9	GND_E9	-	Ground terminal
E10	IO/DIFFIO_R4P/ DM0R	O	Serial data transfer clock signal output to the D/A converter
E11	VCCIO6_E11	-	Power supply terminal (+3.3V)
E12	GND_E12	-	Ground terminal
E13	IO/VREFB6N0	O	Not used
F1, F2	GND_F1, GND_F2	-	Ground terminal
F3	VCCL_GXB_F3	-	Power supply terminal (+1.2V)
F4	GND_F4	-	Ground terminal
F5	VCCINT_F5	-	Power supply terminal (+1.2V)
F6	GND_F6	-	Ground terminal
F7	VCCINT_F7	-	Power supply terminal (+1.2V)
F8	GND_F8	-	Ground terminal
F9	IO_F9	O	Chip select signal output to the audio DSP
F10	IO/DIFFIO_R5P/ DQ0R	I	Serial data input from the audio DSP
F11	IO/DIFFIO_R5N/ DQ0R	O	Serial data output to the audio DSP
F12	CLK7/DIFFCLK_3P	I	Interrupt signal input from the audio DSP
F13	CLK6/DIFFCLK_3N	I	Busy signal input from the audio DSP
G1	GXB_TX0n	O	Receive data (negative) output to the FPGA
G2	GXB_TX0p	O	Receive data (positive) output to the FPGA
G3	VCCH_GXB	-	Power supply terminal (+2.5V)
G4	VCCINT_G4	-	Power supply terminal (+1.2V)
G5	GND_G5	-	Ground terminal
G6	VCCINT_G6	-	Power supply terminal (+1.2V)
G7	GND_G7	-	Ground terminal
G8	VCCINT_G8	-	Power supply terminal (+1.2V)
G9	IO/DIFFIO_R6P/ DQS0R/CQ0R/ DPCLK8	O	Serial data transfer clock signal output to the audio DSP
G10	IO/DIFFIO_R6N/ DEV_OE	O	Reset signal output to the audio DSP "L": reset
G11	VCCIO6_G11	-	Power supply terminal (+3.3V)
G12	GND_G12	-	Ground terminal
G13	CLK4/DIFFCLK_2N	I	5.6448 MHz clock or 6.144 MHz clock signal input terminal
H1, H2	GND_H1, GND_H2	-	Ground terminal
H3	VCCL_GXB_H3	-	Power supply terminal (+1.2V)
H4	GND_H4	-	Ground terminal
H5	VCCINT_H5	-	Power supply terminal (+1.2V)
H6	GND_H6	-	Ground terminal
H7	VCCINT_H7	-	Power supply terminal (+1.2V)
H8	GND_H8	-	Ground terminal
H9	VCCA_H9	-	Power supply terminal (+2.5V)
H10	IO/DIQS1R/CQ0R#/ DPCLK7	O	Power on/off control signal output terminal for the 22.5792 MHz clock "H": power on
H11	VCCIO5_H11	-	Power supply terminal (+3.3V)
H12	IO/VREFB5N0	O	Power on/off control signal output terminal for the 24.576 MHz clock "H": power on
H13	CLK5/DIFFCLK_2P	I	Not used
J1	GXB_RX0n	I	Transmit data (negative) input from the MPU
J2	GXB_RX0P	I	Transmit data (positive) input from the MPU

Pin No.	Pin Name	I/O	Description
J3	VCCA_GXB_J3	-	Power supply terminal (+2.5V)
J4	VCCD_PLL_J4	-	Power supply terminal (+1.2V)
J5	CONF_DONE	O	CONF_DONE signal output to the MPU
J6	CLK12/DIFFCLK_7p/ REFCLK0p	I	Clock signal (positive) input from the MPU
J7	CLK13/DIFFCLK_7n/ REFCLK0n	I	Clock signal (negative) input from the MPU
J8	VCCINT_J8	-	Power supply terminal (+1.2V)
J9	GND_J9	-	Ground terminal
J10	VCCD_PLL_J10	-	Power supply terminal (+1.2V)
J11	VCCIO5_J11	-	Power supply terminal (+3.3V)
J12	GND_J12	-	Ground terminal
J13	IO/DIFFIO_R9N/ DQ0R	O	Not used
K1, K2	GND_K1, GND_K2	-	Ground terminal
K3	GND_K3	-	Ground terminal
K4	VCCA_K4	-	Power supply terminal (+2.5V)
K5	MSEL0	I	Fixed at "L"
K6	nSTATUS	O	Status signal output to the MPU
K7	VCC_CLKIN3A	-	Power supply terminal (+2.5V)
K8	IO/VREFB4N0	O	Not used
K9	IO/DQ0B	O	Not used
K10	IO/PLL3_CLKOUTP	O	Not used
K11	IO/DIFFIO_R14P/ DQ0R	O	Reset signal output to the D/A converter "L": reset
K12	IO/DIFFIO_R14N/ DQ0R	O	Audio muting on/off control signal output terminal "L": muting on
K13	IO/DIFFIO_R9P/ DQ0R	O	L/R sampling clock signal output to the D/A converter
L1	RREF0	I	External reference resistor connection terminal
L2	GND_L2	-	Ground terminal
L3	MSEL2	I	Fixed at "H"
L4	IO/PLL1_CLKOUTP	O	Not used
L5	IO/DQS1B/CQ0B#/ DPCLK2	O	Not used
L6	VCCIO3	-	Power supply terminal (+3.3V)
L7	IO/VREFB3N0	O	Not used
L8	VCCIO4_L8	-	Power supply terminal (+3.3V)
L9	IO/DIFFIO_B19P/ DQ0B	O	Not used
L10	VCCIO4_L10	-	Power supply terminal (+3.3V)
L11	IO/PLL3_CLKOUTN	O	Not used
L12	IO/DIFFIO_R13P/ DQ0R	O	Clock selection signal output terminal
L13	IO/DIFFIO_R13N/ DQ0R	O	Audio data output to the D/A converter
M1	GND_M1	-	Ground terminal
M2	VCCA_GXB_M2	-	Power supply terminal (+2.5V)
M3	NC_M3	O	Not used
M4	IO/PLL1_CLKOUTN	O	Not used
M5	GND_M5	-	Ground terminal
M6	IO/DIFFIO_B3p/ INIT_DONE	O	INIT_DONE signal output to the MPU
M7	CLK14/DIFFCLK_6P	I	Not used
M8	GND_M8	-	Ground terminal
M9	IO/DIFFIO_B19N/ DQS0B/CQ0B/ DPCLK5	O	Not used
M10	GND_M10	-	Ground terminal
M11	IO/RUP2/DQ0B	O	Not used
M12	GND_M12	-	Ground terminal
M13	IO/RDN3	O	Not used

# HAP-S1

Pin No.	Pin Name	I/O	Description
N1	VCCL_GXB_N1	-	Power supply terminal (+1.2V)
N2	NC_N2	O	Not used
N3	MSEL1	I	Fixed at "L"
N4	IO/DIFFIO_B1P/ CRC_ERROR	O	Not used
N5	IO/DIFFIO_B1N/ NCEO	O	Not used
N6	IO/DIFFIO_B3N/ DQ0B	O	Not used
N7	CLK15/DIFFCLK_6N	I	Not used
N8	IO/DIFFIO_B12P/ DQ0B	O	Not used
N9	IO/DIFFIO_B12N/ DQ0B	O	Not used
N10	IO/DIFFIO_B21P/ DQ0B	O	Not used
N11	IO/DIFFIO_B21N/ DQ0B	O	Not used
N12	IO/RDN2/DM0B	O	Not used
N13	IO/RUP3	O	Bit clock signal output to the D/A converter

## FPGA DSP BOARD IC702 CS48L10-CNZR (AUDIO DSP)

Pin No.	Pin Name	I/O	Description
1	CLOCK	I	6 MHz clock signal input terminal
2	VPLL	-	Power supply terminal for the PLL (+1.2V)
3	GND_3	-	Ground terminal
4	VD_4	-	Power supply terminal for the digital core and memory (+1.2V)
5	VL_5	-	Power supply terminal for the digital interface (+3.3V)
6	CLK/SCL	I	Serial data transfer clock signal input from the FPGA
7	nCS	I	Chip select signal input from the FPGA
8	MISO/SDA	O	Serial data output to the FPGA
9	MOSI	I	Serial data input from the FPGA
10	nBUSY/HS0/ nEE_CS	O	Busy signal output to the FPGA
11	nINT/HS1	O	Interrupt signal output to the FPGA
12	nRESET	I	Reset signal input from the FPGA "L": reset
13	DBCK	-	Not used
14	VL_14	-	Power supply terminal for the digital interface (+3.3V)
15	GND_15	-	Ground terminal
16	VD_16	-	Power supply terminal for the digital core and memory (+1.2V)
17	DBDA	-	Not used
18	MCLK	I	Master clock signal input terminal Not used
19	DAO_D1	O	Audio data output to the FPGA
20	DAO_LRCLK	I	L/R sampling clock signal input from the FPGA
21	DAO_SCLK	I	Bit clock signal input from the FPGA
22	DAI_D1	I	Audio data input from the FPGA
23	DAI_LRCLK	I	L/R sampling clock signal input from the FPGA
24	DAI_SCLK	I	Bit clock signal input from the FPGA

## U-COM BOARD IC5006 MB9AF156NPMC-G-JNE2 (SYSTEM CONTROLLER)

Pin No.	Pin Name	I/O	Description
1	VCC	-	Power supply terminal (+3.3V)
2	HP DETECT	I	Headphone insert detection signal input terminal "L": headphone is inserted
3	HP RELAY	O	Relay drive signal (for headphone) output terminal "H": relay on
4	SPK RELAY	O	Relay drive signal (for speaker) output terminal "H": relay on
5	PROTECT	I	Protect detection signal input terminal "L": protect is detected
6	COM DATA	O	Serial data output to the electrical volume
7	COM CLK	O	Serial data transfer clock signal output to the electrical volume
8	CS	O	Chip select signal output to the electrical volume
9	AMUTE	O	Audio muting on/off control signal output terminal "L": muting on
10	POWER_RY	O	Relay drive signal (for main power) output terminal "H": relay on
11	AC_STOP_STBY	I	AC cut detection signal (for sub power) input terminal "H": AC cut is detected
12	AC_STOP_MAIN	I	AC cut detection signal (for main power) input terminal "H": AC cut is detected
13	DCDC_EN	O	DC/DC converter on/off control signal output terminal for the hard disk drive and VBUS power "H": DC/DC converter on
14	NC	-	Not used
15	DIR_REG_EN	O	Regulator on/off control signal output terminal for the digital circuit "H": Regulator on
16	DIR_SEL	O	Audio selection signal output terminal "L": FPGA audio, "H": digital audio interface receiver audio
17	NC	-	Not used
18	DIR_ST_DATA	I	Audio data input from the digital audio interface receiver
19	DIR_INT	I	Interrupt signal input from the digital audio interface receiver
20	DIR_NPCLM	I	No-LPCM signal input from the digital audio interface receiver
21 to 24	NC	-	Not used
25	VSS	-	Ground terminal
26	VCC	-	Power supply terminal (+3.3V)
27	DIR_MISO	I	Serial data input from the digital audio interface receiver
28	DIR_MOSI	O	Serial data output to the digital audio interface receiver
29	DIR_SCK	O	Serial data transfer clock signal output to the digital audio interface receiver
30	DIR_CE	O	Chip enable signal output to the digital audio interface receiver
31	DIR_ERROR	I	Error signal input from the digital audio interface receiver "L": error
32	DIR_CKST	I	Data muting on/off control signal input from the digital audio interface receiver "L": muting on
33	C	-	Regulator stabilization capacitor connection terminal
34	VSS	-	Ground terminal
35	VCC	-	Power supply terminal (+3.3V)
36	DIR_RESET	O	Reset signal output to the digital audio interface receiver "L": reset
37	POWER_EN	O	Power on/off control signal output terminal for the MPU power "H": power on
38	SYS RESET	I	System reset signal input from the MPU and reset signal generator "L": reset For several hundreds msec. after the power supply rises, "L" is input, then it change to "H"
39	UART MPU/SYS	I	Serial data input from the MPU
40	UART SYS/MPU	O	Serial data output to the MPU
41	MPU RESET	O	Reset signal output to the MPU "L": reset
42 to 45	NC	-	Not used
46	MD1	I	Fixed at "L"
47	MD0	I	Update signal input from the MPU "H": update
48	XTALO	O	System clock output terminal (4 MHz)
49	XTALI	I	System clock input terminal (4 MHz)
50	VSS	-	Ground terminal
51	VCC	-	Power supply terminal (+3.3V)
52	VOL JOG+	I	Jog dial pulse (positive) input from the rotary encoder (for VOLUME)
53	VOL JOG-	I	Jog dial pulse (negative) input from the rotary encoder (for VOLUME)
54	SEL JOG+	I	Jog dial pulse (positive) input from the rotary encoder (for selector)
55	SEL JOG-	I	Jog dial pulse (negative) input from the rotary encoder (for selector)
56	DSEE LED	O	LED drive signal output terminal for the DSEE indicator "H": LED on
57	NC	-	Not used
58	AD KEY1	I	BACK and ENTER key input terminal (A/D input)
59	AD KEY2	I	HOME key input terminal (A/D input)
60	AVCC	-	Power supply terminal (+3.3V)
61	AVRH	I	Reference voltage (+3.3V) input terminal

Pin No.	Pin Name	I/O	Description
62	AVSS	-	Ground terminal
63	PWR LED GRN	O	LED drive signal output terminal for the power indicator "H": LED on
64	NC	-	Not used
65	SIRCS IN	I	SIRCS signal input from the remote control receiver
66	PLAY KEY	I	Play key input terminal (A/D input)
67	POWER KEY	I	Power key input terminal (A/D input)
68	MODEL	I	Model setting terminal Fixed at "L" in this unit
69	DST	I	Destination setting terminal Fixed at "L"
70	A_LEVEL_DET	I	Speaker level detection signal input terminal
71	PROG SCK	O	Program clock signal output terminal
72	PROG SYS/JIG	O	Program data output to the MPU
73	PROG JIG/SYS	I	Program data input from the MPU
74	NC	-	Not used
75	VSS	-	Ground terminal
76	VCC	-	Power supply terminal (+3.3V)
77	NC	-	Not used
78	TCK	I	Clock signal input terminal for the JTAG
79	TMS	O	Mode selection signal output terminal for the JTAG
80	TDO	O	Data output terminal for the JTAG
81	TDI	I	Data input terminal for the JTAG
82 to 84	NC	-	Not used
85	AMP_TEMP1	I	Temperature sensor input terminal
86, 87	TEST1, TEST2	-	Not used
88	STBY_EN	O	Power cut on/off control signal output terminal for the sub power "H": sub power cut on
89	FAN_EN	O	Fan motor on/off control signal output terminal "H": fan motor on
90	FAN_SLOW/FAST	O	Fan motor speed selection signal output terminal "L": slow, "H": fast
91	TEST3	-	Not used
92	LINE_RY	O	Line muting on/off control signal output terminal "L": muting on
93	NC	-	Not used
94	E2P SCL	O	Serial data transfer clock signal output to the EEPROM
95	E2P SDA	I/O	Two-way data bus the EEPROM
96	A_SEL1	O	Analog audio selection signal output terminal "L": D/A converter audio, "H": LINE IN audio
97	VCC	-	Power supply terminal (+3.3V)
98	A_SEL2	O	Analog audio selection signal output terminal "L":LINE IN 1 audio, "H": LINE IN 2 audio
99	NC	-	Not used
100	VSS	-	Ground terminal

## SECTION 6 EXPLODED VIEWS

**Note:**

- -XX and -X mean standardized parts, so they may have some difference from the original one.
- Items marked “\*” are not stocked since they are seldom required for routine service. Some delay should be anticipated when ordering these items.
- The mechanical parts with no reference number in the exploded views are not supplied.

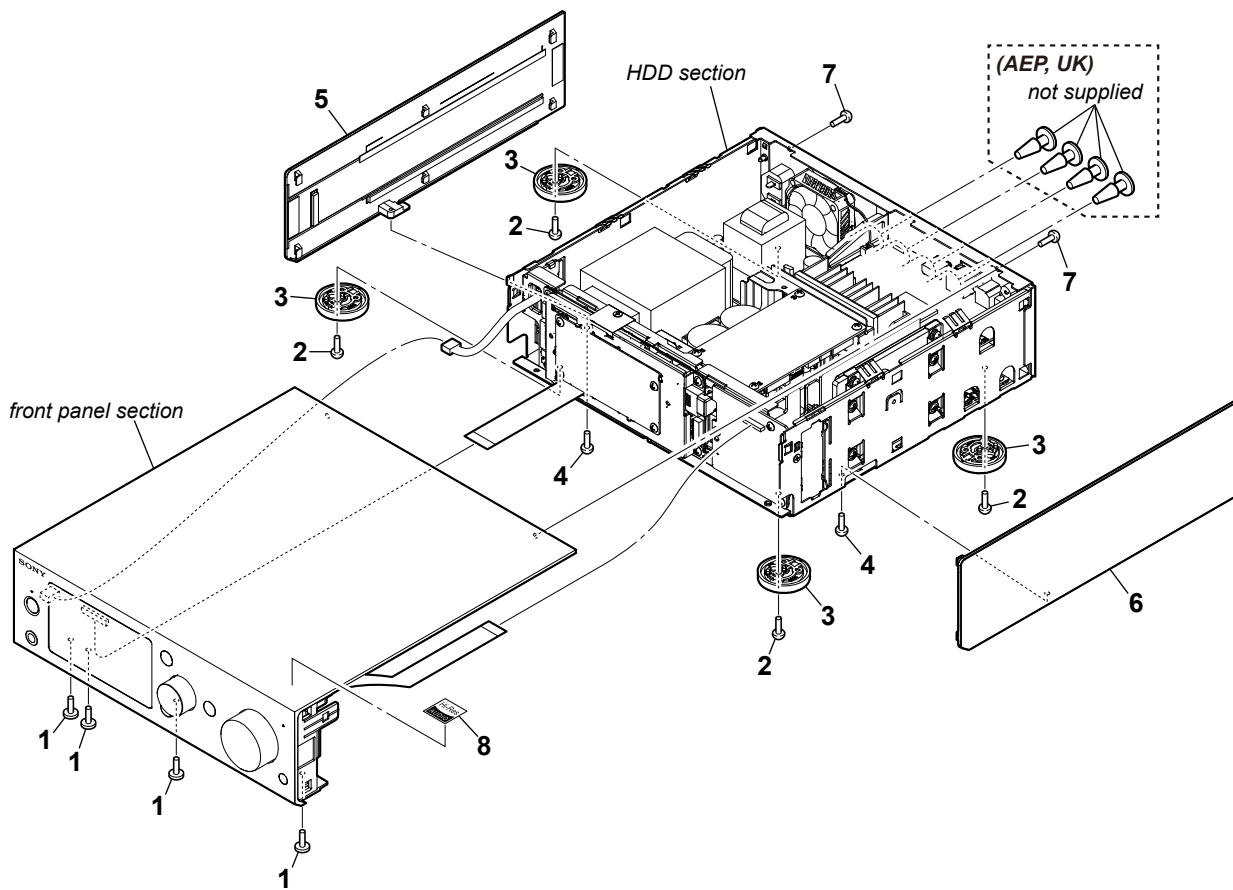
- Color Indication of Appearance Parts Example:  
 KNOB, BALANCE (WHITE) . . . (RED)  
↑            ↑  
 Parts Color   Cabinet's Color
- Abbreviation  
 CND : Canadian model
- Color variations  
 Silver, Black

The components identified by mark △ or dotted line with mark △ are critical for safety.  
 Replace only with part number specified.

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Les composants identifiés par une marque △ sont critiques pour la sécurité.  
 Ne les remplacer que par une pièce portant le numéro spécifié.

### 6-1. SIDE PANEL SECTION



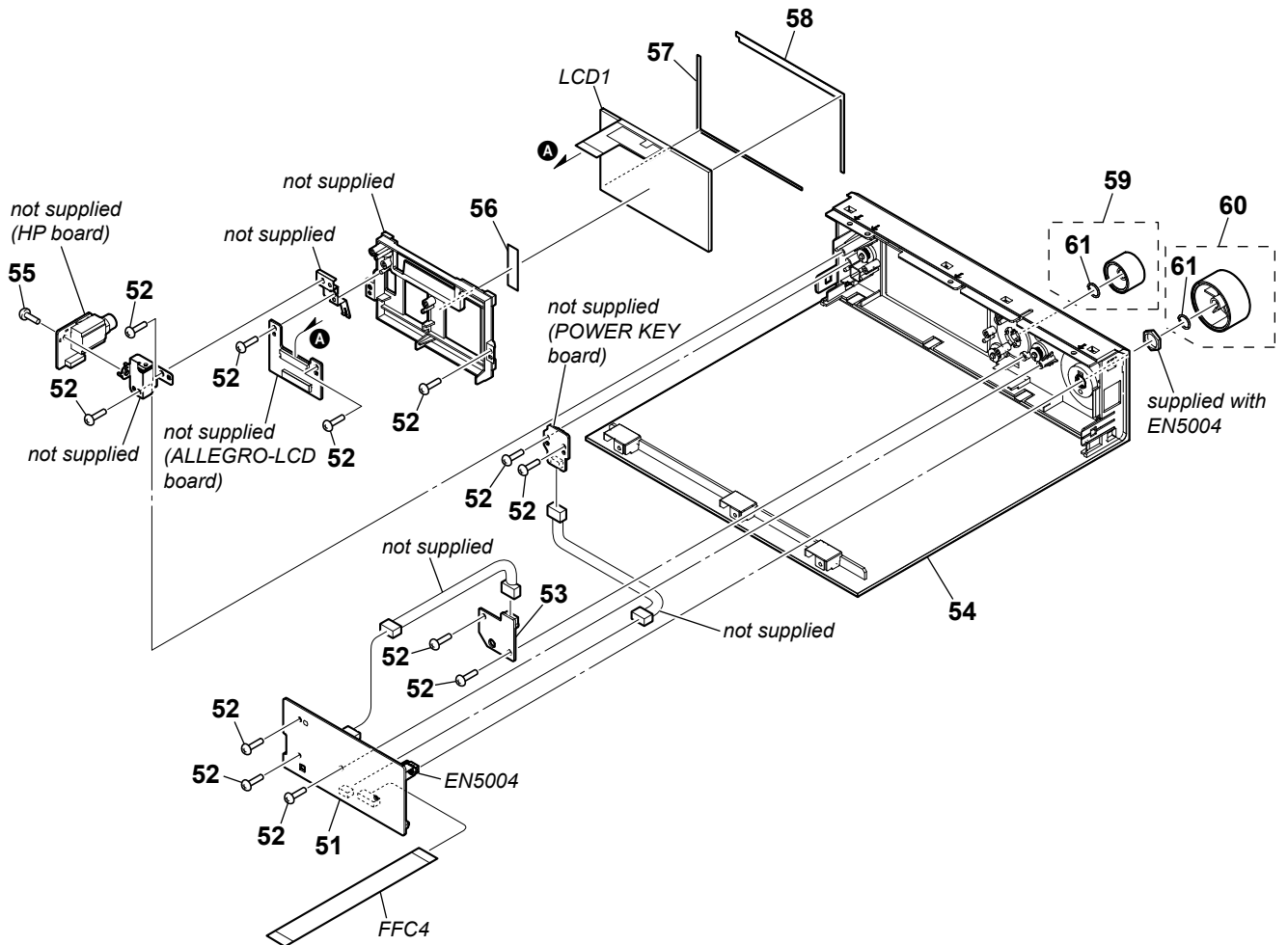
Ref. No.	Part No.	Description	Remark
1	4-227-843-03	SCREW (TP), FLAT HEAD (for BLACK)	
1	4-227-843-31	SCREW (TP), FLAT HEAD (for SILVER)	
2	3-077-331-62	+BV3 (3-CR)	
3	X-2587-364-1	FOOT ASSY (ALG)	
4	4-474-331-01	FLAT SCREW	
5	X-2587-441-1	SIDE PANEL ASSY (L) (for L-ch) (SILVER)	

Ref. No.	Part No.	Description	Remark
5	X-2588-154-1	SIDE PANEL ASSY (L-B) (for L-ch) (BLACK)	
6	X-2587-442-1	SIDE PANEL ASSY (R) (for R-ch) (SILVER)	
6	X-2588-155-1	SIDE PANEL ASSY (R-B) (for R-ch) (BLACK)	
7	3-077-331-41	+BV3 (3-CR)	
8	4-477-465-31	HI-RES LABEL	



6-2. FRONT PANEL SECTION

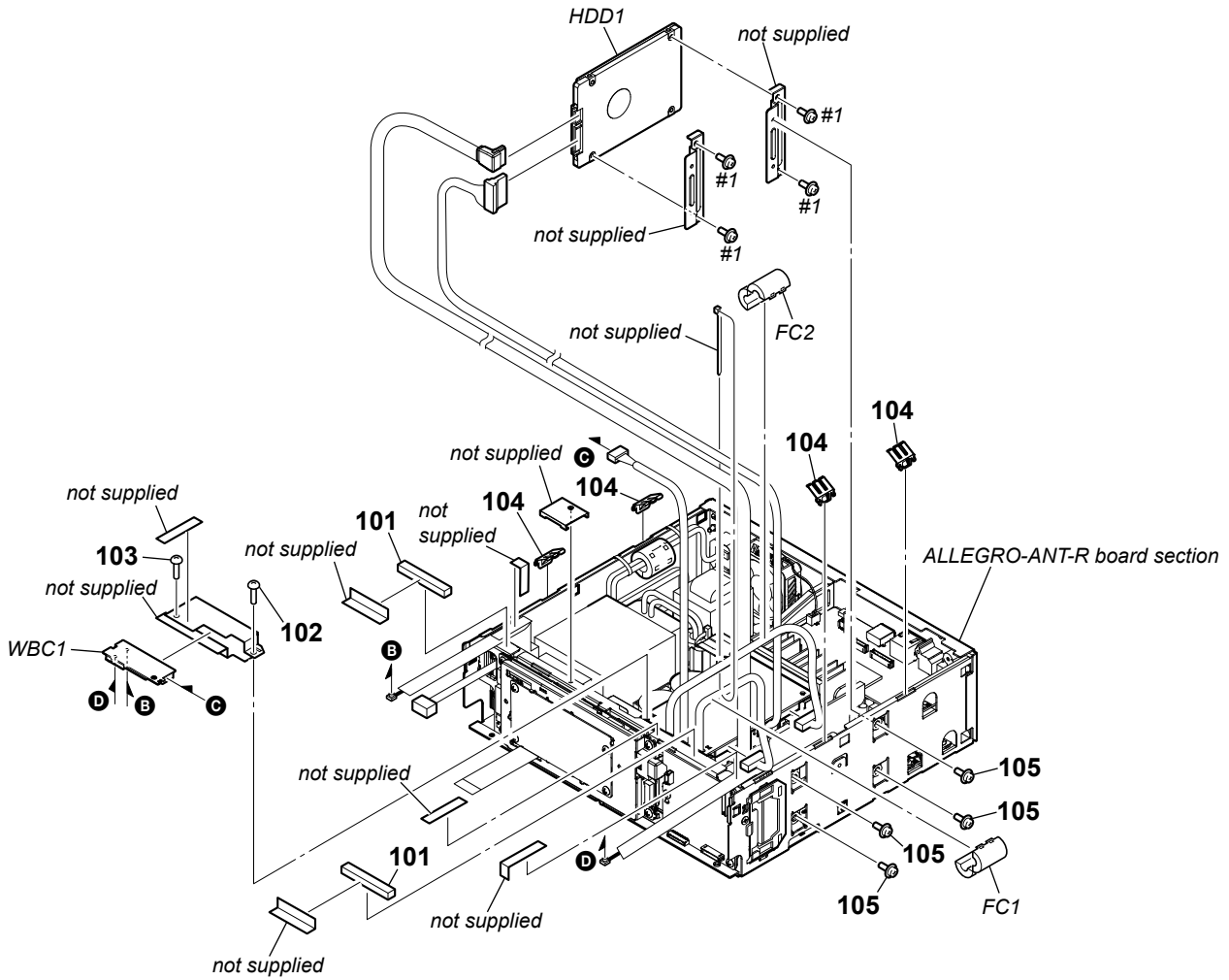
- Rear bottom view



**Note:** Wires (flat type) for service is straight.  
When replacing wire (flat type), install it after bending it in the same form as that before replacement.

Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
51	A-1945-086-A	KEY JOG BOARD, COMPLETE		59	X-2587-366-2	SEL KNOB ASSY (SILVER)	
52	3-087-053-01	+BVTP2.6 (3CR)		59	X-2588-152-2	SEL KNOB ASSY (B) (BLACK)	
53	A-1974-810-A	PENC BOARD, COMPLETE		60	X-2587-365-1	VOL KNOB ASSY (SILVER)	
54	X-2587-367-2	FRONT PANEL ASSY (ALG) (SILVER)		60	X-2588-151-1	VOL KNOB ASSY (B) (BLACK)	
54	X-2588-153-2	FRONT PANEL ASSY (ALG-B) (BLACK)		61	3-350-426-01	SPRING, RING	
55	3-077-331-62	+BV3 (3-CR)		EN5004	1-418-725-41	ENCODER, ROTARY (12 TYPE) (VOLUME)	
56	4-420-224-01	ADHESIVE, A		FFC4	1-828-002-51	WIRE (FLAT TYPE) (17 CORE) (See Note)	
57	4-464-775-01	CUSHION, LCD (A)		LCD1	1-811-873-11	PANEL, LCD	
58	4-464-776-01	CUSHION, LCD (B)					

6-3. HDD SECTION

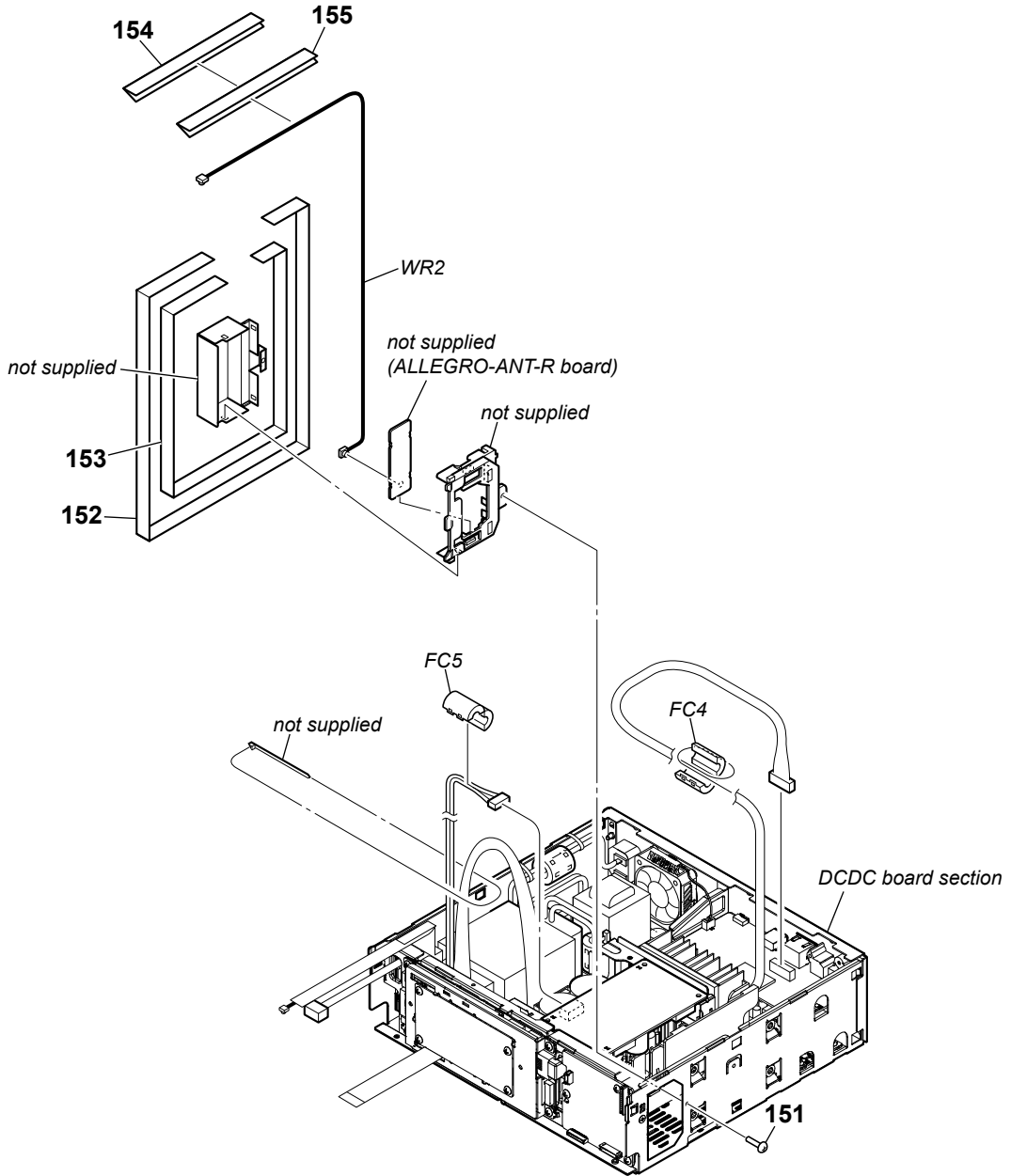


**Note 1:** When the WLAN/BT COMBO card (Ref. No. WBC1) is replaced, refer to “CHECKING METHOD OF NETWORK CONNECTION” on page 5.

**Note 2:** When the hard disk drive (Ref. No. HDD1) is replaced, refer to “NOTE OF REPLACING THE HARD DISK DRIVE (Ref. No. HDD1)” on page 4.

Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
101	4-486-366-01	GASKET (6X6)		FC2	1-481-528-11	FILTER, CLAMP (FERRITE CORE)	
102	3-077-331-62	+BV3 (3-CR)		△ HDD1	1-458-715-11	HDD/TSB-AQUARIUS-SLIM (500GB) (Hard Disk Drive) (See Note 2)	
103	4-474-331-01	FLAT SCREW		WBC1	1-458-601-31	CARD, WLAN/BT COMBO (See Note 1)	
104	4-469-024-01	GND PLATE (AL)		#1	7-682-946-09	SCREW +PSW 3X5	
105	4-467-898-01	STEP SCREW					
FC1	1-481-528-11	FILTER, CLAMP (FERRITE CORE)					

6-4. ALLEGRO-ANT-R BOARD SECTION

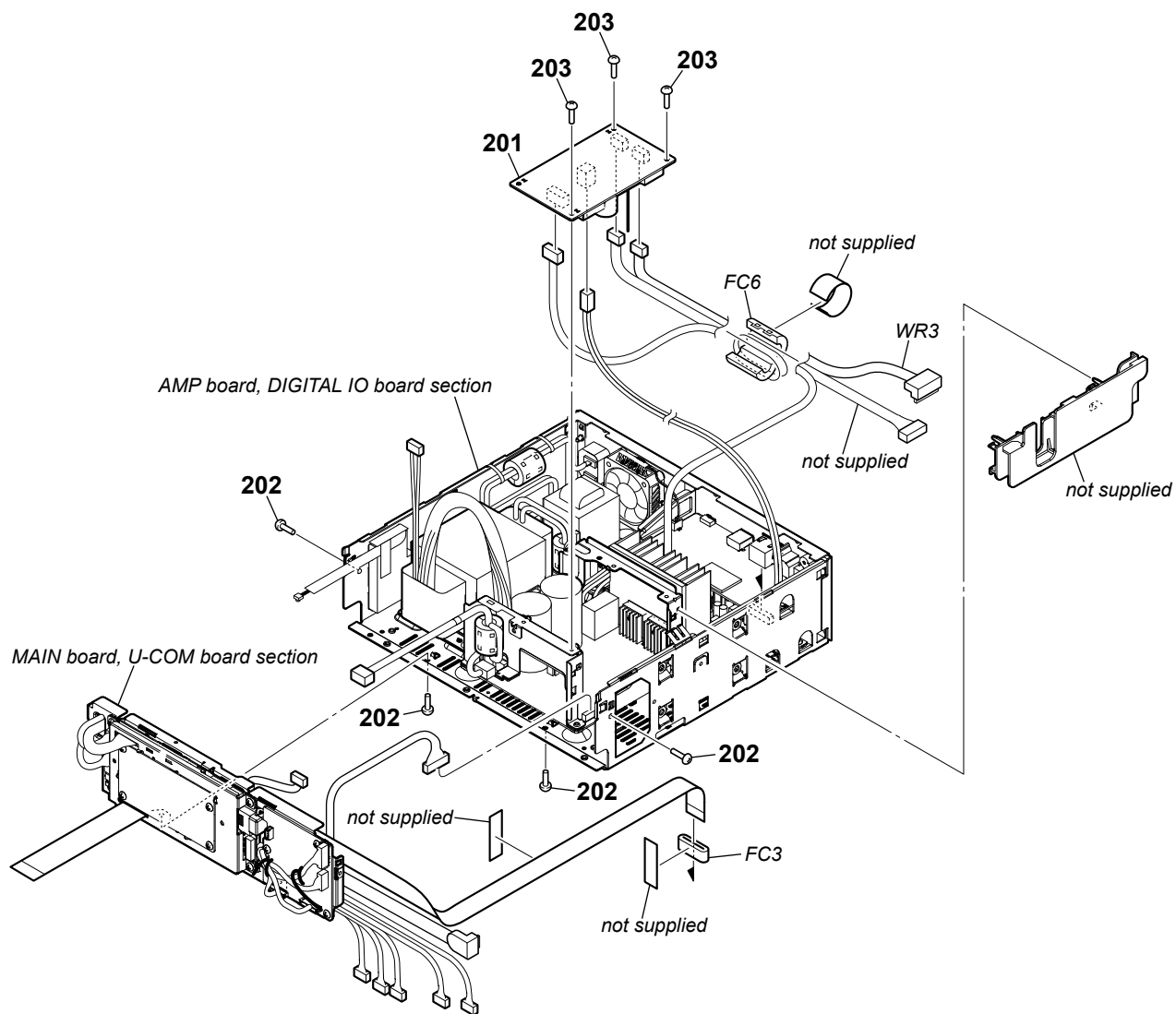


**Note:** When the coaxial (U.FL connector) cable (Ref. No. WR2) is replaced, refer to “CHECKING METHOD OF NETWORK CONNECTION” on page 5.

Ref. No.	Part No.	Description	Remark
151	4-474-331-01	FLAT SCREW	
152	4-485-976-01	TAPE (WA-L)	
153	4-484-735-01	SHEET (WA-L)	
154	4-485-977-01	TAPE (WA-M) (for R-ch coaxial cable)	
155	4-485-586-01	SHEET (WA-M) (for R-ch coaxial cable)	

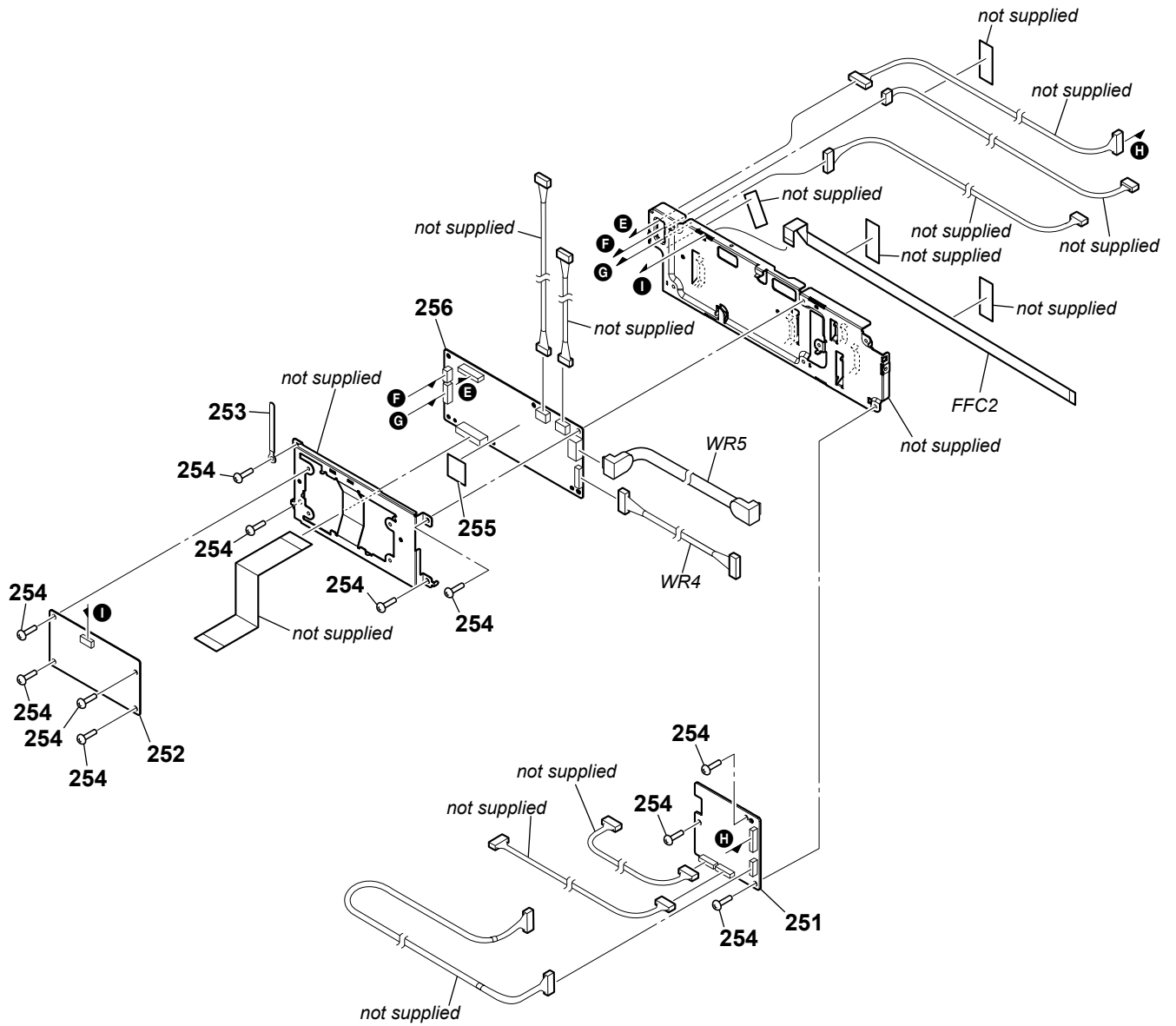
Ref. No.	Part No.	Description	Remark
FC4	1-500-386-11	FILTER, CLAMP (FERRITE CORE)	
FC5	1-481-528-11	FILTER, CLAMP (FERRITE CORE)	
WR2	1-846-781-11	CABLE, COAXIAL (U.FL CONNECTOR) (for R-ch)	(See Note)

## 6-5. DCDC BOARD SECTION



Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
201	A-1945-082-A	DCDC BOARD, COMPLETE		FC6	1-500-082-11	CLAMP, SLEEVE FERRITE	
202	4-474-331-01	FLAT SCREW		WR3	1-969-717-11	HARNESS (S-003)	
203	3-077-331-62	+BV3 (3-CR)					
FC3	1-400-640-11	CORE, FERRITE					

6-6. MAIN BOARD, U-COM BOARD SECTION



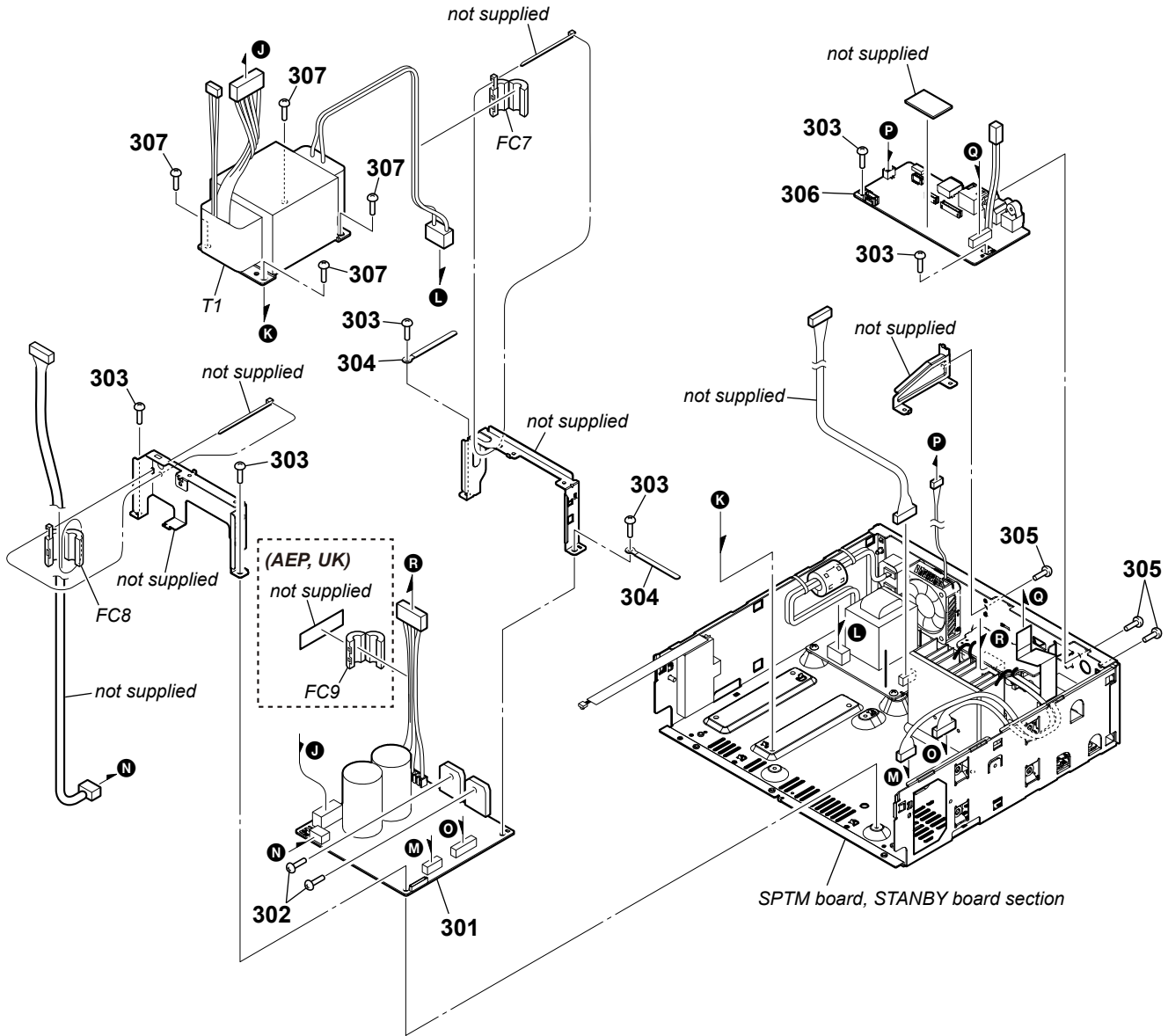
**Note 1:** When the complete MAIN board is replaced, refer to “NOTE OF REPLACING THE COMPLETE MAIN BOARD” and “CHECKING METHOD OF NETWORK CONNECTION” on page 5.

**Note 2:** Wires (flat type) for service is straight. When replacing wire (flat type), install it after bending it in the same form as that before replacement.

Ref. No.	Part No.	Description	Remark
251	A-1945-088-A	U-COM BOARD, COMPLETE	
252	A-1945-063-A	FPGA DSP BOARD, COMPLETE	
* 253	3-703-150-11	CLAMP	
254	3-077-331-62	+BV3 (3-CR)	
255	4-478-826-01	SHEET RADIATION (20)	
256	A-1989-167-A	MAIN BOARD, COMPLETE (for SERVICE) (US, CND) (See Note 1)	

Ref. No.	Part No.	Description	Remark
256	A-1989-168-A	MAIN BOARD, COMPLETE (for SERVICE) (AEP, UK) (See Note 1)	
FFC2	1-828-774-51	WIRE (FLAT TYPE) (24 CORE) (See Note 2)	
WR4	1-969-719-11	HARNESS (E-001)	
WR5	1-969-715-11	HARNESS (S-001)	

6-7. AMP BOARD, DIGITAL IO BOARD SECTION

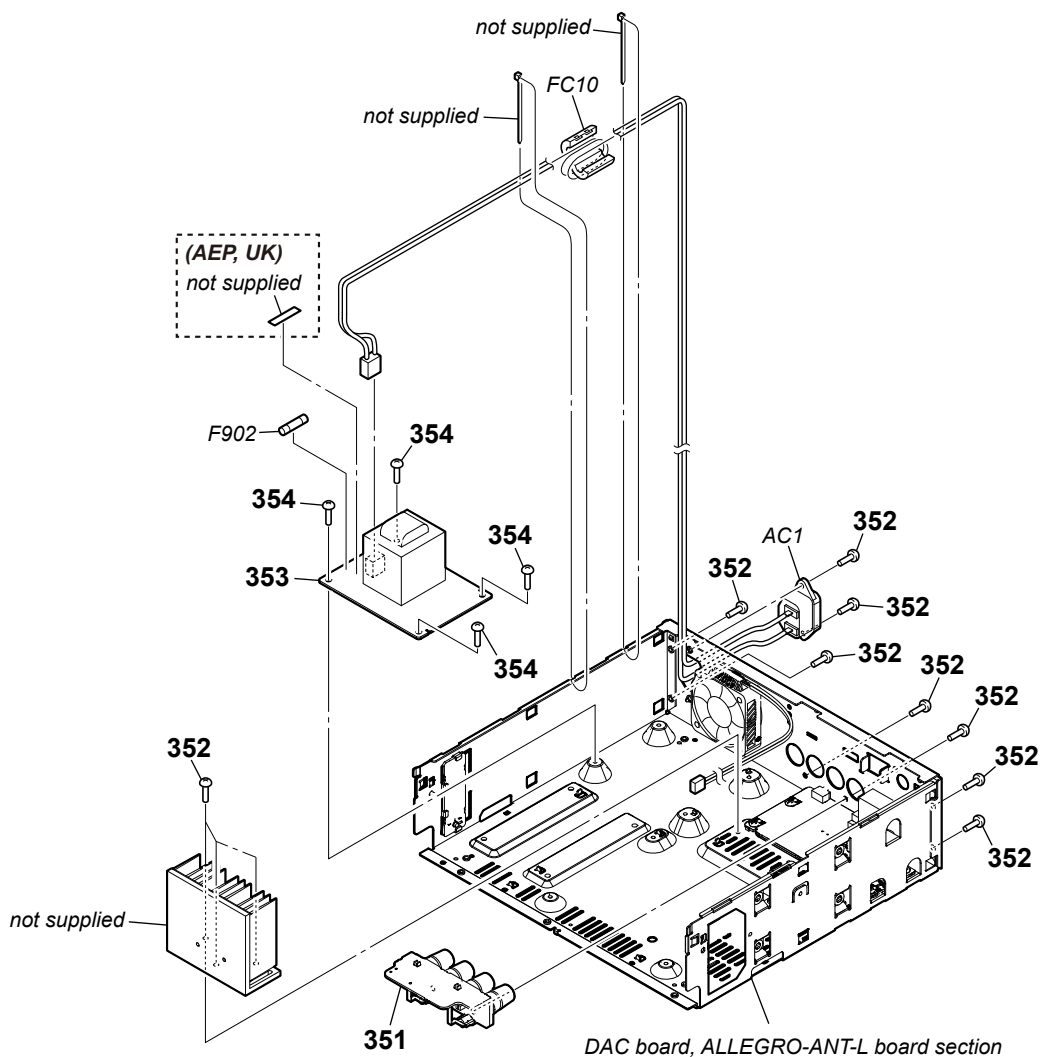


**Note:** When the complete AMP board is replaced, refer to “NOTE OF REPLACING THE D218, IC350 AND IC351 ON THE AMP BOARD AND THE COMPLETE AMP BOARD” on page 4.

Ref. No.	Part No.	Description	Remark
301	A-1945-071-A	AMP BOARD, COMPLETE (AEP, UK) (See Note)	
301	A-1945-072-A	AMP BOARD, COMPLETE (US, CND) (See Note)	
302	3-905-609-01	SCREW (TRANSISTOR)	
303	3-077-331-62	+BV3 (3-CR)	
* 304	3-703-150-11	CLAMP	
305	3-077-331-41	+BV3 (3-CR)	
306	A-1945-092-A	DIGITAL IO BOARD, COMPLETE	

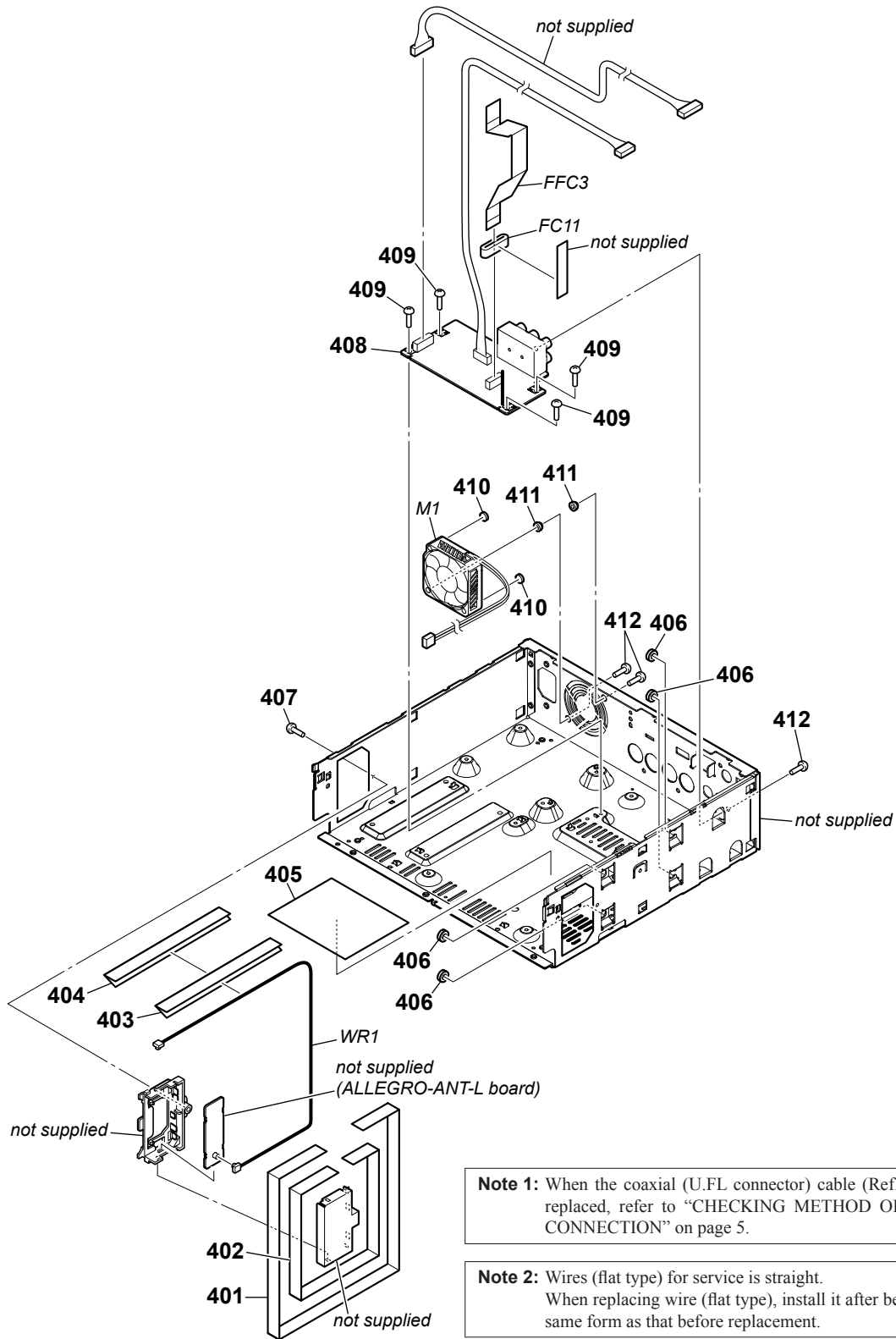
Ref. No.	Part No.	Description	Remark
307	4-249-675-02	+BV SUMITITE S 4X6 ROUND	
FC7	1-500-386-11	FILTER, CLAMP (FERRITE CORE)	
FC8	1-500-082-11	CLAMP, SLEEVE FERRITE	
FC9	1-500-082-11	CLAMP, SLEEVE FERRITE (AEP, UK)	
△ T1	1-697-296-11	TRANSFORMER, POWER (US, CND)	
△ T1	1-697-304-11	TRANSFORMER, POWER (AEP, UK)	

6-8. SPTM BOARD, STANBY BOARD SECTION



Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
351	A-1945-077-A	SPTM BOARD, COMPLETE (AEP, UK)		354	3-077-331-62	+BV3 (3-CR)	
351	A-1945-078-A	SPTM BOARD, COMPLETE (US, CND)		△ AC1	1-821-082-21	INLET, AC 2P	
352	3-077-331-41	+BV3 (3-CR)		△ F902	1-532-388-33	FUSE (T 2 AL/250 V) (AEP, UK)	
353	A-1945-084-A	STANBY BOARD, COMPLETE (AEP, UK)		△ F902	1-532-504-33	FUSE (T 4 AL/250 V) (US, CND)	
353	A-1945-085-A	STANBY BOARD, COMPLETE (US, CND)		FC10	1-500-386-11	FILTER, CLAMP (FERRITE CORE)	

6-9. DAC BOARD, ALLEGRO-ANT-L BOARD SECTION



Ref. No.	Part No.	Description	Remark
401	4-485-976-01	TAPE (WA-L)	
402	4-484-735-01	SHEET (WA-L)	
403	4-484-736-01	SHEET (WA-S) (for L-ch coaxial cable)	
404	4-485-978-01	TAPE (WA-S) (for L-ch coaxial cable)	
405	4-485-979-01	SHEET (AMP)	
406	4-467-899-01	DAMPER (HDD)	
407	4-474-331-01	FLAT SCREW	
408	A-1945-074-A	DAC BOARD, COMPLETE (AEP, UK)	
408	A-1945-075-A	DAC BOARD, COMPLETE (US, CND)	
409	3-077-331-62	+BV3 (3-CR)	

Ref. No.	Part No.	Description	Remark
410	4-471-459-01	CUSHION_F	
411	4-468-810-01	BUSH (FAN)	
412	3-077-331-41	+BV3 (3-CR)	
FC11	1-400-640-11	CORE, FERRITE	
FFC3	1-828-760-51	WIRE (FLAT TYPE) (22 CORE) (See Note 2)	
△ M1	1-855-324-11	DC FAN	
WR1	1-846-782-11	CABLE, COAXIAL (U.FL CONNECTOR) (for L-ch)	(See Note 1)



## SECTION 7 ELECTRICAL PARTS LIST

ALLEGRO-ANT-L

ALLEGRO-ANT-R

ALLEGRO-LCD

AMP

**Note:**

- Due to standardization, replacements in the parts list may be different from the parts specified in the diagrams or the components used on the set.
- -XX and -X mean standardized parts, so they may have some difference from the original one.
- Items marked "\*" are not stocked since they are seldom required for routine service. Some delay should be anticipated when ordering these items.
- RESISTORS  
All resistors are in ohms.  
METAL: Metal-film resistor.  
METAL OXIDE: Metal oxide-film resistor.  
F: nonflammable
- CAPACITORS  
uF:  $\mu$ F  
uH:  $\mu$ H
- COILS  
uH:  $\mu$ H
- SEMICONDUCTORS  
In each case, u:  $\mu$ , for example:  
uA. . . :  $\mu$ A. . . , uPA. . . ,  $\mu$ PA. . . ,  
uPB. . . :  $\mu$ PB. . . , uPC. . . ,  $\mu$ PC. . . ,  
uPD. . . :  $\mu$ PD. . .
- Abbreviation  
CND : Canadian model

When indicating parts by reference number, please include the board name.

The components identified by mark  $\triangle$  or dotted line with mark  $\triangle$  are critical for safety.  
Replace only with part number specified.

Les composants identifiés par une marque  $\triangle$  sont critiques pour la sécurité.  
Ne les remplacer que par une pièce portant le numéro spécifié.

Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
		ALLEGRO-ANT-L BOARD *****		C228	1-136-165-00	FILM 0.1uF 5%	50V
				C229	1-136-165-00	FILM 0.1uF 5%	50V
				C230	1-100-155-91	CERAMIC CHIP 470PF 5%	100V
				C231	1-100-155-91	CERAMIC CHIP 470PF 5%	100V
				C236	1-124-721-11	ELECT 10uF 20%	50V
The ALLEGRO-ANT-L board is not covered in the servicing. *****							
		ALLEGRO-ANT-R BOARD *****		C237	1-124-721-11	ELECT 10uF 20%	50V
				C240	1-118-647-11	ELECT (BLOCK) 6800uF 20%	50V
				C241	1-118-647-11	ELECT (BLOCK) 6800uF 20%	50V
				C242	1-126-964-11	ELECT 10uF 20%	50V
				C243	1-126-964-11	ELECT 10uF 20%	50V
The ALLEGRO-ANT-R board is not covered in the servicing. *****							
		ALLEGRO-LCD BOARD *****		C244	1-116-717-11	CERAMIC CHIP 10uF 20%	10V
				C245	1-116-717-11	CERAMIC CHIP 10uF 20%	10V
		< CAPACITOR >		C246	1-126-961-11	ELECT 2.2uF 20%	50V
				C251	1-124-748-11	ELECT 22uF 20%	100V
				C252	1-124-748-11	ELECT 22uF 20%	100V
C004	1-118-386-11	CERAMIC CHIP 0.1uF 10%	16V	C256	1-124-748-11	ELECT 22uF 20%	100V
		< CONNECTOR >		C257	1-124-748-11	ELECT 22uF 20%	100V
CN001	1-815-231-61	CONNECTOR, FFC/FPC (ZIF) 40P		C261	1-112-083-11	ELECT 100uF 20%	16V
CN002	1-843-774-81	CONNECTOR, FFC/FPC (ZIF) 40P		C262	1-112-083-11	ELECT 100uF 20%	16V
		< RESISTOR >		C269	1-112-100-11	ELECT 10uF 20%	50V
R003	1-218-929-11	METAL CHIP 10 5%	1/16W	C270	1-124-721-11	ELECT 10uF 20%	50V
*****				C271	1-124-721-11	ELECT 10uF 20%	50V
	A-1945-071-A	AMP BOARD, COMPLETE (AEP, UK) (See Note)		C272	1-127-947-21	FILM CHIP 0.0033uF 5%	16V
	A-1945-072-A	AMP BOARD, COMPLETE (US, CND) (See Note)		C273	1-127-947-21	FILM CHIP 0.0033uF 5%	16V
		*****		C274	1-136-165-00	FILM 0.1uF 5%	50V
	3-077-331-41	+BV3 (3-CR)		C275	1-136-165-00	FILM 0.1uF 5%	50V
		< CAPACITOR >		C276	1-112-099-11	ELECT 4.7uF 20%	50V
C200	1-116-707-11	CERAMIC CHIP 47uF 20%	10V	C277	1-112-099-11	ELECT 4.7uF 20%	50V
C201	1-118-044-11	CERAMIC CHIP 1uF 10%	50V	C350	1-124-748-11	ELECT 22uF 20%	100V
C202	1-118-044-11	CERAMIC CHIP 1uF 10%	50V	C351	1-124-699-11	ELECT 220uF 20%	25V
C205	1-112-092-11	ELECT 1000uF 20%	25V	C352	1-136-165-00	FILM 0.1uF 5%	50V
C206	1-112-092-11	ELECT 1000uF 20%	25V	C353	1-136-165-00	FILM 0.1uF 5%	50V
C207	1-162-927-11	CERAMIC CHIP 100PF 5%	50V	C354	1-124-748-11	ELECT 22uF 20%	100V
C208	1-162-927-11	CERAMIC CHIP 100PF 5%	50V	C355	1-124-699-11	ELECT 220uF 20%	25V
C212	1-118-290-11	CERAMIC CHIP 0.001uF 10%	50V	C356	1-136-165-00	FILM 0.1uF 5%	50V
C213	1-126-940-11	ELECT 330uF 20%	25V	C357	1-136-165-00	FILM 0.1uF 5%	50V
C214	1-118-347-11	CERAMIC CHIP 0.1uF 10%	25V	C358	1-116-713-11	CERAMIC CHIP 22uF 20%	10V
C216	1-116-299-91	CERAMIC CHIP 220PF 1%	50V	C359	1-118-290-11	CERAMIC CHIP 0.001uF 10%	50V
C217	1-116-299-91	CERAMIC CHIP 220PF 1%	50V	< CONNECTOR >			
C218	1-118-290-11	CERAMIC CHIP 0.001uF 10%	50V	CN201	1-785-103-11	PIN, CONNECTOR (3.96 mm PITCH) 5P	
C221	1-118-044-11	CERAMIC CHIP 1uF 10%	50V	* CN202	1-750-005-11	PIN, CONNECTOR (PC BOARD) 4P	
C222	1-118-044-11	CERAMIC CHIP 1uF 10%	50V	CN211	1-779-799-11	PIN, CONNECTOR 9P	
				CN212	1-785-728-21	PIN (PC BOARD), CONNECTOR 7P	
				CN213	1-564-320-00	PIN, CONNECTOR (3.96 mm PITCH) 2P	

**Note:** When the complete AMP board is replaced, refer to "NOTE OF REPLACING THE D218, IC350 AND IC351 ON THE AMP BOARD AND THE COMPLETE AMP BOARD" on page 4.

# HAP-S1

**AMP**

Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
CN215	1-816-113-21	CONNECTOR 15P				< RESISTOR >	
		< DIODE >					
D200	6-502-961-01	DIODE DA2J10100L		R200	1-216-833-11	METAL CHIP 10K	5% 1/10W
D201	6-502-961-01	DIODE DA2J10100L		R201	1-216-845-11	METAL CHIP 100K	5% 1/10W
D202	8-719-053-18	DIODE 1SR154-400TE-25		R202	1-216-825-11	METAL CHIP 2.2K	5% 1/10W
D203	6-502-961-01	DIODE DA2J10100L		△ R203	1-249-405-91	CARBON 100	5% 1/4W F
D204	8-719-053-18	DIODE 1SR154-400TE-25		R204	1-216-841-11	METAL CHIP 47K	5% 1/10W
D205	6-502-961-01	DIODE DA2J10100L		R205	1-216-825-11	METAL CHIP 2.2K	5% 1/10W
D206	6-502-961-01	DIODE DA2J10100L		R206	1-250-624-11	METAL CHIP 2.2K	1% 1/10W
D207	8-719-053-18	DIODE 1SR154-400TE-25		R207	1-216-825-11	METAL CHIP 2.2K	5% 1/10W
D208	6-502-961-01	DIODE DA2J10100L		R208	1-257-502-11	CARBON 820	5% 1/2W
D209	8-719-053-18	DIODE 1SR154-400TE-25		R209	1-257-502-11	CARBON 820	5% 1/2W
D216	6-502-961-01	DIODE DA2J10100L		R210	1-216-864-11	SHORT CHIP 0	
△ D218	8-719-061-07	DIODE D5SBA60-F (See Note)		R211	1-216-833-11	METAL CHIP 10K	5% 1/10W
D220	6-502-961-01	DIODE DA2J10100L		R214	1-216-833-11	METAL CHIP 10K	5% 1/10W
D221	6-500-400-01	DIODE BAV99-215		R215	1-216-864-11	SHORT CHIP 0	
D222	6-502-961-01	DIODE DA2J10100L		R220	1-257-502-11	CARBON 820	5% 1/2W
D223	6-502-961-01	DIODE DA2J10100L		R221	1-257-502-11	CARBON 820	5% 1/2W
D227	6-502-961-01	DIODE DA2J10100L		△ R222	1-249-399-91	CARBON 33	5% 1/4W F
D228	6-502-961-01	DIODE DA2J10100L		R223	1-216-825-11	METAL CHIP 2.2K	5% 1/10W
D231	8-719-053-18	DIODE 1SR154-400TE-25		R224	1-216-841-11	METAL CHIP 47K	5% 1/10W
D232	8-719-053-18	DIODE 1SR154-400TE-25		R225	1-216-837-11	METAL CHIP 22K	5% 1/10W
		< LUG TERMINAL >		R226	1-216-837-11	METAL CHIP 22K	5% 1/10W
* ET200	1-780-408-11	TERMINAL, LUG		R227	1-216-841-11	METAL CHIP 47K	5% 1/10W
		< FUSE >		R228	1-216-845-11	METAL CHIP 100K	5% 1/10W
△ F200	1-523-085-11	FUSE (2.5 A/250 V)		R229	1-216-845-11	METAL CHIP 100K	5% 1/10W
△ F201	1-523-085-11	FUSE (2.5 A/250 V)		R230	1-216-845-11	METAL CHIP 100K	5% 1/10W
△ F202	1-523-080-11	FUSE (6.3 A/250 V)		R231	1-216-845-11	METAL CHIP 100K	5% 1/10W
△ F203	1-523-080-11	FUSE (6.3 A/250 V)		△ R232	1-249-405-91	CARBON 100	5% 1/4W F
		< IC >		R233	1-216-845-11	METAL CHIP 100K	5% 1/10W
IC203	6-712-294-01	IC KIA7807API-U/PF		R234	1-216-841-11	METAL CHIP 47K	5% 1/10W
IC204	6-712-295-01	IC KIA7907PI		R235	1-216-845-11	METAL CHIP 100K	5% 1/10W
IC206	6-720-687-01	IC NJW1194		R236	1-216-845-11	METAL CHIP 100K	5% 1/10W
△ IC350	8-759-331-41	IC LM3876TF (See Note)		R237	1-216-825-11	METAL CHIP 2.2K	5% 1/10W
△ IC351	8-759-331-41	IC LM3876TF (See Note)		△ R238	1-249-405-91	CARBON 100	5% 1/4W F
		< TRANSISTOR >		R239	1-216-841-11	METAL CHIP 47K	5% 1/10W
Q200	6-553-266-01	TRANSISTOR 2PD601ART		R240	1-216-825-11	METAL CHIP 2.2K	5% 1/10W
Q201	6-553-266-01	TRANSISTOR 2PD601ART		R241	1-216-845-11	METAL CHIP 100K	5% 1/10W
* Q202	6-551-623-01	TRANSISTOR 2SA2154MFV (TL3S)		R242	1-216-809-11	METAL CHIP 100	5% 1/10W
* Q203	6-551-623-01	TRANSISTOR 2SA2154MFV (TL3S)		R243	1-257-451-11	CARBON 100K	5% 1/2W
Q204	6-553-266-01	TRANSISTOR 2PD601ART		R244	1-257-451-11	CARBON 100K	5% 1/2W
* Q205	6-551-623-01	TRANSISTOR 2SA2154MFV (TL3S)		R247	1-257-372-11	CARBON 2.2K	5% 1/2W
* Q206	6-551-623-01	TRANSISTOR 2SA2154MFV (TL3S)		R248	1-257-372-11	CARBON 2.2K	5% 1/2W
Q207	6-553-266-01	TRANSISTOR 2PD601ART		R251	1-216-825-11	METAL CHIP 2.2K	5% 1/10W
Q208	6-553-266-01	TRANSISTOR 2PD601ART		R252	1-216-825-11	METAL CHIP 2.2K	5% 1/10W
Q209	8-729-023-22	TRANSISTOR 2SD2114K		R256	1-216-845-11	METAL CHIP 100K	5% 1/10W
Q210	8-729-023-22	TRANSISTOR 2SD2114K		R260	1-216-833-11	METAL CHIP 10K	5% 1/10W
Q213	6-552-891-01	TRANSISTOR LSAR523UBFS8TL		R261	1-216-833-11	METAL CHIP 10K	5% 1/10W
Q214	6-552-891-01	TRANSISTOR LSAR523UBFS8TL		R262	1-216-845-11	METAL CHIP 100K	5% 1/10W
Q216	6-553-266-01	TRANSISTOR 2PD601ART		R264	1-216-841-11	METAL CHIP 47K	5% 1/10W
Q217	6-552-891-01	TRANSISTOR LSAR523UBFS8TL		R267	1-216-833-11	METAL CHIP 10K	5% 1/10W
Q218	6-552-891-01	TRANSISTOR LSAR523UBFS8TL		R271	1-216-833-11	METAL CHIP 10K	5% 1/10W
Q219	6-553-266-01	TRANSISTOR 2PD601ART		R281	1-257-434-11	CARBON 4.7K	5% 1/2W
				R282	1-257-434-11	CARBON 4.7K	5% 1/2W
				R283	1-216-841-11	METAL CHIP 47K	5% 1/10W
				R284	1-216-809-11	METAL CHIP 100	5% 1/10W
				R285	1-216-809-11	METAL CHIP 100	5% 1/10W
				R286	1-216-809-11	METAL CHIP 100	5% 1/10W
				R287	1-216-825-11	METAL CHIP 2.2K	5% 1/10W
				R288	1-216-825-11	METAL CHIP 2.2K	5% 1/10W
				R289	1-216-809-11	METAL CHIP 100	5% 1/10W

**Note:** When the D218, IC350 and IC351 on the AMP board is replaced, refer to "NOTE OF REPLACING THE D218, IC350 AND IC351 ON THE AMP BOARD AND THE COMPLETE AMP BOARD" on page 4.

Ref. No.	Part No.	Description				Remark	Ref. No.	Part No.	Description				Remark
R290	1-216-841-11	METAL CHIP	47K	5%	1/10W	C424	1-116-740-11	CERAMIC CHIP	0.47uF	10%	16V		
R350	1-216-835-11	METAL CHIP	15K	5%	1/10W	C425	1-124-721-11	ELECT	10uF	20%	50V		
R351	1-257-371-11	CARBON	1K	5%	1/2W	C426	1-124-721-11	ELECT	10uF	20%	50V		
R352	1-257-451-11	CARBON	100K	5%	1/2W	C427	1-124-721-11	ELECT	10uF	20%	50V		
R353	1-257-371-11	CARBON	1K	5%	1/2W	C428	1-136-165-00	FILM	0.1uF	5%	50V		
R354	1-257-448-11	CARBON	47K	5%	1/2W	C429	1-136-165-00	FILM	0.1uF	5%	50V		
R355	1-216-835-11	METAL CHIP	15K	5%	1/10W	C430	1-112-089-11	ELECT	47uF	20%	25V		
R356	1-257-371-11	CARBON	1K	5%	1/2W	C431	1-118-347-11	CERAMIC CHIP	0.1uF	10%	25V		
R357	1-257-451-11	CARBON	100K	5%	1/2W	C432	1-124-721-11	ELECT	10uF	20%	50V		
R358	1-257-371-11	CARBON	1K	5%	1/2W	C433	1-118-347-11	CERAMIC CHIP	0.1uF	10%	25V		
R359	1-257-448-11	CARBON	47K	5%	1/2W	C434	1-116-717-11	CERAMIC CHIP	10uF	20%	10V		
R360	1-216-833-11	METAL CHIP	10K	5%	1/10W	C435	1-118-347-11	CERAMIC CHIP	0.1uF	10%	25V		
R361	1-216-845-11	METAL CHIP	100K	5%	1/10W	C436	1-118-347-11	CERAMIC CHIP	0.1uF	10%	25V		
R362	1-216-821-11	METAL CHIP	1K	5%	1/10W	C437	1-162-915-11	CERAMIC CHIP	10PF	0.5PF	50V		
R363	1-216-825-11	METAL CHIP	2.2K	5%	1/10W	C438	1-162-915-11	CERAMIC CHIP	10PF	0.5PF	50V		
R364	1-216-833-11	METAL CHIP	10K	5%	1/10W	C439	1-118-290-11	CERAMIC CHIP	0.001uF	10%	50V		
R365	1-216-845-11	METAL CHIP	100K	5%	1/10W	C440	1-118-347-11	CERAMIC CHIP	0.1uF	10%	25V		
R366	1-216-833-11	METAL CHIP	10K	5%	1/10W	C441	1-118-290-11	CERAMIC CHIP	0.001uF	10%	50V		
R367	1-216-833-11	METAL CHIP	10K	5%	1/10W	C442	1-118-347-11	CERAMIC CHIP	0.1uF	10%	25V		
R368	1-216-845-11	METAL CHIP	100K	5%	1/10W	C443	1-162-916-11	CERAMIC CHIP	12PF	5%	50V		
R369	1-216-841-11	METAL CHIP	47K	5%	1/10W	C444	1-162-916-11	CERAMIC CHIP	12PF	5%	50V		
< RELAY >													
RY200	1-755-486-11	RELAY											
RY201	1-755-170-11	RELAY											
RY202	1-755-486-11	RELAY											
RY203	1-755-486-11	RELAY											
< THERMISTOR >													
TH200	1-804-045-11	THERMISTOR											
*****													
A-1945-074-A	DAC BOARD, COMPLETE (AEP, UK)												
A-1945-075-A	DAC BOARD, COMPLETE (US, CND)												
*****													
< CAPACITOR >													
C400	1-118-290-11	CERAMIC CHIP	0.001uF	10%	50V	C464	1-124-748-11	ELECT	22uF	20%	100V		
C401	1-116-299-91	CERAMIC CHIP	220PF	1%	50V	C465	1-124-748-11	ELECT	22uF	20%	100V		
C402	1-162-927-11	CERAMIC CHIP	100PF	5%	50V	C466	1-118-347-11	CERAMIC CHIP	0.1uF	10%	25V		
C403	1-162-927-11	CERAMIC CHIP	100PF	5%	50V	C467	1-118-290-11	CERAMIC CHIP	0.001uF	10%	50V		
C404	1-112-080-11	ELECT	470uF	20%	10V	C486	1-118-347-11	CERAMIC CHIP	0.1uF	10%	25V		
C405	1-112-080-11	ELECT	470uF	20%	10V	C487	1-118-290-11	CERAMIC CHIP	0.001uF	10%	50V		
C406	1-162-927-11	CERAMIC CHIP	100PF	5%	50V	C488	1-118-347-11	CERAMIC CHIP	0.1uF	10%	25V		
C407	1-162-927-11	CERAMIC CHIP	100PF	5%	50V	C489	1-118-290-11	CERAMIC CHIP	0.001uF	10%	50V		
C408	1-100-155-91	CERAMIC CHIP	470PF	5%	100V	C490	1-118-347-11	CERAMIC CHIP	0.1uF	10%	25V		
C409	1-135-820-21	FILM CHIP	0.001uF	2%	50V	C491	1-118-290-11	CERAMIC CHIP	0.001uF	10%	50V		
C410	1-135-820-21	FILM CHIP	0.001uF	2%	50V	C492	1-118-347-11	CERAMIC CHIP	0.1uF	10%	25V		
C411	1-135-820-21	FILM CHIP	0.001uF	2%	50V	C493	1-118-290-11	CERAMIC CHIP	0.001uF	10%	50V		
C412	1-135-820-21	FILM CHIP	0.001uF	2%	50V	C494	1-118-347-11	CERAMIC CHIP	0.1uF	10%	25V		
C413	1-135-825-21	FILM CHIP	0.0047uF	2%	16V	C495	1-116-734-11	CERAMIC CHIP	1uF	20%	16V		
C414	1-135-825-21	FILM CHIP	0.0047uF	2%	16V	C496	1-116-734-11	CERAMIC CHIP	1uF	20%	16V		
C415	1-118-290-11	CERAMIC CHIP	0.001uF	10%	50V	< CONNECTOR >							
C416	1-118-290-11	CERAMIC CHIP	0.001uF	10%	50V	CN401	1-785-728-21	PIN (PC BOARD), CONNECTOR 7P					
C417	1-118-290-11	CERAMIC CHIP	0.001uF	10%	50V	CN402	1-820-840-31	CONNECTOR, FFC/FPC (LIF) 22P					
C418	1-118-290-11	CERAMIC CHIP	0.001uF	10%	50V	< DIODE >							
C419	1-127-803-91	CERAMIC CHIP	270PF	1%	50V	D400	6-502-961-01	DIODE DA2J10100L					
C420	1-127-803-91	CERAMIC CHIP	270PF	1%	50V	D401	6-502-961-01	DIODE DA2J10100L					
C421	1-127-803-91	CERAMIC CHIP	270PF	1%	50V	D402	6-502-961-01	DIODE DA2J10100L					
C422	1-127-803-91	CERAMIC CHIP	270PF	1%	50V								
C423	1-112-100-11	ELECT	10uF	20%	50V								

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## DAC

Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
		< LUG TERMINAL >		R420	1-257-429-11	CARBON 680	5% 1/2W
* EE400	1-780-408-11	TERMINAL, LUG		R421	1-257-429-11	CARBON 680	5% 1/2W
* EE401	1-780-408-11	TERMINAL, LUG		R422	1-257-441-11	CARBON 10K	5% 1/2W
* EE402	1-780-408-11	TERMINAL, LUG		R423	1-216-801-11	METAL CHIP 22	5% 1/10W
* EE403	1-780-408-11	TERMINAL, LUG		R424	1-216-801-11	METAL CHIP 22	5% 1/10W
		< FERRITE BEAD >		R425	1-216-801-11	METAL CHIP 22	5% 1/10W
FB400	1-414-760-21	FERRITE, EMI (SMD) (1608)		R426	1-216-801-11	METAL CHIP 22	5% 1/10W
FB401	1-469-152-11	FERRITE, EMI (SMD) (2012)		R427	1-216-801-11	METAL CHIP 22	5% 1/10W
FB402	1-469-152-11	FERRITE, EMI (SMD) (2012)		R428	1-216-801-11	METAL CHIP 22	5% 1/10W
FB404	1-469-139-21	FERRITE, EMI (SMD) (2012)		R429	1-216-809-11	METAL CHIP 100	5% 1/10W
		< IC >		R430	1-216-801-11	METAL CHIP 22	5% 1/10W
IC400	8-759-832-29	IC NJM4580M- (TE2)		R431	1-216-809-11	METAL CHIP 100	5% 1/10W
IC401	8-759-832-29	IC NJM4580M- (TE2)		R432	1-216-809-11	METAL CHIP 100	5% 1/10W
IC402	8-759-832-29	IC NJM4580M- (TE2)		R433	1-216-809-11	METAL CHIP 100	5% 1/10W
IC403	6-716-834-01	IC MM1836A50NRE		R434	1-216-809-11	METAL CHIP 100	5% 1/10W
IC404	6-708-637-01	IC NJM2871BF33-TE2		R435	1-216-809-11	METAL CHIP 100	5% 1/10W
IC405	6-720-672-01	IC PCM1795DBR		R436	1-216-809-11	METAL CHIP 100	5% 1/10W
IC406	6-706-487-01	IC TC7SH08FU		R437	1-216-797-11	METAL CHIP 10	5% 1/10W
IC407	8-759-680-48	IC TC7WH157FK		R438	1-216-809-11	METAL CHIP 100	5% 1/10W
IC408	8-759-096-87	IC TC7WU04FU (TE12R)		R439	1-216-797-11	METAL CHIP 10	5% 1/10W
IC409	8-759-096-87	IC TC7WU04FU (TE12R)		R440	1-218-845-11	METAL CHIP 820	0.5% 1/10W
IC410	8-759-680-48	IC TC7WH157FK		R441	1-216-857-11	METAL CHIP 1M	5% 1/10W
IC411	6-700-067-01	IC HD74LV161ATELL		R442	1-216-809-11	METAL CHIP 100	5% 1/10W
IC412	6-600-060-01	IC TC7WZ32FK		R443	1-216-809-11	METAL CHIP 100	5% 1/10W
IC413	6-708-637-01	IC NJM2871BF33-TE2		R444	1-216-809-11	METAL CHIP 100	5% 1/10W
IC414	6-708-637-01	IC NJM2871BF33-TE2		R445	1-216-833-11	METAL CHIP 10K	5% 1/10W
IC415	8-759-832-29	IC NJM4580M- (TE2)		R446	1-216-809-11	METAL CHIP 100	5% 1/10W
		< JACK >		R447	1-216-817-11	METAL CHIP 470	5% 1/10W
J401	1-794-984-11	JACK, PIN 6P (D/A DIRECT LINE OUT, LINE IN 1, LINE IN 2)		R448	1-216-857-11	METAL CHIP 1M	5% 1/10W
		< TRANSISTOR >		R449	1-216-797-11	METAL CHIP 10	5% 1/10W
Q400	8-729-023-22	TRANSISTOR 2SD2114K		R450	1-218-845-11	METAL CHIP 820	0.5% 1/10W
Q401	8-729-023-22	TRANSISTOR 2SD2114K		R452	1-216-809-11	METAL CHIP 100	5% 1/10W
		< RESISTOR >		R455	1-216-833-11	METAL CHIP 10K	5% 1/10W
R400	1-257-470-11	CARBON 220K	5% 1/2W	R458	1-216-833-11	METAL CHIP 10K	5% 1/10W
R401	1-257-470-11	CARBON 220K	5% 1/2W	R461	1-216-864-11	SHORT CHIP 0	
R402	1-257-371-11	CARBON 1K	5% 1/2W	R462	1-216-845-11	METAL CHIP 100K	5% 1/10W
R403	1-257-371-11	CARBON 1K	5% 1/2W	R463	1-216-845-11	METAL CHIP 100K	5% 1/10W
R404	1-257-371-11	CARBON 1K	5% 1/2W	R464	1-216-809-11	METAL CHIP 100	5% 1/10W
R405	1-257-371-11	CARBON 1K	5% 1/2W	R465	1-257-372-11	CARBON 2.2K	5% 1/2W
R406	1-257-428-11	CARBON 560	5% 1/2W	R466	1-257-372-11	CARBON 2.2K	5% 1/2W
R407	1-257-429-11	CARBON 680	5% 1/2W	R467	1-216-825-11	METAL CHIP 2.2K	5% 1/10W
R408	1-257-428-11	CARBON 560	5% 1/2W	R468	1-216-825-11	METAL CHIP 2.2K	5% 1/10W
R409	1-257-429-11	CARBON 680	5% 1/2W	R469	1-216-845-11	METAL CHIP 100K	5% 1/10W
R410	1-257-428-11	CARBON 560	5% 1/2W	R470	1-216-845-11	METAL CHIP 100K	5% 1/10W
R411	1-257-428-11	CARBON 560	5% 1/2W	R471	1-216-864-11	SHORT CHIP 0	
R412	1-257-429-11	CARBON 680	5% 1/2W	R472	1-216-864-11	SHORT CHIP 0	
R413	1-257-429-11	CARBON 680	5% 1/2W	R473	1-216-864-11	SHORT CHIP 0	
R414	1-257-428-11	CARBON 560	5% 1/2W	R478	1-216-864-11	SHORT CHIP 0	
R415	1-257-428-11	CARBON 560	5% 1/2W	R479	1-216-864-11	SHORT CHIP 0	
R416	1-257-428-11	CARBON 560	5% 1/2W	R484	1-216-864-11	SHORT CHIP 0	
R417	1-257-428-11	CARBON 560	5% 1/2W	R485	1-216-864-11	SHORT CHIP 0	
R418	1-257-429-11	CARBON 680	5% 1/2W	R486	1-216-813-11	METAL CHIP 220	5% 1/10W
R419	1-257-429-11	CARBON 680	5% 1/2W	R489	1-216-833-11	METAL CHIP 10K	5% 1/10W
		< VIBRATOR >		X400	1-795-779-21	VIBRATOR, CRYSTAL (22.5792 MHz)	
		< VIBRATOR >		X401	1-814-344-11	QUARTZ CRYSTAL UNIT (24.576 MHz)	
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Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
A-1945-082-A DCDC BOARD, COMPLETE *****				< COIL >			
		< CAPACITOR >		L2401	1-460-576-11	COIL, CHOKE 4.7uH	
				L2402	1-460-576-11	COIL, CHOKE 4.7uH	
				L2403	1-460-576-11	COIL, CHOKE 4.7uH	
				< TRANSISTOR >			
				Q2401	6-553-266-01	TRANSISTOR 2PD601ART	
				Q2402	6-553-268-01	TRANSISTOR PDTTC114ET	
				Q2403	6-553-268-01	TRANSISTOR PDTTC114ET	
				< RESISTOR >			
				R2401	1-218-879-11	METAL CHIP 22K 0.5%	1/10W
				R2402	1-218-865-11	METAL CHIP 5.6K 0.5%	1/10W
				R2403	1-250-640-11	METAL CHIP 10K 1%	1/10W
				R2407	1-216-845-11	METAL CHIP 100K 5%	1/10W
				R2408	1-250-592-11	METAL CHIP 100 1%	1/10W
				R2409	1-216-797-11	METAL CHIP 10 5%	1/10W
				R2410	1-216-797-11	METAL CHIP 10 5%	1/10W
				R2411	1-216-864-11	SHORT CHIP 0	
				R2412	1-218-879-11	METAL CHIP 22K 0.5%	1/10W
				R2413	1-218-863-11	METAL CHIP 4.7K 0.5%	1/10W
				R2414	1-218-863-11	METAL CHIP 4.7K 0.5%	1/10W
				R2415	1-250-592-11	METAL CHIP 100 1%	1/10W
				R2416	1-216-864-11	SHORT CHIP 0	
				R2417	1-218-879-11	METAL CHIP 22K 0.5%	1/10W
				R2418	1-218-863-11	METAL CHIP 4.7K 0.5%	1/10W
				R2419	1-218-863-11	METAL CHIP 4.7K 0.5%	1/10W
				R2420	1-218-831-11	METAL CHIP 220 0.5%	1/10W
				R2421	1-216-845-11	METAL CHIP 100K 5%	1/10W
				R2422	1-216-797-11	METAL CHIP 10 5%	1/10W
				R2423	1-216-864-11	SHORT CHIP 0	
				R2424	1-216-845-11	METAL CHIP 100K 5%	1/10W
				R2425	1-250-640-11	METAL CHIP 10K 1%	1/10W
				R2426	1-218-863-11	METAL CHIP 4.7K 0.5%	1/10W
				R2427	1-216-864-11	SHORT CHIP 0	
				R2428	1-216-864-11	SHORT CHIP 0	
				R2429	1-216-864-11	SHORT CHIP 0	
				R2430	1-216-864-11	SHORT CHIP 0	
				R2431	1-216-864-11	SHORT CHIP 0	
				R2432	1-216-864-11	SHORT CHIP 0	
				R2433	1-216-864-11	SHORT CHIP 0	
				R2434	1-218-863-11	METAL CHIP 4.7K 0.5%	1/10W
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A-1945-092-A DIGITAL IO BOARD, COMPLETE *****				< CAPACITOR >			
				C4001	1-118-361-11	CERAMIC CHIP 0.1uF 10%	50V
				C4002	1-112-080-11	ELECT 470uF 20%	10V
				C4003	1-112-089-11	ELECT 47uF 20%	25V
				C4004	1-118-361-11	CERAMIC CHIP 0.1uF 10%	50V
				C4009	1-112-080-11	ELECT 470uF 20%	10V
				C4010	1-118-361-11	CERAMIC CHIP 0.1uF 10%	50V
				C4012	1-118-386-11	CERAMIC CHIP 0.1uF 10%	16V
				C4013	1-116-151-11	CERAMIC CHIP 0.001uF 2%	50V
				C4014	1-164-874-11	CERAMIC CHIP 100PF 5%	50V
				C4016	1-112-089-11	ELECT 47uF 20%	25V
				C4017	1-116-734-11	CERAMIC CHIP 1uF 20%	16V
				C4018	1-116-734-11	CERAMIC CHIP 1uF 20%	16V
				< DIODE >			
				D2402	6-502-961-01	DIODE DA2J10100L	
				D2403	6-502-961-01	DIODE DA2J10100L	
				D2404	8-719-060-88	DIODE D4SBS6	
				D2405	8-719-060-88	DIODE D4SBS6	
				D2406	6-502-968-01	DIODE DZ2J062M0L	
				< FUSE >			
				F2402	1-523-086-11	FUSE (3.15 A/250 V)	
				F2404	1-523-086-11	FUSE (3.15 A/250 V)	
				< IC >			
				IC2402	6-719-190-01	IC RT7256ALZSP	
				IC2403	6-719-190-01	IC RT7256ALZSP	
				IC2404	6-719-190-01	IC RT7256ALZSP	

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## DIGITAL IO

Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
C4019	1-116-734-11	CERAMIC CHIP 1uF	20% 16V	FB4008	1-469-139-21	FERRITE, EMI (SMD) (2012)	
C4020	1-116-734-11	CERAMIC CHIP 1uF	20% 16V	FB4009	1-469-152-11	FERRITE, EMI (SMD) (2012)	
C4021	1-118-386-11	CERAMIC CHIP 0.1uF	10% 16V	FB4011	1-469-139-21	FERRITE, EMI (SMD) (2012)	
C4022	1-118-386-11	CERAMIC CHIP 0.1uF	10% 16V	FB4012	1-469-139-21	FERRITE, EMI (SMD) (2012)	
C4023	1-118-386-11	CERAMIC CHIP 0.1uF	10% 16V	FB4013	1-469-139-21	FERRITE, EMI (SMD) (2012)	
C4024	1-112-090-11	ELECT 100uF	20% 25V			< IC >	
C4025	1-116-151-11	CERAMIC CHIP 0.001uF	2% 50V				
C4026	1-112-090-11	ELECT 100uF	20% 25V				
C4027	1-118-386-11	CERAMIC CHIP 0.1uF	10% 16V	IC4001	6-600-827-01	IC JSR1124 (OPTICAL IN)	
C4028	1-112-090-11	ELECT 100uF	20% 25V	IC4002	6-709-888-01	IC TC7WHU04FK	
C4029	1-118-386-11	CERAMIC CHIP 0.1uF	10% 16V	IC4003	6-719-061-01	IC MM1839A33NRE	
C4030	1-118-386-11	CERAMIC CHIP 0.1uF	10% 16V	IC4004	6-717-987-11	IC LC89075WA-H	
* C4031	1-118-387-11	CERAMIC CHIP 0.068uF	10% 16V	IC4006	8-759-680-48	IC TC7WH157FK	
C4032	1-118-386-11	CERAMIC CHIP 0.1uF	10% 16V	IC4007	6-707-870-01	IC TC74VHC157FT (EKJ)	
C4033	1-118-386-11	CERAMIC CHIP 0.1uF	10% 16V	IC4008	6-715-699-01	IC CS230002-CZZR	
C4034	1-164-852-11	CERAMIC CHIP 12PF	5% 50V			< JACK >	
C4035	1-164-852-11	CERAMIC CHIP 12PF	5% 50V	J4023	1-818-300-21	JACK, PIN 1P (COAXIAL IN)	
C4036	1-118-386-11	CERAMIC CHIP 0.1uF	10% 16V			< RESISTOR >	
* C4037	1-118-407-11	CERAMIC CHIP 470PF	10% 50V	R4001	1-216-809-11	METAL CHIP 100	5% 1/10W
C4038	1-116-151-11	CERAMIC CHIP 0.001uF	2% 50V	R4002	1-218-839-11	METAL CHIP 470	0.5% 1/10W
C4039	1-118-386-11	CERAMIC CHIP 0.1uF	10% 16V	* R4003	1-250-589-11	METAL CHIP 75	1% 1/10W
C4041	1-112-089-11	ELECT 47uF	20% 25V	R4008	1-218-903-11	METAL CHIP 220K	0.5% 1/10W
C4042	1-118-412-11	CERAMIC CHIP 220PF	10% 50V	R4009	1-218-871-11	METAL CHIP 10K	0.5% 1/10W
C4045	1-107-826-91	CERAMIC CHIP 0.1uF	10% 16V	R4010	1-216-864-11	SHORT CHIP 0	
C4046	1-116-717-11	CERAMIC CHIP 10uF	20% 10V	R4011	1-218-990-81	SHORT CHIP 0	
C4047	1-118-386-11	CERAMIC CHIP 0.1uF	10% 16V	R4012	1-218-990-81	SHORT CHIP 0	
C4048	1-118-386-11	CERAMIC CHIP 0.1uF	10% 16V	R4013	1-218-965-11	METAL CHIP 10K	5% 1/16W
C4052	1-118-412-11	CERAMIC CHIP 220PF	10% 50V	R4015	1-216-864-11	SHORT CHIP 0	
C4055	1-118-412-11	CERAMIC CHIP 220PF	10% 50V	R4016	1-216-864-11	SHORT CHIP 0	
C4056	1-118-412-11	CERAMIC CHIP 220PF	10% 50V	R4017	1-216-864-11	SHORT CHIP 0	
		< JACK/CONNECTOR >		R4018	1-216-864-11	SHORT CHIP 0	
CN4001	1-842-235-11	JACK, MODULAR (LAN (10/100/1000))		R4019	1-218-990-81	SHORT CHIP 0	
CN4002	1-822-423-11	CONNECTOR, USB (A) (5V $\overline{=}$ 1A $\Psi$ EXT)		R4020	1-218-990-81	SHORT CHIP 0	
* CN4003	1-779-268-21	PIN, CONNECTOR (1.5 mm) (SMD) 11P		R4022	1-218-965-11	METAL CHIP 10K	5% 1/16W
CN4005	1-573-806-21	PIN, CONNECTOR (1.5 mm) (SMD) 6P		R4023	1-218-990-81	SHORT CHIP 0	
CN4006	1-815-763-32	CONNECTOR, FFC/FPC 24P		R4024	1-218-990-81	SHORT CHIP 0	
CN4007	1-820-840-31	CONNECTOR, FFC/FPC (LIF) 22P		R4025	1-218-965-11	METAL CHIP 10K	5% 1/16W
CN4008	1-779-772-11	CONNECTOR 13P		R4026	1-218-941-81	METAL CHIP 100	5% 1/16W
CN4009	1-764-250-21	PIN, CONNECTOR (PC BOARD) 4P		R4027	1-218-965-11	METAL CHIP 10K	5% 1/16W
CN4010	1-770-469-21	PIN, CONNECTOR (PC BOARD) 2P		R4028	1-218-953-11	METAL CHIP 1K	5% 1/16W
CN4011	1-784-859-51	CONNECTOR, FFC (LIF (NON-ZIF)) 7P		R4030	1-218-973-11	METAL CHIP 47K	5% 1/16W
CN4013	1-573-768-21	PIN, CONNECTOR (1.5 mm) (SMD) 5P		R4031	1-218-989-11	METAL CHIP 1M	5% 1/16W
		< DIODE >		R4032	1-218-947-11	METAL CHIP 330	5% 1/16W
D4003	6-502-961-01	DIODE DA2J10100L		R4033	1-208-675-11	METAL CHIP 470	0.5% 1/16W
		< LUG TERMINAL >		R4034	1-218-965-11	METAL CHIP 10K	5% 1/16W
* ET4001	1-780-408-11	TERMINAL, LUG		R4035	1-218-965-11	METAL CHIP 10K	5% 1/16W
* ET4002	1-780-408-11	TERMINAL, LUG		R4036	1-216-864-11	SHORT CHIP 0	
		< FERRITE BEAD >		R4037	1-218-945-11	METAL CHIP 220	5% 1/16W
FB4001	1-469-152-11	FERRITE, EMI (SMD) (2012)		R4038	1-218-951-11	METAL CHIP 680	5% 1/16W
FB4002	1-469-152-11	FERRITE, EMI (SMD) (2012)		R4039	1-218-947-11	METAL CHIP 330	5% 1/16W
FB4003	1-500-445-21	FERRITE, EMI (SMD) (2012)		R4040	1-218-947-11	METAL CHIP 330	5% 1/16W
FB4004	1-500-445-21	FERRITE, EMI (SMD) (2012)		R4041	1-218-953-11	METAL CHIP 1K	5% 1/16W
FB4005	1-469-125-21	FERRITE, EMI (SMD) (1608)		R4042	1-218-989-11	METAL CHIP 1M	5% 1/16W
FB4006	1-469-125-21	FERRITE, EMI (SMD) (1608)		R4044	1-218-941-81	METAL CHIP 100	5% 1/16W
FB4007	1-469-152-11	FERRITE, EMI (SMD) (2012)		R4046	1-218-945-11	METAL CHIP 220	5% 1/16W
				R4047	1-216-864-11	SHORT CHIP 0	
				R4052	1-218-933-11	METAL CHIP 22	5% 1/16W
				R4053	1-218-933-11	METAL CHIP 22	5% 1/16W



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## FPGA DSP

Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
C260	1-118-386-11	CERAMIC CHIP 0.1uF 10%	16V			< RESISTOR >	
C261	1-118-386-11	CERAMIC CHIP 0.1uF 10%	16V				
C262	1-116-151-11	CERAMIC CHIP 0.001uF 2%	50V	R102	1-216-295-91	SHORT CHIP 0	
C263	1-118-386-11	CERAMIC CHIP 0.1uF 10%	16V	R104	1-216-295-91	SHORT CHIP 0	
C264	1-118-459-11	CERAMIC CHIP 0.01uF 10%	25V	R105	1-218-965-11	METAL CHIP 10K 5%	1/16W
C265	1-116-151-11	CERAMIC CHIP 0.001uF 2%	50V	R112	1-208-709-11	METAL CHIP 12K 0.5%	1/16W
C266	1-116-151-11	CERAMIC CHIP 0.001uF 2%	50V	R113	1-208-898-11	METAL CHIP 3K 0.5%	1/16W
C267	1-116-151-11	CERAMIC CHIP 0.001uF 2%	50V	R114	1-208-918-11	METAL CHIP 20K 0.5%	1/16W
C301	1-118-459-11	CERAMIC CHIP 0.01uF 10%	25V	R116	1-208-905-11	METAL CHIP 5.6K 0.5%	1/16W
C303	1-118-459-11	CERAMIC CHIP 0.01uF 10%	25V	R118	1-216-864-11	SHORT CHIP 0	
C401	1-118-386-11	CERAMIC CHIP 0.1uF 10%	16V	R119	1-216-864-11	SHORT CHIP 0	
C402	1-118-386-11	CERAMIC CHIP 0.1uF 10%	16V	R120	1-216-864-11	SHORT CHIP 0	
* C701	1-116-720-11	CERAMIC CHIP 10uF 20%	6.3V	R121	1-216-864-11	SHORT CHIP 0	
* C702	1-116-720-11	CERAMIC CHIP 10uF 20%	6.3V	R122	1-218-965-11	METAL CHIP 10K 5%	1/16W
C703	1-118-386-11	CERAMIC CHIP 0.1uF 10%	16V	R127	1-216-864-11	SHORT CHIP 0	
C704	1-118-386-11	CERAMIC CHIP 0.1uF 10%	16V	R128	1-216-864-11	SHORT CHIP 0	
C705	1-118-386-11	CERAMIC CHIP 0.1uF 10%	16V	R129	1-216-864-11	SHORT CHIP 0	
C706	1-118-459-11	CERAMIC CHIP 0.01uF 10%	25V	R130	1-216-864-11	SHORT CHIP 0	
C707	1-118-386-11	CERAMIC CHIP 0.1uF 10%	16V	R132	1-250-495-11	METAL CHIP 1K 1%	1/16W
C708	1-118-386-11	CERAMIC CHIP 0.1uF 10%	16V	R201	1-216-864-11	SHORT CHIP 0	
C709	1-118-386-11	CERAMIC CHIP 0.1uF 10%	16V	R202	1-218-965-11	METAL CHIP 10K 5%	1/16W
C710	1-118-459-11	CERAMIC CHIP 0.01uF 10%	25V	R301	1-218-965-11	METAL CHIP 10K 5%	1/16W
		< CONNECTOR >		R303	1-218-965-11	METAL CHIP 10K 5%	1/16W
CN401	1-815-136-21	CONNECTOR, BOARD TO BOARD		R304	1-218-941-81	METAL CHIP 100 5%	1/16W
CN506	1-778-172-61	CONNECTOR, FFC/FPC (ZIF) 24P		R305	1-218-965-11	METAL CHIP 10K 5%	1/16W
		< LUG TERMINAL >		R306	1-218-965-11	METAL CHIP 10K 5%	1/16W
* ET201	1-780-408-11	TERMINAL, LUG		R308	1-218-965-11	METAL CHIP 10K 5%	1/16W
* ET202	1-780-408-11	TERMINAL, LUG		R309	1-218-965-11	METAL CHIP 10K 5%	1/16W
* ET203	1-780-408-11	TERMINAL, LUG		R310	1-218-965-11	METAL CHIP 10K 5%	1/16W
* ET204	1-780-408-11	TERMINAL, LUG		R311	1-218-953-11	METAL CHIP 1K 5%	1/16W
		< FERRITE BEAD >		R312	1-218-965-11	METAL CHIP 10K 5%	1/16W
FB101	1-469-094-21	FERRITE, EMI (SMD) (1608)		R313	1-218-953-11	METAL CHIP 1K 5%	1/16W
FB102	1-469-094-21	FERRITE, EMI (SMD) (1608)		R315	1-218-965-11	METAL CHIP 10K 5%	1/16W
FB103	1-469-094-21	FERRITE, EMI (SMD) (1608)		R316	1-218-965-11	METAL CHIP 10K 5%	1/16W
FB104	1-469-094-21	FERRITE, EMI (SMD) (1608)		R325	1-218-953-11	METAL CHIP 1K 5%	1/16W
FB106	1-469-094-21	FERRITE, EMI (SMD) (1608)		R401	1-218-941-81	METAL CHIP 100 5%	1/16W
FB107	1-469-094-21	FERRITE, EMI (SMD) (1608)		R402	1-218-929-11	METAL CHIP 10 5%	1/16W
FB108	1-469-094-21	FERRITE, EMI (SMD) (1608)		R403	1-218-929-11	METAL CHIP 10 5%	1/16W
FB201	1-469-094-21	FERRITE, EMI (SMD) (1608)		R404	1-218-965-11	METAL CHIP 10K 5%	1/16W
FB501	1-400-822-21	BEAD, FERRITE (1005)		R405	1-218-965-11	METAL CHIP 10K 5%	1/16W
FB701	1-469-094-21	FERRITE, EMI (SMD) (1608)		R409	1-218-929-11	METAL CHIP 10 5%	1/16W
		< IC >		R411	1-218-929-11	METAL CHIP 10 5%	1/16W
IC001	(Not supplied)	IC EP4CGX30BF14C8N (See Note)		R412	1-218-929-11	METAL CHIP 10 5%	1/16W
IC101	6-718-705-01	IC TPS54295PWPR		R413	1-218-929-11	METAL CHIP 10 5%	1/16W
IC102	6-715-866-01	IC MM3464A25NRE		R418	1-218-929-11	METAL CHIP 10 5%	1/16W
* IC103	6-718-253-01	IC BD2231G-TR		R420	1-218-929-11	METAL CHIP 10 5%	1/16W
IC701	6-709-888-01	IC TC7WHU04FK		R421	1-218-929-11	METAL CHIP 10 5%	1/16W
IC702	(Not supplied)	IC CS48L10-CNZR (See Note)		R422	1-218-990-81	SHORT CHIP 0	
		< COIL >		R424	1-218-965-11	METAL CHIP 10K 5%	1/16W
L102	1-457-870-11	CHOKO COIL 1.5uH		R426	1-208-894-81	METAL CHIP 2K 0.5%	1/16W
		< TRANSISTOR >		R512	1-218-929-11	METAL CHIP 10 5%	1/16W
Q301	8-729-928-90	TRANSISTOR DTC114EE		R513	1-218-929-11	METAL CHIP 10 5%	1/16W
				R514	1-218-945-11	METAL CHIP 220 5%	1/16W
				R515	1-218-941-81	METAL CHIP 100 5%	1/16W
				R518	1-218-952-11	METAL CHIP 820 5%	1/16W
				R519	1-218-929-11	METAL CHIP 10 5%	1/16W
				R520	1-218-929-11	METAL CHIP 10 5%	1/16W
				R521	1-218-929-11	METAL CHIP 10 5%	1/16W
				R522	1-218-929-11	METAL CHIP 10 5%	1/16W
				R523	1-218-929-11	METAL CHIP 10 5%	1/16W
				R524	1-218-929-11	METAL CHIP 10 5%	1/16W

**Note:** IC001 and IC702 on the FPGA DSP board cannot exchange with single. When these parts are damaged, exchange the complete mounted board.













# HAP-S1

**MAIN** **PENC** **POWER KEY** **SPTM** **STANBY**

Ref. No.	Part No.	Description	Remark
< COMPOSITION CIRCUIT BLOCK >			
RB601	1-234-400-21	CONDUCTOR, NETWORK (1005X4)	
RB602	1-234-400-21	CONDUCTOR, NETWORK (1005X4)	
RB701	1-234-400-21	CONDUCTOR, NETWORK (1005X4)	
RB702	1-234-400-21	CONDUCTOR, NETWORK (1005X4)	
RB703	1-234-400-21	CONDUCTOR, NETWORK (1005X4)	
RB704	1-234-400-21	CONDUCTOR, NETWORK (1005X4)	
RB705	1-234-400-21	CONDUCTOR, NETWORK (1005X4)	
RB706	1-234-400-21	CONDUCTOR, NETWORK (1005X4)	
RB801	1-234-378-21	RES, NETWORK 10K (1005X4)	
RB802	1-234-378-21	RES, NETWORK 10K (1005X4)	
RB810	1-234-378-21	RES, NETWORK 10K (1005X4)	
RB811	1-234-378-21	RES, NETWORK 10K (1005X4)	
RB812	1-234-378-21	RES, NETWORK 10K (1005X4)	
RB813	1-234-378-21	RES, NETWORK 10K (1005X4)	
RB814	1-234-378-21	RES, NETWORK 10K (1005X4)	
RB815	1-234-378-21	RES, NETWORK 10K (1005X4)	
< TRANSFORMER >			
T601	1-697-310-11	PULSE TRANSFORMER	
T602	1-697-310-11	PULSE TRANSFORMER	
T603	1-697-310-11	PULSE TRANSFORMER	
T604	1-697-310-11	PULSE TRANSFORMER	
< VIBRATOR >			
X401	1-814-404-11	QUARTZ CRYSTAL UNITS (24 MHz)	
X403	1-814-273-11	QUARTZ CRYSTAL UNIT (32.768 kHz)	
X601	1-814-242-11	VIBRATOR, CRYSTAL (25 MHz)	
*****			
A-1974-810-A	PENC BOARD, COMPLETE		
*****			
< CAPACITOR >			
C5051	1-118-385-11	CERAMIC CHIP 0.001uF 10% 50V	
C5053	1-118-385-11	CERAMIC CHIP 0.001uF 10% 50V	
< CONNECTOR >			
CN5301	1-569-775-21	PIN, CONNECTOR (SMD) 5P	
< ROTARY ENCODER >			
EN5005	1-487-023-22	ROTARY ENCODER (PUSH ENTER)	
< RESISTOR >			
R5119	1-216-809-11	METAL CHIP 100 5% 1/10W	
R5120	1-216-809-11	METAL CHIP 100 5% 1/10W	
R5574	1-216-833-11	METAL CHIP 10K 5% 1/10W	
*****			
POWER KEY BOARD			
*****			
< CONNECTOR >			
CN1002	1-580-057-11	PIN, CONNECTOR (SMD) 4P	
< LED >			
D1002	6-503-970-01	LED SELU5423E-STP15 (I/⊘)	

Ref. No.	Part No.	Description	Remark
< SWITCH >			
S1029	1-762-875-21	SWITCH, KEYBOARD (I/⊘)	
*****			
A-1945-077-A	SPTM BOARD, COMPLETE (AEP, UK)		
A-1945-078-A	SPTM BOARD, COMPLETE (US, CND)		
*****			
< CAPACITOR >			
C700	1-100-153-91	CERAMIC CHIP 220PF 5% 100V	
C701	1-118-345-11	CERAMIC CHIP 0.01uF 10% 25V	
C702	1-100-153-91	CERAMIC CHIP 220PF 5% 100V	
C703	1-118-345-11	CERAMIC CHIP 0.01uF 10% 25V	
< CONNECTOR >			
* CN701	1-564-216-00	PIN, CONNECTOR (3.96 mm PITCH) 5P	
< COIL >			
L700	1-411-906-11	COIL, AIR-CORE	
L701	1-411-906-11	COIL, AIR-CORE	
< RESISTOR >			
△ R700	1-249-393-91	CARBON 10 5% 1/4W F	
△ R701	1-249-393-91	CARBON 10 5% 1/4W F	
△ R702	1-249-389-91	CARBON 4.7 5% 1/4W F	
△ R703	1-249-389-91	CARBON 4.7 5% 1/4W F	
< TERMINAL >			
△ TB700	1-854-056-11	TERMINAL BOARD, SPEAKER 2P (SPEAKERS R)	
△ TB701	1-854-057-11	TERMINAL BOARD, SPEAKER 2P (SPEAKERS L)	
*****			
A-1945-084-A	STANBY BOARD, COMPLETE (AEP, UK)		
A-1945-085-A	STANBY BOARD, COMPLETE (US, CND)		
*****			
< CAPACITOR >			
C1901	1-128-991-21	ELECT CHIP 10uF 20% 50V	
C1903	1-126-948-11	ELECT 100uF 20% 35V	
C1906	1-118-361-11	CERAMIC CHIP 0.1uF 10% 50V	
C1907	1-114-329-11	CERAMIC CHIP 0.47uF 10% 50V	
△ C1909	1-118-661-11	CERAMIC 0.01uF 20% 250V	
< CONNECTOR >			
CN1901	1-770-470-21	PIN, CONNECTOR (PC BOARD) 6P	
△ *CN1903	1-565-792-11	PIN, CONNECTOR (3.96 mm PITCH) 2P	
△ *CN1904	1-793-660-11	PIN, CONNECTOR (PC BOARD) 3P	
< DIODE >			
D1901	8-719-053-18	DIODE 1SR154-400TE-25	
D1902	8-719-053-18	DIODE 1SR154-400TE-25	
D1903	8-719-053-18	DIODE 1SR154-400TE-25	
D1904	8-719-053-18	DIODE 1SR154-400TE-25	
D1905	6-502-961-01	DIODE DA2J10100L	
D1906	6-502-961-01	DIODE DA2J10100L	
D1907	6-502-961-01	DIODE DA2J10100L	
< FUSE HOLDER >			
△ FH1903	1-533-313-11	FUSE HOLDER	
△ FH1904	1-533-313-11	FUSE HOLDER	

Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
		< TRANSISTOR >		C5022	1-118-417-11	CERAMIC CHIP 0.1uF 10%	16V
Q1901	6-553-266-01	TRANSISTOR 2PD601ART		C5023	1-118-417-11	CERAMIC CHIP 0.1uF 10%	16V
Q1902	6-553-266-01	TRANSISTOR 2PD601ART		C5024	1-118-417-11	CERAMIC CHIP 0.1uF 10%	16V
Q1903	6-553-268-01	TRANSISTOR PDTC114ET		C5025	1-118-417-11	CERAMIC CHIP 0.1uF 10%	16V
Q1904	6-553-266-01	TRANSISTOR 2PD601ART		C5026	1-118-417-11	CERAMIC CHIP 0.1uF 10%	16V
* Q1905	6-551-721-01	FET SSM6J50TU (T5RSONYF)		C5027	1-118-417-11	CERAMIC CHIP 0.1uF 10%	16V
Q1906	6-553-266-01	TRANSISTOR 2PD601ART		C5028	1-116-151-11	CERAMIC CHIP 0.001uF 2%	50V
		< RESISTOR >		C5029	1-116-151-11	CERAMIC CHIP 0.001uF 2%	50V
R1901	1-218-879-11	METAL CHIP 22K 0.5%	1/10W	C5030	1-116-151-11	CERAMIC CHIP 0.001uF 2%	50V
R1902	1-218-863-11	METAL CHIP 4.7K 0.5%	1/10W	C5031	1-116-151-11	CERAMIC CHIP 0.001uF 2%	50V
R1903	1-218-879-11	METAL CHIP 22K 0.5%	1/10W	C5033	1-118-417-11	CERAMIC CHIP 0.1uF 10%	16V
R1904	1-216-821-11	METAL CHIP 1K 5%	1/10W	C5034	1-118-417-11	CERAMIC CHIP 0.1uF 10%	16V
R1905	1-250-664-11	METAL CHIP 100K 1%	1/10W	C5035	1-118-417-11	CERAMIC CHIP 0.1uF 10%	16V
△ R1907	1-249-389-91	CARBON 4.7 5%	1/4W F	C5036	1-118-417-11	CERAMIC CHIP 0.1uF 10%	16V
R1908	1-216-853-11	METAL CHIP 470K 5%	1/10W	C5037	1-118-417-11	CERAMIC CHIP 0.1uF 10%	16V
R1909	1-216-849-11	METAL CHIP 220K 5%	1/10W	C5041	1-118-391-11	CERAMIC CHIP 0.01uF 10%	50V
R1910	1-216-841-11	METAL CHIP 47K 5%	1/10W	C5042	1-118-391-11	CERAMIC CHIP 0.01uF 10%	50V
R1911	1-216-841-11	METAL CHIP 47K 5%	1/10W			< CONNECTOR >	
R1913	1-216-853-11	METAL CHIP 470K 5%	1/10W	CN5002	1-816-113-21	CONNECTOR 15P	
R1914	1-216-864-11	SHORT CHIP 0		CN5003	1-766-382-21	PIN, CONNECTOR (1.5 mm) (SMD) 10P	
		< RELAY >		CN5005	1-817-097-21	PIN, CONNECTOR (1.5 mm) (SMD) 13P	
△ RY1901	1-755-266-11	RELAY, AC POWER		CN5006	1-785-466-51	CONNECTOR, FFC/FPC 7P	
		< TRANSFORMER >		CN5007	1-785-466-51	CONNECTOR, FFC/FPC 7P	
△ T1901	1-492-498-11	STANDBY TRANSFORMER (AEP, UK)		CN5008	1-779-772-11	CONNECTOR 13P	
△ T1901	1-492-499-11	STANDBY TRANSFORMER (US, CND)		CN5010	1-820-116-51	CONNECTOR, FFC/FPC 17P	
		< VARISTOR >				< DIODE >	
△ VDR902	1-811-165-31	VARISTOR (TVR10471-D)		D5004	6-503-704-01	DIODE CUS521, H3SONYF	
*****				D5005	6-503-704-01	DIODE CUS521, H3SONYF	
A-1945-088-A	U-COM BOARD, COMPLETE	*****		D5006	6-503-704-01	DIODE CUS521, H3SONYF	
		< CAPACITOR >		D5007	6-503-704-01	DIODE CUS521, H3SONYF	
C1001	1-116-151-11	CERAMIC CHIP 0.001uF 2%	50V	D5011	8-719-073-35	DIODE RB551V-30TE-17	
C5001	1-118-418-11	CERAMIC CHIP 22uF 20%	6.3V	D5013	6-503-704-01	DIODE CUS521, H3SONYF	
C5002	1-116-734-11	CERAMIC CHIP 1uF 20%	16V	D5014	6-502-961-01	DIODE DA2J10100L	
C5003	1-118-417-11	CERAMIC CHIP 0.1uF 10%	16V	D5015	6-502-961-01	DIODE DA2J10100L	
C5004	1-118-417-11	CERAMIC CHIP 0.1uF 10%	16V	D5016	6-502-961-01	DIODE DA2J10100L	
C5005	1-116-734-11	CERAMIC CHIP 1uF 20%	16V	D5017	6-502-961-01	DIODE DA2J10100L	
C5006	1-118-418-11	CERAMIC CHIP 22uF 20%	6.3V	D5018	6-502-961-01	DIODE DA2J10100L	
C5007	1-118-417-11	CERAMIC CHIP 0.1uF 10%	16V	D5019	6-502-961-01	DIODE DA2J10100L	
* C5008	1-116-720-11	CERAMIC CHIP 10uF 20%	6.3V			< LUG TERMINAL >	
C5009	1-116-734-11	CERAMIC CHIP 1uF 20%	16V	* ET5001	1-780-408-11	TERMINAL, LUG	
C5010	1-118-417-11	CERAMIC CHIP 0.1uF 10%	16V	* ET5002	1-780-408-11	TERMINAL, LUG	
C5011	1-118-417-11	CERAMIC CHIP 0.1uF 10%	16V	* ET5003	1-780-408-11	TERMINAL, LUG	
C5012	1-118-417-11	CERAMIC CHIP 0.1uF 10%	16V			< FERRITE BEAD >	
C5013	1-118-417-11	CERAMIC CHIP 0.1uF 10%	16V	FB5001	1-400-862-11	BEAD, FERRITE	
C5014	1-118-041-11	CERAMIC CHIP 4.7uF 10%	10V	FB5002	1-400-862-11	BEAD, FERRITE	
C5015	1-118-417-11	CERAMIC CHIP 0.1uF 10%	16V			< IC >	
C5016	1-118-417-11	CERAMIC CHIP 0.1uF 10%	16V	IC5001	6-711-653-01	IC S-1206B33-U3T1G	
C5017	1-118-417-11	CERAMIC CHIP 0.1uF 10%	16V	IC5003	6-714-351-01	IC R1EX24016ASAS0A	
C5018	1-116-151-11	CERAMIC CHIP 0.001uF 2%	50V	IC5004	6-719-856-01	IC BU4229F-TR	
C5019	1-116-151-11	CERAMIC CHIP 0.001uF 2%	50V	IC5005	6-712-384-01	IC TC74VHC4052AFT (EK)	
C5020	1-118-417-11	CERAMIC CHIP 0.1uF 10%	16V	IC5006	A-1945-130-A	IC MB9AF156NPMC-G-JNE2 (for SERVICE)	
C5021	1-118-417-11	CERAMIC CHIP 0.1uF 10%	16V	IC5007	6-707-842-01	IC TC74LCX08FT (EKJ)	





Ref. No.	Part No.	Description	Remark
R5163	1-218-957-11	METAL CHIP 2.2K 5%	1/16W
R5164	1-216-864-11	SHORT CHIP 0	
R5165	1-218-941-81	METAL CHIP 100 5%	1/16W
R5166	1-218-965-11	METAL CHIP 10K 5%	1/16W
R5167	1-216-797-11	METAL CHIP 10 5%	1/10W
R5168	1-216-864-11	SHORT CHIP 0	
R5169	1-216-864-11	SHORT CHIP 0	
R5171	1-216-295-91	SHORT CHIP 0	
R5172	1-218-989-11	METAL CHIP 1M 5%	1/16W
R5173	1-218-989-11	METAL CHIP 1M 5%	1/16W
R5174	1-216-857-11	METAL CHIP 1M 5%	1/10W
R5178	1-216-833-11	METAL CHIP 10K 5%	1/10W
R5179	1-216-837-11	METAL CHIP 22K 5%	1/10W
R5186	1-218-990-81	SHORT CHIP 0	

< COMPOSITION CIRCUIT BLOCK >

RB5001	1-234-373-21	RES, NETWORK 220 (1005X4)
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< VIBRATOR >

X5001	1-781-646-21	VIBRATOR, CERAMIC (4 MHz)
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MISCELLANEOUS

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△ AC1	1-821-082-21	INLET, AC 2P
△ F902	1-532-388-33	FUSE (T 2 AL/250 V) (AEP, UK)
△ F902	1-532-504-33	FUSE (T 4 AL/250 V) (US, CND)
FC1	1-481-528-11	FILTER, CLAMP (FERRITE CORE)
FC2	1-481-528-11	FILTER, CLAMP (FERRITE CORE)
FC3	1-400-640-11	CORE, FERRITE
FC4	1-500-386-11	FILTER, CLAMP (FERRITE CORE)
FC5	1-481-528-11	FILTER, CLAMP (FERRITE CORE)
FC6	1-500-082-11	CLAMP, SLEEVE FERRITE
FC7	1-500-386-11	FILTER, CLAMP (FERRITE CORE)
FC8	1-500-082-11	CLAMP, SLEEVE FERRITE
FC9	1-500-082-11	CLAMP, SLEEVE FERRITE (AEP, UK)
FC10	1-500-386-11	FILTER, CLAMP (FERRITE CORE)
FC11	1-400-640-11	CORE, FERRITE
FFC2	1-828-774-51	WIRE (FLAT TYPE) (24 CORE) (See Note 3)
FFC3	1-828-760-51	WIRE (FLAT TYPE) (22 CORE) (See Note 3)
FFC4	1-828-002-51	WIRE (FLAT TYPE) (17 CORE) (See Note 3)
△ HDD1	1-458-715-11	HDD/TSB-AQUARIUS-SLIM (500GB) (Hard Disk Drive) (See Note 2)
LCD1	1-811-873-11	PANEL, LCD
△ M1	1-855-324-11	DC FAN
△ T1	1-697-296-11	TRANSFORMER, POWER (US, CND)
△ T1	1-697-304-11	TRANSFORMER, POWER (AEP, UK)
WBC1	1-458-601-31	CARD, WLAN/BT COMBO (See Note 1)
WR1	1-846-782-11	CABLE, COAXIAL (U.FL CONNECTOR) (for L-ch) (See Note 1)
WR2	1-846-781-11	CABLE, COAXIAL (U.FL CONNECTOR) (for R-ch) (See Note 1)
WR3	1-969-717-11	HARNESS (S-003)
WR4	1-969-719-11	HARNESS (E-001)
WR5	1-969-715-11	HARNESS (S-001)

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**Note 1:** When the WLAN/BT COMBO card (Ref. No. WBC1) and coaxial (U.FL connector) cables (Ref. No. WR1, WR2) are replaced, refer to "CHECKING METHOD OF NETWORK CONNECTION" on page 5.

**Note 2:** When the hard disk drive (Ref. No. HDD1) is replaced, refer to "NOTE OF REPLACING THE HARD DISK DRIVE (Ref. No. HDD1)" on page 4.

Ref. No.	Part No.	Description	Remark
		ACCESSORIES *****	
	1-492-558-11	REMOTE COMMANDER RM-ANU183 (S) (SILVER)	
	1-492-558-21	REMOTE COMMANDER RM-ANU183 (B) (BLACK)	
	1-837-633-12	POWER-SUPPLY CORD (AC power cord) (US, CND)	
	1-839-699-12	CORD, POWER (AC power cord) (AEP)	
	1-846-946-11	CABLE, ETHERNET (LAN cable)	

**Note 3:** Wires (flat type) for service is straight.  
When replacing wire (flat type), install it after bending it in the same form as that before replacement.

REVISION HISTORY

Ver.	Date	Description of Revision
1.0	2013.10	New

**How to search for a contact point of signal lines or the like in DIAGRAMS SECTION**

If a contact point of a BLOCK DIAGRAM, PRINTED WIRING BOARD or SCHEMATIC DIAGRAM is shown in a different page, use the PDF file search function to find one.

e.g.) If a contact point is shown as , follow the procedure below.

**Procedure:**

1. Press the [F] key while pressing the [Ctrl] key.
2. Input ">001Z" in the search box and press the [Enter] key.
3. The relevant part (page), where the contact point is shown, appears.

**Note:** If you still see the original page, press the [Enter] key again.